
STM32 microcontroller system memory boot mode

Introduction

The bootloader is stored in the internal boot ROM (system memory) of STM32 devices, and is programmed by ST during production. Its main task is to download the application program to the internal flash memory through one of the available serial peripherals (such as USART, CAN, USB, I²C, SPI). A communication protocol is defined for each serial interface, with a compatible command set and sequence.

This application note applies to the products listed in [Table 1](#), referred to as STM32 throughout the document. It describes the supported peripherals and hardware requirements to consider when using the bootloader.

Table 1. Applicable products

Type	Part number or product series
Microcontrollers	STM32C0 series: STM32C011xx, STM32C031xx
	STM32F0 series: STM32F03xxx, STM32F04xxx, STM32F05xxx, STM32F07xxx, STM32F09xxx
	STM32F1 series
	STM32F2 series
	STM32F3 series: STM32F301xx, STM32F302xx, STM32F303xx, STM32F318xx, STM32F328xx, STM32F334xx, STM32F358xx, STM32F373xx, STM32F378xx, STM32F398xx
	STM32F4 series: STM32F401xx, STM32F405xx, STM32F407xx, STM32F410xx, STM32F411xx, STM32F412xx, STM32F413xx, STM32F415xx, STM32F417xx, STM32F423xx, STM32F427xx, STM32F429xx, STM32F437xx, STM32F439xx, STM32F446xx, STM32F469xx, STM32F479xx
	STM32F7 series: STM32F722xx, STM32F723xx, STM32F732xx, STM32F733xx, STM32F745xx, STM32F746xx, STM32F756xx, STM32F765xx, STM32F767xx, STM32F769xx, STM32F777xx, STM32F779xx
	STM32G0 series: STM32G030xx, STM32G031xx, STM32G041xx, STM32G07xxx, STM32G08xxx, STM32G0B0xx, STM32G0B1xx, STM32G0C1xx, STM32G050xx, STM32G051xx, STM32G061xx
	STM32G4 series: STM32G431xx, STM32G441xx, STM32G47xxx, STM32G48xxx, STM32G491xx, STM32G4A1xx
	STM32H5 series: STM32H503xx, STM32H563xx, STM32H573xx
	STM32H7 series: STM32H72xxx, STM32H73xxx, STM32H74xxx, STM32H75xxx, STM32H7A3xx, STM32H7B3xx
	STM32L0 series
	STM32L1 series: STM32L100xx, STM32L151xx, STM32L152xx, STM32L162xx
	STM32L4 series: STM32L431xx, STM32L432xx, STM32L433xx, STM32L442xx, STM32L443xx, STM32L451xx, STM32L452xx, STM32L462xx, STM32L471xx, STM32L475xx, STM32L476xx, STM32L486xx, STM32L496xx, STM32L4A6xx, STM32L4R5xx, STM32L4R7xx, STM32L4R9xx, STM32L4S5xx, STM32L4S7xx, STM32L4S9xx, STM32L412xx, STM32L422xx, STM32L4P5xx, STM32L4Q5xx, STM32L431xx, STM32L432xx, STM32L433xx, STM32L442xx, STM32L443xx, STM32L451xx, STM32L452xx, STM32L462xx, STM32L471xx, STM32L475xx, STM32L476xx, STM32L486xx, STM32L496xx, STM32L4A6xx, STM32L4R5xx, STM32L4R7xx, STM32L4R9xx, STM32L4S5xx, STM32L4S7xx, STM32L4S9xx, STM32L412xx, STM32L422xx, STM32L4P5xx, STM32L4Q5xx
	STM32L5 series: STM32L552xx, STM32L562xx
	STM32WBA series: STM32WBA52xx
	STM32WB series: STM32WB10xx, STM32WB15xx, STM32WB30xx, STM32WB35xx, STM32WB50xx, STM32WB55xx
	STM32WL series: STM32WLE5xx STM32WL55xx
STM32U5 series: STM32U535xx, STM32U545xx, STM32U575xx, STM32U585xx, STM32U595xx, STM32U599xx, STM32U5A5xx, STM32U5A9xx, STM32U5F7xx, STM32U5F9xx, STM32U5G7xx, STM32U5G9xx	

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1 General information

This document applies to Arm^{®(a)}-based devices.

2 Related documents

For each supported product (listed in [Table 1](#)) refer to the following documents available on www.st.com:

- Datasheet or databrief
- Reference manual
- Application notes
 - AN3154: *CAN protocol used in the STM32 bootloader*
 - AN3155: *USART protocol used in the STM32 bootloader*
 - AN3156: *USB DFU protocol used in the STM32 bootloader*
 - AN4221: *I2C protocol used in the STM32 bootloader*
 - AN4286: *SPI protocol used in the STM32 bootloader*
 - AN5405: *FDCAN protocol used in the STM32 bootloader*
 - AN5927: *I3C protocol used in the STM32 bootloader*

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3 Glossary

C0 series:

STM32C011xx indicates STM32C011xx devices.

STM32C031xx indicates STM32C031xx devices.

F0 series:

STM32F03xxx indicates STM32F030x4, STM32F030x6, STM32F038x6, STM32F030xC, STM32F031x4, and STM32F031x6 devices.

STM32F04xxx indicates STM32F042x4 and STM32F042x6 devices.

STM32F05xxx and STM32F030x8 devices indicates STM32F051x4, STM32F051x6, STM32F051x8, STM32F058x8, and STM32F030x8 devices.

STM32F07xxx indicates STM32F070x6, STM32F070xB, STM32F071xB, STM32F072x8, and STM32F072xB devices.

STM32F09xxx indicates STM32F091xx and STM32F098xx devices.

F1 series:

STM32F10xxx indicates Low-density, Medium-density, High-density, Low-density value line, Medium-density value line, and High-density value line devices:

Low-density devices are STM32F101xx, STM32F102xx, and STM32F103xx microcontrollers, where the flash memory density ranges between 16 and 32 Kbytes.

Medium-density devices are STM32F101xx, STM32F102xx, and STM32F103xx microcontrollers, where the flash memory density ranges between 64 and 128 Kbytes.

High-density devices are STM32F101xx and STM32F103xx microcontrollers, where the flash memory density ranges between 256 and 512 Kbytes.

Low-density value line devices are STM32F100xx microcontrollers, where the flash memory density ranges between 16 and 32 Kbytes.

Medium-density value line devices are STM32F100xx microcontrollers, where the flash memory density ranges between 64 and 128 Kbytes.

High-density value line devices are STM32F100xx microcontrollers, where the flash memory density ranges between 256 and 512 Kbytes.

STM32F105xx/107xx indicates STM32F105xx and STM32F107xx devices.

STM32F10xxx XL-density indicates STM32F101xx and STM32F103xx devices, where the flash memory density ranges between 768 Kbytes and 1 Mbyte.

F2 series:

STM32F2xxxx indicates STM32F215xx, STM32F205xx, STM32F207xx, and STM32F217xx devices.

F3 series:

STM32F301xx/302x4(6/8) indicates STM32F301x4, STM32F301x6, STM32F301x8, STM32F302x4, STM32F302x6, and STM32F302x8 devices.

STM32F302xB(C)/303xB(C) indicates STM32F302xB, STM32F302xC, STM32F303xB and STM32F303xC devices.

STM32F302xD(E)/303xD(E) indicates STM32F302xD, STM32F302xE, STM32F303xD, and STM32F303xE devices.

STM32F303x4(6/8)/334xx/328xx indicates STM32F303x4, STM32F303x6, STM32F303x8, STM32F334x4, STM32F334x6, STM32F334x8, and STM32F328x8 devices.

STM32F318xx indicates STM32F318x8 devices.

STM32F358xx indicates STM32F358xC devices.

STM32F373xx indicates STM32F373x8, STM32F373xB and STM32F373xC devices.

STM32F378xx indicates STM32F378xC devices.

STM32F398xx indicates STM32F398xE devices.

F4 series:

STM32F40xxx/41xxx indicates STM32F405xx, STM32F407xx, STM32F415xx, and STM32F417xx devices.

STM32F401xB(C) indicates STM32F401xB and STM32F401xC devices.

STM32F401xD(E) indicates STM32F401xD and STM32F401xE devices.

STM32F410xx indicates STM32F410x8 and STM32F410xB devices.

STM32F411xx indicates STM32F411xD and STM32F411xE devices.

STM32F412xx indicates STM32F412Cx, STM32F412Rx, STM32F412Vx and STM32F412Zx devices.

STM32F413xx/423xx indicates STM32F413xG, STM32F413xH and STM32F423xH devices.

STM32F42xxx/43xxx indicates STM32F427xx, STM32F429xx, STM32F437xx, and STM32F439xx devices.

STM32F446xx indicates STM32F446xE and STM32F446xC devices.

STM32F469xx/479xx indicates STM32F469xE, STM32F469xG, STM32F469xI, STM32F479xG, and STM32F479xI devices.

F7 series:

STM32F72xxx/73xxx indicates STM32F722xx, STM32F723xx, STM32F732xx, and STM32F733xx devices.

STM32F74xxx/75xxx indicates STM32F745xx, STM32F746xx, and STM32F756xx devices.

STM32F76xxx/77xxx indicates STM32F765xx, STM32F767xx, STM32F769xx, STM32F777xx, and STM32F779xx devices.

G0 series:

STM32G03xxx/04xxx indicates STM32G03xxx and STM32G04xxx devices.

STM32G07xxx/08xxx indicates STM32G07xxx and STM32G08xxx devices.

STM32G0B1xx/C1xx indicates STM32GB1xx and STM32G0C1xxx devices.

STM32G0B0xx indicates STM32G0B0xx devices.

STM32G05xxx/61xx indicates STM32G050xx, STM32G051xx, STM32G061xx devices.

G4 series:

STM32G431xx indicates STM32G431xx devices.

STM32G441xx indicates STM32G441xx devices.

STM32G47xxx indicates STM32G471xx, STM32G473xx, and STM32G474xx devices.

STM32G48xxx indicates STM32G483xx and STM32G484xx devices.

STM32G491xx indicates STM32G491xx devices.

STM32G4A1xx indicates STM32G4A1xx devices.

H5 series:

STM32H503xx indicates STM32H503xx devices.

STM32H563xx/73xx indicates STM32H563xx and STM32H573xx devices.

H7 series:

STM32H72xxx/73xxx indicates STM32H72xxx and STM32H73xxx devices.

STM32H74xxx/75xxx indicates STM32H74xxx and STM32H75xxx devices.

STM32H7A3xx/7B3xx indicates STM32H7A3xx/STM32H7B3xx devices.

L0 series:

STM32L01xxx/02xxx indicates STM32L011xx and STM32L021xx devices.

STM32L031xx/041xx indicates STM32L031xx and STM32L041xx devices.

STM32L05xxx/06xxx indicates STM32L051xx, STM32L052xx, STM32L053xx, STM32L062xx, and STM32L063xx ultra-low power devices.

STM32L07xxx/08xxx indicates STM32L071xx, STM32L072xx, STM32L073xx, STM32L081xx, STM32L082xx, and STM32L083xx devices.

L1 series:

STM32L1xxx6(8/B) indicates STM32L1xxV6T6, STM32L1xxV6H6, STM32L1xxR6T6, STM32L1xxR6H6, STM32L1xxC6T6, STM32L1xxC6H6, STM32L1xxV8T6, STM32L1xxV8H6, STM32L1xxR8T6, STM32L1xxR8H6, STM32L1xxC8T6, STM32L1xxC8H6, STM32L1xxVBT6, STM32L1xxVBH6, STM32L1xxRBT6, STM32L1xxRBH6, STM32L1xxCBT6, and STM32L1xxCBH6 ultra-low power devices.

STM32L1xxx6(8/B)A indicates STM32L1xxV6T6-A, STM32L1xxV6H6-A, STM32L1xxR6T6-A, STM32L1xxR6H6-A, STM32L1xxC6T6-A, STM32L1xxC6H6-A, STM32L1xxV8T6-A, STM32L1xxV8H6-A, STM32L1xxR8T6-A, STM32L1xxR8H6-A, STM32L1xxC8T6-A, STM32L1xxC8H6-A, STM32L1xxVBT6-A, STM32L1xxVBH6-A, STM32L1xxRBT6-A, STM32L1xxRBH6-A, STM32L1xxCBT6-A, and STM32L1xxCBH6-A ultra-low power devices.

STM32L1xxxC indicates STM32L1xxVCT6, STM32L1xxVCH6, STM32L1xxRCT6, STM32L1xxUCY6, STM32L1xxCCT6, and STM32L1xxCCU6 ultra-low power devices.

STM32L1xxxD indicates STM32L1xxZDT6, STM32L1xxQDH6, STM32L1xxVDT6, STM32L1xxRDY6, STM32L1xxRDT6, STM32L1xxZCT6, STM32L1xxQCH6, STM32L1xxRCY6, STM32L1xxVCT6-A, and STM32L1xxRCT6-A ultra-low power devices.

STM32L1xxxE indicates STM32L1xxZET6, STM32L1xxQEH6, STM32L1xxVET6, STM32L1xxVEY6, and STM32L1xxRET6 ultra-low power devices.

L4 series:

STM32L412xx/422xx indicates STM32L412xB, STM32L412x8, and STM32L422xB devices.

STM32L43xxx/44xxx indicates STM32L431xx, STM32L432xx, STM32L433xx and STM32L442xx, and STM32L443xx devices.

STM32L45xxx/46xxx indicates STM32L451xx, STM32L452xx, and STM32L462xx devices.

STM32L47xxx/48xxx indicates STM32L471xx, STM32L475xx, STM32L476xx, and STM32L486xx devices.

STM32L496xx/4A6xx indicates STM32L496xE, STM32L496xG, and STM32L4A6xG devices.

STM32L4Rxxx/4Sxxx indicates STM32L4R5xx, STM32L4R7xx, STM32L4R9xx, STM32L4S5xx, STM32L4S7xx, and STM32L4S9xx devices.

STM32L4P5xx/4Q5xx indicates STM32L4P5xx/STM32L4Q5xx devices.

L5 series:

STM32L552xx indicates STM32L552xx devices.

STM32L562xx indicates STM32L562xx devices.

WBA series:

STM32WBA52xx indicates STM32WBA52xx devices.

WB series:

STM32WB10xx indicates STM32WB10xx devices.

STM32WB15xx indicates STM32WB15xx devices.

STM32WB30xx indicates STM32WB30xx devices.

STM32WB35xx indicates STM32WB35xx devices.

STM32WB50xx indicates STM32WB50xx devices.

STM32WB55xx indicates STM32WB55Cx, STM32WB55Rx, and STM32WB55Vx devices.

WL series:

STM32WLE5xx indicates STM32WLE5xx devices.

STM32WL55xx indicates STM32WL55xx devices.

U5 series:

STM32U535xx indicates STM32U535xx devices.

STM32U545xx indicates STM32U545xx devices.

STM32U575xx indicates STM32U575xx devices.

STM32U585xx indicates STM32U585xx devices.

STM32U595xx indicates STM32U595xx devices.

STM32U599xx indicates STM32U599xx devices.

STM32U5A5xx indicates STM32U5A5xx devices.

STM32U5A9xx indicates STM32U5A9xx devices.

STM32U5F7xx indicates STM32U5F7xx devices.

STM32U5F9xx indicates STM32U5F9xx devices.

STM32U5G7xx indicates STM32U5G7xx devices.

STM32U5G9xx indicates STM32U5G9xx devices.

Note: *BL_USART_Loop* refers to the USART bootloader execution loop.
BL_CAN_Loop refers to the CAN bootloader execution loop.
BL_I2C_Loop refers to the I2C bootloader execution loop.
BL_SPI_Loop refers to the SPI bootloader execution loop.

4 General bootloader description

4.1 Bootloader activation

The bootloader is activated by applying one of the patterns described in [Table 2](#).

If boot from Bank2 option is activated (for products supporting this feature), the bootloader executes Dual Boot mechanism as described in figures “Dual bank boot implementation for STM32xxxx” (example: [Figure 40](#)), otherwise bootloader selection protocol is executed as described in figures “Bootloader VY.x selection for STM32xxxx” (example: [Figure 21](#)), where STM32xxxx is the relative STM32 product.

When readout protection Level2 is activated, the MCU does not boot on system memory, and bootloader cannot be executed (unless jumping to it from flash user code, all commands are not accessible except Get, GetID, and GetVersion).

Table 2. Bootloader activation patterns

Pattern	Condition
Pattern 1	Boot0(pin) = 1 and Boot1(pin) = 0
Pattern 2	Boot0(pin) = 1 and nBoot1(bit) = 1
Pattern 3	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 1
	Boot0(pin) = 0, BFB2(bit) = 0 and both banks do not contain valid code
Pattern 4	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 1
	Boot0(pin) = 0, BFB2(bit) = 0 and both banks do not contain valid code
	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 0
Pattern 5	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2(bit) = 0
	Boot0(pin) = 0, BFB2(bit) = 1 and both banks do not contain valid code
	Boot0(pin) = 1, Boot1(pin) = 0 and BFB2 (bit) = 1
Pattern 6	Boot0(pin) = 1, nBoot1(bit) = 1 and nBoot0_SW(bit) = 1
	nBoot0(bit) = 0, nBoot1(bit) = 1 and nBoot0_SW(bit) = 0
	Boot0(pin) = 0, nBoot0_SW(bit) = 1 and main flash memory empty
	nBoot0(bit) = 1, nBoot0_SW(bit)=0 and main flash memory empty
Pattern 7	Boot0(pin) = 1, nBoot1(bit) = 1 and BFB2(bit) = 0
	Boot0(pin) = 0, BFB2(bit) = 1 and both banks do not contain valid code
	Boot0(pin) = 1, nBoot1(bit) = 1 and BFB2(bit) = 1
Pattern 8	Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x0040
	Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x0040

Table 2. Bootloader activation patterns (continued)

Pattern	Condition
Pattern 9	nDBANK(bit) = 1, Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x0040
	nDBANK(bit) = 1, Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x0040
	nDBANK(bit) = 0, nDBOOT(bit) = 1, Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x0040
	nDBANK(bit) = 0, nDBOOT(bit) = 1, Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x0040
	nDBANK(bit) = 0, nDBOOT(bit) = 0, BOOT_ADDx(optionbyte) out of memory range or in ICP memory range
	nDBANK(bit) = 0, nDBOOT(bit) = 0, BOOT_ADDx(optionbyte) in flash memory range and both banks do not contain valid code
Pattern 10	Boot(pin) = 0 and BOOT_ADD0(optionbyte) = 0x1FF0
	Boot(pin) = 1 and BOOT_ADD1(optionbyte) = 0x1FF0
Pattern 11	nBoot0(bit) = 0, nBoot1(bit) = 1, nBOOT0_SEL(bit) = 1 and BOOT_LOCK(bit) = 0
	Boot0(pin) = 1, nBoot1(bit) = 1, BOOT_LOCK(bit) = 0 and nBOOT0_SEL (bit) = 0
	nBoot0(bit) = 1, nBOOT0_SEL(bit) = 1, BOOT_LOCK(bit) = 0 and main flash memory empty
	Boot0(pin) = 0, nBOOT0_SEL(bit) = 0, BOOT_LOCK(bit) = 0 and main flash memory empty
Pattern 12	TZen = 0, Boot0(pin) = 0, nSWBoot0(bit) = 1 and NSBOOTADD0 [24:0] = 0x017F200
	TZen = 0, Boot0(pin) = 1, nSWBoot0(bit) = 1 and NSBOOTADD1 [24:0] = 0x017F200
	TZen = 0, nBoot0(bit) = 0, nSWBoot0(bit) = 0 and NSBOOTADD1 [24:0] = 0x017F200
	TZen = 0, nBoot0(bit) = 1, nSWBoot0(bit) = 0 and NSBOOTADD0 [24:0] = 0x017F200
	TZen = 1, Boot0(pin) = 0, nSWBoot0(bit) = 1 and SECBOOTADD0 [24:0] = 0x01FF000 & RSSCMD = 0
	TZen = 1, Boot0(pin) = 1, nSWBoot0(bit) = 1 & RSSCMD = 0, BOOT_LOCK=0 or (BOOT_LOCK = 1 and SECBOOTADD0 [24:0] = 0x01FF000)
	TZen = 1, nBoot0(bit) = 1, nSWBoot0(bit) = 0 and SECBOOTADD0 [24:0] = 0x01FF000 & RSSCMD = 0, BOOT_LOCK=0 or (BOOT_LOCK = 1 and SECBOOTADD0 [24:0] = 0x01FF000)
	TZen = 1, nBoot0(bit) = 0, nSWBoot0(bit) = 0 & RSSCMD = 0, BOOT_LOCK=0 or BOOT_LOCK = 1 and SECBOOTADD1 [24:0] = 0x01FF000
Pattern 13	nBoot0(bit) = 0, nBoot1(bit) = 1 and nSWBoot0(bit) = 0
	nBoot0(bit) = 1, nBoot1(bit) = 1, nSWBoot0(bit) = 0 and user flash empty
	nBoot1(bit) = 1, nSWBoot0(bit) = 1 and Boot0(pin) = 1
	nBoot1(bit) = 1, nSWBoot0(bit) = 1, Boot0(pin) = 0 and user flash empty

Table 2. Bootloader activation patterns (continued)

Pattern	Condition
Pattern 14	BOOT_LOCK(bit) = 0, nBoot1(bit) = 1, Boot0(pin) = 1 and nSWBoot0(bit) = 1
	BOOT_LOCK(bit) = 0, nBoot1(bit) = 1, nBoot0(bit) = 0 and nSWBoot0(bit) = 0
	BOOT_LOCK(bit) = 0, Boot0(pin) = 0, nSWBoot0(bit) = 1, BFB2(bit)=1 and both banks do not contain valid code
	BOOT_LOCK(bit) = 0, nBoot0(bit) = 1, nSWBoot0(bit) = 0, BFB2(bit)=1 and both banks do not contain valid code
Pattern 15	BOOT_LOCK(bit)=0, Boot0(pin) = 1, nBoot1(bit) = 1 and nBoot0_SW(bit) = 1
	BOOT_LOCK(bit)=0, nBoot0(bit) = 0, nBoot1(bit) = 1 and nBoot0_SW(bit) = 0
Pattern 16	Boot0(pin) = 1, nBoot1(bit) = 1 and nBoot0_SW(bit) = 1
	nBoot0(bit) = 0, nBoot1(bit) = 1 and nBoot0_SW(bit) = 0
	Boot0(pin) = 0, nBoot0_SW(bit) = 1 and main flash memory empty
Pattern 17	PRODUCT_STATE = Open and Boot0(pin) = 1
	PRODUCT_STATE = Provisioning

Note: *nBoot0_SW* means either *nSWBoot0* or *nBOOT0_SEL*, depending upon the product.

Note: *BOOT_LOCK* implementation is product dependent. See the reference manual for more details.

In addition to the patterns described above, the user can execute bootloader by performing a jump to system memory from user code. Before jumping to bootloader:

- Disable all peripheral clocks
- Disable used PLL
- Disable interrupts
- Clear pending interrupts

System memory boot mode can be exited by getting out from bootloader activation condition and generating hardware reset or using Go command to execute user code.

Note: *When executing the Go command, the peripheral registers used by the bootloader are not initialized to their default reset values before jumping to the user application. They must be reconfigured in the user application if they are used. So, if the application uses the IWDG, the IWDG prescaler value must be adapted to meet requirements (since the prescaler was set to its maximum value). For some products, not all reset values are set. For more information, refer to the known limitations detailed for each product bootloader version.*

Note: *On devices with dual bank boot, to jump to system memory from user code the user must first remap the system memory bootloader at address 0x00000000 using SYSCFG register (except for STM32F7 series), then jump to bootloader. For the STM32F7 series, the user must disable nDBOOT and/or nDBANK features (in option bytes), then jump to bootloader. For STM32L0 series, the jump to system memory from user code is not possible.*

Note: *For STM32 devices embedding bootloader using the DFU/CAN interface in which the external clock source (HSE) is required for DFU/CAN operations, the detection of the HSE value is done dynamically by the bootloader firmware and is based on the internal oscillator clock (HSI, MSI). When (because of temperature variations or other conditions) the internal*

oscillator precision is altered above the tolerance band (1% around the theoretical value), the bootloader can calculate a wrong HSE frequency value. In this case, the bootloader DFU/CAN interfaces can malfunction, or not work at all.

4.2 Bootloader identification

Depending on the device, the bootloader can support one or more embedded serial peripherals used to download the code to the internal flash memory. The bootloader identifier (ID) provides information about the supported serial peripherals.

For a given STM32 device, the bootloader is identified by means of the:

1. **Bootloader (protocol) version:** version of the serial peripheral (e.g. USART, CAN, USB) communication protocol used in the bootloader. This version can be retrieved using the bootloader Get Version command.
2. **Bootloader identifier (ID):** version of the STM32 device bootloader, coded on one byte in the **0xXY** format, where:
 - **X** specifies the embedded serial peripheral(s) used by the device bootloader:
 - X = 1: one USART is used
 - X = 2: two USARTs are used
 - X = 3: USART, CAN, and DFU are used
 - X = 4: USART and DFU are used
 - X = 5: USART and I²C are used
 - X = 6: I²C is used
 - X = 7: USART, CAN, DFU, and I²C are used
 - X = 8: I2C and SPI are used
 - X = 9: USART, CAN (or FDCAN), DFU, I²C, and SPI are used
 - X = 10: USART, DFU, FDCAN, and SPI are used
 - X = 11: USART, I2C, and SPI are used
 - X = 12: USART and SPI are used
 - X = 13: USART, DFU, I2C, and SPI are used
 - X = 14: USART, DFU, I2C, I3C, FDCAN, and SPI are used
 - **Y** specifies the device bootloader version
For example, if the bootloader ID is 0x10, this is the first version of the device bootloader that uses only one USART.
The bootloader ID is programmed in the last byte address - 1 of the device system memory and can be read by using the bootloader “Read memory” command or by direct access to the system memory via JTAG/SWD.

Note: The bootloader ID format is applied to all STM32 products, except the STM32F1xx devices. The bootloader version for the STM32F1xx applies only to the embedded device bootloader version and not to its supported protocols.

Table 3 provides identification information of the bootloaders embedded in STM32 devices.

Table 3. Embedded bootloaders

Series	Device		Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
				ID	Memory location	
C0	STM32C011xx		USART1 I2C1	0x51	0x1FFF17FE	USART (V3.1) I2C1(V1.1)
	STM32C031xx		USART1 I2C1	0x52	0x1FFF17FE	USART (V3.1) I2C1(V1.1)
F0	STM32F05xxx/STM32F030x8		USART1/USART2	0x21	0x1FFFF7A6	USART (V3.1)
	STM32F03xx4/6		USART1	0x10	0x1FFFF7A6	USART (V3.1)
	STM32F030xC		USART1 I2C1	0x52	0x1FFFF796	USART (V3.1) I2C1(V1.0)
	STM32F04xxx		USART1/USART2 DFU (USB device FS) I2C1	0xA1	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
	STM32F071xx/072xx		USART1/USART2 DFU (USB device FS) I2C1	0xA1	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
F0	STM32F070x6		USART1/USART2 DFU (USB device FS) I2C1	0xA2	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
	STM32F070xB		USART1/USART2 DFU (USB device FS) I2C1	0xA3	0x1FFFF6A6	USART (V3.1) DFU (V2.2) I2C (V1.0)
	STM32F09xxx		USART1/USART2 I2C1	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)
F1	STM32F10xxx	Low-density	USART1	NA	NA	USART (V2.2)
		Medium-density	USART1	NA	NA	USART (V2.2)
		High-density	USART1	NA	NA	USART (V2.2)
		Medium-density value line	USART1	0x10	0x1FFFF7D6	USART (V2.2)
		High-density value line	USART1	0x10	0x1FFFF7D6	USART (V2.2)
	STM32F105xx/107xx		USART1/USART2 (remapped) CAN2 (remapped) DFU (USB device)	NA	NA	USART (V2.2 ⁽¹⁾) CAN (V2.0) DFU(V2.2)
	STM32F10xxx XL-density		USART1/USART2 (remapped)	0x21	0x1FFFF7D6	USART (V3.0)
F2	STM32F2xxxx		USART1/USART3	0x20	0x1FFF77DE	USART (V3.0)
			USART1/USART3 CAN2 DFU (USB device FS)	0x33	0x1FFF77DE	USART (V3.1) CAN (V2.0) DFU (V2.2)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
F3	STM32F373xx	USART1/USART2/DFU (USB device FS)	0x41	0x1FFFF7A6	USART (V3.1) DFU (V2.2)
	STM32F378xx	USART1/USART2/ I2C1	0x50	0x1FFFF7A6	USART (V3.1) I2C (V1.0)
	STM32F302xB(C)/303xB(C)	USART1/USART2/DFU (USB device FS)	0x41	0x1FFFF796	USART (V3.1) DFU (V2.2)
	STM32F358xx	USART1/USART2/ I2C1	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)
	STM32F301xx/302x4(6/8)	USART1/USART2/DFU (USB device FS)	0x40	0x1FFFF796	USART (V3.1) DFU (V2.2)
	STM32F318xx	USART1/USART2/ I2C1/ I2C3	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)
	STM32F302xD(E)/303xD(E)	USART1/USART2/DFU (USB device FS)	0x40	0x1FFFF796	USART (V3.1) DFU (V2.2)
	STM32F303x4(6/8)/334xx/328xx	USART1/USART2/ I2C1	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)
	STM32F398xx	USART1/USART2/ I2C1/I2C3	0x50	0x1FFFF796	USART (V3.1) I2C (V1.0)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
F4	STM32F40xxx/41xxx	USART1/USART3/ CAN2 DFU (USB device FS)	0x31	0x1FFF77DE	USART (V3.1) CAN (V2.0) DFU (V2.2)
		USART1/USART3/ CAN2 DFU (USB device FS) I2C1/I2C2/I2C3/ SPI1/SPI2	0x91	0x1FFF77DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI(V1.1) I2C (V1.0)
	STM32F42xxx/43xxx	USART1/USART3/ CAN2 DFU (USB device FS) / I2C1	0x70	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.0)
		USART1/USART3/ CAN2 DFU (USB device FS) SPI1/ SPI2/ SPI4 I2C1/I2C2/I2C3/	0x91	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI(V1.1) I2C (V1.0)
	STM32F401xB(C)	USART1/USART2 DFU (USB device FS) / SPI1/SPI2/ SPI3 I2C1/I2C2/I2C3	0xD1	0x1FFF76DE	USART (V3.1) DFU (V2.2) SPI(V1.1) I2C (V1.0)
	STM32F401xD(E)	USART1/USART2 DFU (USB device FS) SPI1/SPI2/ SPI3 I2C1/I2C2/I2C3	0xD1	0x1FFF76DE	USART (V3.1) DFU (V2.2) SPI(V1.1) I2C (V1.1)
	STM32F410xx	USART1/USART2/ I2C1/I2C2/I2C4 SPI1/SPI2	0xB1	0x1FFF76DE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32F411xx	USART1/USART2/ DFU (USB device FS)/ SPI1/SPI2/ SPI3 I2C1/I2C2/I2C3	0xD0	0x1FFF76DE	USART (V3.1) DFU (V2.2) SPI(V1.1) I2C (V1.1)
	STM32F412xx	USART1/USART2/ USART3/CAN2 DFU (USB device FS)/ I2C1/I2C2/I2C3/I2C4/ SPI1/SPI3/SPI4	0x91	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI (V1.1) I2C (V1.2)
	STM32F413xx/423xx	USART1/USART2/ USART3/CAN2 DFU (USB device FS)/ I2C1/I2C2/I2C3/I2C4/ SPI1/SPI3/SPI4	0x90	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.2) SPI (V1.1)
	STM32F446xx	USART1/USART3 CAN2 DFU (USB device FS) I2C1/I2C2/I2C3 SPI1/ SPI2/ SPI4	0x90	0x1FFF76DE	USART (V3.1) CAN (V2.0) DFU (V2.2) SPI(V1.1) I2C (V1.2)
	STM32F469xx/479xx	USART1/USART3 I2C1/I2C2/I2C3 CAN2 DFU (USB device FS) SPI1/ SPI2/ SPI4	0x90	0x1FFF76DE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
F7	STM32F72xxx/73xxx	USART1/USART3/ CAN1 DFU (USB device FS)/ I2C1/I2C2/I2C3/ SPI1/SPI2/SPI4	0x90	0x1FF0EDBE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.2) SPI (V1.2)
	STM32F74xxx/75xxx	USART1/USART3/ I2C1/I2C2/I2C3/ CAN2 DFU (USB device FS)	0x70	0x1FF0EDBE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2)
		USART1/USART3/ I2C1/I2C2/I2C3/ CAN2 DFU (USB device FS)/ SPI1/SPI2/SPI4	0x90	0x1FF0EDBE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.2)
	STM32F76xxx/77xxx	USART1/USART3/ CAN2 DFU (USB device FS)/ I2C1/I2C2/I2C3/ SPI1/SPI2/SPI4	0x93	0x1FF0EDBE	USART (V3.1) CAN (V2.0) DFU (V2.2) I2C (V1.2) SPI (V1.2)
G0	STM32G07xxx/08xxx	USART1/USART2/ USART3/I2C1/I2C2/ SPI1/SPI2	0xB3	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32G03xxx/04xxx	USART1/USART2/ I2C1/I2C2	0x53	0x1FFF1FFE	USART (V3.1) I2C (V1.2)
	STM32G0B0xx	USART1/USART2/USART3 I2C1/I2C2 SPI1/SPI2 DFU (USB device FS)	0xD0	0x1FFF9FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)
	STM32G0B1xx/0C1xx	USART1/USART2/USART3 I2C1/I2C2 SPI1/SPI2 DFU (USB device FS) FDCAN	0x92	0x1FFF9FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.0)
	STM32G05xxx/061xx	USART1/USART2 I2C1/I2C2	0x51	0x1FFF1FFE	USART (V3.1) I2C (V1.2)
G4	STM32G431xx/441xx	USART1/USART2/USART3 I2C2/I2C3 SPI1/SPI2 DFU (USB device FS)	0xD4	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)
	STM32G47xxx/48xxx	USART1/USART2/USART3 I2C2/I2C3/I2C4 SPI1/SPI2 DFU (USB device FS)	0xD5	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)
	STM32G491xx/4A1xx	USART1/USART2/USART3 I2C2/I2C3 SPI1/SPI2 DFU (USB device FS)	0xD2	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
H5	STM32H503xx	USART1/USART2/USART3 I2C2 I3C1 SPI1/SPI2/SPI3 USB DFU FDCAN1	0xE1	0x0BF8FFFE	USART (V4.0) I2C (V2.0) I3C (V1.0) SPI (V2.0) USB (V3.0) FDCAN (V2.0)
	STM32H563xx/73xx	USART1/USART2/USART3 I2C3/I2C4 I3C1 SPI1/SPI2/SPI3 USB DFU FDCAN2	0xE4	0x0BF9FAFE	USART (V4.0) I2C (V2.0) I3C (V1.0) SPI (V2.0) USB (V3.0) FDCAN (V2.0)
H7	STM32H72xxx/73xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2/SPI3/SPI4 FDCAN1	0x93	0x1FF1E7FE	USART (V3.1) I2C (V1.2) DFU (V2.2) SPI (V1.1) FDCAN (V1.1)
	STM32H74xxx/75xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2/SPI3/SPI4 FDCAN1	0x91	0x1FF1E7FE	USART (V3.1) I2C (V1.1) DFU (V2.2) SPI (V1.1) FDCAN (V1.1)
	STM32H7A3xx/B3xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2/SPI3/SPI4 FDCAN1	0x92	0x1FF13FFE	USART (V3.1) I2C (V1.2) DFU (V2.2) SPI (V1.2) FDCAN (V1.1)
L0	STM32L01xxx/02xxx	USART2 SPI1	0xC3	0x1FF00FFE	USART (V3.1) SPI (V1.1)
	STM32L031xx/041xx	USART2 SPI1	0xC0	0x1FF00FFE	USART (V3.1) SPI (V1.1)
	STM32L05xxx/06xxx	USART1/USART2/ SPI1/ SPI2	0xC0	0x1FF00FFE	USART (V3.1) SPI (V1.1)
	STM32L07xxx/08xxx	USART1/USART2/ DFU (USB device FS)	0x41	0x1FF01FFE	USART (V3.1) DFU (V2.2)
USART1/USART2 SPI1/SPI2/ I2C1/I2C2		0xB2	0x1FF01FFE	USART (V3.1) SPI (V1.1) I2C (V1.2)	
L1	STM32L1xxx6(8/B)	USART1/USART2	0x20	0x1FF00FFE	USART (V3.0)
	STM32L1xxx6(8/B)A	USART1/USART2	0x20	0x1FF00FFE	USART (V3.1)
	STM32L1xxxC	USART1/USART2 DFU (USB device FS)	0x40	0x1FF01FFE	USART (V3.1) DFU (V2.2)
	STM32L1xxxD	USART1/USART2 DFU (USB device FS)	0x45	0x1FF01FFE	USART (V3.1) DFU (V2.2)
	STM32L1xxxE	USART1/USART2 DFU (USB device FS)	0x40	0x1FF01FFE	USART (V3.1) DFU (V2.2)

Table 3. Embedded bootloaders (continued)

Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
L4	STM32L412xx/422xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 DFU (USB device FS) SPI1/SPI2	0xD1	0x1FFF6FFE	USART (V3.1) I2C (V1.2) DFU (V2.2) SPI (V1.1)
	STM32L43xxx/44xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS) SPI1/SPI2	0x91	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
	STM32L45xxx/46xxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS) SPI1/SPI2	0x92	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
	STM32L47xxx/48xxx	USART1/USART2/ USART3 I2C1/I2C2/I2C3 DFU (USB device FS)	0xA3	0x1FFF6FFE	USART (V3.1) I2C (V1.2) DFU (V2.2)
		USART1/USART2/ USART3 I2C/I2C2/I2C3 SPI1/SPI2 CAN1 DFU (USB device FS)	0x92	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) CAN(V2.0) DFU(V2.2)
	STM32L496xx/4A6xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS)/ SPI1/SPI2	0x93	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
	STM32L4Rxxx/STM32L4Sxxx	USART1/USART2/USART3 I2C1/I2C2/I2C3 CAN1 DFU (USB device FS)/ SPI1/SPI2	0x95	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)
STM32L4P5xx /Q5xx	USART1/USART2/USART3 I2C1/I2C2/I2C3/ CAN1 DFU (USB device FS)/ SPI1/SPI2	0x90	0x1FFF6FFE	USART (V3.1) I2C (V1.2) CAN (V2.0) DFU (V2.2) SPI (V1.1)	
L5	STM32L552xx/562xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device FS) FDCAN1	0x92	0x0BF97FFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.0)

Table 3. Embedded bootloaders (continued)

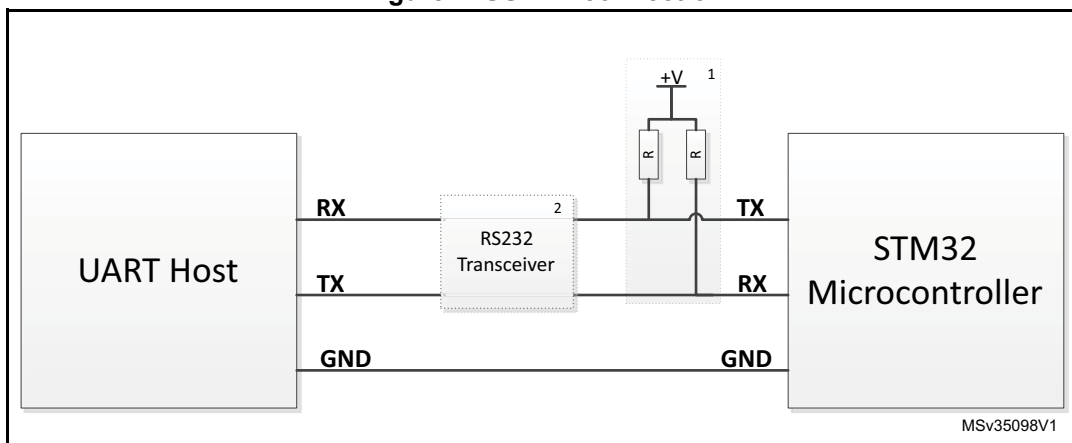
Series	Device	Supported serial peripherals	Bootloader ID		Bootloader (protocol) version
			ID	Memory location	
WBA	STM32WBA52xx	USART1/USART2 I2C1/I2C3 SPI3	0XB0	0x0BF8FEFE	USART (V3.1) I2C (V1.2) SPI (V1.1)
WB	STM32WB10xx/15xx	USART1 I2C1/ SPI1	0xB1	0x1FFF6FFE	USART (V3.1) I2C (V1.2) SPI (V1.1)
	STM32WB30xx/35xx/50xx/55xx	USART1 I2C1/I2C3 SPI1/SPI2 DFU (USB device FS)	0xD5	0x1FFF6FFE	USART (V3.2) I2C (V1.2) SPI (V1.1) DFU (V2.2)
WL	STM32WLE5xx/55xx	USART1/USART2 SPI1/SPI2	0xC4	0x1FFF3EFE	USART (V3.1) SPI (V1.1)
U5	STM32U535xx/545xx	USART1/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device FS) FDCAN1	0x91	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)
	STM32U575xx/STM32U585xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device FS) FDCAN1	0x92	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)
	STM32U595xx/599xx/ STM32U5A5xx/5A9xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device HS) FDCAN1	0x92	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)
	STM32U5F7xx/5F9xx/ STM32U5G7xx/5G9xx	USART1/USART2/USART3 I2C1/I2C2/I2C3 SPI1/SPI2/SPI3 DFU (USB device HS) FDCAN1	0x90	0x0BF99EFE	USART (V3.1) I2C (V1.2) SPI (V1.1) DFU (V2.2) FDCAN (V1.1)

1. For connectivity line devices, the USART bootloader returns V2.0 instead of V2.2 for the protocol version. For more details refer to the "STM32F105xx and STM32F107xx revision Z" errata sheet available from www.st.com.

4.3 Hardware connection requirements

To use the USART bootloader, the host must be connected to the RX and TX pins of the desired USARTx interface via a serial cable.

Figure 1. USART connection

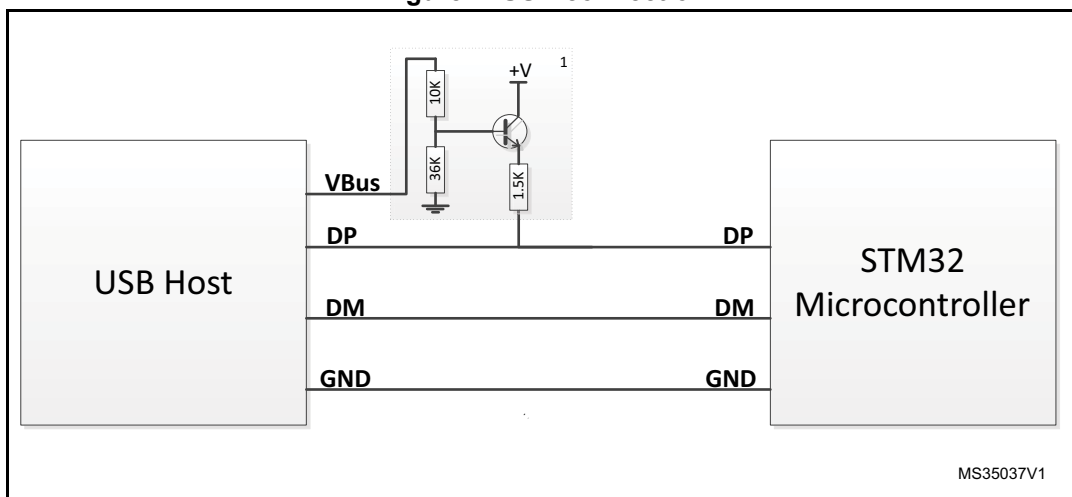


1. A pull-up resistor must be added, if they are not connected in host side.
2. An RS232 transceiver must be connected to adapt the voltage level (3.3 to 12 V) between the STM32 device and the host.

Note: Typically V is 3.3 V, and R is 100 K Ω . These values depend upon the application and the used hardware.

To use the DFU, connect the microcontroller USB interface to a USB host (such as a PC).

Figure 2. USB connection

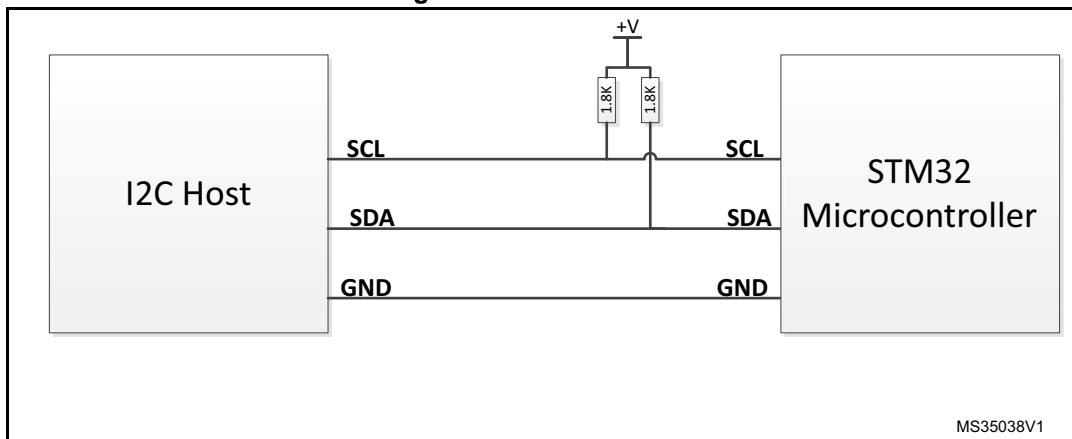


1. This additional circuit permits to connect a pull-up resistor to DP pin using VBus when needed. Refer to product section (table describing STM32 configuration in system memory boot mode) to know if an external pull-up resistor must be connected to DP pin.

Note: V typically is 3.3 V. This value depends upon the application and the used hardware.

To use the I2C bootloader, connect the host (master) and the desired I2Cx interface (slave) together via the data (SDA) and clock (SCL) pins. A 1.8 K Ω pull-up resistor must be connected to both SDA and SCL lines.

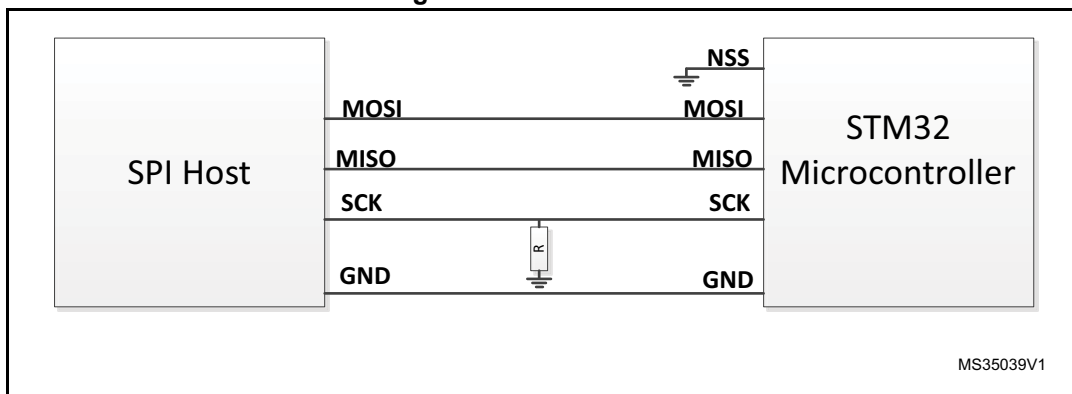
Figure 3. I2C connection



Note: *V* is typically 3.3 V. This value depends upon the application and the used hardware.

To use the SPI bootloader, connect the host (master) and the desired SPIx interface (slave) together via the MOSI, MISO, and SCK pins. The NSS pin must be connected to GND. A pull-down resistor must be connected to the SCK line.

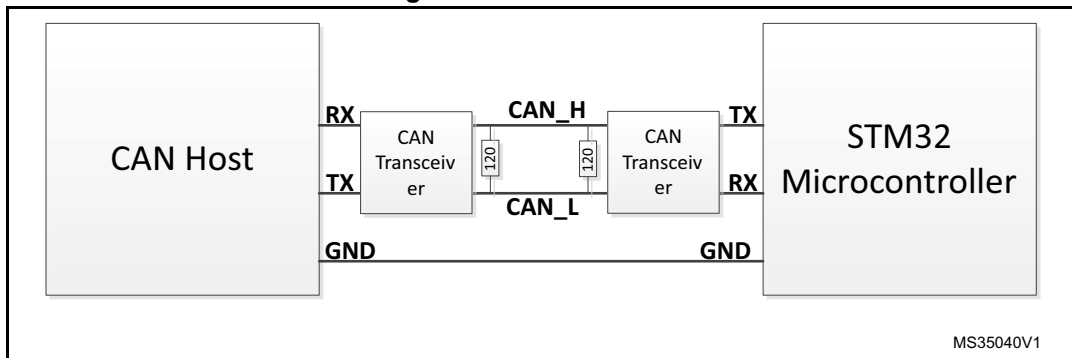
Figure 4. SPI connection



Note: *R* is typically 10 KΩ. This value depends upon the application and the used hardware.

To use the CAN interface, the host must be connected to the RX and TX pins of the desired CANx interface via CAN transceiver and a serial cable. A 120 Ω resistor must be added as terminating resistor.

Figure 5. CAN connection



Note: When a bootloader firmware supports DFU, it is mandatory that no USB Host is connected to the USB peripheral during the selection phase of the other interfaces. After selection phase, the user can plug a USB cable without impacting the selected bootloader execution except for commands generating a system reset.

It is recommended to keep the RX pins of unused bootloader interfaces (USART_RX, SPI_MOSI, CAN_RX and USB D+/D- lines if present) at a known (low or high) level at the startup of the bootloader (detection phase). Leaving these pins floating during the detection phase might lead to activating unused interfaces.

4.4 Bootloader memory management

All write operations using bootloader commands must only be Word-aligned (the address must be a multiple of 4). The number of data to be written must also be a multiple of 4 (non-aligned half page write addresses are accepted).

Some Products embed bootloader that has some specific features:

- Some products do not support Mass erase operation. To perform a mass erase operation using bootloader, two options are available:
 - Erase all sectors one by one using the Erase command
 - Set protection level to Level 1. Then, set it to Level 0 (using the Read protect and then the Read Unprotect command). This operation results in a mass erase of the internal flash memory.
- Bootloader firmware of STM32 L1 and L0 series supports Data memory in addition to standard memories (internal flash, internal SRAM, option bytes and System memory). The start address and the size of this area depends on product, refer to the product reference manual for more information. Data memory can be read and written but cannot be erased using the Erase Command. When writing in a Data memory location, the bootloader firmware manages the erase operation of this location before any write. A write to Data memory must be Word-aligned (address to be written must be a multiple of 4) and the number of data must also be a multiple of 4. To erase a Data memory location, write zeros at this location.
- Bootloader firmware of the F2, F4, F7, and L4 series supports OTP memory in addition to standard memories (internal flash, internal SRAM, option bytes and System memory). The start address and the size of this area depends on product, refer to product reference manual for more information. OTP memory can be read and written but cannot be erased using Erase command. When writing in an OTP memory location, make sure that the relative protection bit is not reset.
- For STM32 F2, F4 and F7 series the internal flash memory write operation format depends on voltage Range. By default write operations are allowed by one byte format (Half-Word, Word and Double-Word operations are not allowed). to increase the speed of write operation, the user must apply the adequate voltage range that allows write operation by Half-Word, Word or Double-Word and update this configuration on the fly by the bootloader software through a virtual memory location. This memory location is not physical but can be read and written using usual bootloader read/write operations according to the protocol in use. This memory location contains 4 bytes described in [Table 4](#). It can be accessed by 1, 2, 3, or 4 bytes. However, reserved bytes must remain at their default values (0xFF), otherwise the request is NACKed.

Table 4. STM32 F2, F4, and F7 voltage range configuration using bootloader

Address	Size	Description
0xFFFF0000	1 byte	This byte controls the current value of the voltage range. 0x00: voltage range [1.8 V, 2.1 V] 0x01: voltage range [2.1 V, 2.4 V] 0x02: voltage range [2.4 V, 2.7 V] 0x03: voltage range [2.7 V, 3.6 V] 0x04: voltage range [2.7 V, 3.6 V] and double word write/erase operation is used. In this case it is mandatory to supply 9 V through the VPP pin (refer to the product reference manual for more details about the double-word write procedure). Other: all other values are not supported and are NACKed.
0xFFFF0001	1 byte	Reserved. 0xFF: default value. Other: all other values are not supported and are NACKed.
0xFFFF0002	1 byte	Reserved. 0xFF: default value. Other: all other values are not supported and is NACKed.
0xFFFF0003	1 byte	Reserved. 0xFF: default value. Other: all other values are not supported and are NACKed.

The table below lists the valid memory areas, depending upon the bootloader commands.

Table 5. Supported memory area by Write, Read, Erase, and Go commands

Memory area	Write command	Read command	Erase command	Go command
Flash	Supported	Supported	Supported	Supported
RAM	Supported	Supported	Not supported	Supported
System memory	Not supported	Supported	Not supported	Not supported
Data memory	Supported	Supported	Not supported	Not supported
OTP memory	Supported	Supported	Not supported	Not supported

4.5 Bootloader UART baudrate detection

For the UART interface baudrate detection, there are two types of mechanisms implemented on different STM32 devices:

- Software baudrate detection using internal HSI and timer (use GPIO as input, detect falling edge and rising edge as explained in AN3155).
The devices using this mechanism are subject to software jitter (variable error of baudrate calculation) that can reach up to $\pm 5\%$. In this case, the host connecting to the STM32 bootloader UART interface must support a $\pm 5\%$ deviation in baudrate.
The software jitter value is variable and different at each retry, so it is possible to use multiple retry connections to overcome it (connect and check for correct bootloader answer, if answer is not correct, reset the device and retry connection until the correct answer is received. Once correct answer is received the rest of the communication is

not impacted by software jitter).

It is also possible to reduce software jitter by reducing baudrate value (i.e. use 56000 bps instead of 115200).

[Table 6](#) provides the maximum software jitter value for the baudrate 115200 bps. The lower the baudrate the lower the software jitter.

- Baudrate detection using UART auto-baudrate feature. Devices using this mechanism do not present any software jitter.

Table 6. Jitter software calculation on bootloader USART detection

Series	Baudrate detection method	Maximum software jitter for 115200 bps
STM32F0	Software baudrate detection	-1%
STM32F1	Software baudrate detection	-3%
STM32F2	Software baudrate detection	-5%
STM32F3	Software baudrate detection	-2%
STM32F4	Software baudrate detection	-6%
STM32F7	Software baudrate detection	-6%
STM32L0	Software baudrate detection	-2%
STM32L1	Software baudrate detection	-3%
STM32L4	Software baudrate detection	-5%
STM32G07x/8x UART3 STM32G03x/4x UART2	Software baudrate detection	-4%
STM32G07x/8x UART1/UART2 STM32G03x/4x UART1	Auto-baudrate	N/A
STM32G4	Auto-baudrate	N/A
STM32H7	Auto-baudrate	N/A
STM32WB	Auto-baudrate	N/A
STM32WL	Auto-baudrate	N/A

4.6 Programming constraints

When using bootloader interface to write in the flash memory, alignment on the programmed address must be respected according to [Table 7](#).

If the address to which the write operation is not aligned, it fails and all following program operations fail as well.

Table 7. Flash memory alignment constraints on STM32 products

Series	Alignment
STM32F0	4 bytes
STM32F1	4 bytes
STM32F2	4 bytes

Table 7. Flash memory alignment constraints on STM32 products (continued)

Series	Alignment
STM32F3	4 bytes
STM32F4	4 bytes
STM32F7	8 bytes
STM32G0	4 bytes
STM32G4	4 bytes
STM32H5	16 bytes
STM32H7	8 bytes
STM32L0	8 bytes
STM32L1	8 bytes
STM32L4	8 bytes
STM32L5	16 bytes
STM32WBA	16 bytes
STM32WB	8 bytes
STM32WL	8 bytes
STM32U5	16 bytes

Examples of alignment:

- 4 bytes: 0x08000014 is aligned and passes, 0x08000012 is not aligned and fails
- 8 bytes: 0x08000010 is aligned and passes, 0x08000014 is not aligned and fails

Note: On some products (STM32F4 and STM32F7) it is possible to change the alignment constraint by writing in the device feature space.

4.7 ExitSecureMemory feature

The securable memory area is used to isolate secure boot code/data, which handle sensitive information (secrets), from application code:

- Access is controlled by a securable memory bit SEC_PROT (write once), in the FLASH_CR register
- Executed once at boot, then locked by writing the securable memory bit
 - The code protected: in the securable memory area is hidden until the next reset that unlocks the SEC_PROT bit
- Width (number of flash memory pages) is defined through an option byte, SEC_SIZE, in the flash memory FLASH_SEC_R register

The ExitSecureMemory is a software developed and hosted on the system memory. When the user boot code jump to it, the software allows setting the SEC_PROT bit to 1 and then jumping to the application code. The SEC_SIZE must be set to the needed value before jumping to the ExitSecureMemory function.

As shown in [Figure 6](#), two jump methods can be used by the customer:

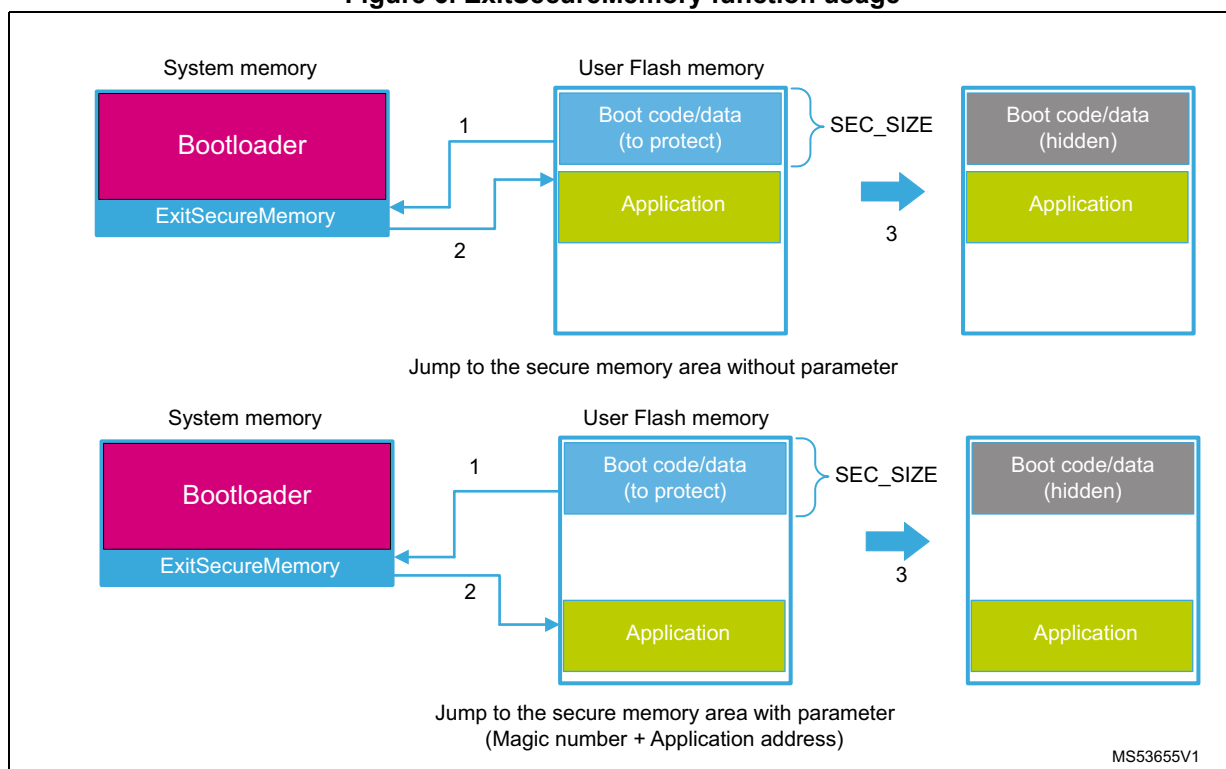
Jump to the secure memory function without parameter

In this case the application must be loaded just after the secure memory defined.

Jump to the secure memory function using two parameters

1. Magic number
 - 0x08192A3C
 - Used to secure boot code/data in flash and jump in case of a single bank product
 - Used to secure boot code/data in Bank1 and jump in case of a dual bank product
 - 0x08192A3D
 - Used to secure boot code/data and jump to application in Bank2 in case of a dual bank product
2. User address = Application address
 - In this case the application can be loaded to any desired address (as per user address defined)

Figure 6. ExitSecureMemory function usage



Note: For more information regarding the option bytes configuration refer to the reference manual.

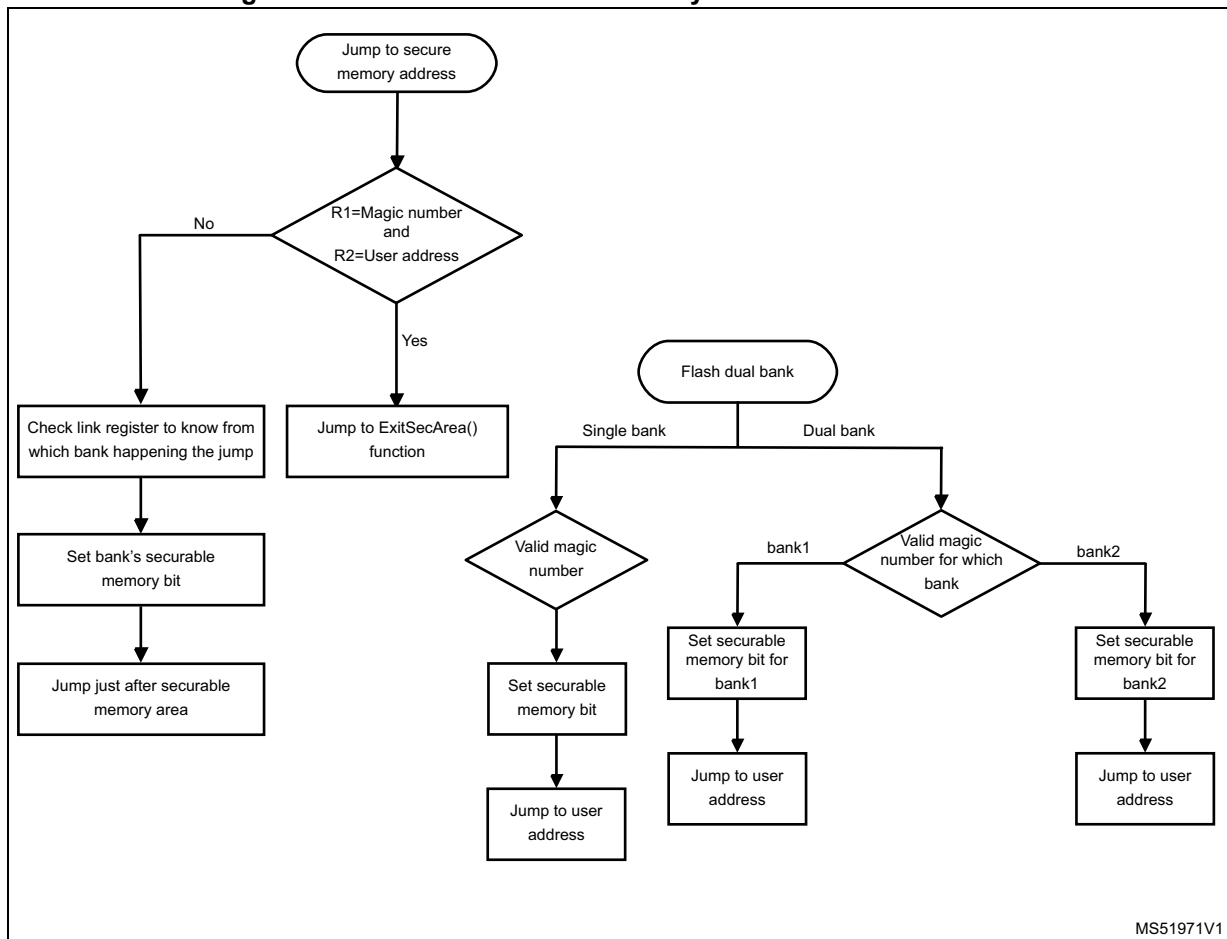
Note: An example of a function that can be used to call the “ExitSecureMemory” is in [Appendix A](#).

Table 8. ExitSecureMemory entry address

MCU		ExitSecureMemory address
STM32G0	STM32G07xxx/08xxx	0x1FFF6800
	STM32G03xxx/04xxx	0x1FFF1E00
	STM32G0Bxxx/0Cxxx	0x1FFF6800
	STM32G05xxx/061xx	0x1FFF6800
STM32G4	STM32G47xxx/48xxx	0x1FFF6800
	STM32G431xx/441xx	0x1FFF6800
	STM32G491xx/4A1xx	0x1FFF6800

For more details refer to [Figure 7](#).

Figure 7. Access to securable memory area from the bootloader



MS51971V1

1. The Bootloader does not check the integrity of the user address, it is up to the user to ensure the validity of the address to jump to.

4.8 IWDG usage in Bootloader

The Bootloader does not enable IWDG, it only tries to update the pre-scaler value if the IWDG was enabled by HW (through option bytes) or by SW in case of an application that jumps to Bootloader.

If the IWDG was not enabled prior boot on Bootloader (using HW boot or by a jump from an application), the Watchdog pre-scaler value update bit (PVU) is set to 0x1 when the Bootloader tries to change the pre-scaler value.

This value does not change, it remains at 0x1 as the pre-scaler update never happens (IWDG is not enabled), and this even after the jump from Bootloader.

So, when using the Bootloader to jump to the application, and when there is the need to enable the IWDG, consider that the PVU bit in IWDG_SR register is set to 0x1.

5 STM32C011xx devices bootloader

5.1 Bootloader configuration

The STM32C011xx bootloader is activated by applying Pattern 11(see [Table 2: Bootloader activation patterns](#)). [Table 13](#) shows the hardware resources used by this bootloader.

Table 9. STM32C011xx configuration in system memory boot mode

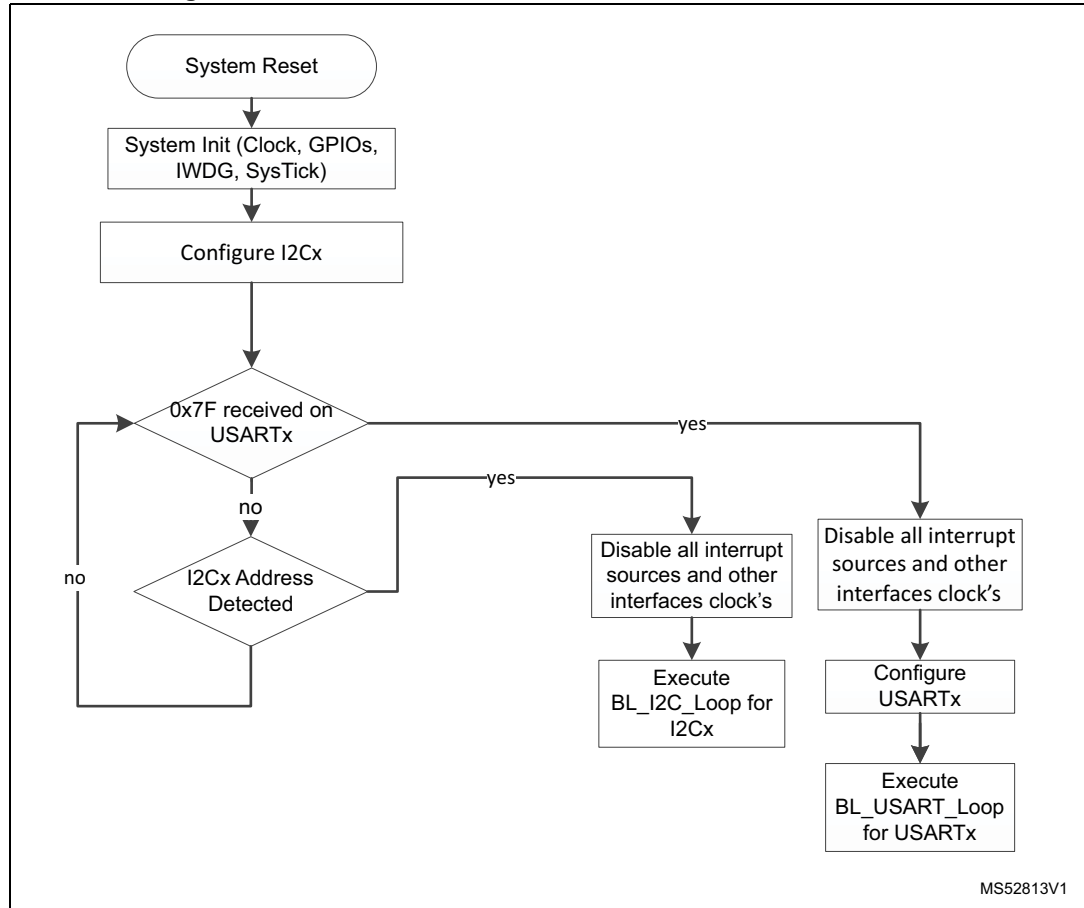
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz (no PLL)
	RAM	-	3.5 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	6 Kbytes, starting from address 0x1FFF0000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF1600
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1100100x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Note: On WLCSP12, SO8N, TSSOP20, and UFQFN20 packages USART1 PA9/PA10 IOs are remapped on PA11/PA12.

5.2 Bootloader selection

Figure 10 shows the bootloader selection mechanism.

Figure 8. Bootloader V5.x selection for STM32C011xx devices



5.3 Bootloader version

Table 10 lists the STM32C011xx devices bootloader versions.

Table 10. STM32C011xx bootloader versions

Version number	Description	Known limitations
V5.1	Initial bootloader version	None

6 STM32C031xx devices bootloader

6.1 Bootloader configuration

The STM32C031xx bootloader is activated by applying Pattern 11(see [Table 2](#)). [Table 13](#) shows the hardware resources used by this bootloader.

Table 11. STM32C031xx configuration in system memory boot mode

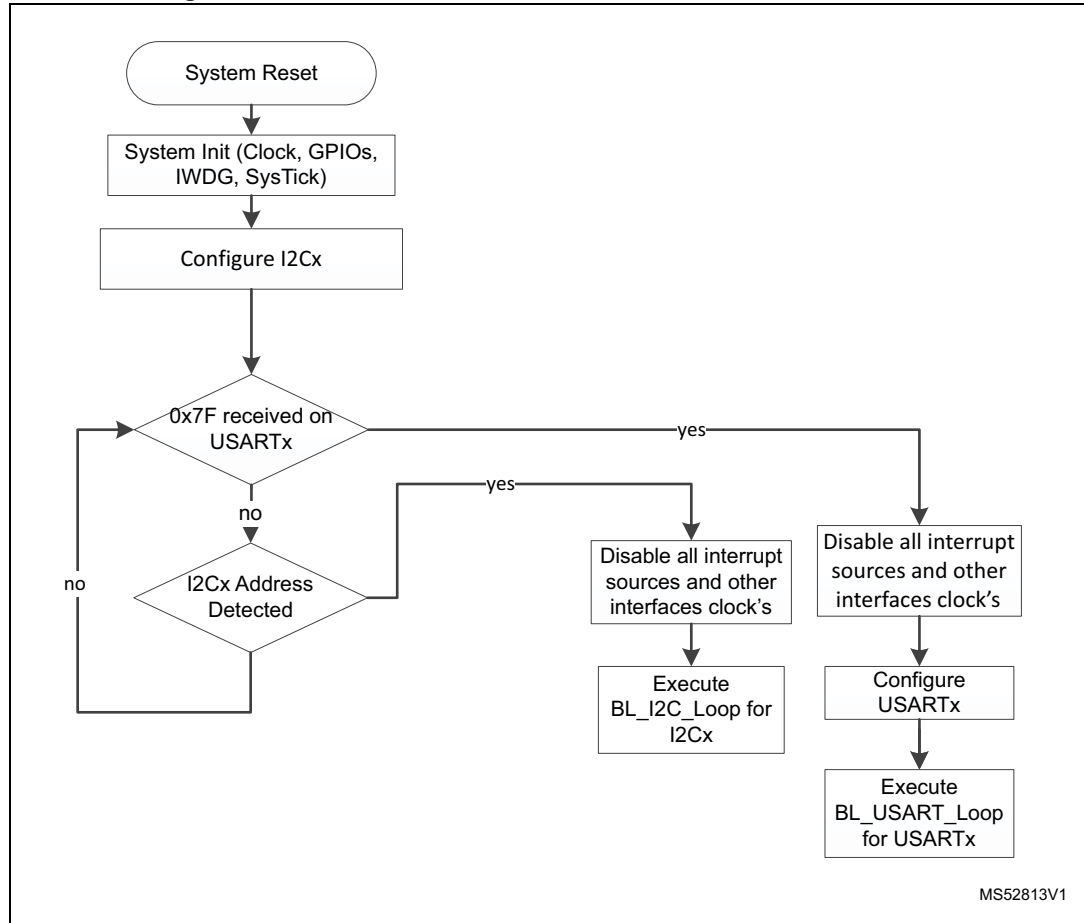
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz (no PLL)
	RAM	-	3.5 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	6 Kbytes, starting from address 0x1FFF0000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF1600
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1100011x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Note: On TSSOP20 and UFQFN28 packages USART1 PA9/PA10 IOs are remapped on PA11/PA12.

6.2 Bootloader selection

Figure 10 shows the bootloader selection mechanism.

Figure 9. Bootloader V5.x selection for STM32C031xx devices



6.3 Bootloader version

Table 12 lists the STM32C031xx devices bootloader versions.

Table 12. STM32C031xx bootloader versions

Version number	Description	Known limitations
V5.2	Initial bootloader version	None

7 STM32F03xx4/6 devices bootloader

7.1 Bootloader configuration

The STM32F03xx4/6 bootloader is activated by applying Pattern 2 (see [Table 2](#)). [Table 13](#) shows the hardware resources used by this bootloader.

Table 13. STM32F03xx4/6 configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI). 1 flash Wait State.
	RAM	-	2 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	3 Kbytes, starting from address 0x1FFFE000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
USART1 bootloader (on PA10/PA9)	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART1 bootloader (on PA14/PA15)	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA15 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA14 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART1 bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

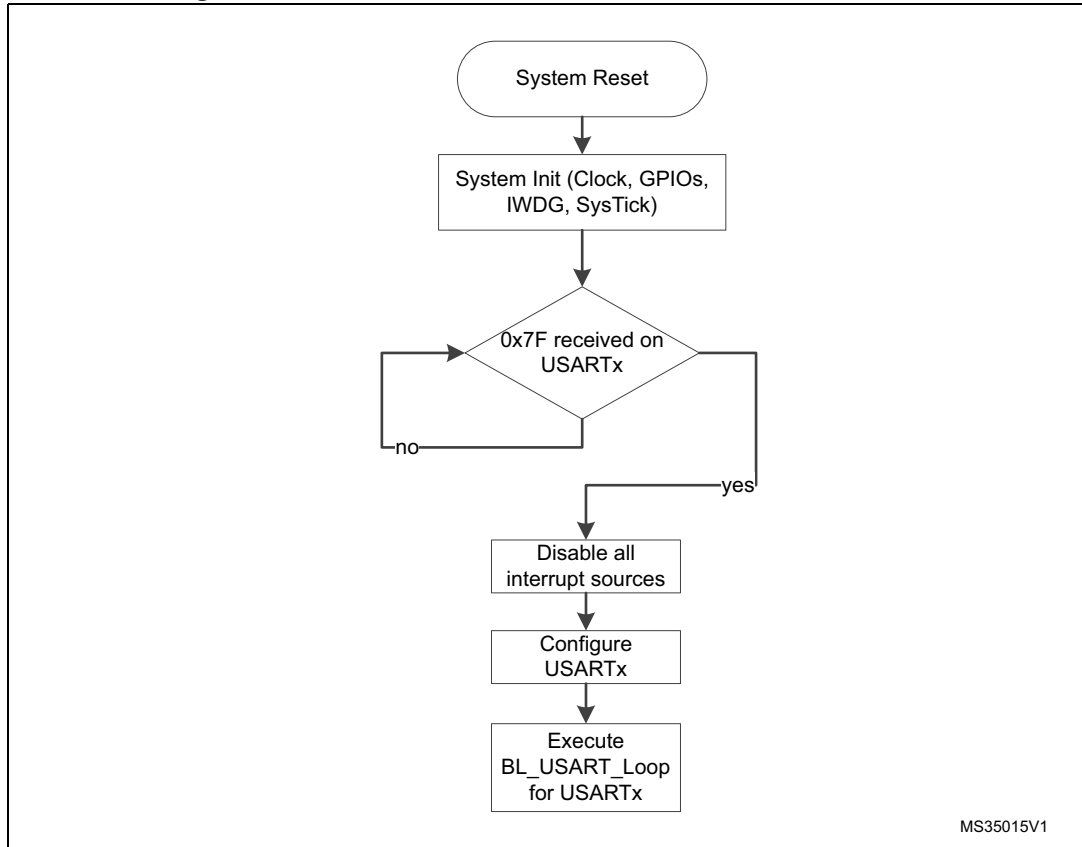
The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

Note: After the STM32F03xx4/6 device has booted in bootloader mode, serial wire debug (SWD) communication is no longer possible until the system is reset. This is because the SWD uses the PA14 pin (SWCLK), already used by the bootloader (USART1_TX).

7.2 Bootloader selection

Figure 10 shows the bootloader selection mechanism.

Figure 10. Bootloader selection for STM32F03xx4/6 devices



7.3 Bootloader version

Table 14 lists the STM32F03xx4/6 devices bootloader versions.

Table 14. STM32F03xx4/6 bootloader versions

Version number	Description	Known limitations
V1.0	Initial bootloader version	For the USART interface, two consecutive NACKs instead of 1 NACK are sent when a Read Memory or Write Memory command is sent and the RDP level is active.

8 STM32F030xC devices bootloader

8.1 Bootloader configuration

The STM32F030xC bootloader is activated by applying Pattern 2 (see [Table 2](#)). [Table 15](#) shows the hardware resources used by this bootloader.

Table 15. STM32F030xC configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader (on PA2/PA3)	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART2 bootloader (on PA14/PA15)	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

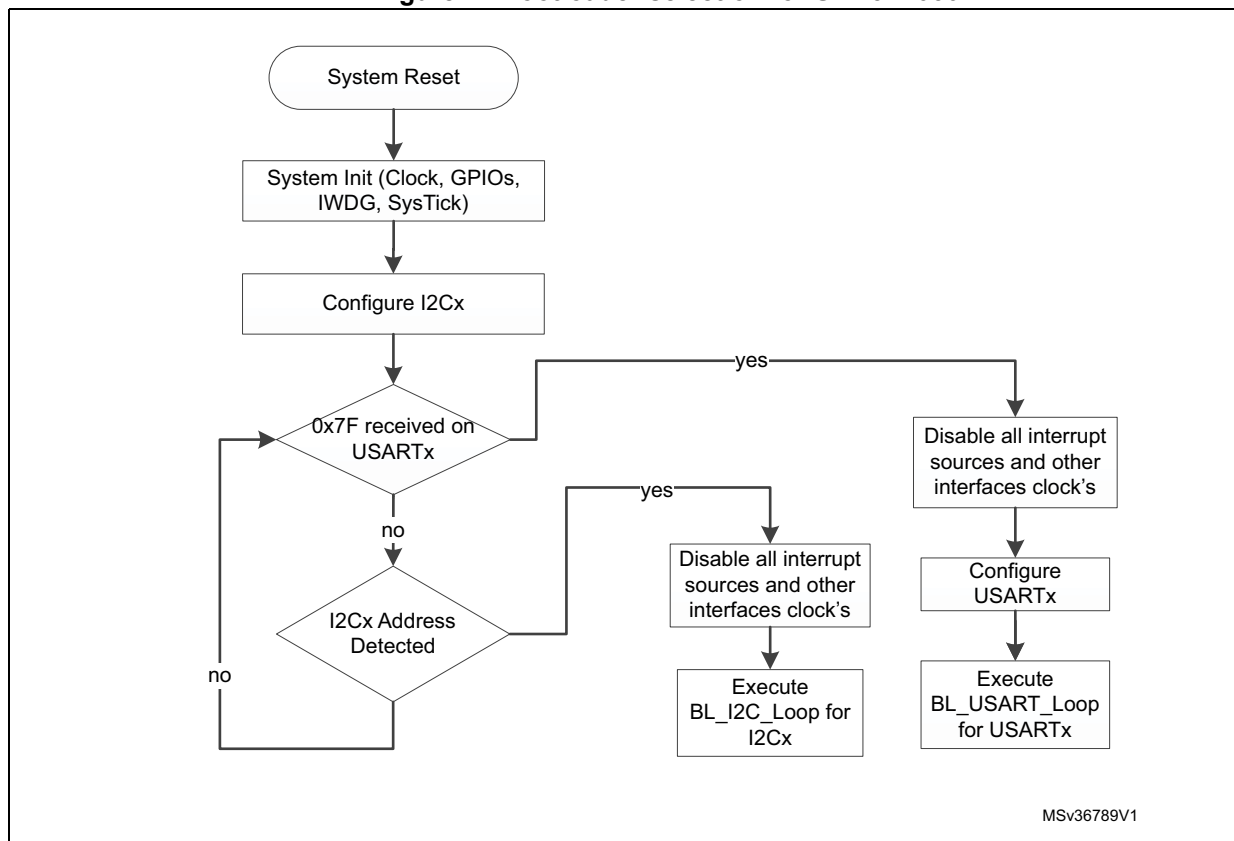
Note: After the STM32F030xC devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

8.2 Bootloader selection

Figure 11 shows the bootloader selection mechanism.

Figure 11.Bootloader selection for STM32F030xC



8.3 Bootloader version

Table 16 lists the STM32F030xC devices bootloader versions.

Table 16. STM32F030xC bootloader versions

Version number	Description	Known limitations
V5.2	Initial bootloader version	PA13 is set in input pull-up mode even if not used by the bootloader

9 STM32F05xxx and STM32F030x8 devices bootloader

9.1 Bootloader configuration

The STM32F05xxx and STM32F030x8 devices bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 17](#) shows the hardware resources used by this bootloader.

Table 17. STM32F05xxx and STM32F030x8 devices configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI). 1 flash Wait State.
	RAM	-	2 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	3 Kbytes, starting from address 0x1FFFE000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset if the hardware IWDG option was previously enabled by the user.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

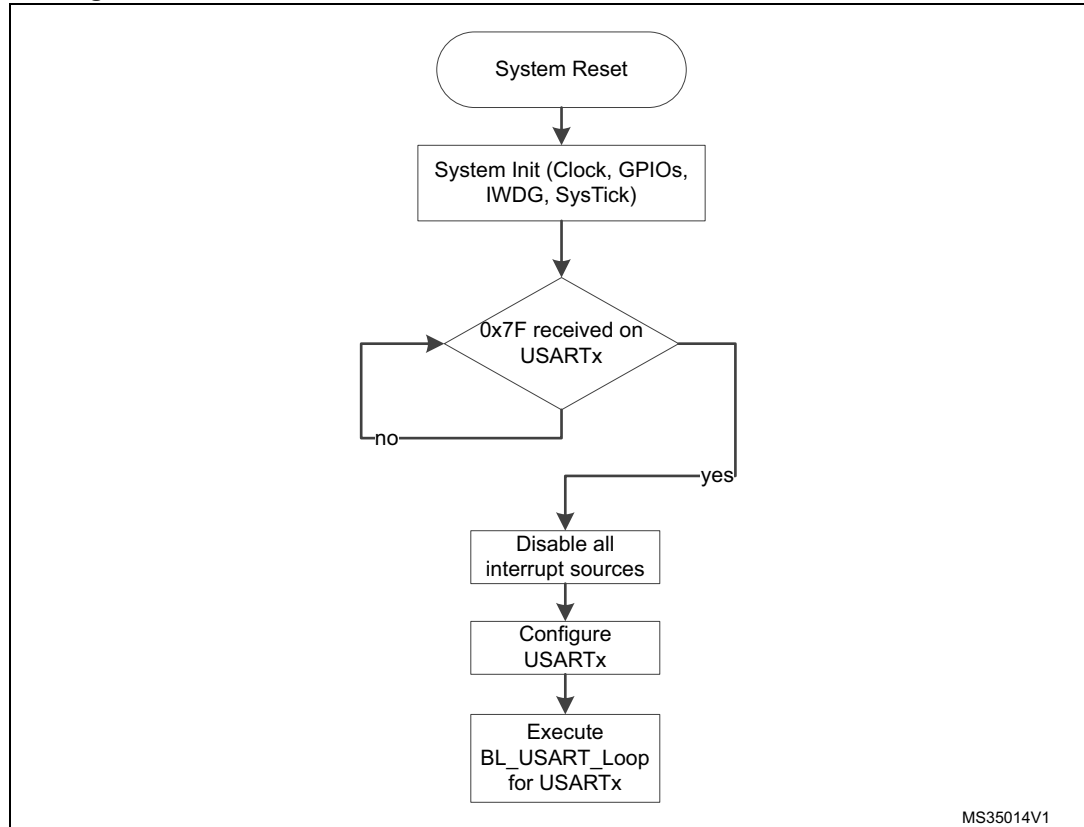
The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

Note: After the STM32F05xxx and STM32F030x8 devices have booted in bootloader mode, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_TX).

9.2 Bootloader selection

Figure 12 shows the bootloader selection mechanism.

Figure 12. Bootloader selection for STM32F05xxx and STM32F030x8 devices



9.3 Bootloader version

Table 18 lists the STM32F05xxx and STM32F030x8 devices bootloader versions.

Table 18. STM32F05xxx and STM32F030x8 devices bootloader versions

Version number	Description	Known limitations
V2.1	Initial bootloader version	<ul style="list-style-type: none"> – At bootloader startup, the HSITRIM value is set to 0 (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (i.e. 4 MHz). – For the USART interface, two consecutive NACKs instead of 1 NACK are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – PA13 is set in input pull-up mode even if not used by the Bootloader.

10 STM32F04xxx devices bootloader

10.1 Bootloader configuration

The STM32F04xxx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 19](#) shows the hardware resources used by this bootloader.

Table 19. STM32F04xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	13 Kbytes, starting from address 0x1FFFC400, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Use in input pull-up mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111110x (where x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Table 19. STM32F04xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line No external pull-up resistor is required. Used in alternate push-pull, no pull mode.

Note: After the STM32F04xxx devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

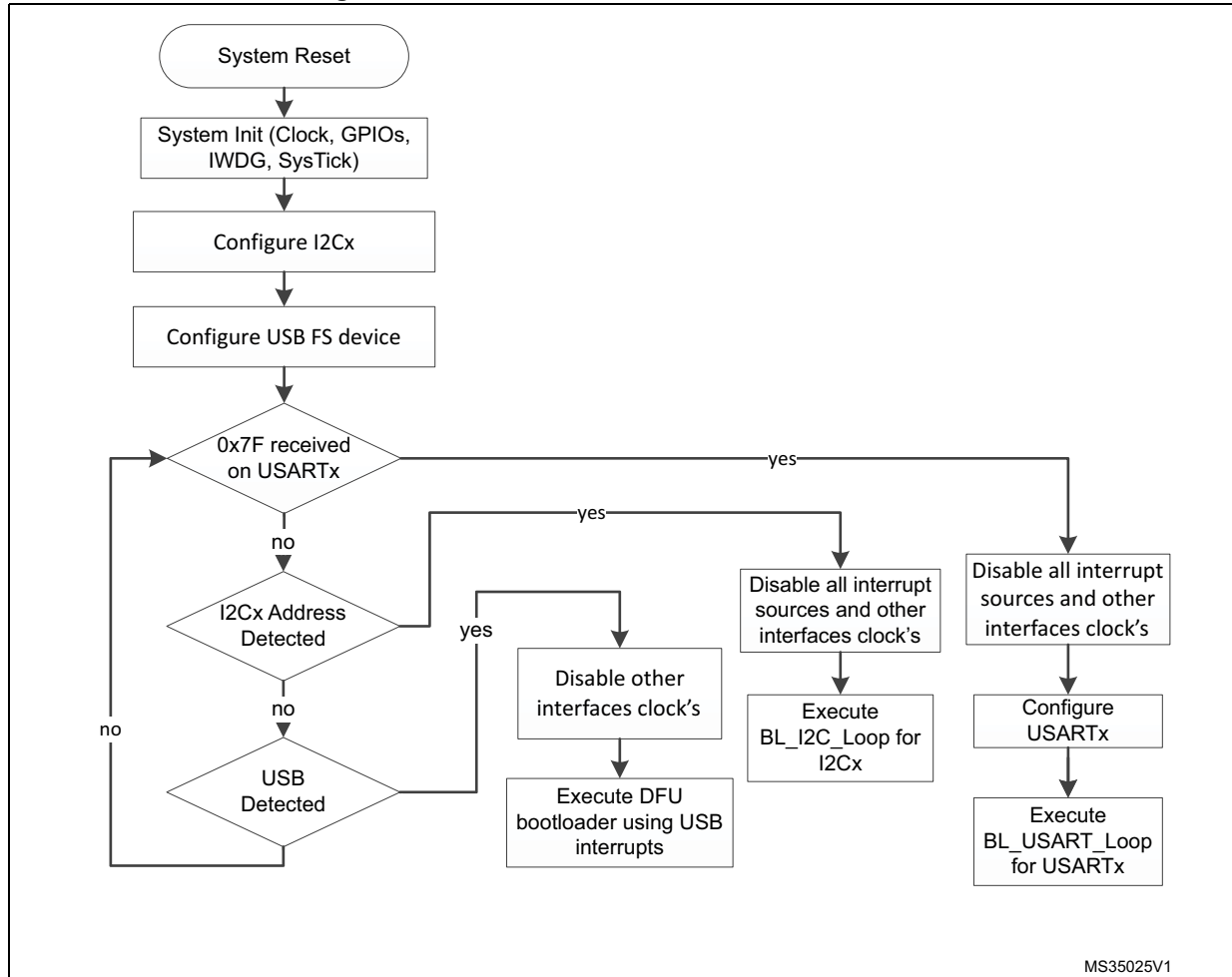
The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

Note: Due to empty check mechanism present on this product, it is not possible to jump from user code to system bootloader. Such jump results in a jump back to user flash memory space. But if the first 4 bytes of User flash (at 0x0800 0000) are empty at the moment of jump (i.e. erase first sector before jump or execute code from SRAM while flash is empty), then system bootloader is executed when jumped to.

10.2 Bootloader selection

Figure 13 shows the bootloader selection mechanism.

Figure 13. Bootloader selection for STM32F04xxx



10.3 Bootloader version

Table 20. STM32F04xxx bootloader versions

Version number	Description	Known limitations
V10.0	Initial bootloader version	At bootloader startup, the HSITRIM value is set to 0 (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement.
V10.1	Add dynamic support of USART/USB interfaces on PA11/12 IOs for small packages.	For better results, use the smallest supported crystal value (i.e. 4 MHz). PA13 is set in input pull-up mode even if not used by the bootloader.

11 STM32F070x6 devices bootloader

11.1 Bootloader configuration

The STM32F070x6 bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 21](#) shows the hardware resources used by this bootloader.

Table 21. STM32F070x6 configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one of the following values: 24, 18, 16, 12, 8, 6, 4 MHz. The PLL is used to generate 48 MHz for USB and system clock.
		-	The CSS interrupt is enabled for HSE. Any failure (or removal) of the external clock generates system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	13 Kbytes, starting from address 0x1FFFC400, contain the bootloader firmware.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111110x where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain mode.

Table 21. STM32F070x6 configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line
	USB_DP pin		PA12 pin: USB FS DP line. No external pull-up resistor is required.

Note: If HSI deviation exceeds 1% the bootloader might not function correctly.

Note: After the STM32F070x6 devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

- If HSE is present and has a value of 24, 18, 16, 12, 8, 6, 4 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1, USART2, and I2C1 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source and only USART1, USART2, and I2C1 are functional.

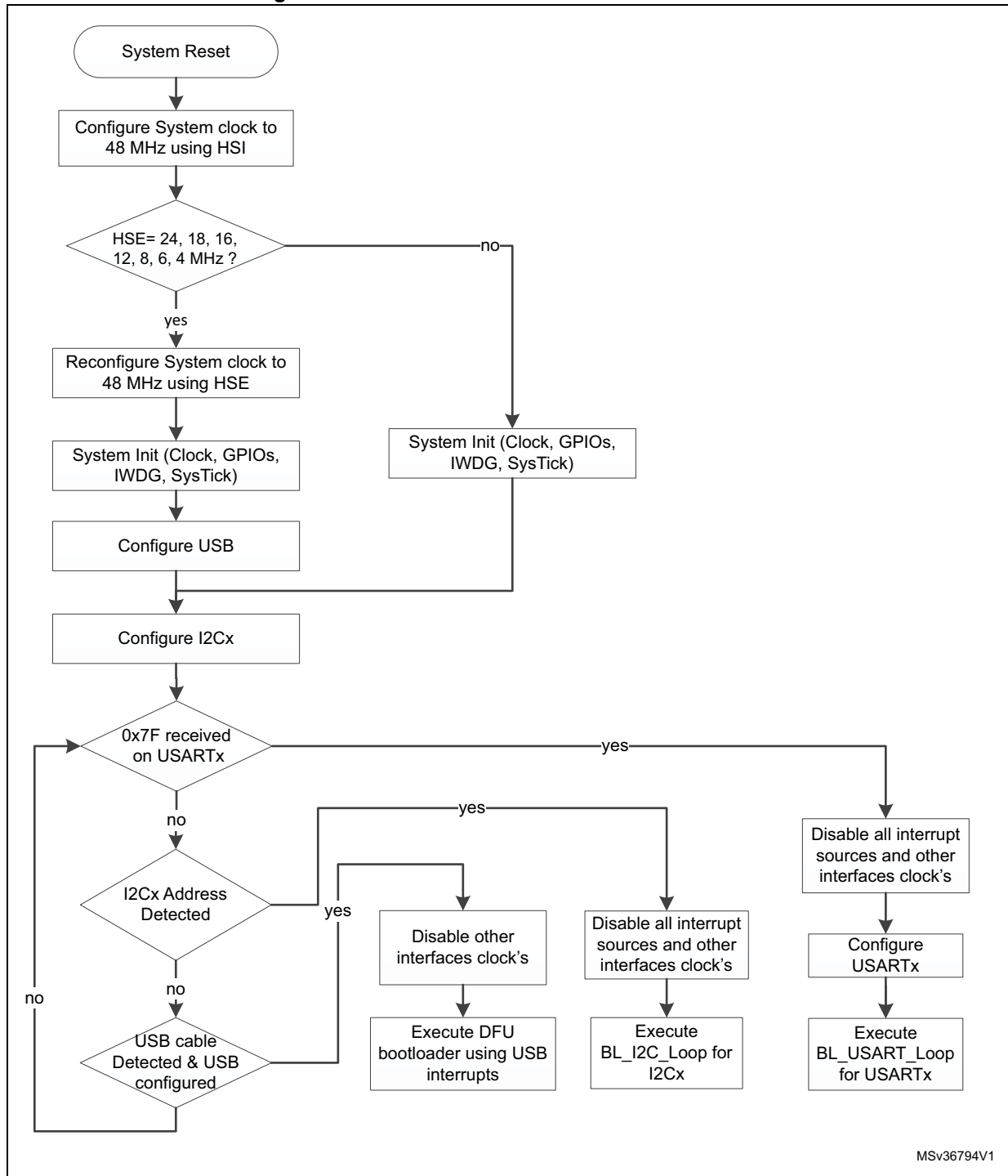
The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

Note: Due to empty check mechanism present on this product, it is not possible to jump from user code to system bootloader. Such jump results in a jump back to user flash space, but if the first four bytes of user flash (at 0x0800 0000) are empty at the moment of jump (i.e. erase first sector before jump or execute code from SRAM while flash is empty), then system bootloader is executed when jumped to.

11.2 Bootloader selection

Figure 14 shows the bootloader selection mechanism.

Figure 14. Bootloader selection for STM32F070x6



11.3 Bootloader version

[Table 22](#) lists the STM32F070x6 devices bootloader versions.

Table 22. STM32F070x6 bootloader versions

Version number	Description	Known limitations
V10.2	Initial bootloader version	At bootloader startup, the HSITRIM value is set to 0 (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (i.e. 4 MHz).
V10.3	Clock configuration fixed to HSI 8 MHz	

12 STM32F070xB devices bootloader

12.1 Bootloader configuration

The STM32F070xB bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 23](#) shows the hardware resources used by this bootloader.

Table 23. STM32F070xB configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one of the following values: 24, 18, 16, 12, 8, 6, 4 MHz. The PLL is used to generate 48 MHz for USB and system clock.
		-	The clock security system (CSS) interrupt is enabled for HSE. Any failure (or removal) of the external clock generates system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	12 Kbytes, starting from address 0x1FFFC800, contain the bootloader firmware.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input pull-up mode
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b0111011x – (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Table 23. STM32F070xB configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line used in alternate push-pull, no pull mode. No external pull-up resistor is required.

Note: If HSI deviation exceeds 1% the bootloader might not function correctly.

Note: After the STM32F070xB devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

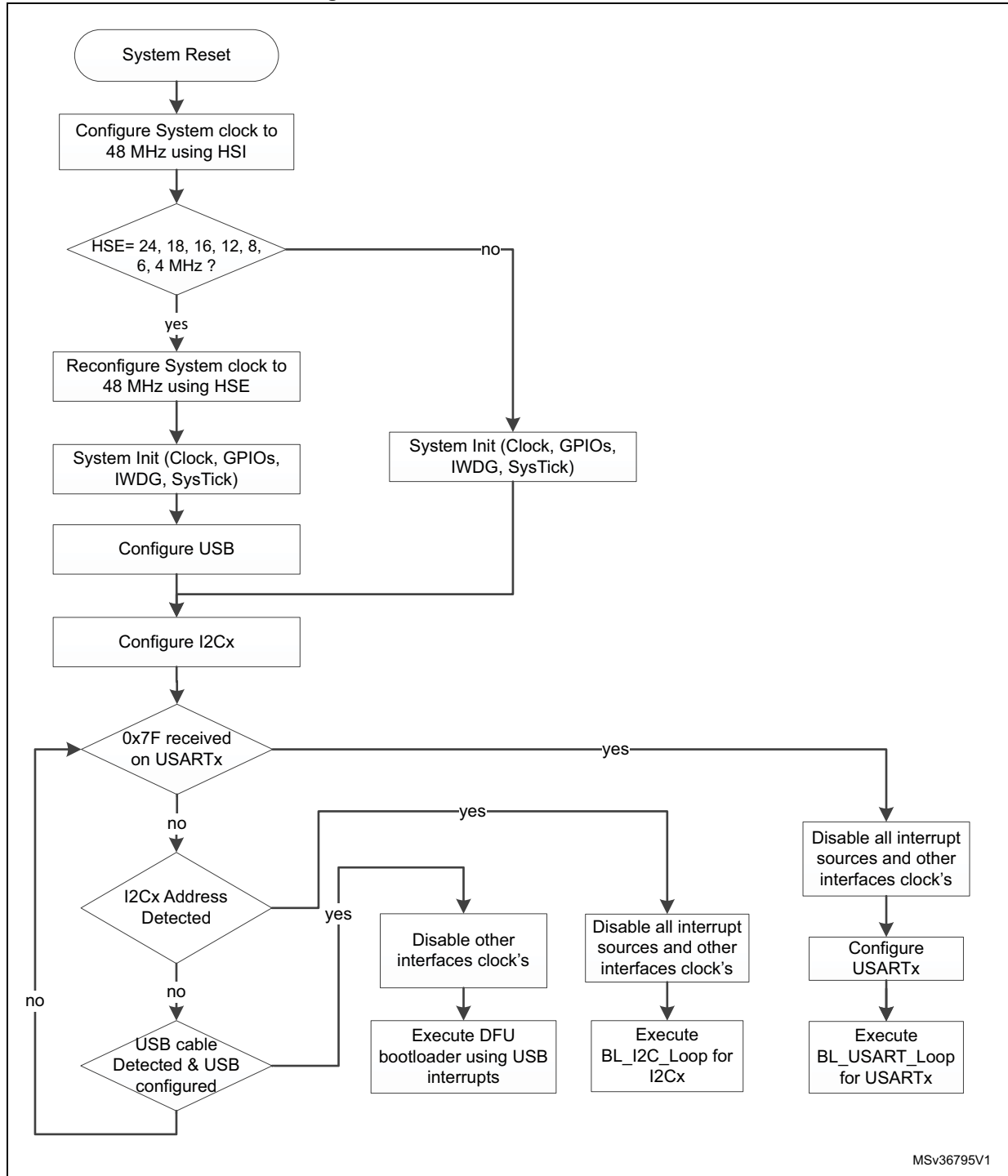
- If HSE is present and has a value of 24, 18, 16, 12, 8, 6, 4 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1, USART2, and I2C1 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source and only USART1, USART2, and I2C1 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

12.2 Bootloader selection

Figure 15 shows the bootloader selection mechanism.

Figure 15.Bootloader selection for STM32F070xB



12.3 Bootloader version

[Table 24](#) lists the STM32F070xB devices bootloader versions.

Table 24. STM32F070xB bootloader versions

Version number	Description	Known limitations
V10.2	Initial bootloader version	At bootloader startup, the HSITRIM value is set to (0) (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (i.e. 4 MHz). PA13 is set in alternate push-pull mode even if not used by the bootloader.
V10.3	Clock configuration fixed to HSI 8 MHz	

13 STM32F071xx/072xx devices bootloader

13.1 Bootloader configuration

The STM32F071xx/072xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 25](#) shows the hardware resources used by this bootloader.

Table 25. STM32F071xx/072xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	12 Kbytes, starting from address 0x1FFFC800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in input pull-up mode
	USART2_TX pin	Output	PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 25. STM32F071xx/072xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111011x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line No external pull-up resistor is required. Used in alternate push-pull, no pull mode.

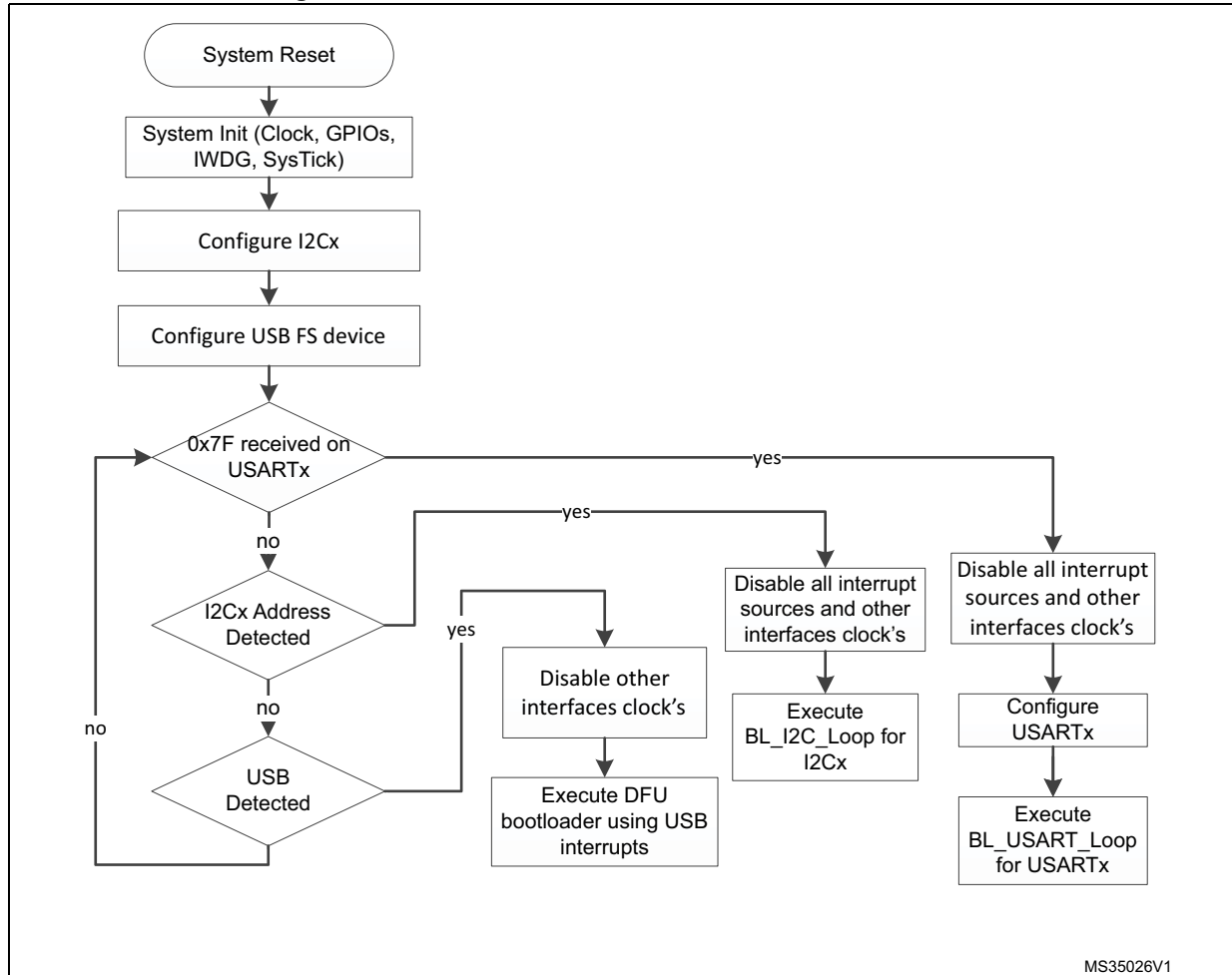
Note: After the STM32F071xx/072xx devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no more possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

13.2 Bootloader selection

Figure 16 shows the bootloader selection mechanism.

Figure 16. Bootloader selection for STM32F071xx/072xx



MS35026V1

13.3 Bootloader version

Table 26 lists the STM32F071xx/072xx devices bootloader versions.

Table 26. STM32F071xx/072xx bootloader versions

Version number	Description	Known limitations
V10.1	Initial bootloader version	At bootloader startup, the HSITRIM value is set to (0) (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (i.e. 4 MHz). PA13 set in alternate push-pull, pull-up mode even if not used by bootloader.

14 STM32F09xxx devices bootloader

14.1 Bootloader configuration

The STM32F09xxx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 27](#) shows the hardware resources used by this bootloader.

Table 27. STM32F09xxx configuration in system memory boot mode

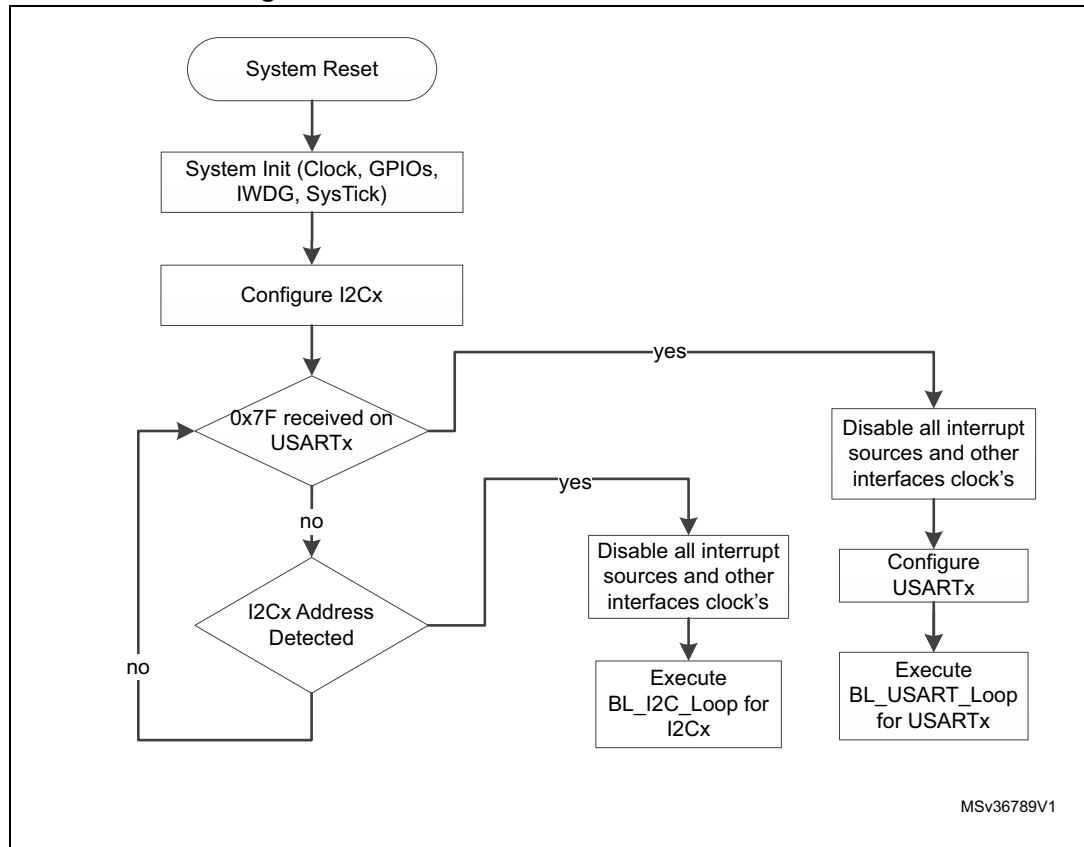
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memor	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
			PA15 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
PA14 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.			
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Note: After the STM32F09xxx devices have booted in bootloader mode using USART2, the serial wire debug (SWD) communication is no longer possible until the system is reset, because SWD uses PA14 pin (SWCLK), already used by the bootloader (USART2_RX).

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

14.2 Bootloader selection

Figure 17. Bootloader selection for STM32F09xxx



14.3 Bootloader version

Table 28 lists the STM32F09xxx devices bootloader versions.

Table 28. STM32F09xxx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	At bootloader startup, the HSITRIM value is set to (0) (in HSITRIM bits on RCC_CR register) instead of default value (16), as a consequence a deviation is generated in crystal measurement. For better results, use the smallest supported crystal value (i.e. 4 MHz). PA13 set in input pull-up mode even if not used by the bootloader.

15 STM32F10xxx devices bootloader

15.1 Bootloader configuration

The STM32F10xxx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 29](#) shows the hardware resources used by this bootloader.

Table 29. STM32F10xxx configuration in system memory boot mode

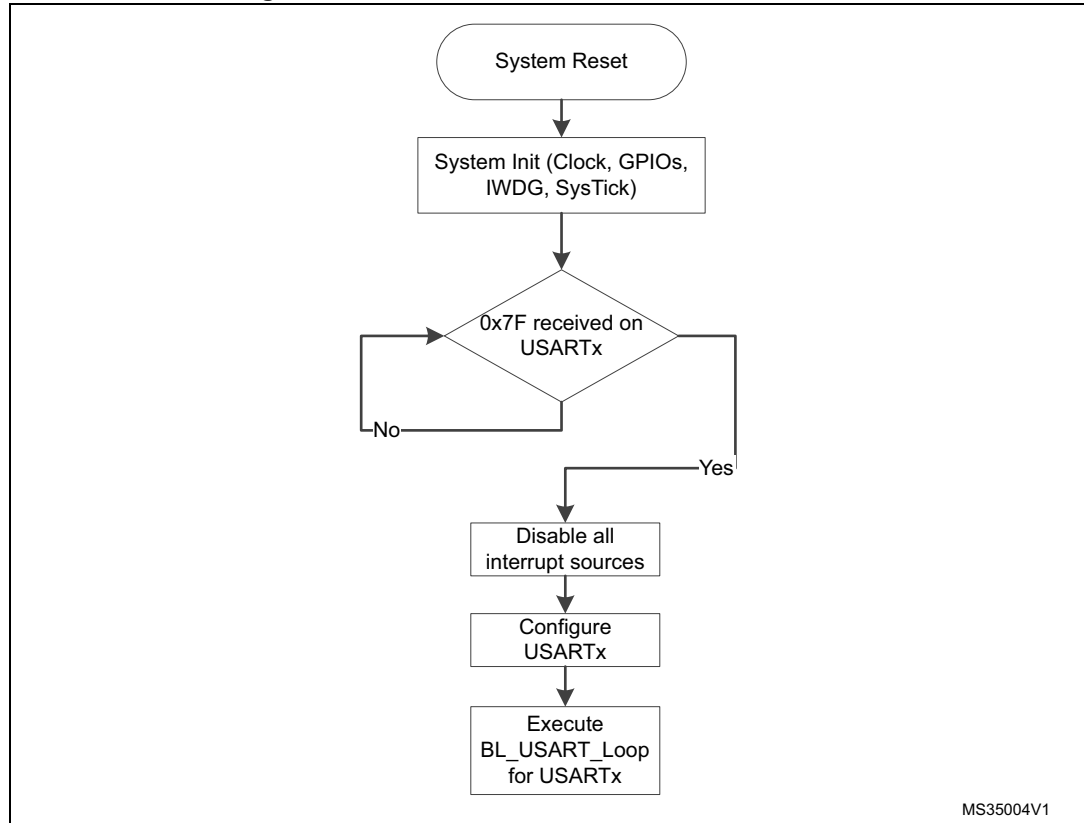
Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL.
	RAM	-	512 byte starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	2 Kbytes, starting from address 0x1FFFF000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output push-pull	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

15.2 Bootloader selection

Figure 18 shows the bootloader selection mechanism.

Figure 18. Bootloader selection for STM32F10xxx



15.3 Bootloader version

Table 30 lists the STM32F10xxx devices bootloader versions:

Table 30. STM32F10xxx bootloader versions

Version number	Description
V2.0	Initial bootloader version
V2.1	<ul style="list-style-type: none"> – Updated Go Command to initialize the main stack pointer – Updated Go command to return NACK when jump address is in the Option byte area or System memory area – Updated Get ID command to return the device ID on two bytes – Update the bootloader version to V2.1
V2.2	<ul style="list-style-type: none"> – Updated Read Memory, Write Memory and Go commands to deny access with a NACK response to the first 0x200 bytes of RAM used by the bootloader – Updated Readout Unprotect command to initialize the whole RAM content to 0x0 before ROP disable operation

Note: The bootloader ID format is applied to all STM32 devices families except the STM32F1xx family. The bootloader version for the STM32F1xx applies only to the embedded device's bootloader version and not to its supported protocols.

16 STM32F105xx/107xx devices bootloader

16.1 Bootloader configuration

The STM32F105xx/107xx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 31](#) shows the hardware resources used by this bootloader.

Table 31. STM32F105xx/107xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. This is used only for USARTx bootloaders and during CAN2, USB detection for CAN and DFU bootloaders (once CAN or DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for DFU and CAN bootloaders and it must provide one of the following frequencies: 8 MHz, 14.7456 MHz or 25 MHz. For CAN bootloader, the PLL is used only to generate 48 MHz when 14.7456 MHz is used as HSE. For DFU bootloader, the PLL is used to generate a 48 MHz system clock from all supported external clock frequencies.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock will generate system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	18 Kbytes, starting from address 0x1FFFB000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output push-pull	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 receive (remapped pin)
	USART2_TX pin	Output push-pull	PD5 pin: USART2 transmit (remapped pin)

Table 31. STM32F105xx/107xx configuration in system memory boot mode (continued)

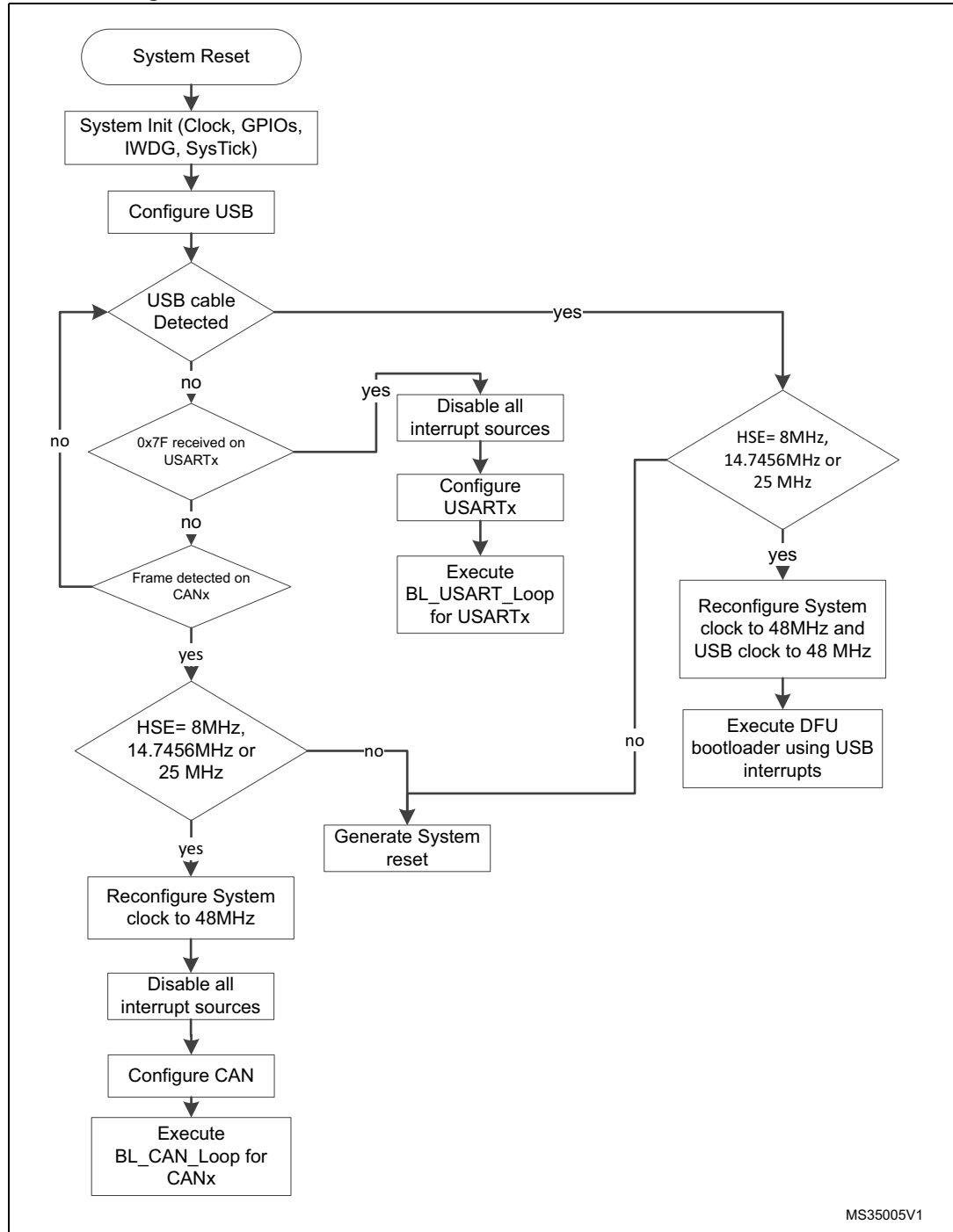
Bootloader	Feature/Peripheral	State	Comment
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
CAN2 bootloader	CAN2	Enabled	Once initialized, the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during the CAN bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 receives (remapped pin). Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output push-pull	PB6 pin: CAN2 transmits (remapped pin). Used in input no pull mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_VBUS pin	Input	PA9: Power supply voltage line
	USB_DM pin	Input/output	PA11 pin: USB_DM line
	USB_DP pin		PA12 pin: USB_DP line. No external pull-up resistor is required

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU and CAN bootloaders, but only for the selection phase. An external clock (8, 14.7456, or 25 MHz) is required for DFU and CAN bootloader execution after the selection phase.

16.2 Bootloader selection

Figure 19 shows the bootloader selection mechanism.

Figure 19. Bootloader selection for STM32F105xx/107xx devices



MS35005V1

16.3 Bootloader version

[Table 32](#) lists the STM32F105xx/107xx devices bootloader versions:

Table 32. STM32F105xx/107xx bootloader versions

Version number	Description
V1.0	Initial bootloader version
V2.0	<ul style="list-style-type: none"> – Bootloader detection mechanism updated to fix the issue when GPIOs of unused peripherals in this bootloader are connected to low level or left floating during the detection phase. For more details refer to Section 16.3.2. – Vector table set to 0x1FFFB000 instead of 0x00000000 – Go command updated (for all bootloaders): USART1, USART2, CAN2, GPIOA, GPIOB, GPIOD and SysTick peripheral registers are set to their default reset values – DFU bootloader: USB pending interrupt cleared before executing the Leave DFU command – DFU subprotocol version changed from V1.0 to V1.2 – Bootloader version updated to V2.0
V2.1	<ul style="list-style-type: none"> – Fixed PA9 excessive consumption described in Section 16.3.4. – Get-Version command (defined in AN3155) corrected. It returns 0x22 instead of 0x20 in bootloader V2.0. Refer to Section 16.3.3 for more details. – Bootloader version updated to V2.1
V2.2	<ul style="list-style-type: none"> – Fixed DFU option bytes descriptor (set to 'e' instead of 'g' because it is read/write and not erasable). – Fixed DFU polling timings for flash Read/Write/Erase operations. – Robustness enhancements for DFU bootloader interface. – Updated bootloader version to V2.2.

Note: The bootloader ID format is applied to all STM32 devices families except the STM32F1xx family. The bootloader version for the STM32F1xx applies only to the embedded device's bootloader version and not to its supported protocols.

16.3.1 How to identify STM32F105xx/107xx bootloader versions

Bootloader V1.0 is implemented on devices whose date code is lower than 937 (refer to STM32F105xx and STM32F107xx datasheet to find the date code on the device marking).

Bootloader V2.0 and V2.1 are implemented on devices with a date code higher than or equal to 937.

Bootloader V2.2 is implemented on devices with a date code higher than or equal to 227.

There are two ways to distinguish between bootloader versions:

- When using the USART bootloader, the Get-Version command defined in AN2606 and AN3155 has been corrected in V2.1 version. It returns 0x22 instead of 0x20 as in bootloader V2.0.

- The values of the vector table at the beginning of the bootloader code are different. The user software (or via JTAG/SWD) reads 0x1FFFE945 at address 0x1FFFB004 for bootloader V2.0 0x1FFFE9A1 for bootloader V2.1, and 0x1FFFE9C1 for bootloader V2.2.
- The DFU version is the following:
 - V2.1 in bootloader V2.1
 - V2.2 in bootloader V2.2.It can be read through the `bcdDevice` field of the DFU Device Descriptor.

16.3.2 Bootloader unavailability on STM32F105xx/STM32F107xx devices with date code lower than 937

Description

The bootloader cannot be used if the USART1_RX (PA10), USART2_RX (PD6, remapped), CAN2_Rx (PB5, remapped), OTG_FS_DM (PA11), and/or OTG_FS_DP (PA12) pin(s) are held low or left floating during the bootloader activation phase.

The bootloader cannot be connected through CAN2 (remapped), DFU (OTG FS in Device mode), USART1 or USART2 (remapped).

On 64-pin packages, the USART2_RX signal remapped PD6 pin is not available and it is internally grounded. In this case, the bootloader cannot be used at all.

Workaround

- For 64-pin packages
None. The bootloader cannot be used.
- For 100-pin packages
Depending on the used peripheral, the pins for the unused peripherals must be kept at a high level during the bootloader activation phase as described below:
 - If USART1 is used to connect to the bootloader, PD6 and PB5 must be kept at a high level.
 - If USART2 is used to connect to the bootloader, PA10, PB5, PA11, and PA12 must be kept at a high level.
 - If CAN2 is used to connect to the bootloader, PA10, PD6, PA11, and PA12 must be kept at a high level.
 - If DFU is used to connect to the bootloader, PA10, PB5, and PD6 must be kept at a high level.

Note: This limitation applies only to STM32F105xx and STM32F107xx devices with a date code lower than 937. STM32F105xx and STM32F107xx devices with a date code higher or equal to 937 are not impacted. See STM32F105xx and STM32F107xx datasheets for where to find the date code on the device marking.

16.3.3 USART bootloader Get-Version command returns 0x20 instead of 0x22

Description

In USART mode, the Get-Version command (defined in AN3155) returns 0x20 instead of 0x22. This limitation is present on bootloader versions V1.0 and V2.0, while it is fixed in bootloader version 2.1.

Workaround

None.

16.3.4 PA9 excessive power consumption when USB cable is plugged in bootloader V2.0

Description

When connecting a USB cable after booting from System-Memory mode, PA9 pin (connected to $V_{BUS} = 5\text{ V}$) is also shared with USART TX pin, configured as alternate push-pull and forced to 0 since the USART peripheral is not yet clocked. As a consequence, a current higher than 25 mA is drained by PA9 I/O and may affect the I/O pad reliability.

This limitation is fixed in bootloader version 2.1 by configuring PA9 as alternate function push-pull when a correct 0x7F is received on RX pin and the USART is clocked. Otherwise, PA9 is configured as alternate input floating.

Workaround

None.

17 STM32F10xxx XL-density devices bootloader

17.1 Bootloader configuration

The STM32F10xxx XL-density bootloader is activated by applying Pattern 3 (described in [Table 2](#)). [Table 33](#) shows the hardware resources used by this bootloader.

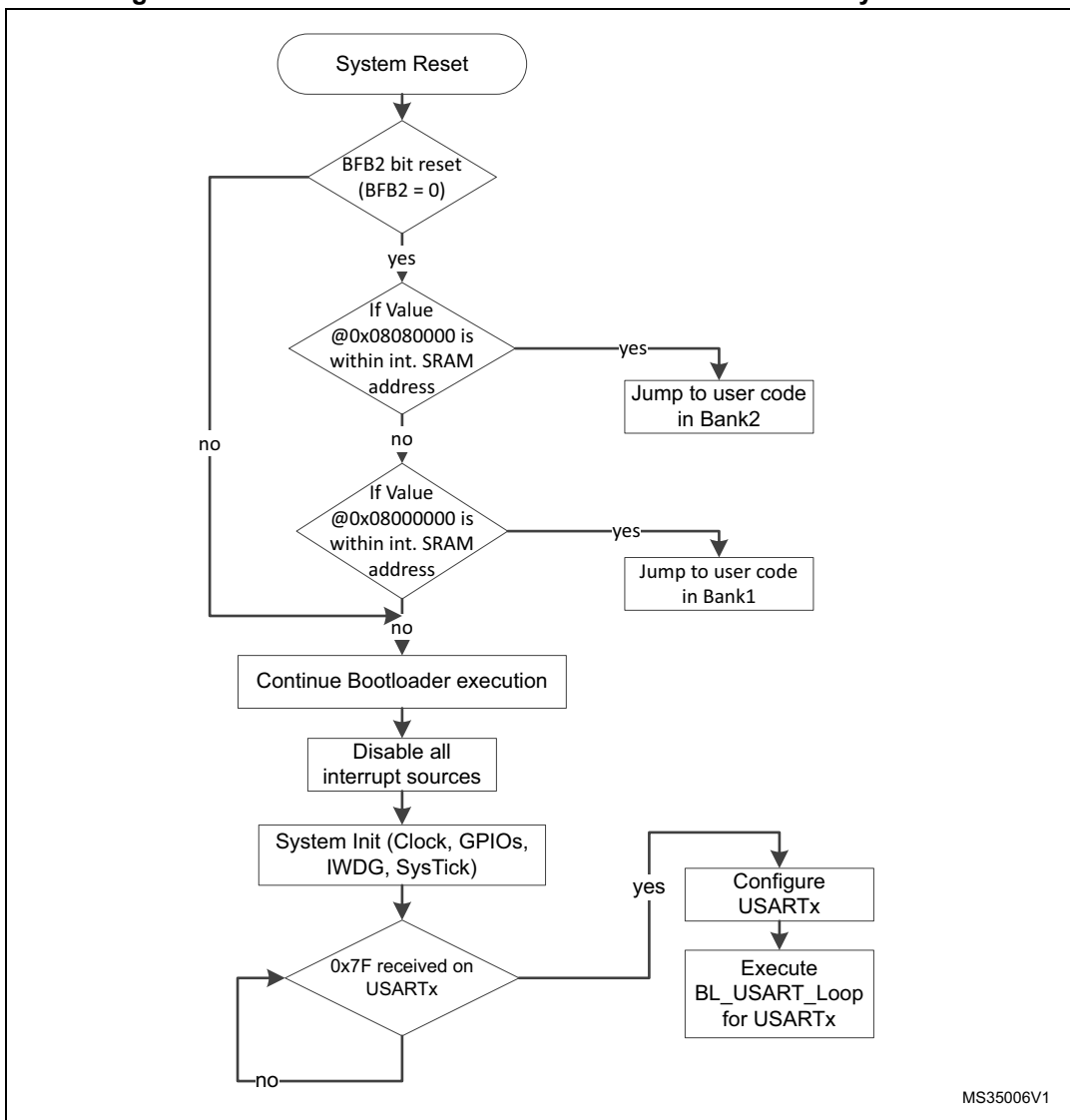
Table 33. STM32F10xxx XL-density configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL.
	RAM	-	2 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	6 Kbytes, starting from address 0x1FFFE000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output push-pull	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PD6 pin: USART2 receives (remapped pins). Used in input pull-up mode.
	USART2_TX pin	Output push-pull	PD5 pin: USART2 transmits (remapped pins). Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

17.2 Bootloader selection

Figure 20. Bootloader selection for STM32F10xxx XL-density devices



17.3 Bootloader version

Table 34. STM32F10xxx XL-density bootloader versions

Version number	Description
V2.1	Initial bootloader version

Note: The bootloader ID format is applied to all STM32 devices families except the STM32F1xx family. The bootloader version for the STM32F1xx applies only to the embedded device bootloader version and not to its supported protocols.

18 STM32F2xxxx devices bootloader

Two bootloader versions are available on STM32F2xxxx devices:

- V2.x supporting USART1 and USART3
This version is embedded in revisions A, Z, and B
- V3.x supporting USART1, USART3, CAN2, and DFU (USB FS device)
This version is embedded in all other revisions (Y, X, W, 1, V, 2, 3, and 4)

18.1 Bootloader V2.x

18.1.1 Bootloader configuration

The STM32F2xxxx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 35](#) shows the hardware resources used by this bootloader.

Table 35. STM32F2xxxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz.
	RAM	-	8 Kbytes, starting from address 0x20000000.
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode

Table 35. STM32F2xxxx configuration in system memory boot mode (continued)

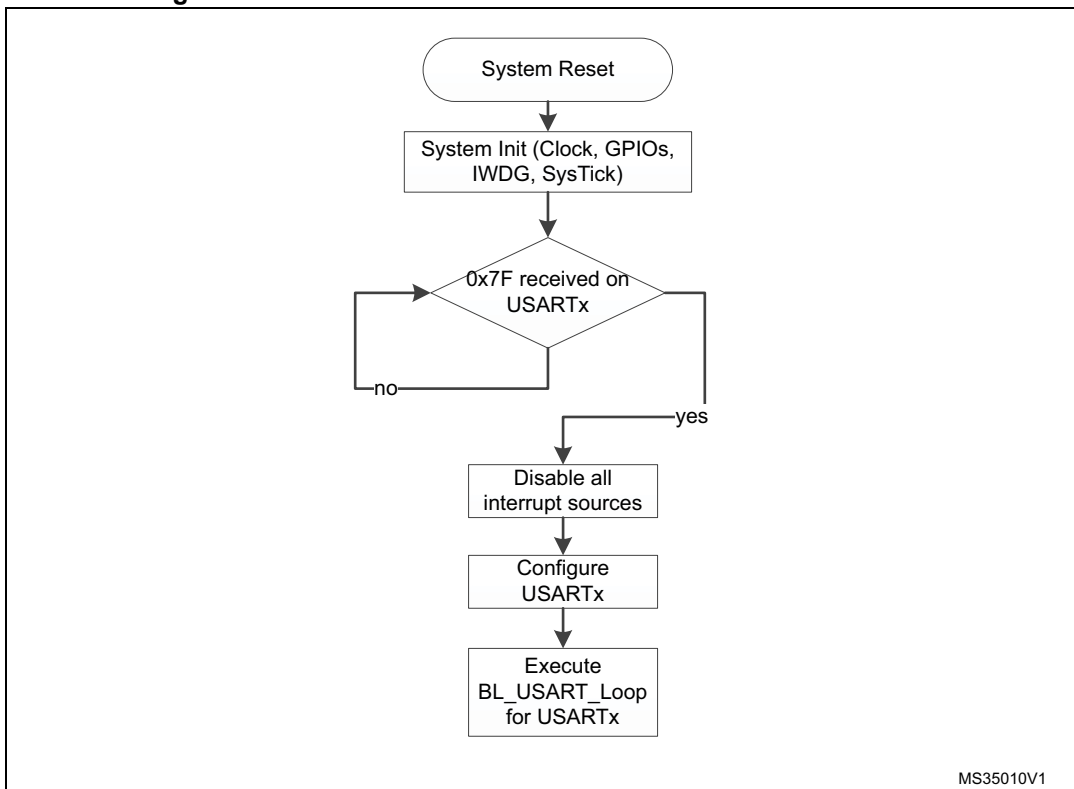
Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader code.

18.1.2 Bootloader selection

Figure 21 shows the bootloader selection mechanism.

Figure 21. Bootloader V2.x selection for STM32F2xxxx devices



18.1.3 Bootloader version

Table 36 lists the STM32F2xxxx devices V2.x bootloader versions:

Table 36. STM32F2xxxx bootloader V2.x versions

Version number	Description	Known limitations
V2.0	Initial bootloader version	When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum. For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection. ⁽¹⁾

1. If the "number of data - 1" (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), the limitation is not perceived from the host, as the command is NACKed anyway (as an unsupported new command).

18.2 Bootloader V3.x

18.2.1 Bootloader configuration

The STM32F2xxxx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 37](#) shows the hardware resources used by this bootloader.

Table 37. STM32F2xxxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USARTx interfaces are selected (once CAN or DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	8 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	29 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	Voltage range is set to 1.62 V, 2.1 V. In this range internal flash write operations are allowed only in byte format (half-word, word and double-word operations are not allowed). The voltage range can be configured in run time using bootloader commands.	
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in no pull mode.
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in pull-up mode
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in pull-up mode

Table 37. STM32F2xxxx configuration in system memory boot mode (continued)

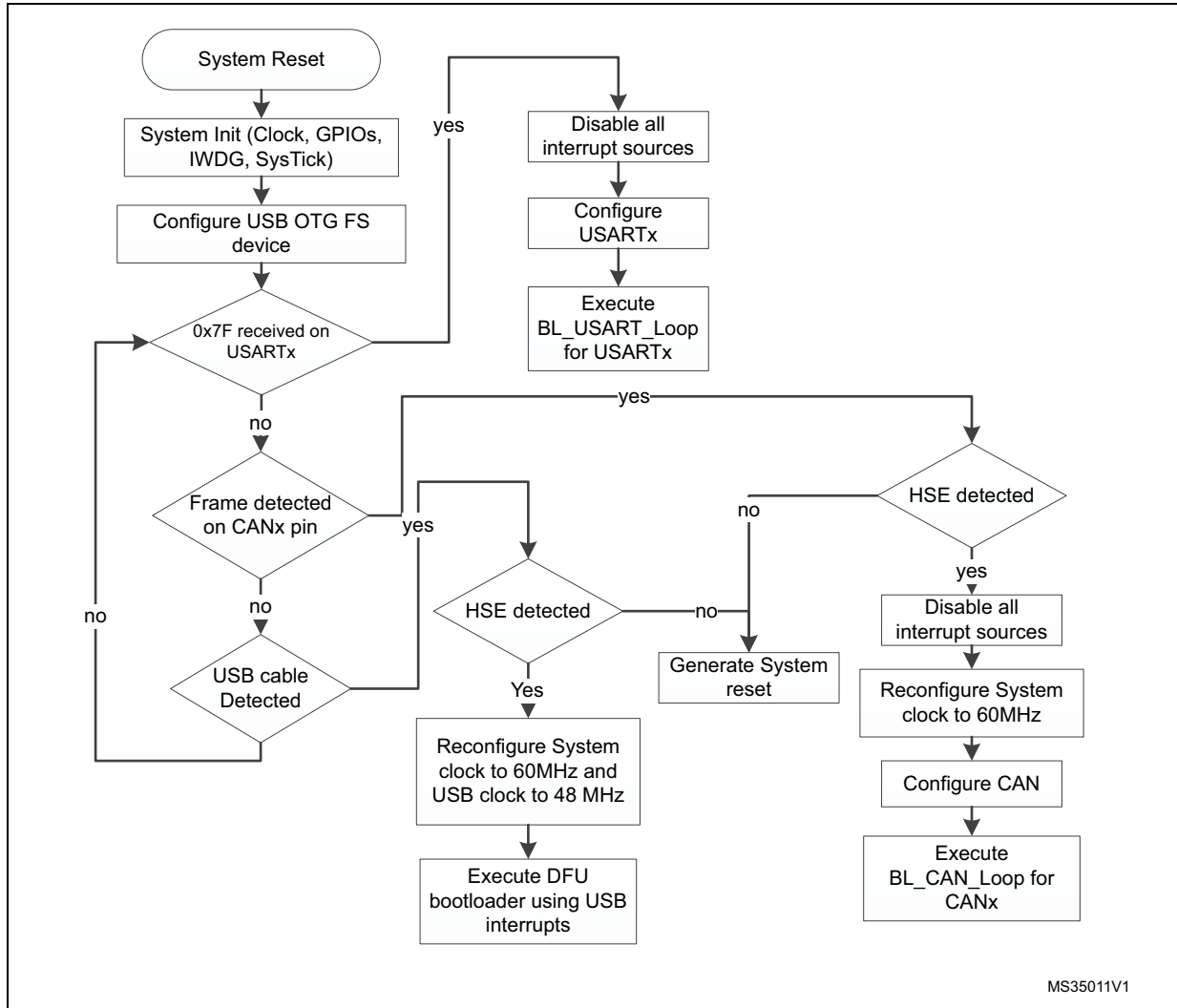
Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized, the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in inpt no pull mode. No external pull-up resistor is required
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

18.2.2 Bootloader selection

Figure 22 shows the bootloader selection mechanism.

Figure 22. Bootloader V3.x selection for STM32F2xxxx devices



18.2.3 Bootloader version

Table 38 lists the STM32F2xxxx devices V3.x bootloader versions:

Table 38. STM32F2xxxx bootloader V3.x versions

Version number	Description	Known limitations
V3.2	Initial bootloader version	<ul style="list-style-type: none"> – When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum⁽¹⁾. – Option bytes, OTP and Device Feature descriptors (in DFU interface) are set to “g” instead of “e” (not erasable memory areas).
V3.3	Fix V3.2 limitations. DFU interface robustness enhancement	<ul style="list-style-type: none"> – For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection.

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), the limitation is not perceived from the host, as the command is NACKed anyway (as an unsupported new command).

19 STM32F301xx/302x4(6/8) devices bootloader

19.1 Bootloader configuration

The STM32F301xx/302x4(6/8) bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 39](#) shows the hardware resources used by this bootloader.

Table 39. STM32F301xx/302x4(6/8) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one the following values: 24, 18, 16, 12, 9, 8, 6, 4, 3 MHz. The PLL is used to generate the USB48 MHz clock and the 48 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 39. STM32F301xx/302x4(6/8) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 KΩ must be connected to USB_DP pin.

The bootloader has two cases of operation, depending upon the presence of the external clock (HSE) at bootloader startup:

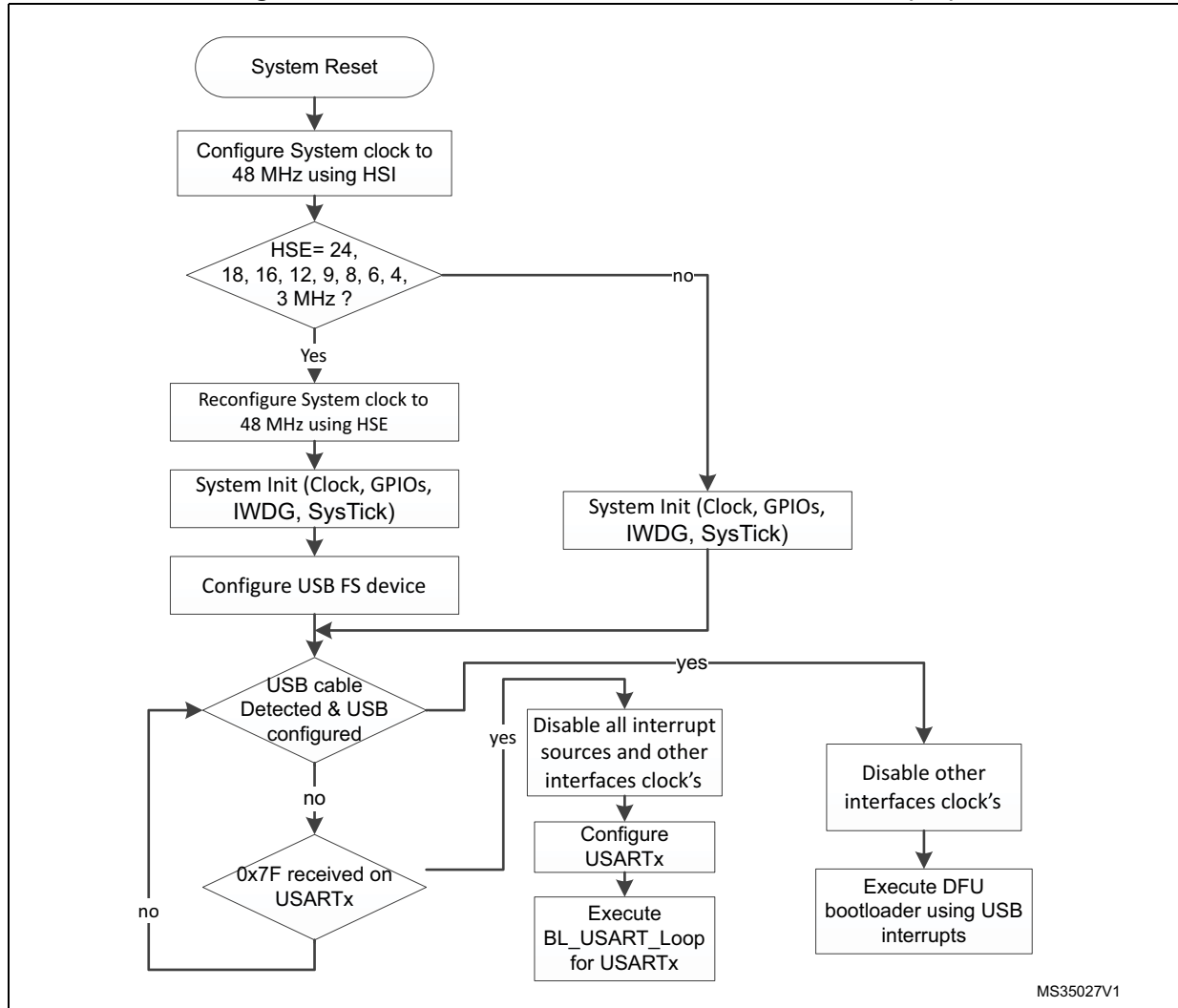
- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4, or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

19.2 Bootloader selection

Figure 23 shows the bootloader selection mechanism.

Figure 23. Bootloader selection for STM32F301xx/302x4(6/8)



19.3 Bootloader version

Table 40 lists the STM32F301xx/302x4(6/8) devices bootloader versions:

Table 40. STM32F301xx/302x4(6/8) bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	None

20 STM32F302xB(C)/303xB(C) devices bootloader

20.1 Bootloader configuration

The STM32F302xB(C)/303xB(C) bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 41](#) shows the hardware resources used by this bootloader.

Table 41. STM32F302xB(C)/303xB(C) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment	
Common to all bootloaders	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.	
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one of the following values: 24, 18, 16, 12, 9, 8, 6, 4, 3 MHz. The PLL is used to generate the USB 48 MHz clock and the 48 MHz clock for the system clock.	
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.	
	RAM	-	5 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.	
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware.	
IWDG	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).	
		USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
		USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
USART1 bootloader	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.	
	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.	
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.	
USART2 bootloader	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.	
	USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.

Table 41. STM32F302xB(C)/303xB(C) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 K Ω must be connected to USB_DP pin.

The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

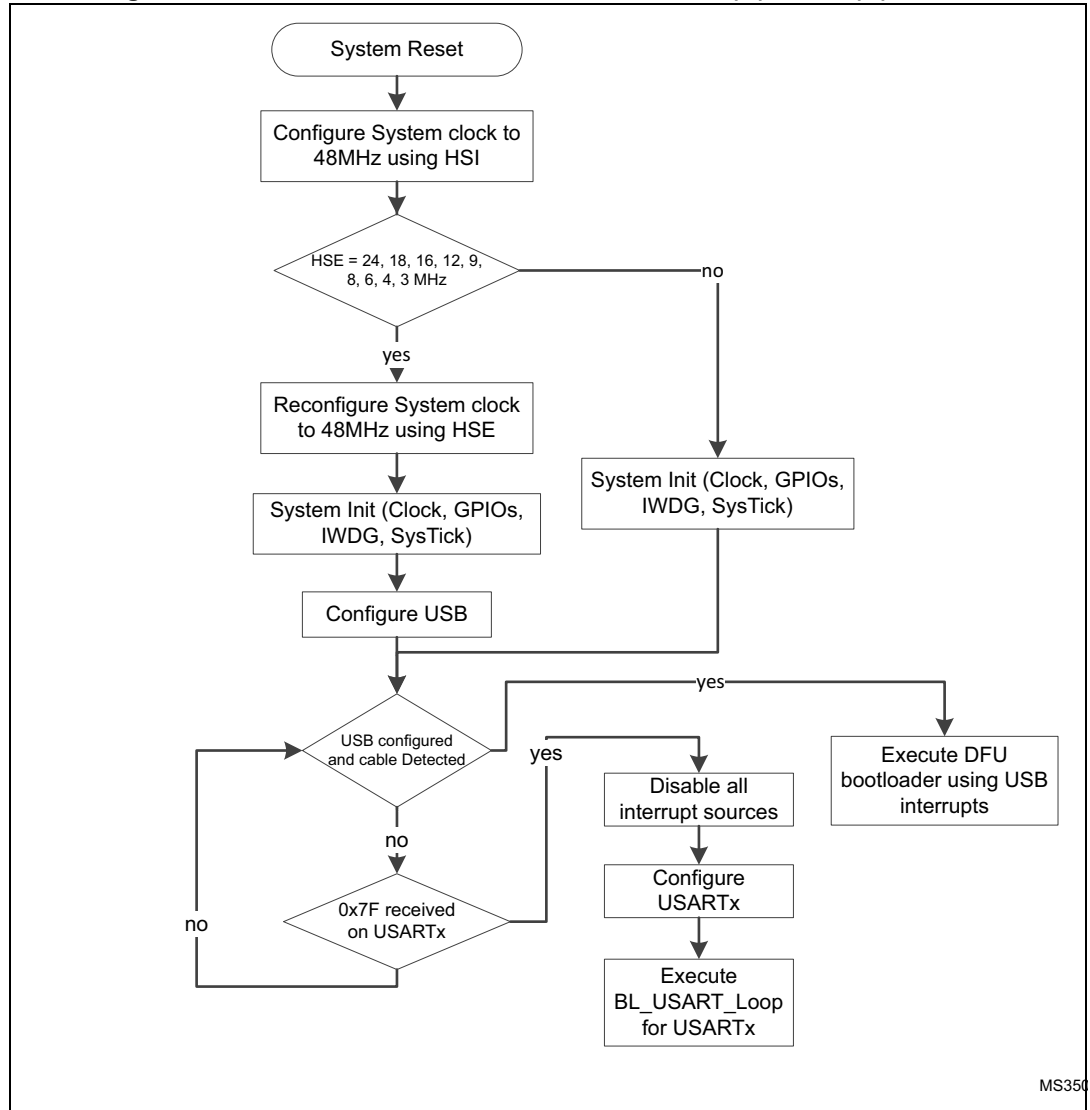
- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4 or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

20.2 Bootloader selection

Figure 24 shows the bootloader selection mechanism.

Figure 24. Bootloader selection for STM32F302xB(C)/303xB(C) devices



20.3 Bootloader version

Table 42 lists the STM32F302xB(C)/303xB(C) devices bootloader versions.

Table 42. STM32F302xB(C)/303xB(C) bootloader versions

Version number	Description	Known limitations
V4.1	Initial bootloader version	None

21 STM32F302xD(E)/303xD(E) devices bootloader

21.1 Bootloader configuration

The STM32F302xD(E)/303xD(E) bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 43](#) shows the hardware resources used by this bootloader.

Table 43. STM32F302xD(E)/303xD(E) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 48 MHz with HSI48 48 MHz as clock source.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one the following values: 24, 18, 16, 12, 9, 8, 6, 4, 3 MHz. The PLL is used to generate the USB 48 MHz clock and the 48 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 43. STM32F302xD(E)/303xD(E) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 KΩ must be connected to USB_DP pin.

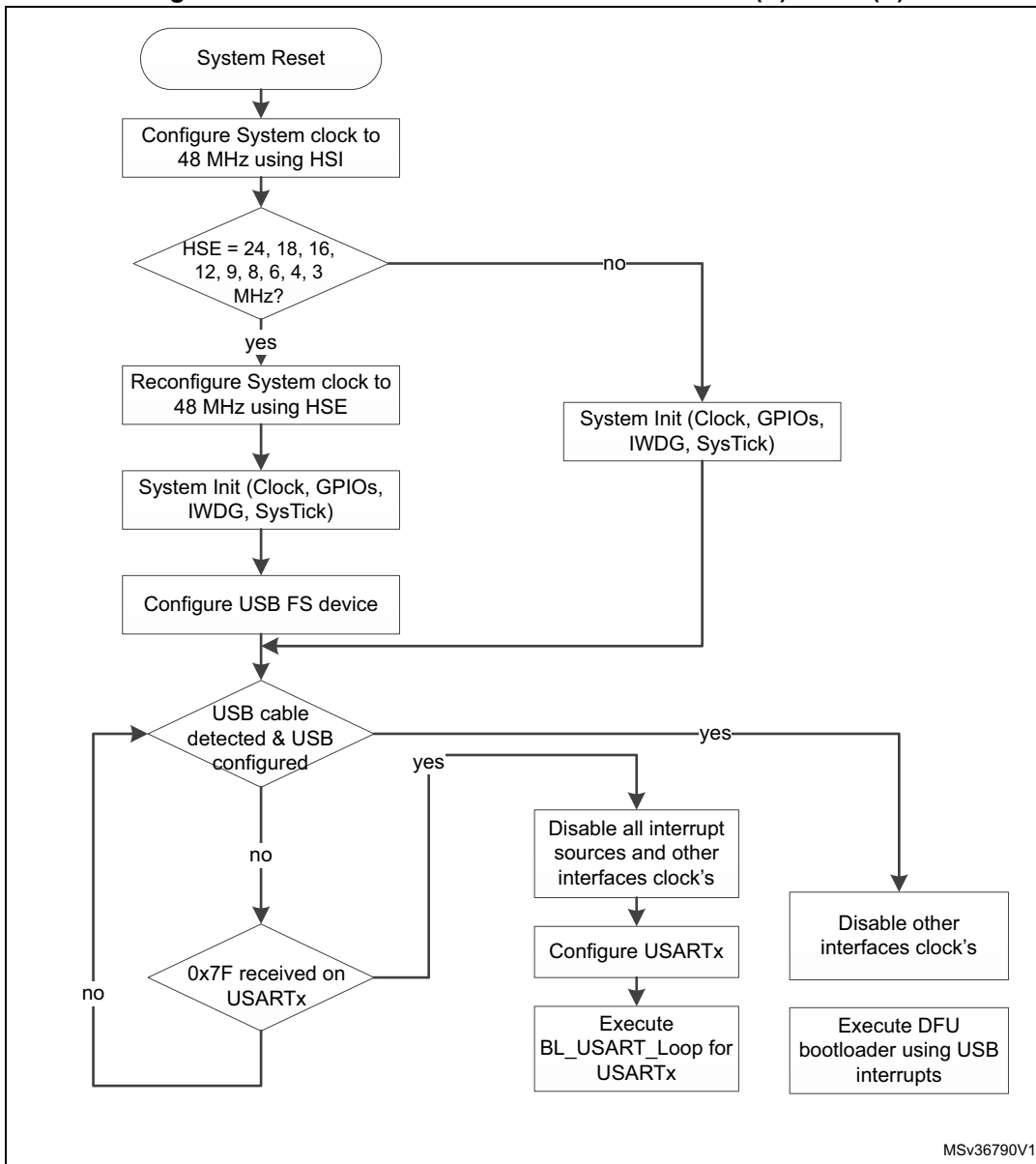
The bootloader has two cases of operation depending on the presence of the external clock (HSE) at bootloader startup:

- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4 or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader device.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

21.2 Bootloader selection

Figure 25. Bootloader selection for STM32F302xD(E)/303xD(E)



21.3 Bootloader version

Table 44. STM32F302xD(E)/303xD(E) bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	None

22 STM32F303x4(6/8)/334xx/328xx devices bootloader

22.1 Bootloader configuration

The STM32F303x4(6/8)/334xx/328xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 45](#) shows the hardware resources used by this bootloader.

Table 45. STM32F303x4(6/8)/334xx/328xx configuration in system memory boot mode

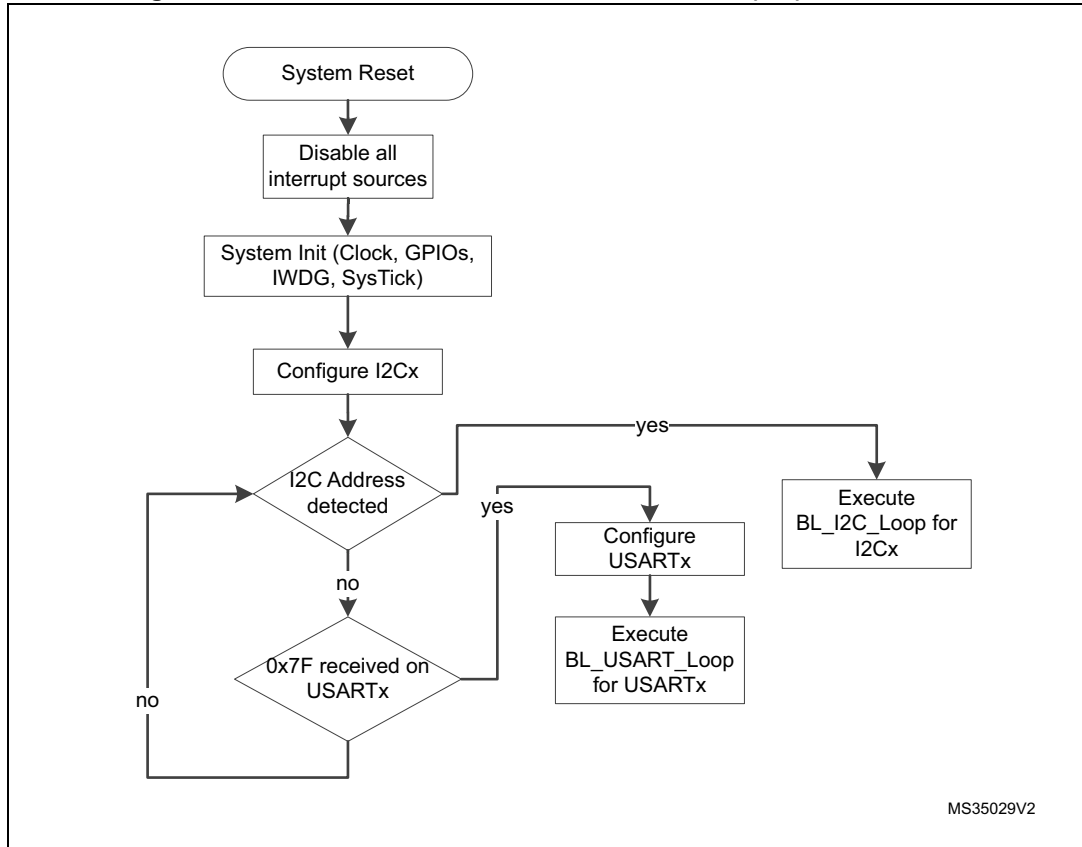
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111111x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

22.2 Bootloader selection

Figure 26 shows the bootloader selection mechanism.

Figure 26. Bootloader selection for STM32F303x4(6/8)/334xx/328xx



22.3 Bootloader version

Table 46 lists the STM32F303x4(6/8)/334xx/328xx devices bootloader versions:

Table 46. STM32F303x4(6/8)/334xx/328xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	None

23 STM32F318xx devices bootloader

23.1 Bootloader configuration

The STM32F318xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 47](#) shows the hardware resources used by this bootloader.

Table 47. STM32F318xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value, and periodically refreshed to prevent a reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111101x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

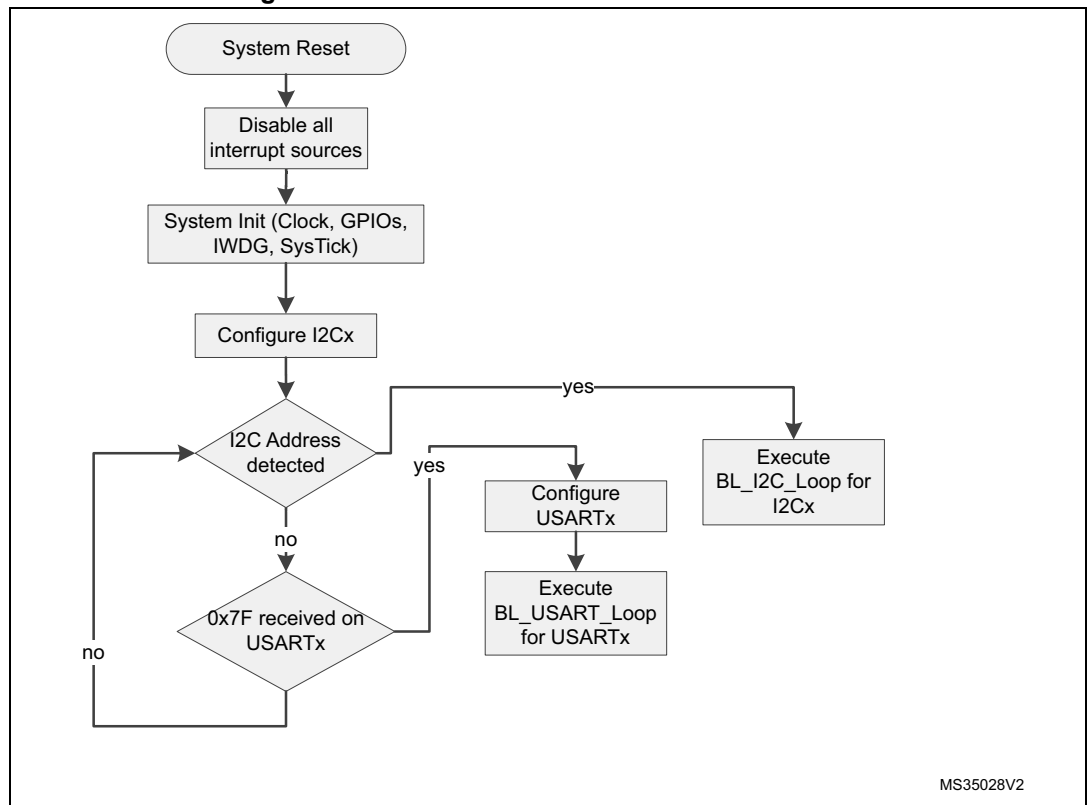
Table 47. STM32F318xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111101x (where x = 0 for write and x = 1 for read) and digital filter disabled.
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB5 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

23.2 Bootloader selection

Figure 27. Bootloader selection for STM32F318xx



23.3 Bootloader version

Table 48. STM32F318xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	None

24 STM32F358xx devices bootloader

24.1 Bootloader configuration

The STM32F358xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 49](#) shows the hardware resources used by this bootloader.

Table 49. STM32F358xx configuration in system memory boot mode

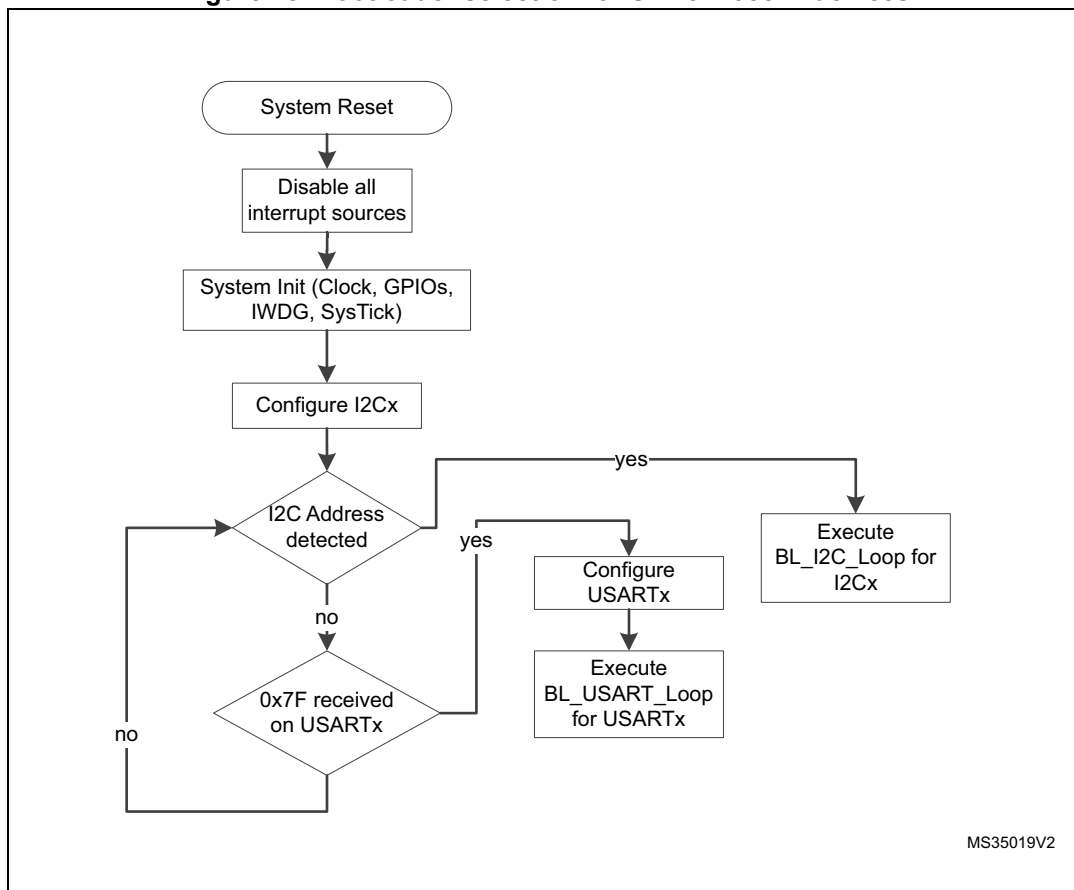
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 8 MHz using the HSI.
	RAM	-	5 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user). Window feature is disabled.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0110111x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

24.2 Bootloader selection

Figure 28 shows the bootloader selection mechanism.

Figure 28. Bootloader selection for STM32F358xx devices



24.3 Bootloader version

Table 50 lists the STM32F358xx devices bootloader versions.

Table 50. STM32F358xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	For USART1 and USART2 interfaces, the maximum baudrate supported by the bootloader is 57600 baud.

25 STM32F373xx devices bootloader

25.1 Bootloader configuration

The STM32F373xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 51](#) shows the hardware resources used by this bootloader.

Table 51. STM32F373xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	At startup, the system clock frequency is configured to 48 MHz using the HSI. If an external clock (HSE) is not present, the system is kept clocked from the HSI.
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one the following values: 24, 18, 16, 12, 9, 8, 6, 4, 3 MHz. The PLL is used to generate the USB 48 MHz clock and the 48 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	RAM	-	5 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware
USART1 bootloader	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.

Table 51. STM32F373xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. An external pull-up resistor 1.5 K Ω must be connected to USB_DP pin.

There are two operation modes, depending upon the presence of the external clock (HSE) at bootloader startup:

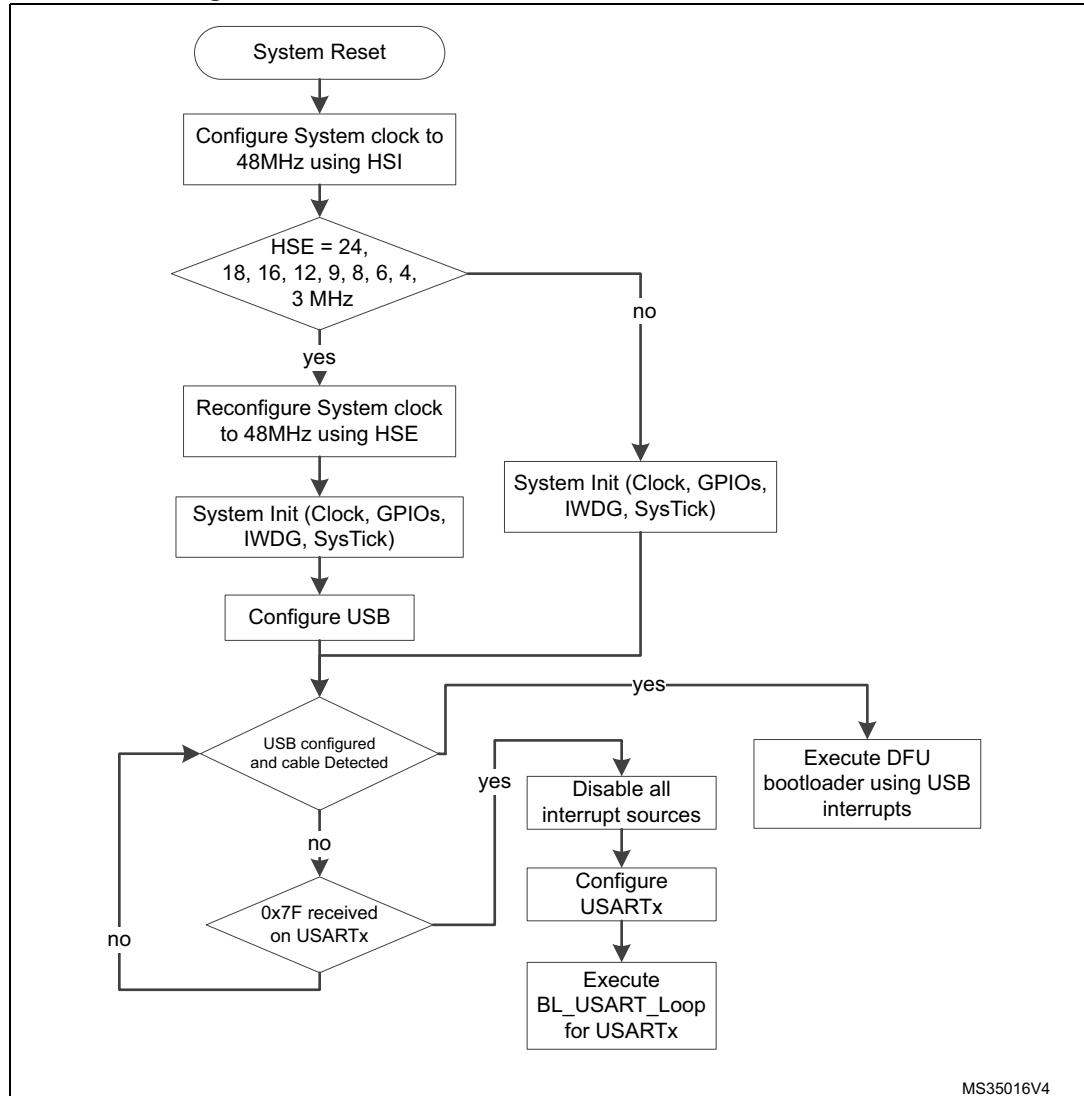
- If HSE is present and has a value of 24, 18, 16, 12, 9, 8, 6, 4, or 3 MHz, the system clock is configured to 48 MHz with HSE as clock source. The DFU interface, USART1 and USART2 are functional and can be used to communicate with the bootloader.
- If HSE is not present, the HSI is kept as default clock source, and only USART1 and USART2 are functional.

Note: The external clock (HSE) must be kept if it is connected at bootloader startup, because it is used as system clock source.

25.2 Bootloader selection

Figure 29 shows the bootloader selection mechanism.

Figure 29. Bootloader selection for STM32F373xx devices



MS35016V4

25.3 Bootloader version

Table 52 lists the STM32F373xx devices bootloader versions.

Table 52. STM32F373xx bootloader versions

Version number	Description	Known limitations
V4.1	Initial bootloader version	None

26 STM32F378xx devices bootloader

26.1 Bootloader configuration

The STM32F378xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 53](#) shows the hardware resources used by this bootloader.

Table 53. STM32F378xx configuration in system memory boot mode

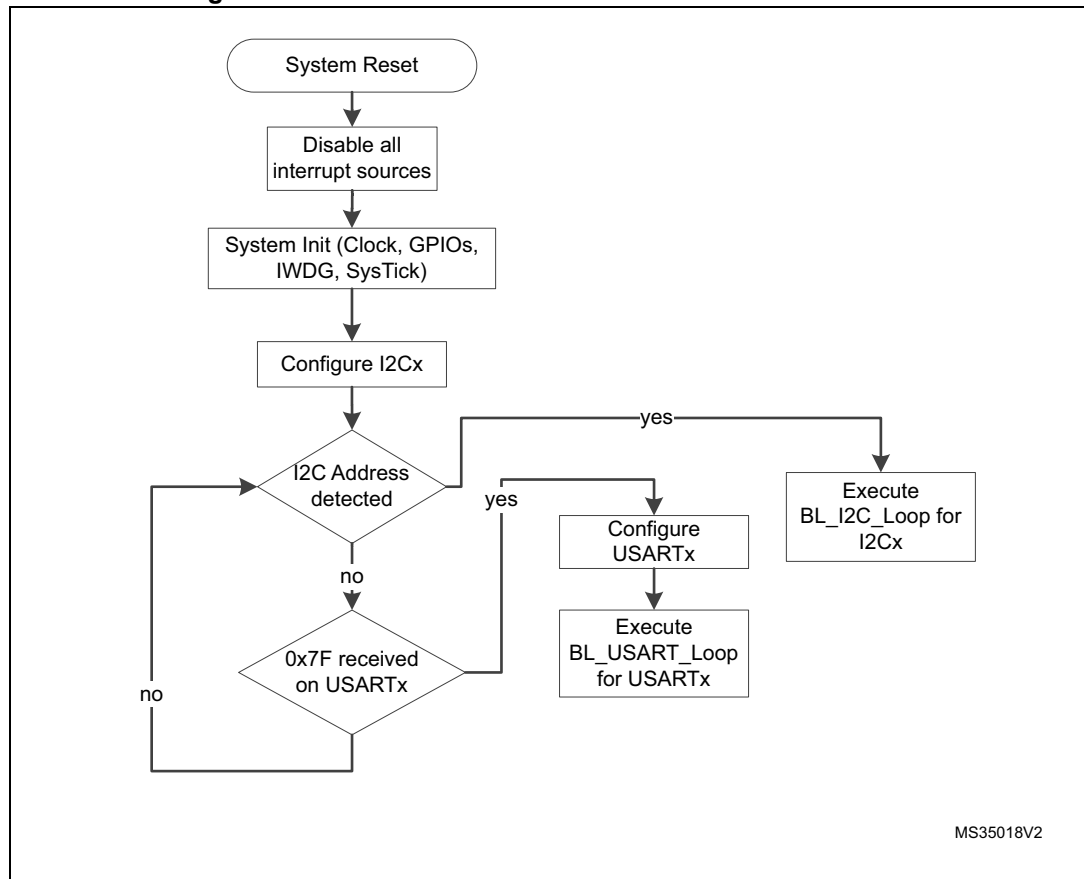
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 8 MHz using the HSI.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FFFD800, contains the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user). Window feature is disabled.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0110111x (where x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC. No external quartz is required for the bootloader execution.

26.2 Bootloader selection

Figure 30 shows the bootloader selection mechanism.

Figure 30. Bootloader selection for STM32F378xx devices



26.3 Bootloader version

Table 54 lists the STM32F378xx devices bootloader versions.

Table 54. STM32F378xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	For USART1 and USART2 interfaces, the maximum baudrate supported by the bootloader is 57600 baud.

27 STM32F398xx devices bootloader

27.1 Bootloader configuration

The STM32F398xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). [Table 55](#) shows the hardware resources used by this bootloader.

Table 55. STM32F398xx configuration in system memory boot mode

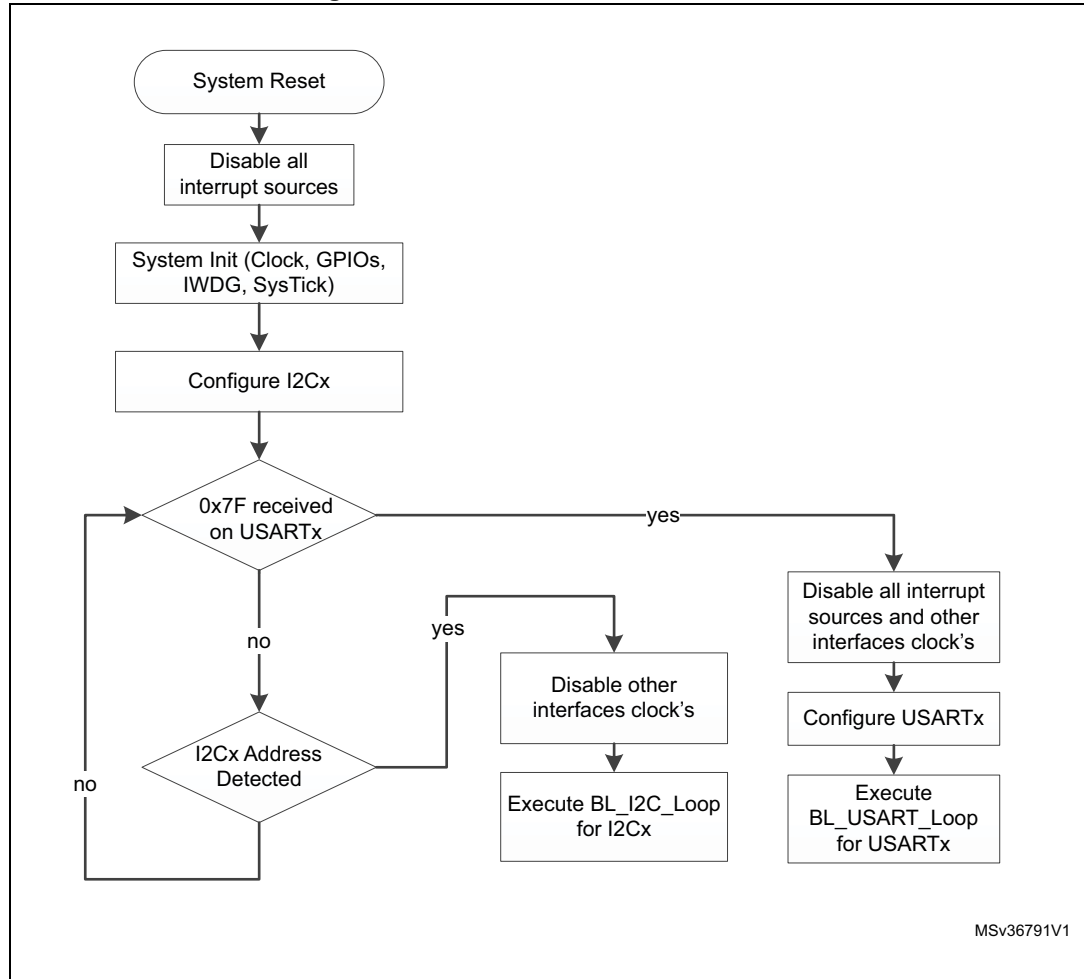
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz with HSI 8 MHz as clock source.
	RAM	-	6 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	7 Kbytes, starting from address 0x1FFFD800, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000000x (where x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000000x (where x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB5 pin: data line is used in open-drain no pull mode.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

27.2 Bootloader selection

Figure 31 shows the bootloader selection mechanism.

Figure 31.Bootloader selection for STM32F398xx



27.3 Bootloader version

Table 56 lists the STM32F398xx devices bootloader versions.

Table 56. STM32F398xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	None

28 STM32F40xxx/41xxx devices bootloader

28.1 Bootloader V3.x

28.1.1 Bootloader configuration

The STM32F40xxx/41xxx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 57](#) shows the hardware resources used by this bootloader.

Table 57. STM32F40xxx/41xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USARTx interfaces are selected (once CAN or DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	8 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	29 Kbytes, starting from address 0x1FFF0000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.

Table 57. STM32F40xxx/41xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized, the USART3 configuration is 8 bits, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized, the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

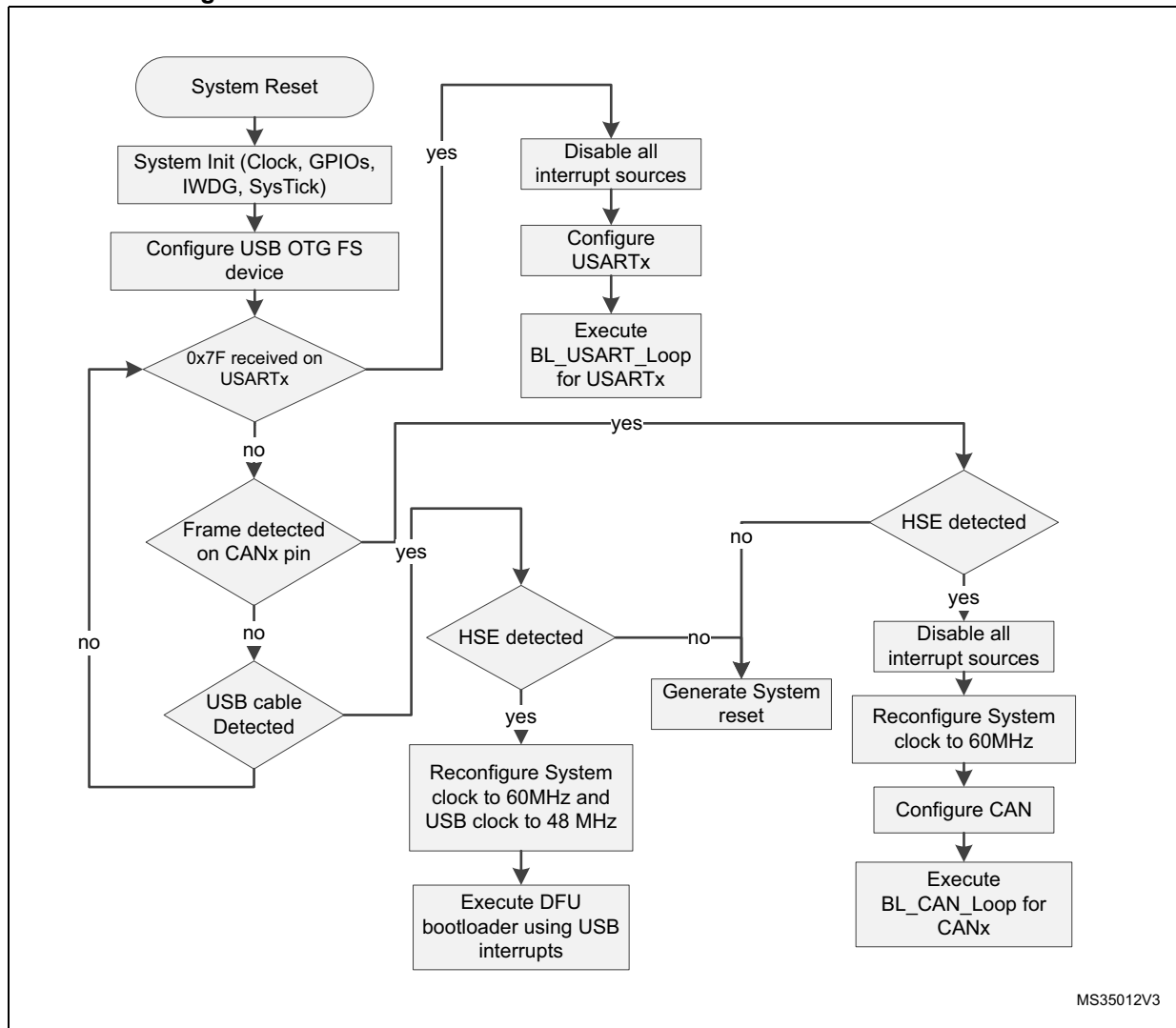
The system clock is derived from the embedded internal high-speed RC for USARTx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystals (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

28.1.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 32. Bootloader V3.x selection for STM32F40xxx/41xxx devices



MS35012V3

28.1.3 Bootloader version

Table 58 lists the STM32F40xxx/41xxx devices V3.x bootloader versions:

Table 58. STM32F40xxx/41xxx bootloader V3.x versions

Version number	Description	Known limitations
V3.0	Initial bootloader version	<ul style="list-style-type: none"> – When a Read Memory command or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (which are the number of bytes to be read/written and its checksum) are considered as a new command and its checksum⁽¹⁾. – Option bytes, OTP and Device Feature descriptors (in DFU interface) are set to “g” instead of “e” (not erasable memory areas). <p>After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)</p>
V3.1	Fix V3.0 limitations. DFU interface robustness enhancement.	<ul style="list-style-type: none"> – For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection. <p>After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)</p>

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code (0x00, 0x01, 0x02, 0x11, 0x21, 0x31, 0x43, 0x44, 0x63, 0x73, 0x82 or 0x92), the limitation is not perceived from the host, as the command is NACKed anyway (as an unsupported new command).

28.2 Bootloader V9.x

28.2.1 Bootloader configuration

The STM32F40xxx/41xxx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 59](#) shows the hardware resources used by this bootloader.

Note: The bootloader version V9.0 is embedded only in STM32F405xx/415xx devices in WLCSP90 package.

Version V9.1 is populated in all packages of the product.

Table 59. STM32F40xxx/41xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interfaces are selected (once CAN or DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 59. STM32F40xxx/41xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111010x (where x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111010x (where x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111010x (where x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.

Table 59. STM32F40xxx/41xxx configuration in system memory boot mode (continued)

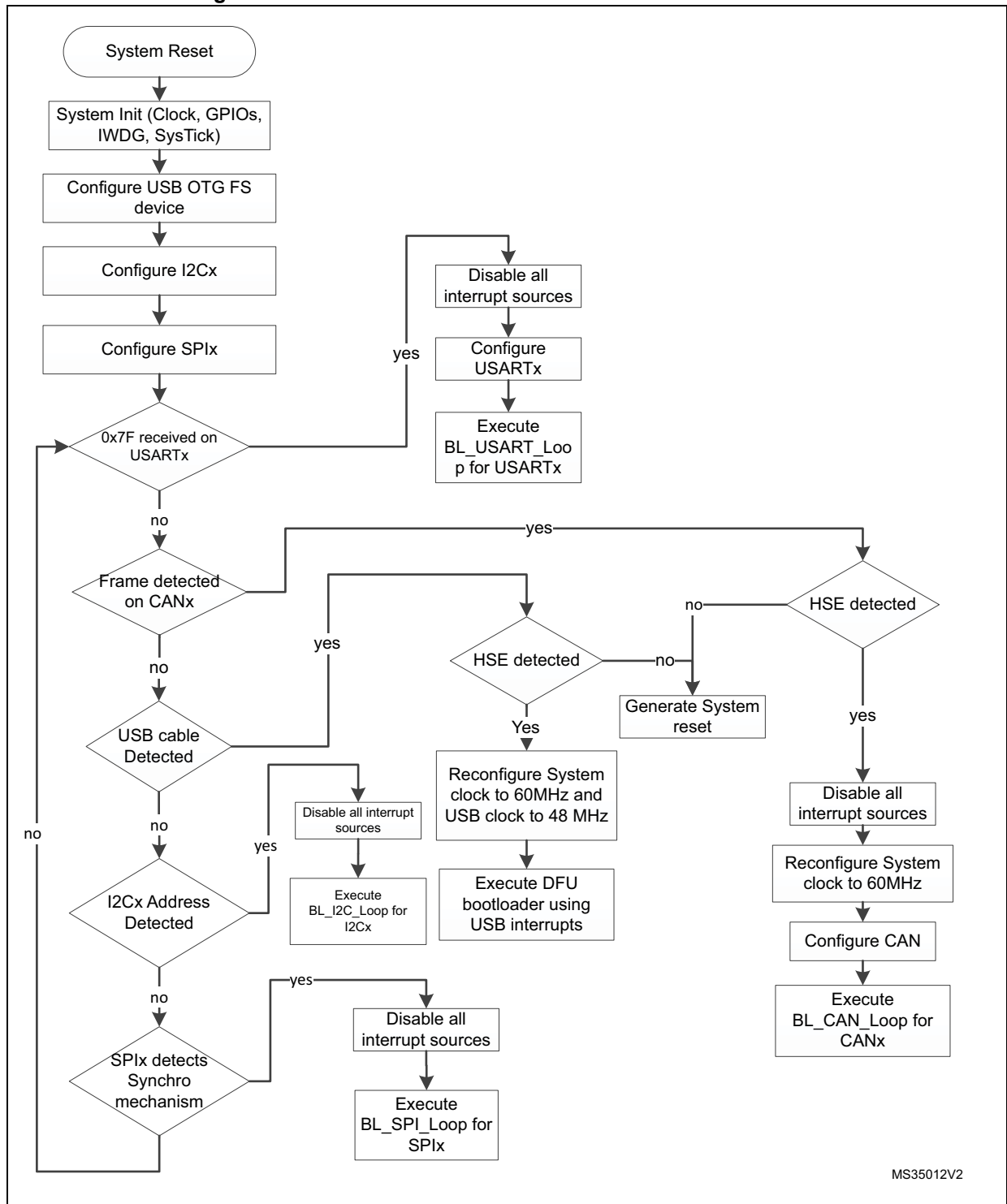
Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

28.2.2 Bootloader selection

Figure 33. Bootloader V9.x selection for STM32F40xxx/41xxx



MS35012V2

28.2.3 Bootloader version

[Table 60](#) lists the STM32F40xxx/41xxx devices V9.x bootloader versions.

Table 60. STM32F40xxx/41xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	<p>This bootloader is an updated version of bootloader v3.1.</p> <p>This new version of bootloader supports I2C1, I2C2, I2C3, SPI1 and SPI2 interfaces.</p> <p>The RAM used by this bootloader is increased from 8Kb to 12Kb.</p> <p>The ID of this bootloader is 0x90.</p> <p>The connection time is increased.</p>	<ul style="list-style-type: none"> – For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. – For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection. <p>After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)</p>
V9.1	<p>This bootloader is an updated version of bootloader v9.0 that will be populated in all packages even the one embedding the V3.1 bootloader version.</p> <p>It contains fixes of the known limitations of the V9.0</p>	None

29 STM32F401xB(C) devices bootloader

29.1 Bootloader configuration

The STM32F401xB(C) bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 61](#) shows the hardware resources used by this bootloader.

Table 61. STM32F401xB(C) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected (once DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the DFU (USB FS device) interface is selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 61. STM32F401xB(C) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB3 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB4 pin: data line is used in open-drain no pull mode.

Table 61. STM32F401xB(C) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.

Table 61. STM32F401xB(C) configuration in system memory boot mode (continued)

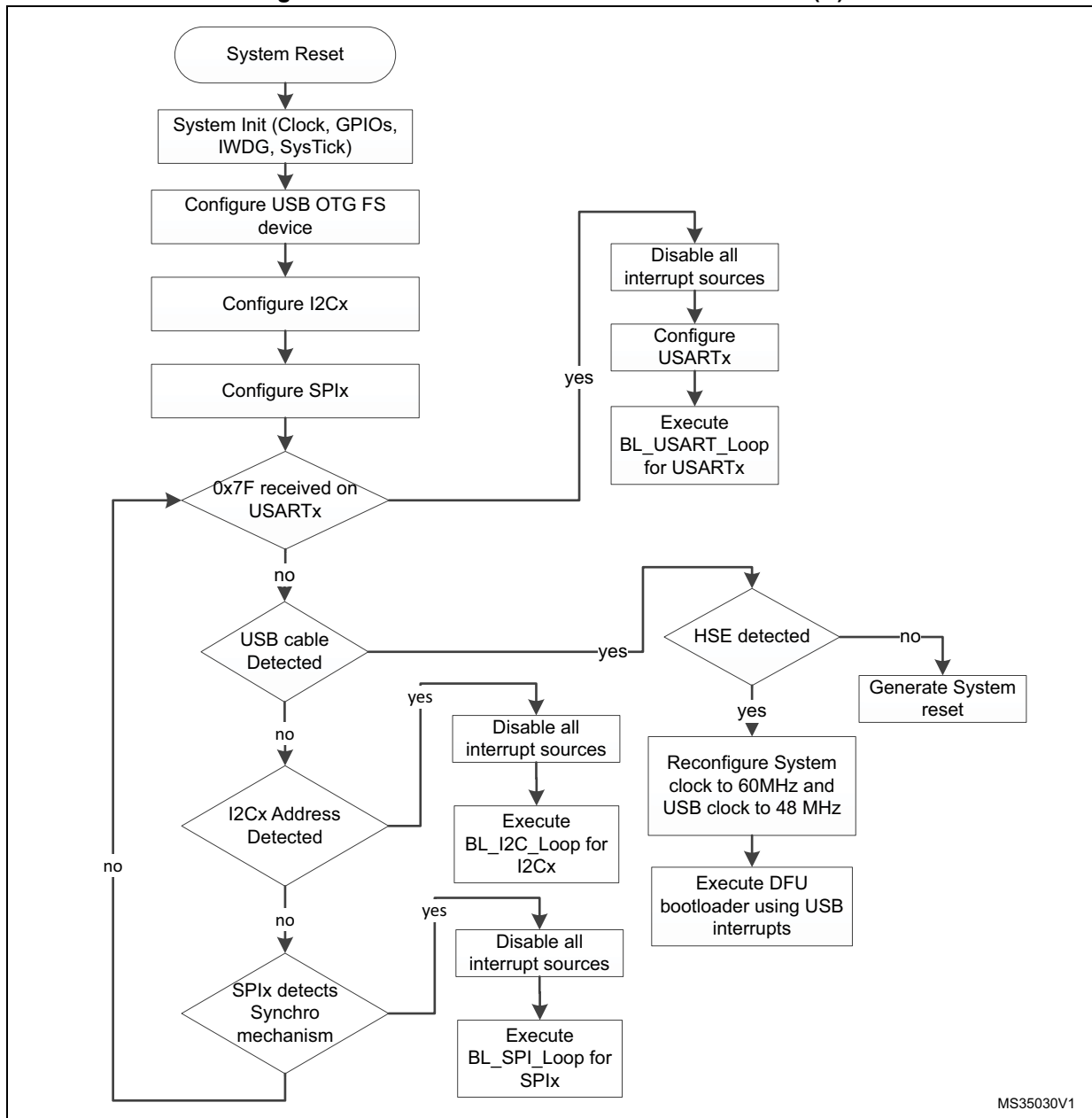
Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock, multiple of 1 MHz (between 4 and 26 MHz), is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

29.2 Bootloader selection

Figure 34. Bootloader selection for STM32F401xB(C)



29.3 Bootloader version

Table 62. STM32F401xB(C) bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version	<ul style="list-style-type: none">– After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)– The bootloader does not support the reset of SPRMOD bit during RDP regression

30 STM32F401xD(E) devices bootloader

30.1 Bootloader configuration

The STM32F401xD(E) bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 63](#) shows the hardware resources used by this bootloader.

Table 63. STM32F401xD(E) configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected (once DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the DFU (USB FS device) interface is selected. The external clock must provide a frequency multiple of 1 MHz, ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	Voltage range is set to 1.62 V, 2.1 V. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.	
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in pull-up mode.

Table 63. STM32F401xD(E) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – slave mode – analog filter ON – Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – slave mode – analog filter ON – . Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB3 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – slave mode – analog filter ON – Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB4 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 63. STM32F401xD(E) configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

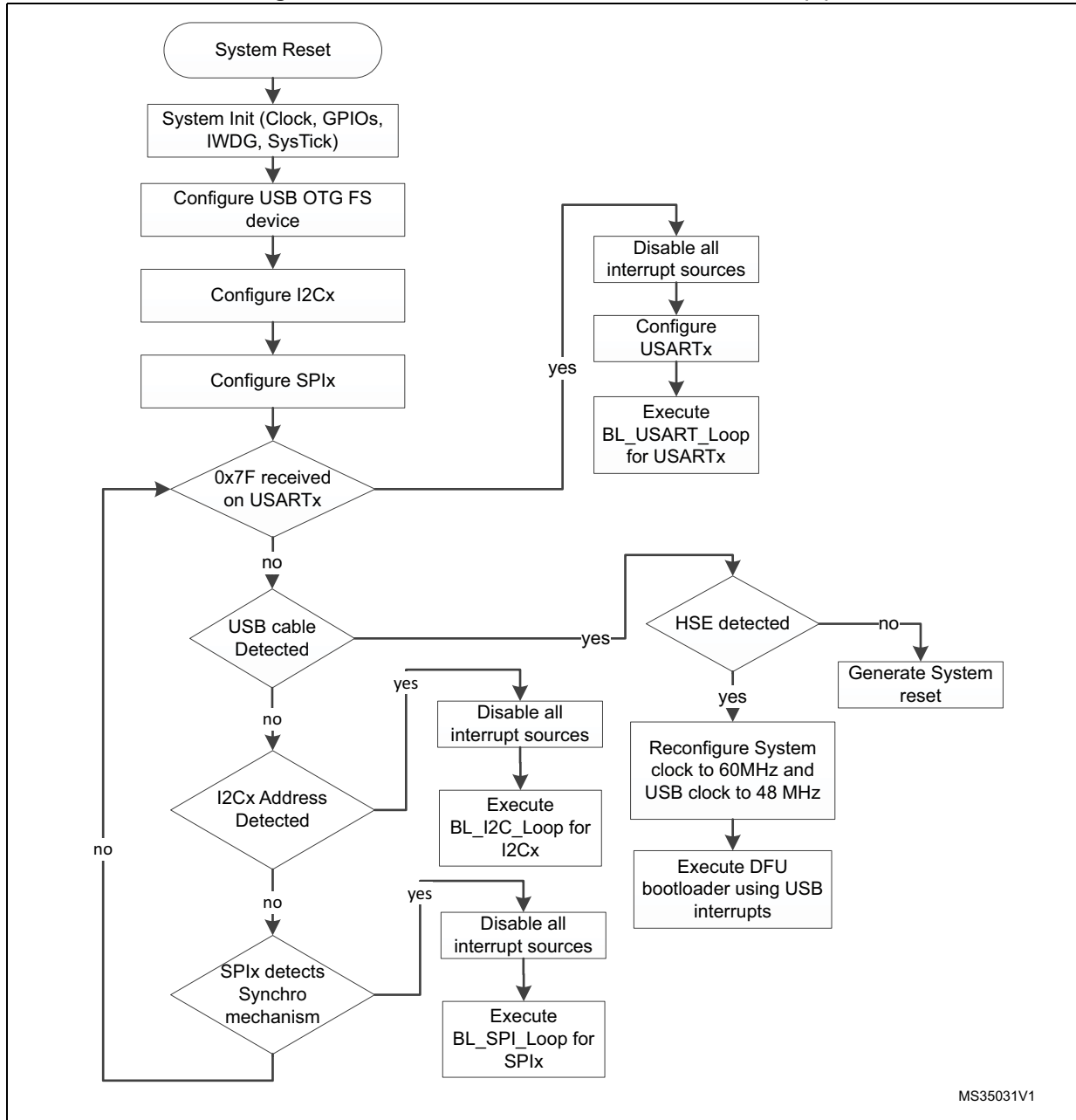
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, and SPIx bootloaders. This internal clock is also used for DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

30.2 Bootloader selection

Figure 35 shows the bootloader selection mechanism.

Figure 35. Bootloader selection for STM32F401xD(E)



MS35031V1

30.3 Bootloader version

The following table lists the STM32F401xD(E) devices bootloader version.

Table 64. STM32F401xD(E) bootloader versions

Version number	Description	Known limitations
V13.1	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

31 STM32F410xx devices bootloader

31.1 Bootloader configuration

The STM32F410xx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 65. STM32F410xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
	RAM	-	5 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V] In this range: - flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - flash write operation by byte (refer to bootloader memory management section for more information).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 65. STM32F410xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000111x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000111x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C4 bootloader	I2C4	Enabled	The I2C4 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000111x (where x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PB15 pin: clock line is used in open-drain no pull mode for STM32F410Cx/Rx devices. PB10 pin: clock line is used in open-drain no pull mode for STM32F410Tx devices.
	I2C4_SDA pin	Input/output	PB14 pin: data line is used in open-drain no pull mode for STM32F410Cx/Rx devices. PB3 pin: data line is used in open-drain no pull mode for STM32F410Tx devices.

Table 65. STM32F410xx configuration in system memory boot mode (continued)

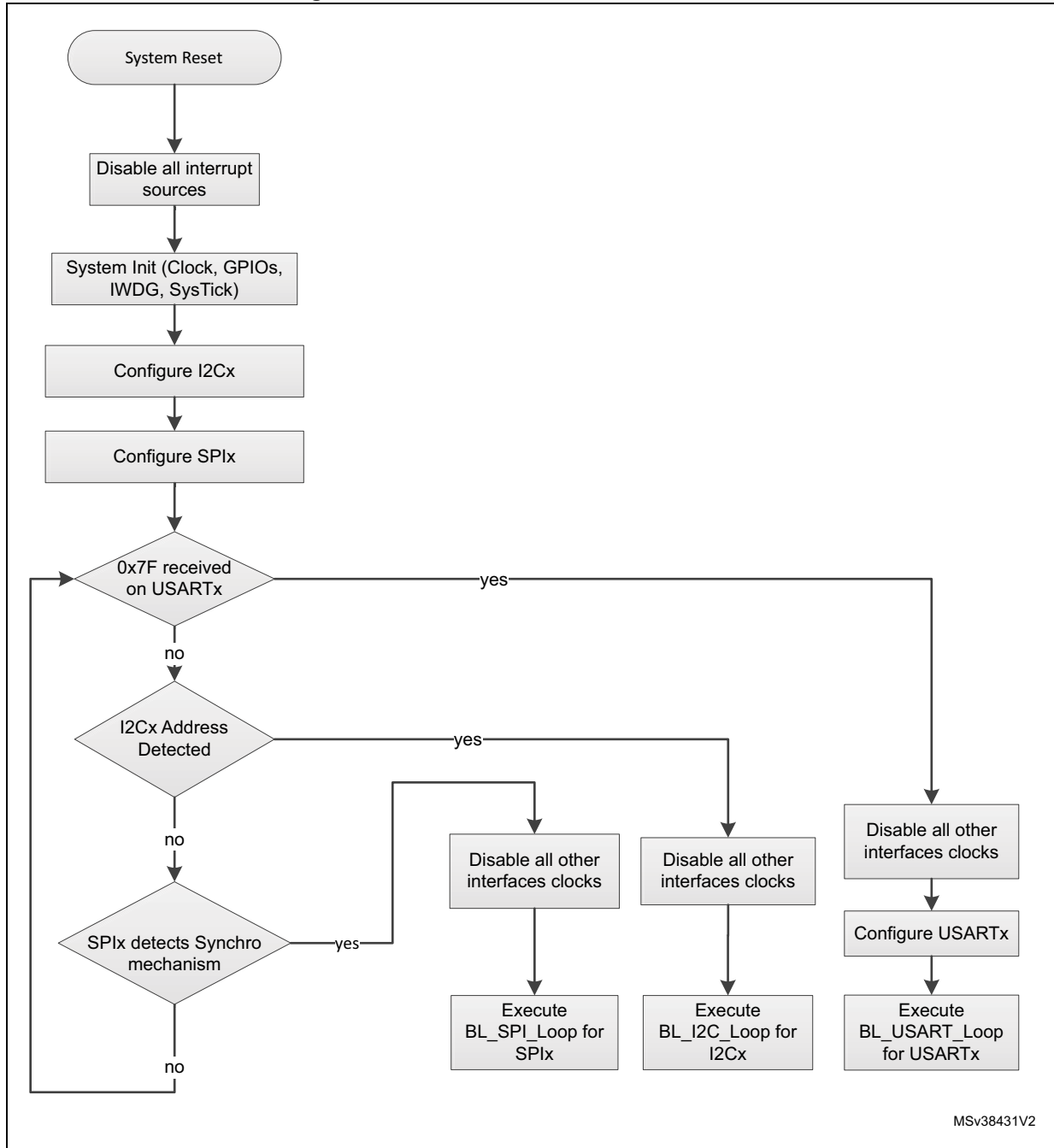
Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode for STM32F410Cx/Rx devices. PB5 pin: slave data Input line, used in push-pull, pull-down mode for STM32F410Tx devices.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode for STM32F410Cx/Rx devices. PB4 pin: slave data output line, used in push-pull, pull-down mode for STM32F410Tx devices.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push- pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-up mode for STM32F410Cx/Rx devices. PA15 pin: slave chip select pin used in push-pull, pull-down mode for STM32F410Tx devices.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PC3 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PC2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push- pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

31.2 Bootloader selection

Figure 36 shows the bootloader selection mechanism.

Figure 36.Bootloader V11.x selection for STM32F410xx



31.3 Bootloader version

The following table lists the STM32F410xx devices bootloader V11.x versions.

Table 66. STM32F410xx bootloader V11.x versions

Version number	Description	Known limitations
V11.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)
V11.1	Support I2C4 and SPI1 for STM32F410Tx devices.	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

32 STM32F411xx devices bootloader

32.1 Bootloader configuration

The STM32F411xx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 67. STM32F411xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected (once DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the DFU (USB FS device) interface is selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 67. STM32F411xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB3 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111001x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB4 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 67. STM32F411xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

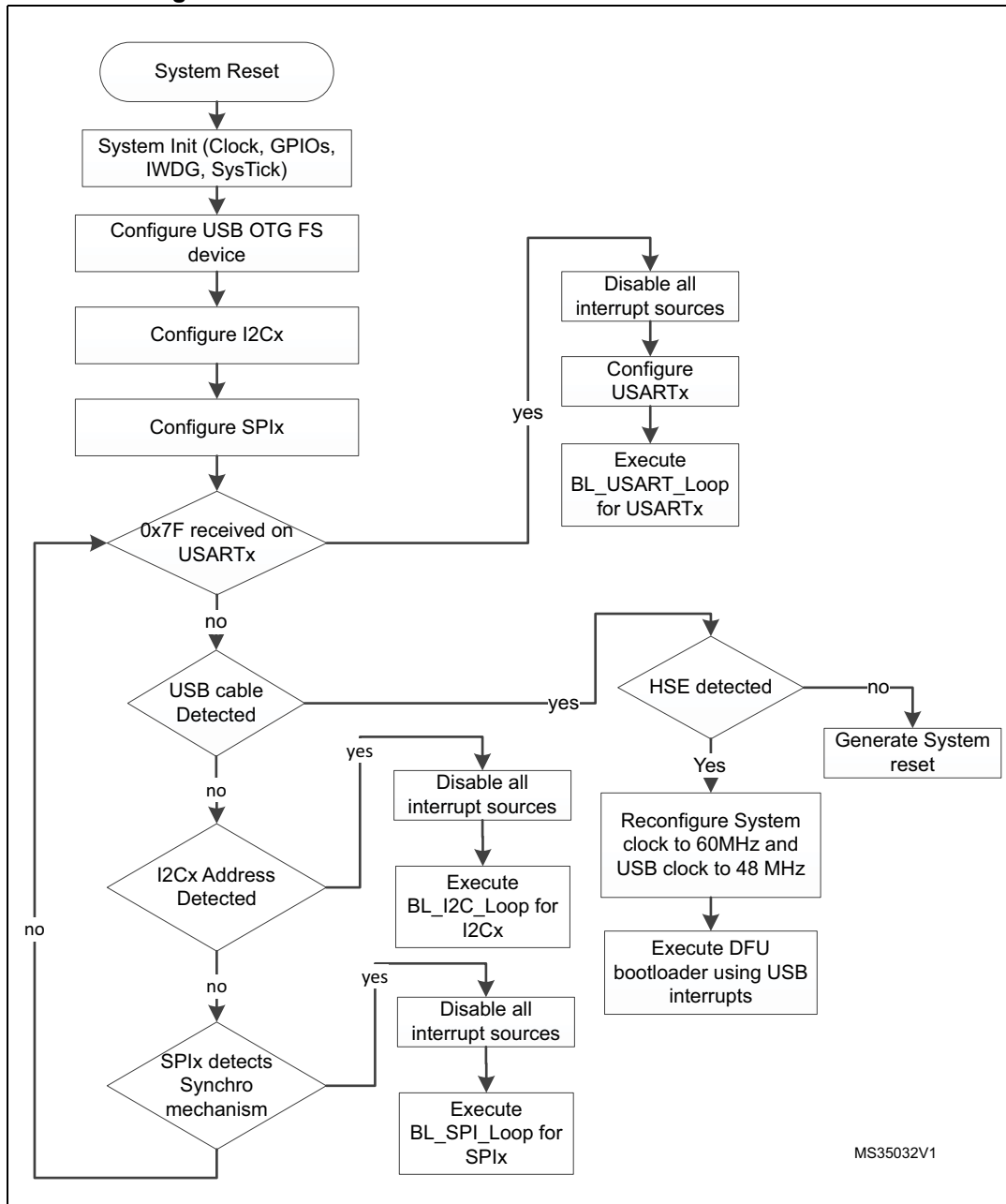
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, I2Cx, and SPIx bootloaders. This internal clock is also used for DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

32.2 Bootloader selection

Figure 37 shows the bootloader selection mechanism.

Figure 37. Bootloader selection for STM32F411xx



32.3 Bootloader version

The following table lists the STM32F411xx devices bootloader version.

Table 68. STM32F411xx bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

33 STM32F412xx devices bootloader

33.1 Bootloader configuration

The STM32F412xx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). [Table 69](#) shows the hardware resources used by this bootloader.

Table 69. STM32F412xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz, ranging from 4 to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	Power	-	The voltage range is [1.8V, 3.6V]. In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).
	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 69. STM32F412xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1000110x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1000110x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.

Table 69. STM32F412xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: <ul style="list-style-type: none"> – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1000110x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB4 pin: data line is used in open-drain no pull mode.
I2C4 bootloader	I2C4	Enabled	The I2C4 configuration is: <ul style="list-style-type: none"> – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1000110x (where x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PB15 pin: clock line is used in open-drain no pull mode.
	I2C4_SDA pin	Input/output	PB14 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: <ul style="list-style-type: none"> – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
SPI3 bootloader	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-up mode.
	SPI3	Enabled	The SPI3 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-up mode.

Table 69. STM32F412xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-up mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

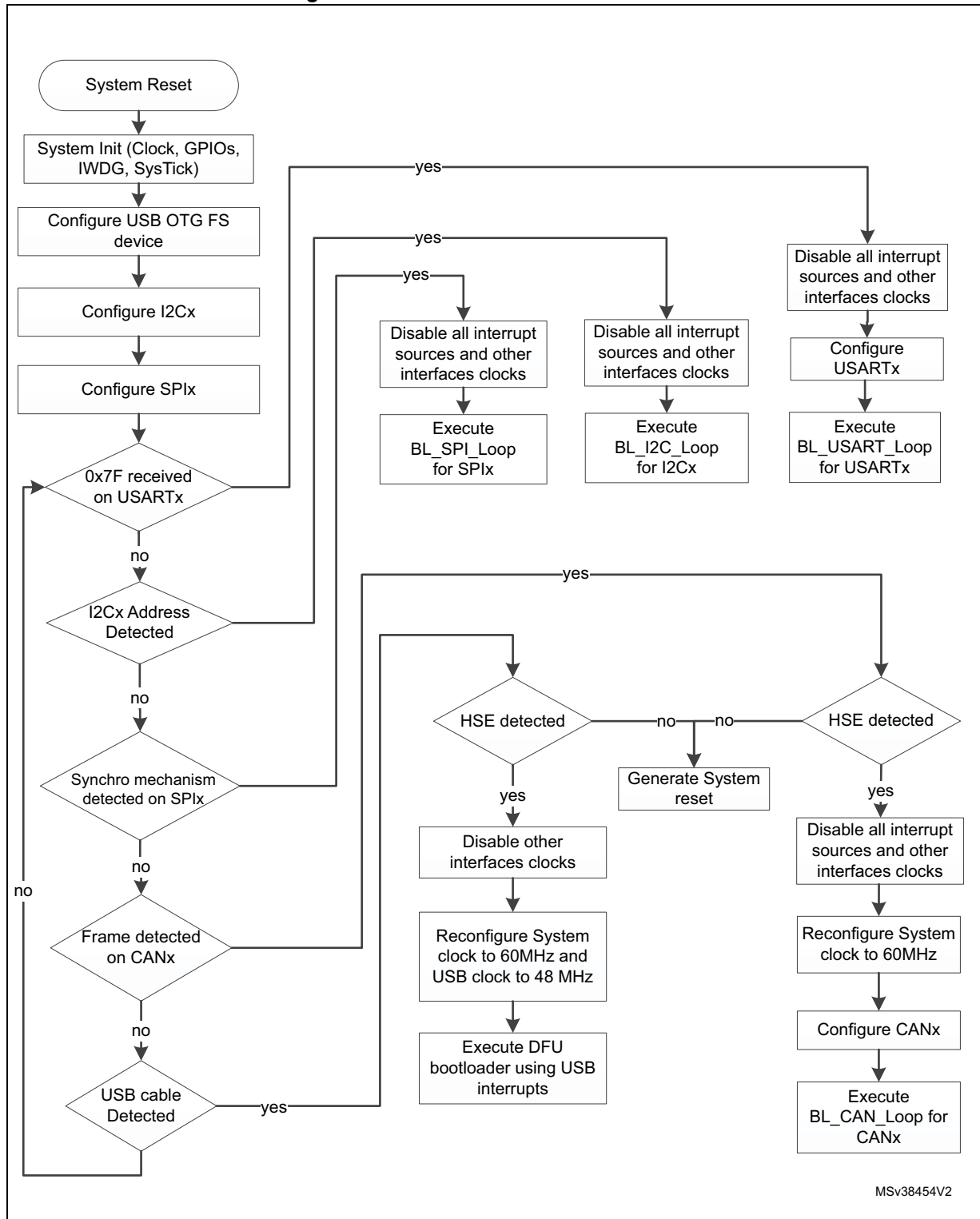
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

33.2 Bootloader selection

Figure 38 shows the bootloader selection mechanism.

Figure 38.Bootloader V9.x selection for STM32F412xx



33.3 Bootloader version

The following table lists the STM32F412xx devices bootloader V9.x versions.

Table 70. STM32F412xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)
V9.1	Fix USART3 interface pinout	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

34 STM32F413xx/423xx devices bootloader

34.1 Bootloader configuration

The STM32F413xx/423xx bootloader is activated by applying Pattern 1 (described in [Table 2h](#)). The following table shows the hardware resources used by this bootloader.

Table 71. STM32F413xx/423xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	60 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V] In this range: <ul style="list-style-type: none"> – Flash wait states 4. – System clock frequency 60 MHz. – ART Accelerator enabled. – Flash write operation by byte (refer to Bootloader memory management for more information).

Table 71. STM32F413xx/423xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in input pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 71. STM32F413xx/423xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001011x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001011x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001011x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PB4 pin: data line is used in open-drain no pull mode.
I2C4 bootloader	I2C4	Enabled	The I2C4 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001011x (where x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PB15 pin: clock line is used in open-drain no pull mode.
	I2C4_SDA pin	Input/output	PB14 pin: data line is used in open-drain no pull mode.

Table 71. STM32F413xx/423xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB, speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB, speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, pull-down mode.
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB, speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.

Table 71. STM32F413xx/423xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

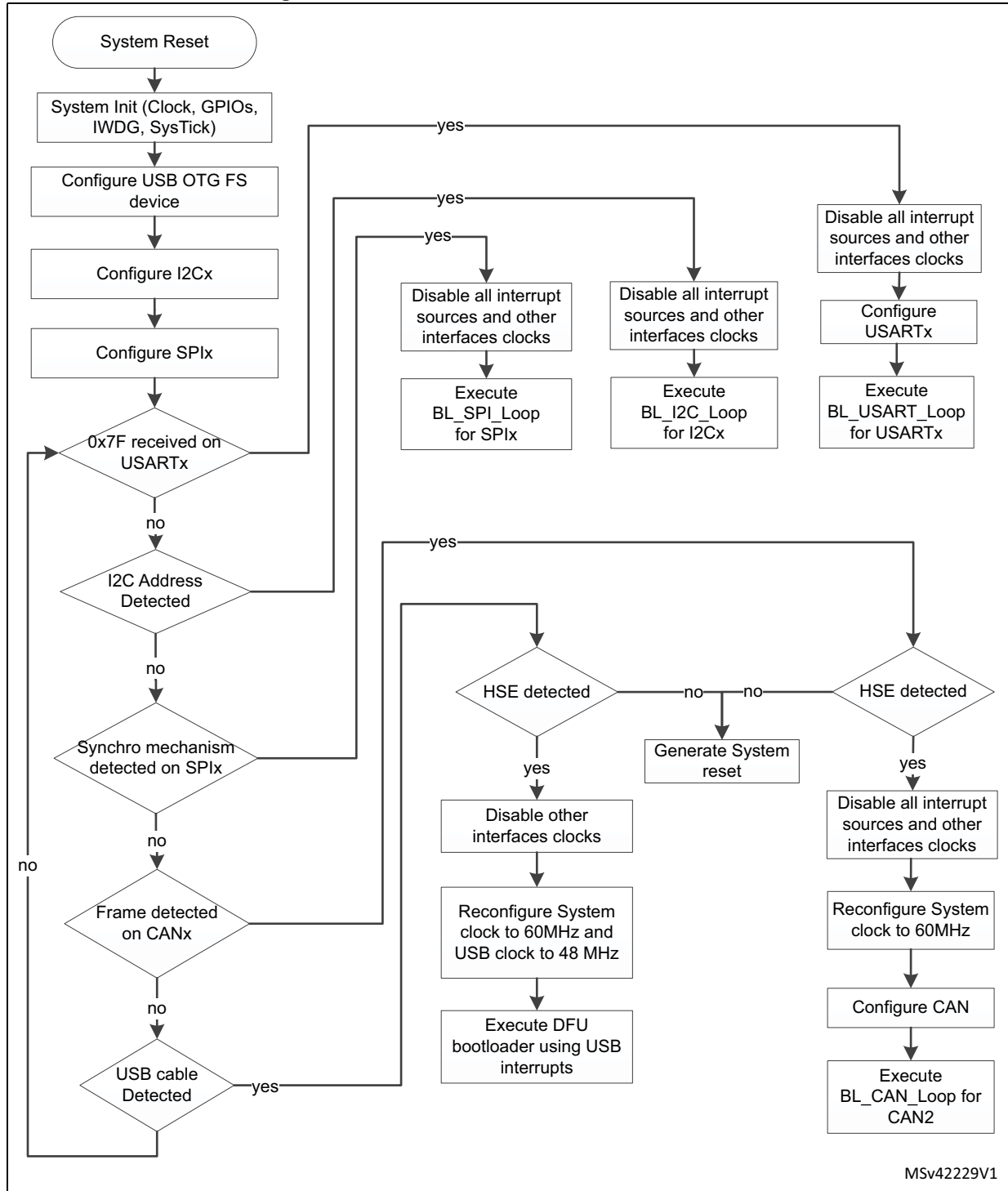
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

34.2 Bootloader selection

Figure 39 shows the bootloader selection mechanism.

Figure 39.Bootloader V9.x selection for STM32F413xx/423xx



34.3 Bootloader version

The following table lists the STM32F413xx/423xx devices bootloader V9.x versions.

Table 72. STM32F413xx/423xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

35 STM32F42xxx/43xxx devices bootloader

35.1 Bootloader V7.x

35.1.1 Bootloader configuration

The STM32F42xxx/43xxx bootloader is activated by applying Pattern 5 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 73. STM32F42xxx/43xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or I2C interfaces are selected (once CAN or DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock /generates system reset.
	RAM	-	8 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.

Table 73. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8 bits, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8 bits, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is 8 bits, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111000x (where x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 73. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push pull no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push pull no pull mode. No external pull-up resistor is required
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

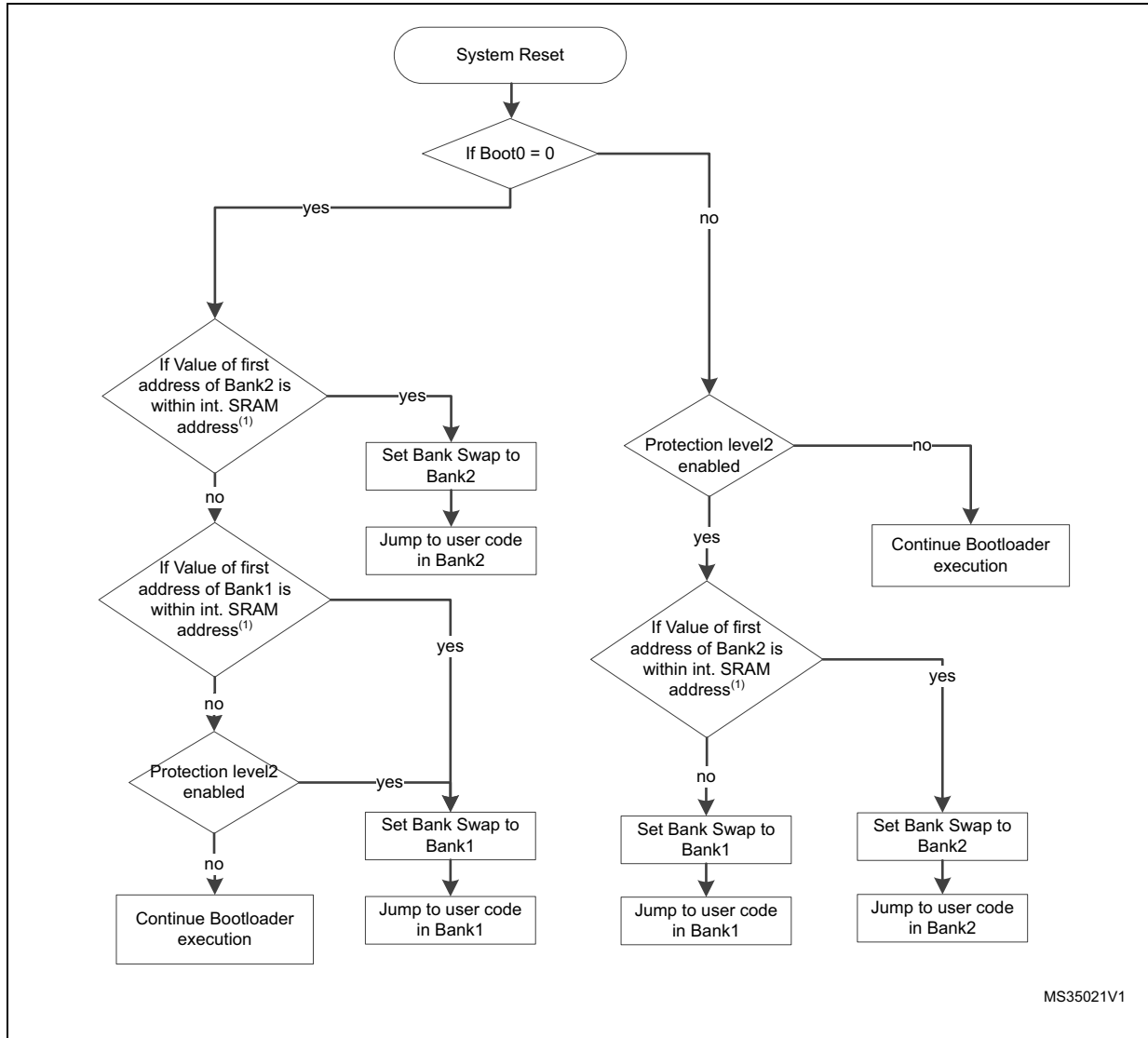
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

35.1.2 Bootloader selection

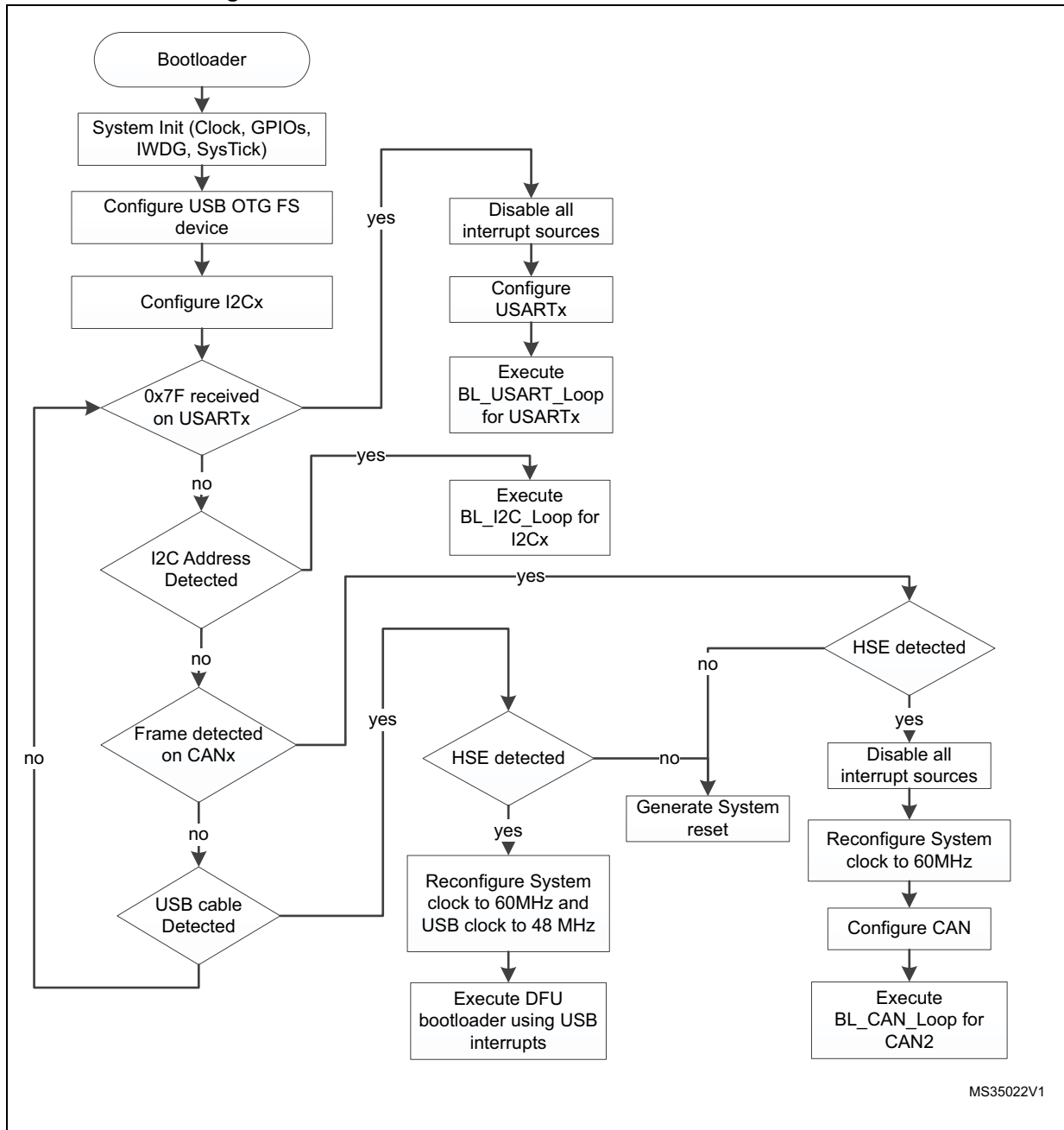
Figure 40 and Figure 41 show the bootloader selection mechanism.

Figure 40. Dual bank boot implementation for STM32F42xxx/43xxx Bootloader V7.x



1. CCM RAM is not considered valid as stack pointer address for the dual bank boot mechanism.

Figure 41. Bootloader V7.x selection for STM32F42xxx/43xxx



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35.1.3 Bootloader version

The following table lists the STM32F42xxx/43xxx devices bootloader V7.x versions.

Table 74. STM32F42xxx/43xxx bootloader V7.x versions

Version number	Description	Known limitations
V7.0	Initial bootloader version	<p>For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes to disable the write protection.</p> <p>For the USB DFU interface, in Dual Bank mode, the Erase operation is not functional for the second bank. Return to Single Bank mode, erase desired sector(s) and then reactivate the Dual Bank mode.</p> <p>After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup).</p>

35.2 Bootloader V9.x

35.2.1 Bootloader configuration

The STM32F42xxx/43xxx bootloader is activated by applying Pattern 5 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 75. STM32F42xxx/43xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interfaces are selected (once CAN or DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 75. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit.
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111000x (where x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111000x (where x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111000x (where x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain mode.

Table 75. STM32F42xxx/43xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, -bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull no pull mode. No external pull-up resistor is required
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

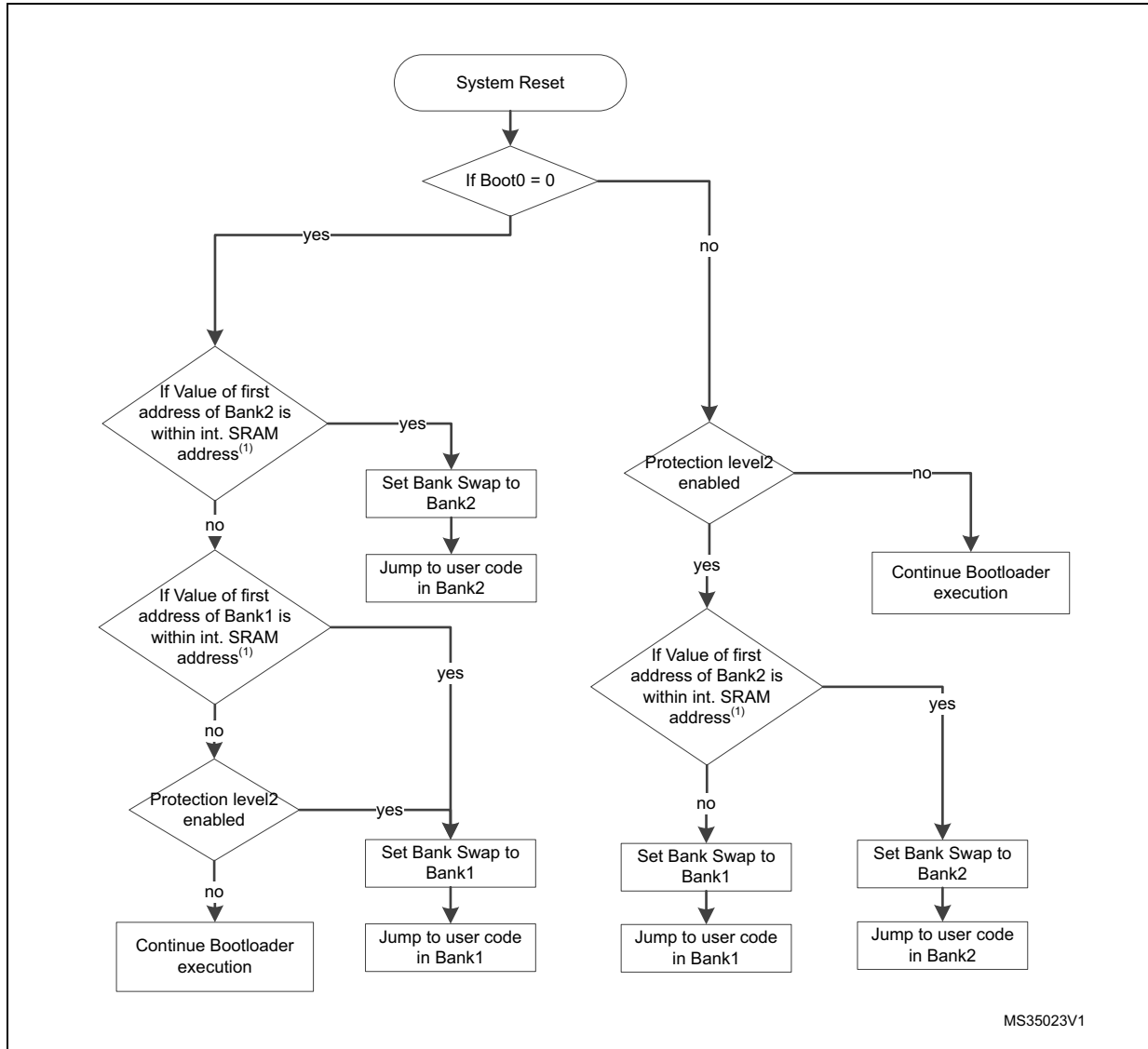
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

35.2.2 Bootloader selection

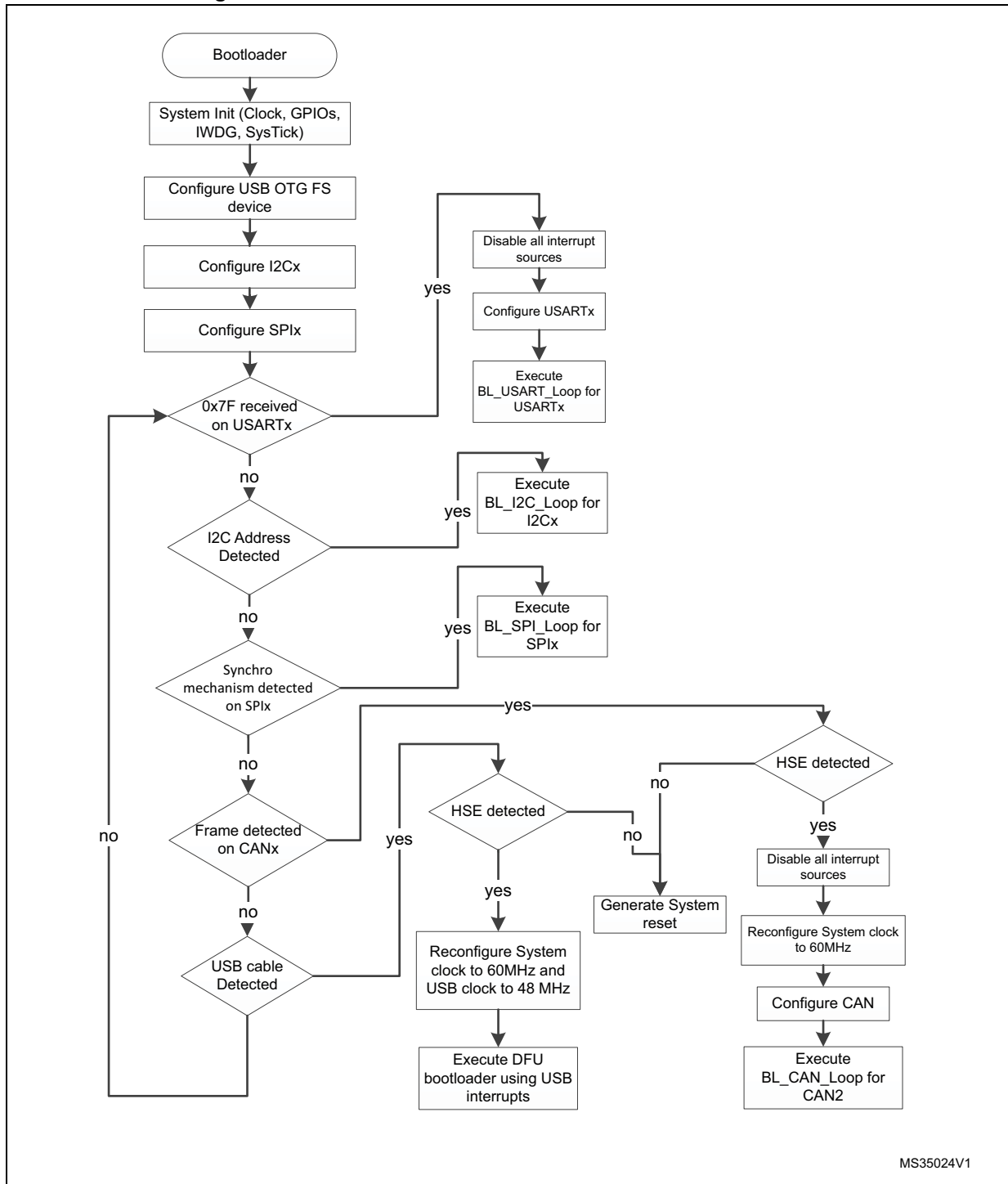
Figure 42 and Figure 43 show the bootloader selection mechanism.

Figure 42. Dual bank boot implementation for STM32F42xxx/43xxx bootloader V9.x



1. CCM RAM is not considered valid as stack pointer address for the dual bank boot mechanism.

Figure 43. Bootloader V9.x selection for STM32F42xxx/43xxx



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35.2.3 Bootloader version

Table 76 lists the STM32F42xxx/43xxx devices bootloader V9.x versions.

Table 76. STM32F42xxx/43xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	<p>This bootloader is an updated version of bootloader v7.0. This new version of bootloader supports I2C2, I2C3, SPI1, SPI2, and SPI4 interfaces. The RAM used by this bootloader is increased from 8 Kb to 12 Kb. The ID of this bootloader is 0x90. The connection time is increased.</p>	<p>For the USB DFU interface, in Dual Bank mode, the Erase operation is not functional for the second bank. Return to Single Bank mode, erase desired sector(s) and then reactivate the Dual Bank mode. After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)</p>
V9.1	<p>This bootloader is an updated version of bootloader v9.0. This new version implements the new I2C No-stretch commands (I2C protocol v1.1) and the capability of disabling PcROP when RDP1 is enabled with ReadOutUnprotect command for all protocols(USB, USART, CAN, I2C and SPI). The ID of this bootloader is 0x91</p>	<p>For the CAN interface, the Write Unprotect command is not functional. Use Write Memory command and write directly to the option bytes in order to disable the write protection.</p> <p>For the USB DFU interface, in Dual Bank mode, the Erase operation is not functional for the second bank. Return to Single Bank mode, erase desired sector(s) and then reactivate the Dual Bank mode. After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)</p>

36 STM32F446xx devices bootloader

36.1 Bootloader configuration

The STM32F446xx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 77. STM32F446xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C and SPI bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.71 V, 3.6 V]. In this range: - Flash wait states: 3. - System Clock 60 MHz. - Prefetch disabled. - Flash write operation by byte (refer to section bootloader memory management for more information).

Table 77. STM32F446xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because in CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111100x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 77. STM32F446xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111100x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0111100x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PC7 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.

Table 77. STM32F446xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
CAN2 and DFU bootloaders	TIM17	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

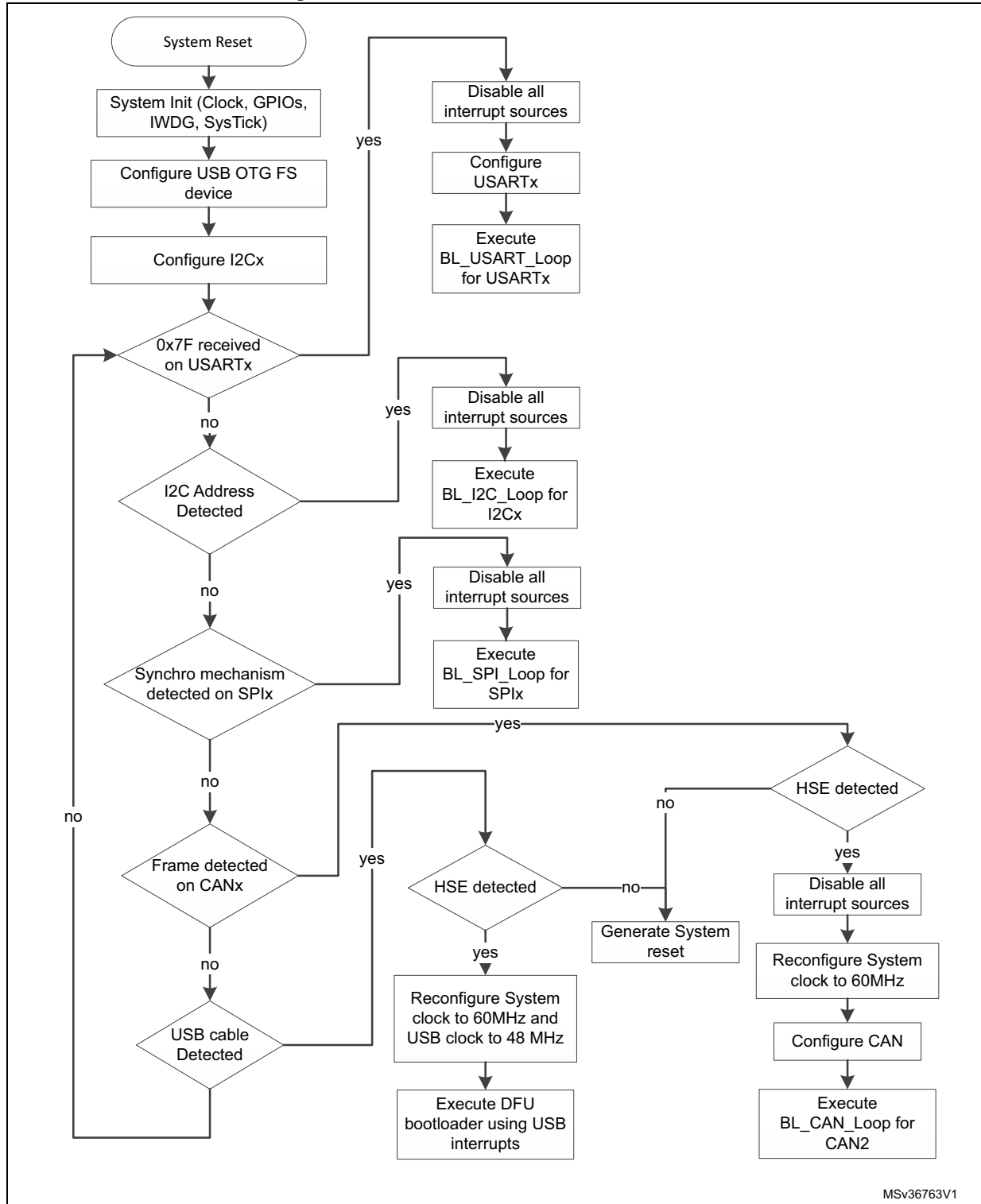
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

36.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 44.Bootloader V9.x selection for STM32F446xx



MSv36763V1

36.3 Bootloader version

The following table lists the STM32F446xx devices bootloader V9.x versions:

Table 78. STM32F446xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup)

37 STM32F469xx/479xx devices bootloader

37.1 Bootloader configuration

The STM32F469xx/479xx bootloader is activated by applying Pattern 5 (described in [Table 2](#)). [Table 79](#) shows the hardware resources used by this bootloader.

Table 79. STM32F469xx/479xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz using the PLL. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interfaces are selected (once CAN or DFU bootloader is selected, the clock source is derived from external crystal).
		HSE enabled	The system clock frequency is 60 MHz. The HSE clock source is used only when the CAN or the DFU (USB FS device) interfaces are selected. The external clock must provide a frequency multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	29 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to [1.62 V, 2.1 V]. In this range internal flash write operations are allowed only in byte format (Half-Word, Word and Double-Word operations are not allowed). The voltage range can be configured in run time using bootloader commands.

Table 79. STM32F469xx/479xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB05 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000100x (where x = 0 for write and x = 1 for read).
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 79. STM32F469xx/479xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000100x (where x = 0 for write and x = 1 for read).
	I2C2_SCL pin	Input/output	PF0 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF1 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000100x (where x = 0 for write and x = 1 for read).
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.

Table 79. STM32F469xx/479xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push- pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode. USB_OTG_FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

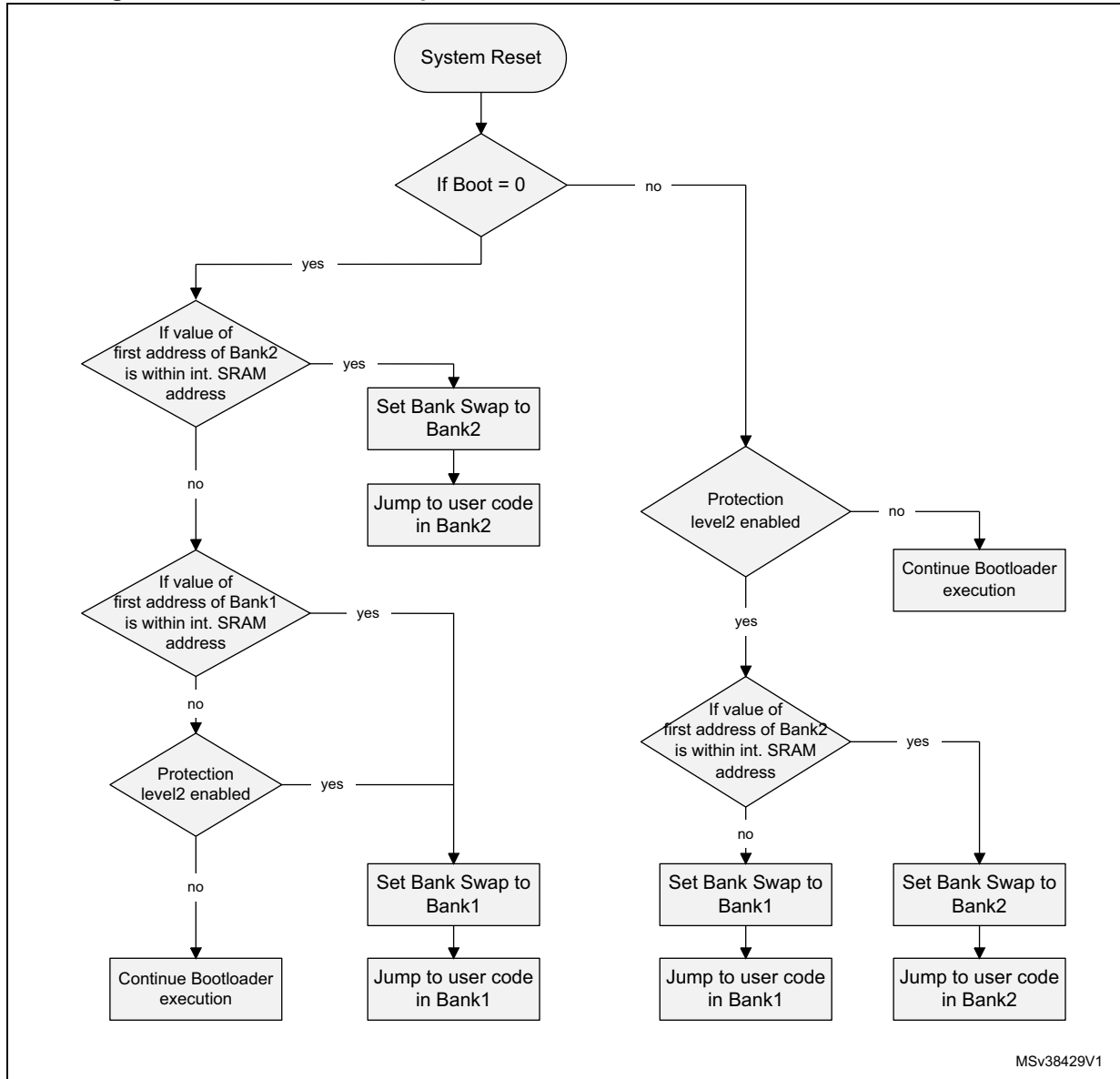
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 48 MHz) is required for CAN and DFU bootloaders execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

37.2 Bootloader selection

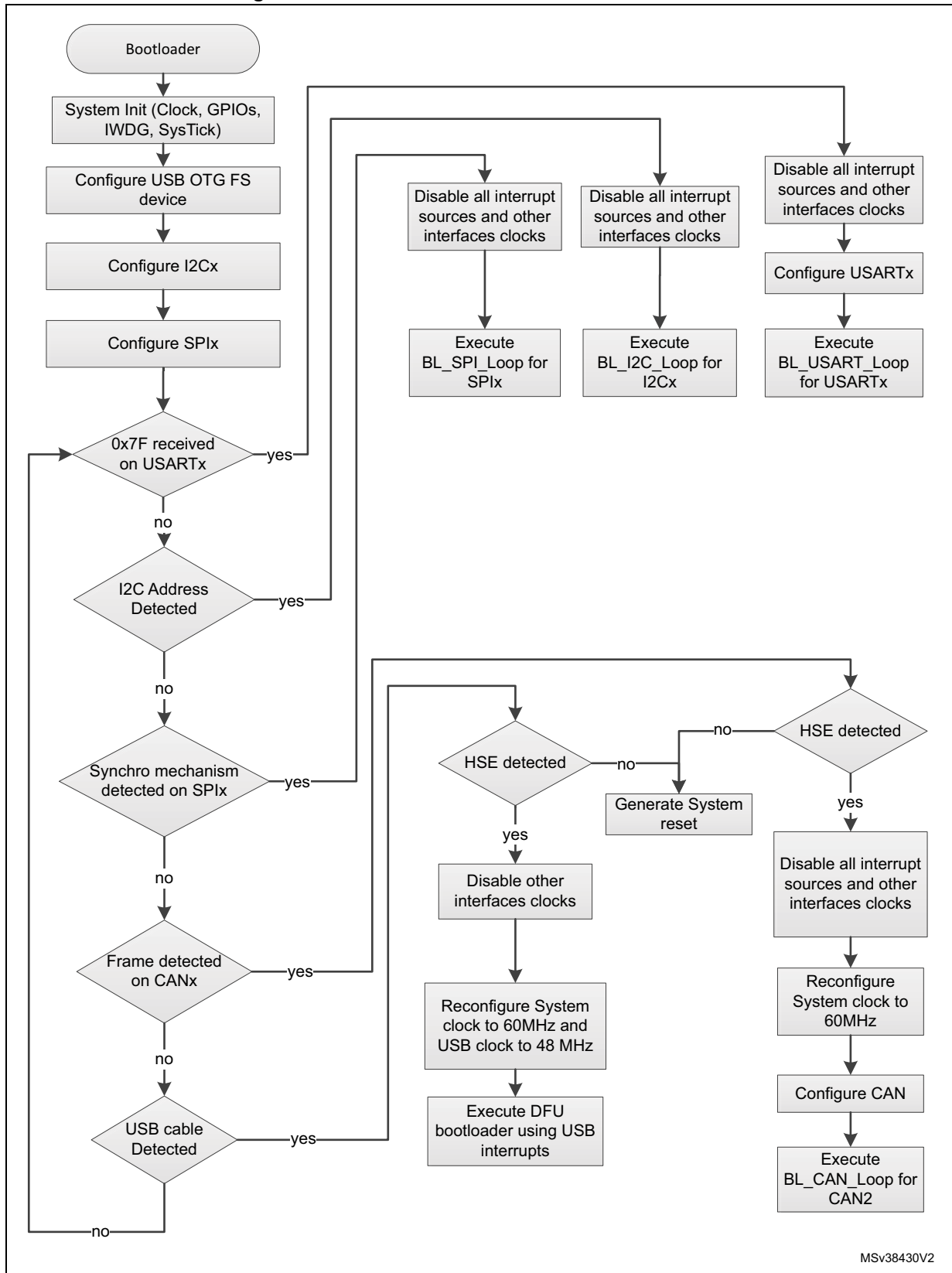
Figure 45 and Figure 46 show the bootloader selection mechanism.

Figure 45. Dual bank boot implementation for STM32F469xx/479xx Bootloader V9.x



MSv38429V1

Figure 46.Bootloader V9.x selection for STM32F469xx/479xx



37.3 Bootloader version

[Table 80](#) lists the STM32F469xx/479xx devices V9.x bootloader versions:

Table 80. STM32F469xx/479xx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	After executing Go command (jump to user code) the bootloader resets AHB1ENR value to 0x0000 0000 and thus CCM RAM, when present, is not active (must be re-enabled by user code at startup).

38 STM32F72xxx/73xxx devices bootloader

38.1 Bootloader configuration

The STM32F72xxx/73xxx bootloader is activated by applying Pattern 8 (described in [Table 2](#)). [Table 81](#) shows the hardware resources used by this bootloader.

Table 81. STM32F72xxx/73xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	59 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V] In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).

Table 81. STM32F72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 bootloader (on PB11/PB10)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC11/PC10)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN1 bootloader	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11-bit identifier.
	CAN1_RX pin	Input	PD0 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PD1 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.

Table 81. STM32F72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001101x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001001x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.

Table 81. STM32F72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN1 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

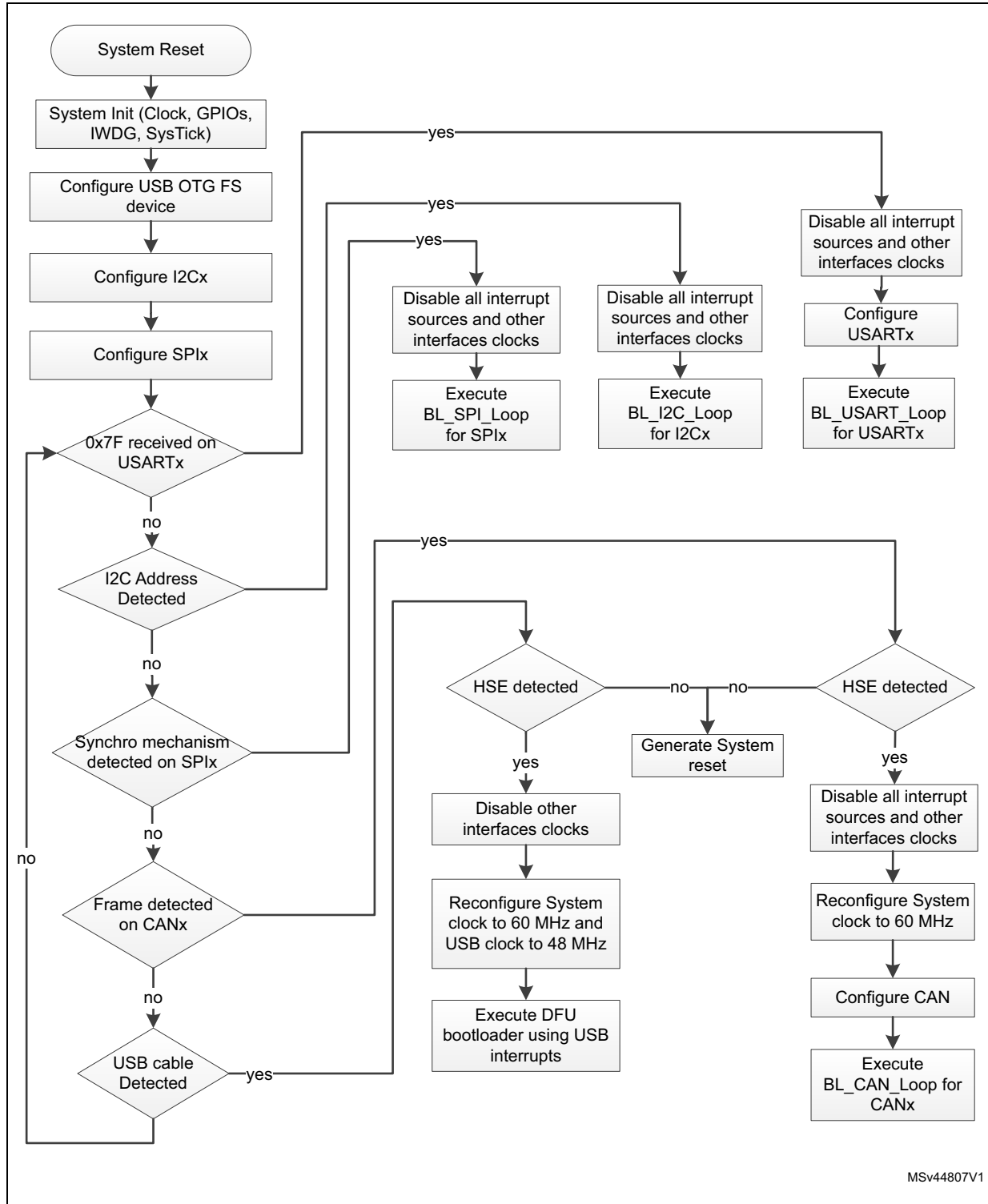
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

38.2 Bootloader selection

Figure 47 shows the bootloader selection mechanism.

Figure 47. Bootloader V9.x selection for STM32F72xxx/73xxx



MSv44807V1



38.3 Bootloader version

[Table 82](#) lists the STM32F72xxx/73xxx devices bootloader V9.x versions.

Table 82. STM32F72xxx/73xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation. In that case bootloader may respond with a baudrate up to $\pm 5\%$ different from host baudrate. Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than $\pm 5\%$

39 STM32F74xxx/75xxx devices bootloader

Two bootloader versions are available on STM32F74xxx/75xxx:

- V7.x supporting USART1, USART3, CAN2, I2C1, I2C2, I2C3, and DFU (USB FS device). This version is embedded in STM32F74xxx/75xxx rev. A devices.
- V9.x supporting USART1, USART3, CAN2, I2C1, I2C2, I2C3, SPI1, SPI2, SPI4, and DFU (USB FS device). This version is embedded in STM32F74xxx/75xxx rev. Z and rev. 1 devices.

Note: When readout protection Level2 is activated, STM32F74xxx/75xxx devices can boot also on system memory and all commands are not accessible except Get, GetID, and GetVersion.

39.1 Bootloader V7.x

39.1.1 Bootloader configuration

The STM32F74xxx/75xxx bootloader is activated by applying Pattern 8 (described in [Table 2](#)). [Table 83](#) shows the hardware resources used by this bootloader.

Table 83. STM32F74xxx/75xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	60 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	The voltage range is [1.8V, 3.6V]. In this range: <ul style="list-style-type: none"> - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information). 	

Table 83. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address, slave mode – analog filter ON. – Slave 7-bit address: 0b1000101x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address, slave mode – analog filter ON. – Slave 7-bit address: 0b1000101x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.

Table 83. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

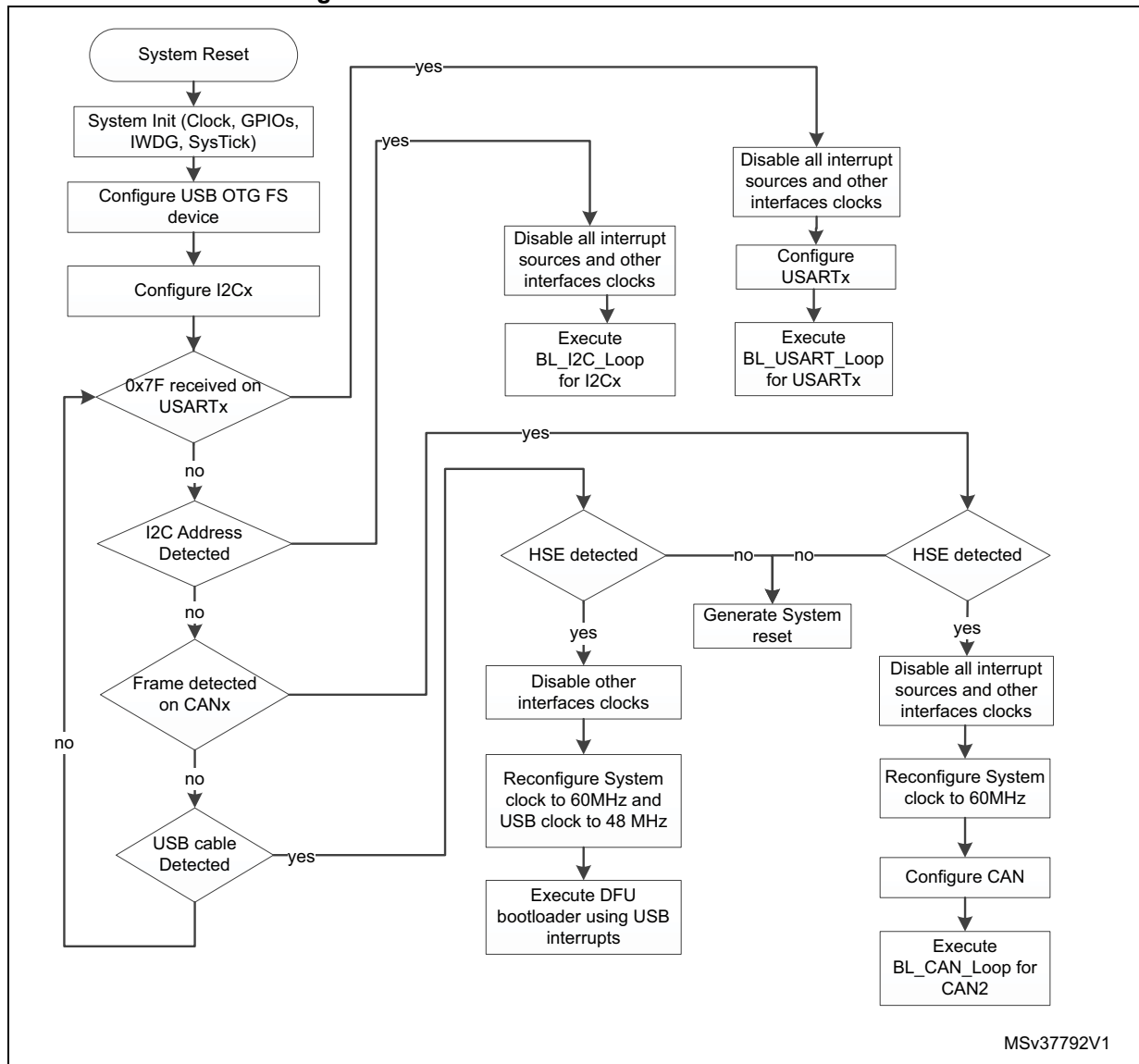
Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – slave mode, analog filter ON. – Slave 7-bit address: 0b1000101x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode.
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

39.1.2 Bootloader selection

Figure 48.Bootloader V7.x selection for STM32F74xxx/75xxx



39.1.3 Bootloader version

Table 84. STM32F74xxx/75xxx bootloader V7.x versions

Version number	Description	Known limitations
V7.0	Initial bootloader version	At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation. In that case bootloader may respond with a baudrate up to $\pm 5\%$ different from host baudrate. Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than $\pm 5\%$

39.2 Bootloader V9.x

39.2.1 Bootloader configuration

The STM32F74xxx/75xxx bootloader is activated by applying Pattern 8 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 85. STM32F74xxx/75xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C and SPI bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	60 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	Power	-	The voltage range is 1.8 V, 3.6V. In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).
	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 85. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC10/PC11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz – 7-bit address – slave mode – analog filter ON. – Slave 7-bit address: 0b1000101x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz – 7-bit address – slave mode – analog filter ON. – Slave 7-bit address: 0b1000101x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.

Table 85. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 400 kHz – 7-bit address – slave mode – analog filter ON. – Slave 7-bit address: 0b1000101x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.

Table 85. STM32F74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode.
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

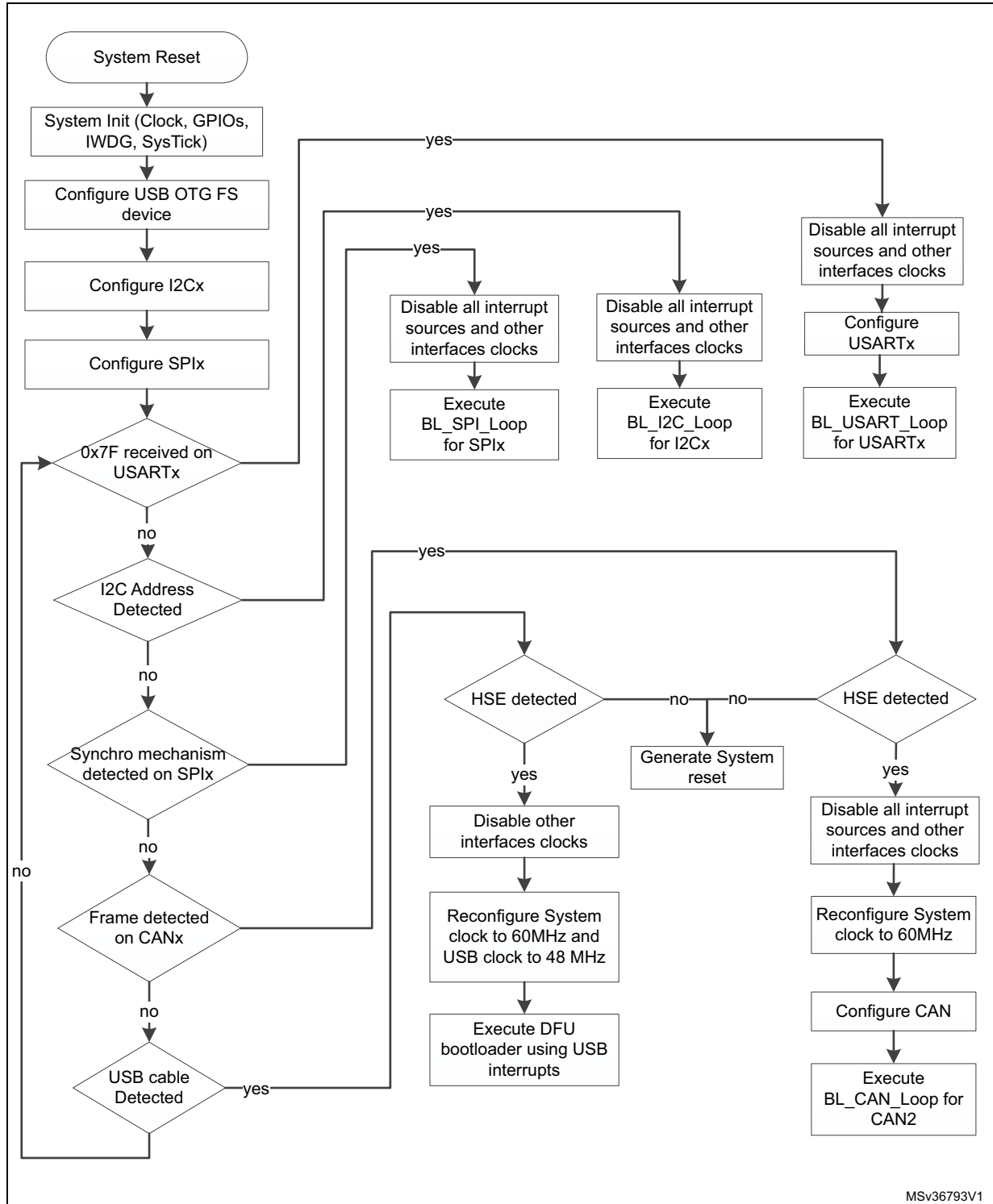
The system clock is derived from the embedded internal high-speed RC for USARTx, I2Cx, I2Cx, and SPIx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: *Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.*

39.2.2 Bootloader selection

Figure 49 shows the bootloader selection mechanism.

Figure 49.Bootloader V9.x selection for STM32F74xxx/75xxx



MSv36793V1

39.2.3 Bootloader version

The following table lists the STM32F74xxx/75xxx bootloader V9.x versions:

Table 86. STM32F74xxx/75xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation. In that case bootloader may respond with a baudrate up to $\pm 5\%$ different from host baudrate. Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than $\pm 5\%$

40 STM32F76xxx/77xxx devices bootloader

40.1 Bootloader configuration

The STM32F76xxx/77xxx bootloader is activated by applying Pattern 9 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 87. STM32F76xxx/77xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the CAN or the DFU (USB FS device) interfaces are selected. In this case the system clock configured to 60 MHz with HSE as clock source. The HSE frequency must be multiple of 1 MHz and ranging from 4 MHz to 26 MHz.
		-	The CSS interrupt is enabled for the CAN and DFU bootloaders. Any failure (or removal) of the external clock generates system reset.
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	59 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The voltage range is [1.8V, 3.6V] In this range: - Flash wait states: 3. - System clock frequency 60 MHz. - ART Accelerator enabled. - Flash write operation by byte (refer to bootloader memory management section for more information).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 87. STM32F76xxx/77xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader (on PB11/PB10)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in input pull-up mode.
USART3 bootloader (on PC11/PC10)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
CAN2 bootloader	CAN2	Enabled	Once initialized the CAN2 configuration is: Baudrate 125 kbps, 11-bit identifier. Note: CAN1 is clocked during CAN2 bootloader execution because CAN1 manages the communication between CAN2 and SRAM.
	CAN2_RX pin	Input	PB5 pin: CAN2 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN2_TX pin	Output	PB13 pin: CAN2 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001001x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.

Table 87. STM32F76xxx/77xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001001x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, pull-down mode.

Table 87. STM32F76xxx/77xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode
	SP4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-down mode.
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11 pin: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.
CAN2 and DFU bootloaders	TIM11	Enabled	This timer is used to determine the value of the HSE. Once HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

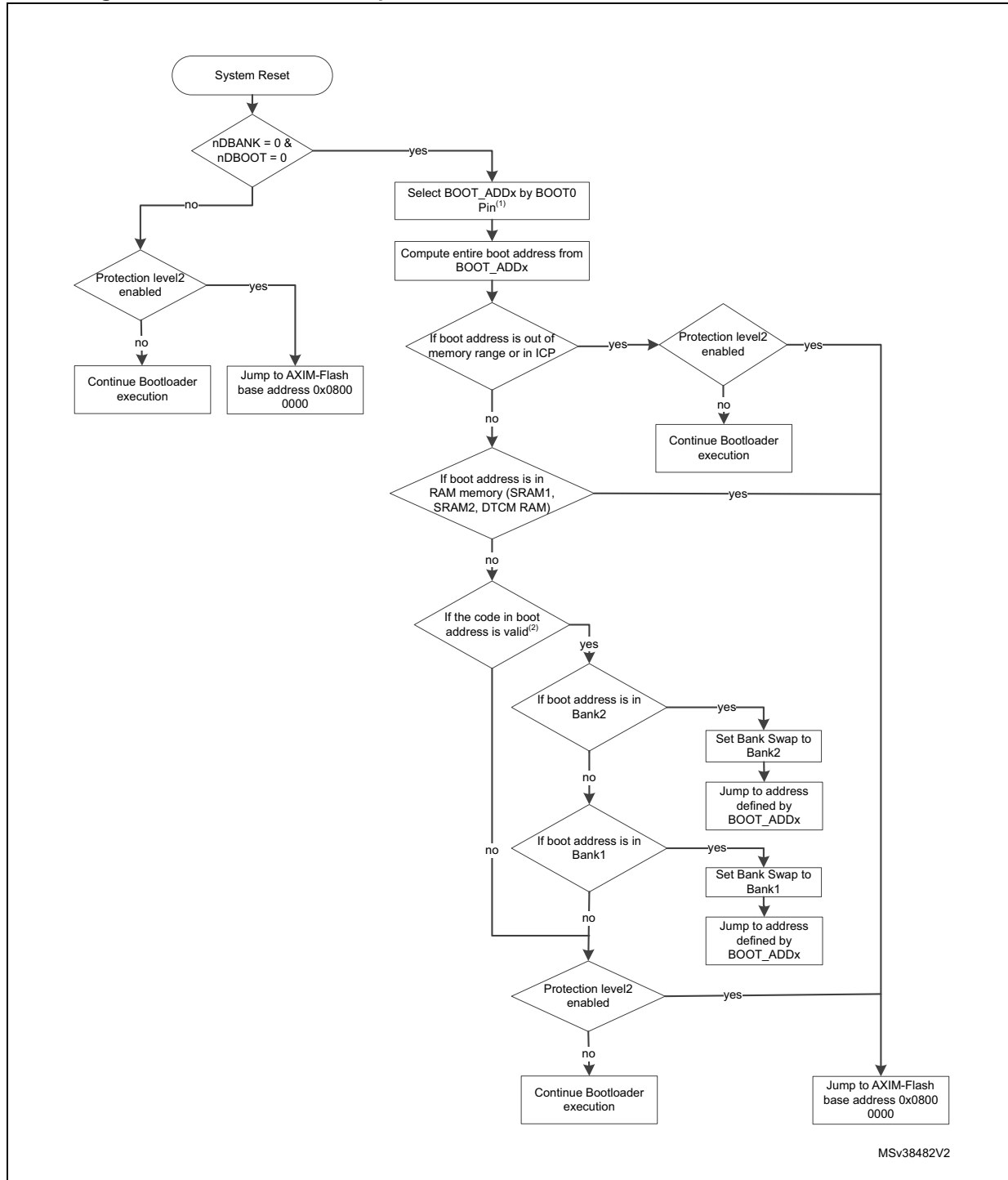
The system clock is derived from the embedded internal high-speed RC for USARTx and I2Cx bootloaders. This internal clock is also used for CAN and DFU (USB FS device), but only for the selection phase. An external clock multiple of 1 MHz (between 4 and 26 MHz) is required for CAN and DFU bootloader execution after the selection phase.

Note: Due to HSI deviation and since HSI is used to detect HSE value, the user must use low rather than high frequency HSE crystal values (low frequency values are better detected due to larger error margin). For example, it is better to use 8 MHz instead of 25 MHz.

40.2 Bootloader selection

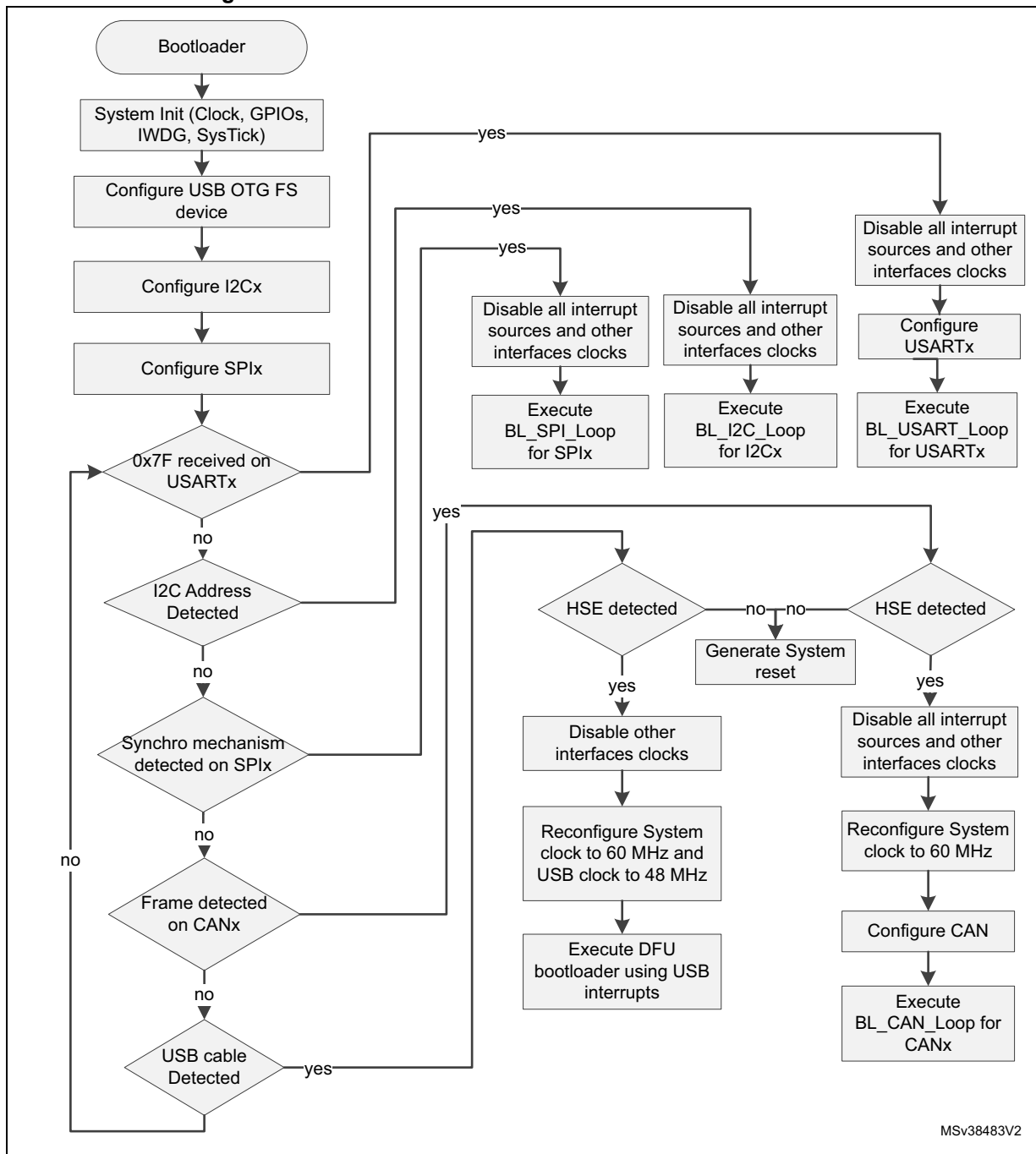
Figure 50 and Figure 51 show the bootloader selection mechanism.

Figure 50. Dual bank boot implementation for STM32F76xxx/77xxx Bootloader V9.x



1. Only BOOT_ADD0 value is considered whatever the BOOT0 pin state, as described in [Table 88](#).
2. ITCM RAM is not considered valid as stack pointer address for the dual bank boot mechanism.

Figure 51. Bootloader V9.x selection for STM32F76xxx/77xxx



40.3 Bootloader version

The following table lists the STM32F76xxx/77xxx devices bootloader V9.x versions.

Table 88. STM32F76xxx/77xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.3	Initial bootloader version	<p>When the flash memory is configured to the dual bank boot mode (nDBANK=nDBOOT=0), whatever the BOOT0 Pin state only BOOT_ADD0 value is considered (when BOOT0 Pin=1, BOOT_ADD0 value is considered not the BOOT_ADD1).</p> <p>Workaround: to manage dual bank boot with BOOT_ADD0 only, refer to AN4826 "<i>STM32F7 series flash memory dual bank mode</i>"</p> <p>At high UART baudrates (115200 bps) connection may fail due to software jitter leading to wrong baudrate calculation.</p> <p>In that case bootloader may respond with a baudrate up to ± 5% different from host baudrate.</p> <p>Workaround: use baudrates lower than 57600 bps if host tolerance to baudrate error is lower than ± 5%.</p> <p>Bank2 sector erase issue when using USB interface. Erasing a sector from bank2 with index (i) leads to erase sector (i+4)</p>

41 STM32G03xxx/STM32G04xxx devices bootloader

41.1 Bootloader configuration

The STM32G03xxx/G04xxx bootloader is activated by applying Pattern 11 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader. Note that STM32G030x do not have BOOT_LOCK(bit), so consider that when using Pattern 11.

Table 89. STM32G03xxx/G04xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI).
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFF0000
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF1D00
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloader	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010110x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.

Table 89. STM32G03xxx/G04xxx configuration in system memory boot mode (continued)

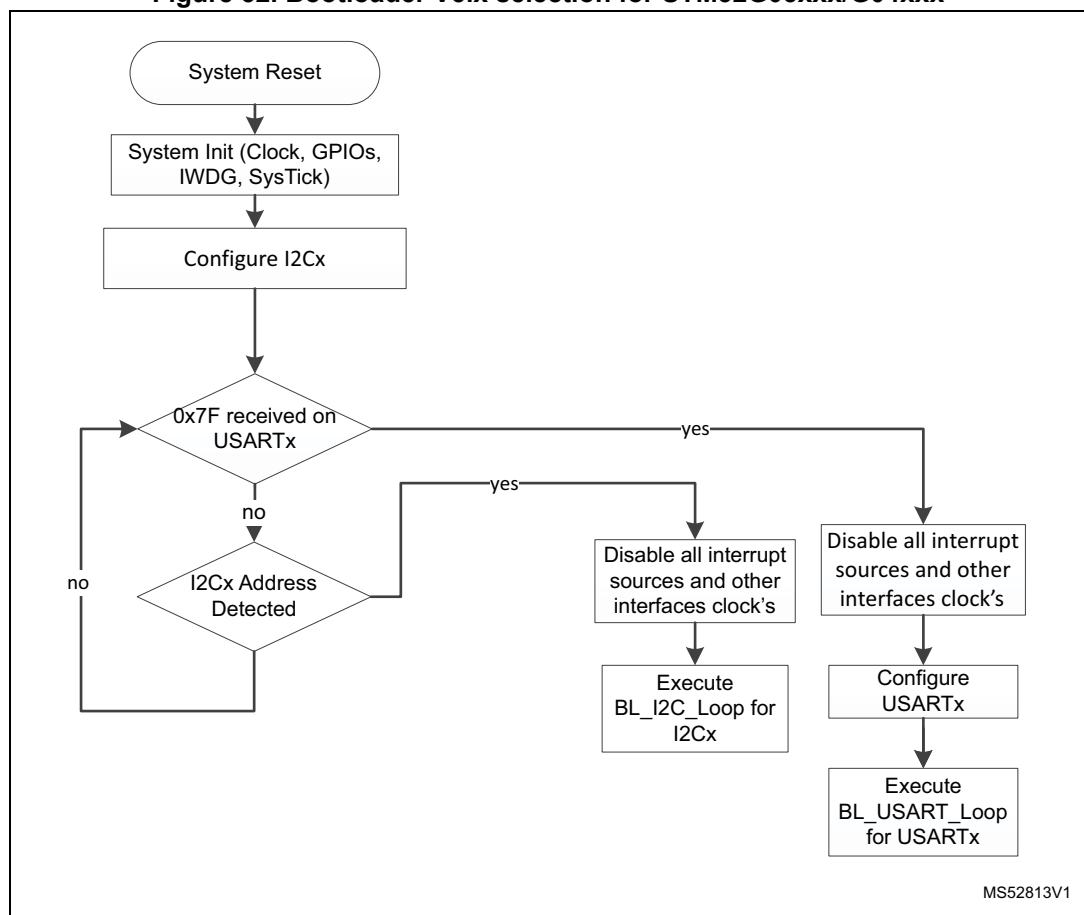
Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010110x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.

Note: On SO8, WLCSP18, TSSOP20, and UFQFN28 packages USART1 PA9/PA10 IOs are remapped on PA11/PA12.

41.2 Bootloader selection

Figure 52 shows the bootloader selection mechanism.

Figure 52. Bootloader V5.x selection for STM32G03xxx/G04xxx



41.3 Bootloader version

[Table 90](#) lists the STM32G03xxx/G04xxx devices bootloader versions.

Table 90. STM32G03xx/04xxx bootloader versions

Version number	Description	Known limitations
V5.1	Initial bootloader version	<ul style="list-style-type: none"> – Supports only 48- and 32-pin packages – Issue is seen for both packages, if PA3 stays to low level, system is stuck in the USART2 detection sequence and no other interface is detected.
V5.2	Add support to small packages 8/20 and 28 pins	Issue is seen for all packages (except SO8, no PA3 pin), if PA3 stays to low level, system is stuck in the USART2 detection sequence and no other interface is detected.
V5.3	Fix V5.2 limitations	None

42 STM32G07xxx/08xxx device bootloader

42.1 Bootloader configuration

The STM32G07xxx/G08xxx bootloader is activated by applying Pattern 11 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader. STM32G070x devices do not have BOOT_LOCK(bit), consider that when using Pattern 11.

Table 91. STM32G07xxx/8xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI).
	RAM	-	12 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF6800
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 91. STM32G07xxx/8xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010001x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010001x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

Table 91. STM32G07xxx/8xxx configuration in system memory boot mode (continued)

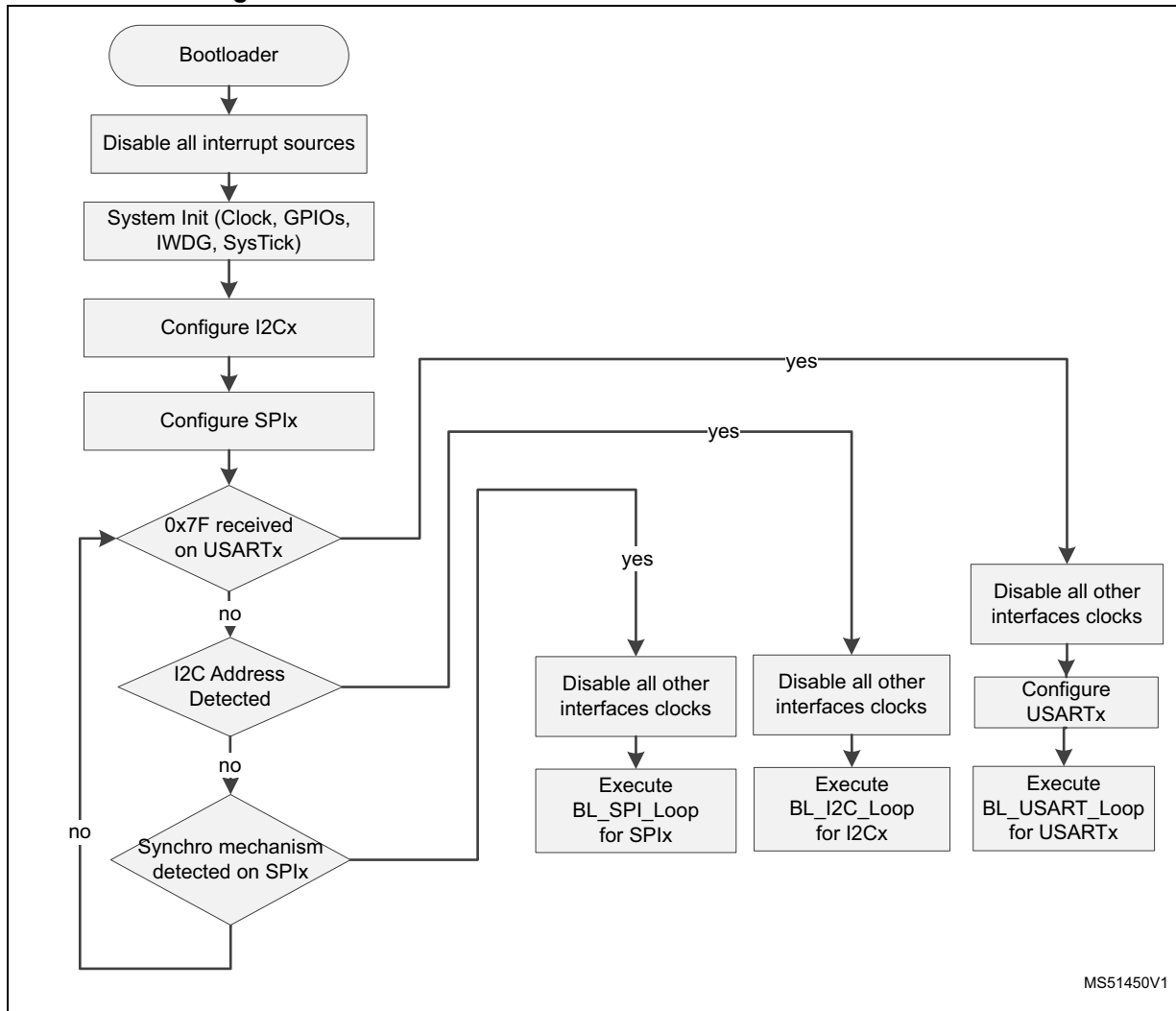
Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down. Note: This IO can be tied to GND if the SPI master does not use it.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

42.2 Bootloader selection

Figure 53 shows the bootloader selection mechanism.

Figure 53. Bootloader V11.0 selection for STM32G07xxx/G08xxx



42.3 Bootloader version

Table 92 lists the STM32G07xxx/8xxx devices bootloader versions.

Table 92. STM32G07xx/08xxx bootloader versions

Version number	Description	Known limitations
V11.0	Initial bootloader version	Not supporting packages smaller than LQFP64
V11.1	Supporting all packages	None

Table 92. STM32G07xx/08xxx bootloader versions (continued)

Version number	Description	Known limitations
V11.2	Add securable memory area feature	<ul style="list-style-type: none"> – Option byte launch missing when using USART protocol – RCC register RCC_ICSCR is not set to its default value when Go command is used. HSITRIM value is set to a value different from default. – RCC registers are not set to their default value when “Go” command is used (HSITRIM is not correctly reset). – Enabling SRAM parity check option byte causes bootloader crash if the SRAM is not initialized before enabling this feature.
V11.3	Fix all V11.2 limitations	None

43 STM32G0B0xx device bootloader

43.1 Bootloader configuration

The STM32G0B0xx bootloader is activated by applying Pattern 11 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader. Note that STM32G0B0x do not have BOOT_LOCK(bit), so consider that when using Pattern 11.

Table 93. STM32G0B0xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI). If an external clock (HSE) is not present, the system is kept clocked from the HSI
		HSE enabled	The external clock can be used for all bootloader interfaces and must have one of the following values [48, 32, 16, 12, 8] MHz. The PLL is used to generate 48 MHz for USB and system clock.
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	The bootloader firmware is shared on two banks: - 28 Kbytes, starting from address 0x1FFF0000 until 0x1FFF6FFF - Part of the 28 KB (0x1FFF8000 – 0x1FFFEFFF)
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the exit securable memory area is 0x1FFF6800
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 93. STM32G0B0xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011101x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011101x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

Table 93. STM32G0B0xx configuration in system memory boot mode (continued)

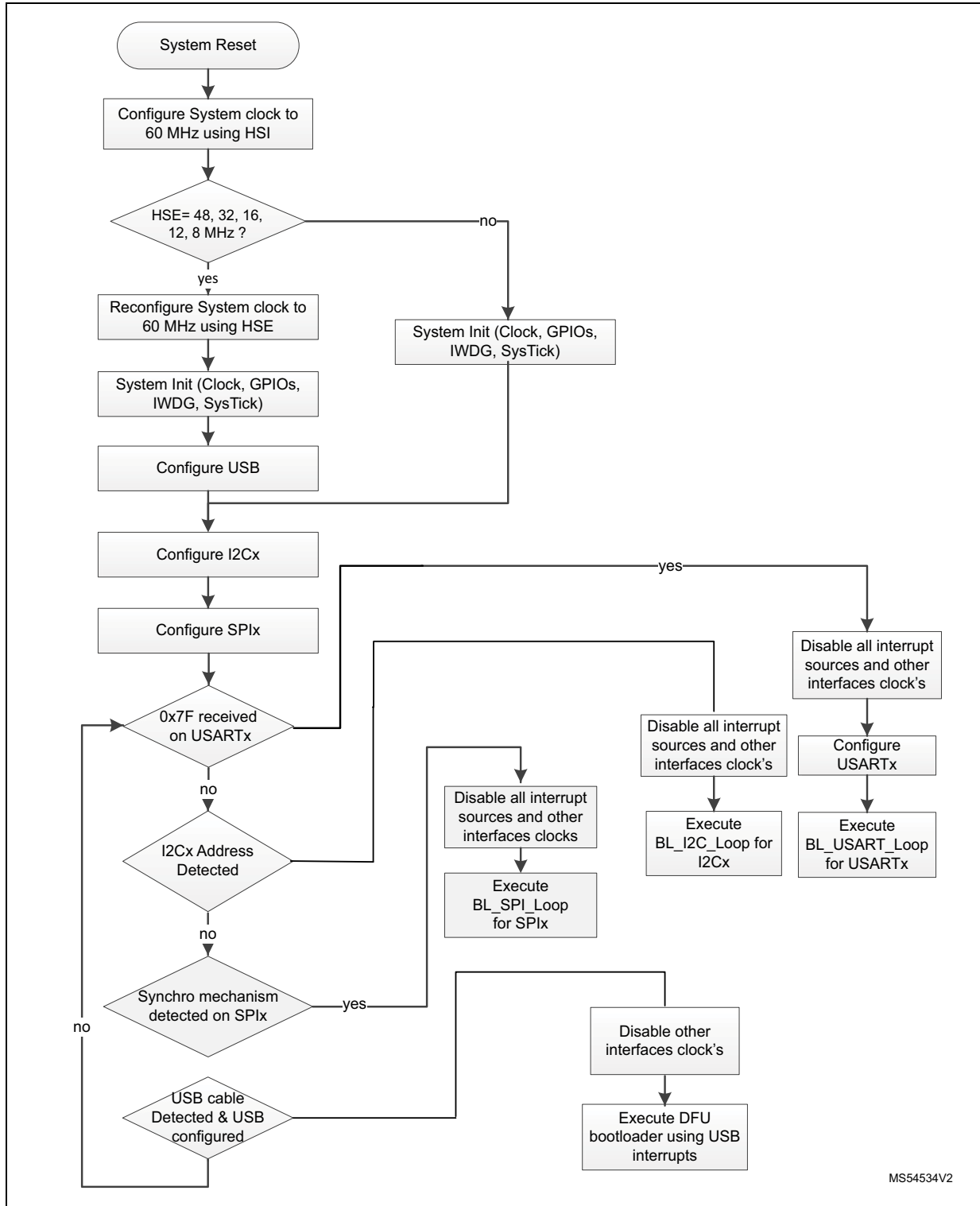
Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down. Note: This IO can be tied to GND if the SPI master does not use it.
DFU bootloader	USB	Enabled	USB FS configured in Forced Device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.'
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

43.2 Bootloader selection

Figure 54 shows the bootloader selection mechanism.

Figure 54. Bootloader selection for STM32G0B0xx



MS54534V2

43.3 Bootloader version

[Table 94](#) lists the STM32G0B0xx devices bootloader versions.

Table 94. STM32G0B0xx bootloader versions

Version number	Description	known limitations
V13.0	Initial bootloader version	None

44 STM32G0B1xx/0C1xx device bootloader

44.1 Bootloader configuration

The STM32G0B1xx/0C1xx bootloader is activated by applying Pattern 11 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 95. STM32G0B1xx/0C1xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz.
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	The bootloader firmware is shared on two banks: - 28 Kbytes, starting from address 0x1FFF0000 until 0x1FFF6FFF - Part of the 28 KB (0x1FFF8000 – 0x1FFFEFFF)
IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).	
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF6800
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 95. STM32G0B1xx/0C1xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011101x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011101x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

Table 95. STM32G0B1xx/0C1xx configuration in system memory boot mode (continued)

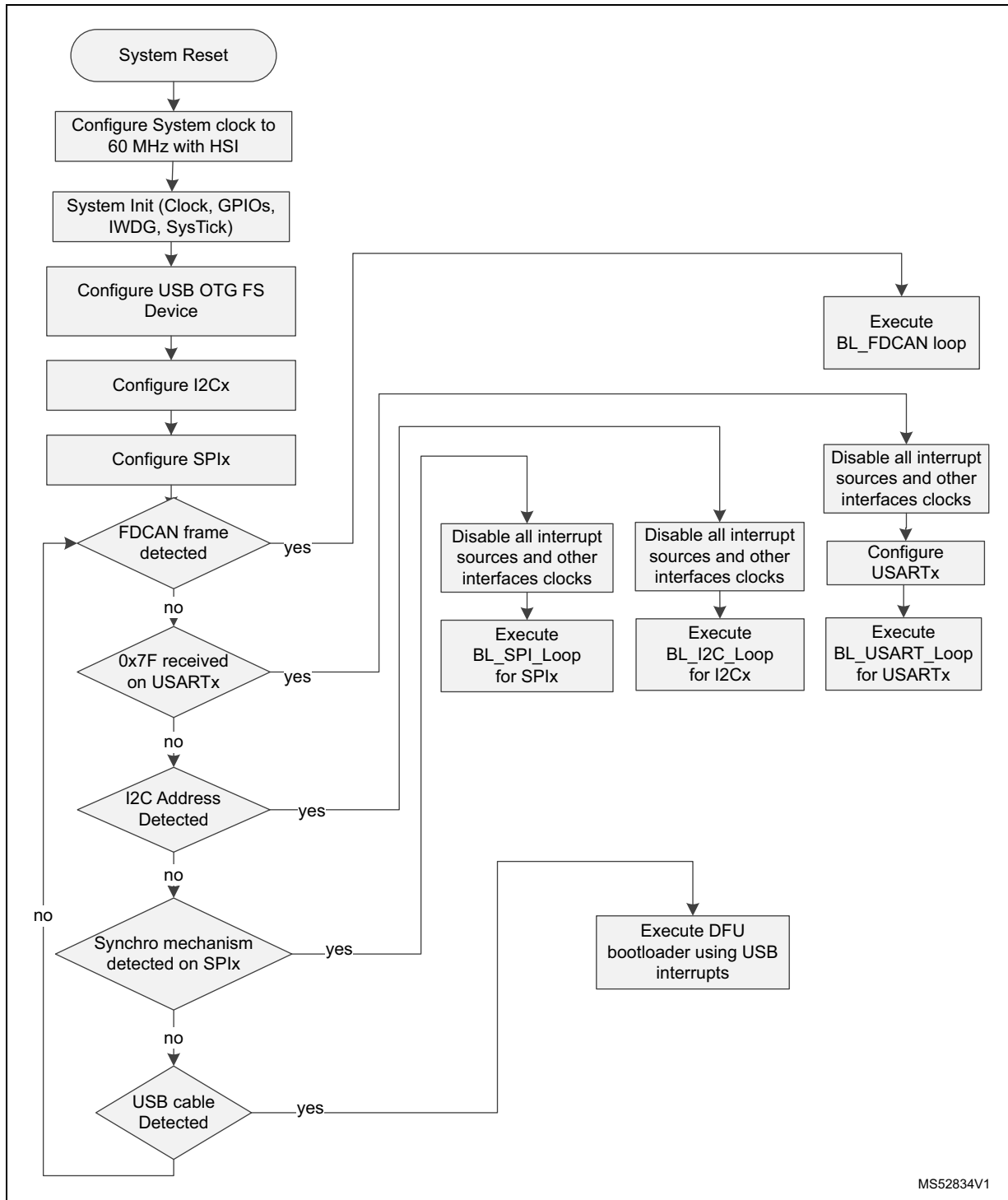
Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down. Note: This IO can be tied to GND if the SPI master does not use it.
DFU bootloader	USB	Enabled	USB FS configured in Forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in no pull mode.
	USB_DP pin		PA12: USB DP line. Used in no pull mode. No external pull-up resistor is required
FDCAN	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PD0 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PD1 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

44.2 Bootloader selection

Figure 55 shows the bootloader selection mechanism.

Figure 55. Bootloader selection for STM32G0B1xx/0C1xx



44.3 Bootloader version

[Table 96](#) lists the STM32G0B1xx/0C1xx devices bootloader versions.

Table 96. STM32G0B1xx/0C1xx bootloader versions

Version number	Description	known limitations
V9.2	Initial bootloader version	None

45 STM32G05xxx/061xx devices bootloader

45.1 Bootloader configuration

The STM32G05xxx/061xx bootloader is activated by applying Pattern 11 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader. Note that STM32G050x do not have BOOT_LOCK(bit), so consider that when using Pattern 11.

Table 97. STM32G05xxx/061xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 24 MHz (using PLL clocked by HSI).
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to for the securable memory area is 0x1FFF6800
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloader	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USART2 bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1100010x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.

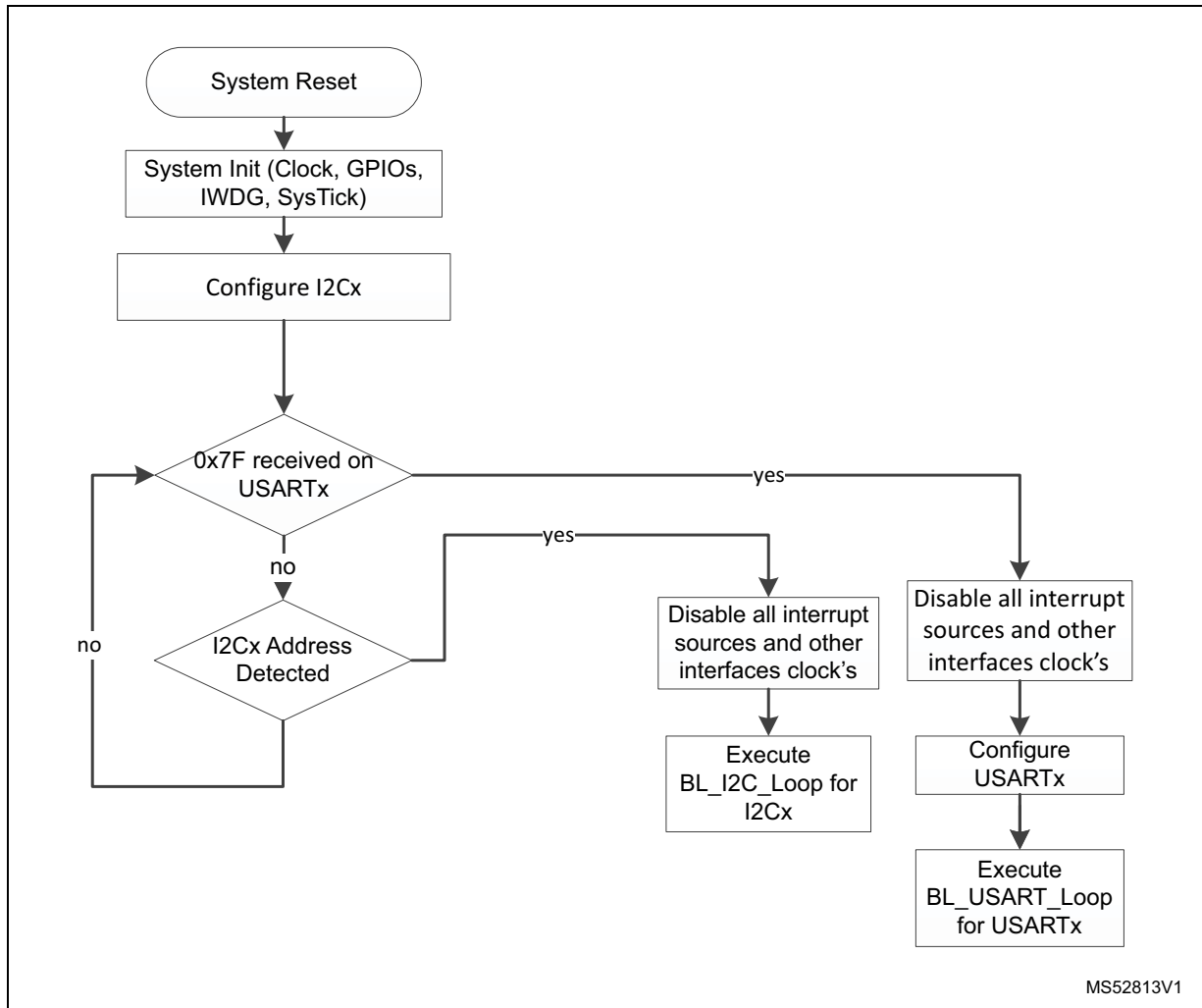
Table 97. STM32G05xxx/061xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1100010x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.

45.2 Bootloader selection

Figure 56 shows the bootloader selection mechanism.

Figure 56. Bootloader selection for STM32G05xxx/061xx



45.3 Bootloader version

Table 98 lists the STM32G05xxx/061xx devices bootloader versions.

Table 98. STM32G05xxx/061xx bootloader versions

Version number	Description	Known limitations
V5.0	Initial bootloader version	USART2 SW jitter issue on detection phase
V5.1	Fix V5.0 limitation	None

46 STM32G431xx/441xx devices bootloader

46.1 Bootloader configuration

The STM32G431xx/441xx bootloader is activated by applying Pattern 15 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 99. STM32G431xx/441xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 72 MHz (using the PLL clocked by HSI)
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to the exit securable memory area @0x1FFF6800
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 99. STM32G431xx/441xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010100x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PC4 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PA8 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010100x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 99. STM32G431xx/441xx configuration in system memory boot mode (continued)

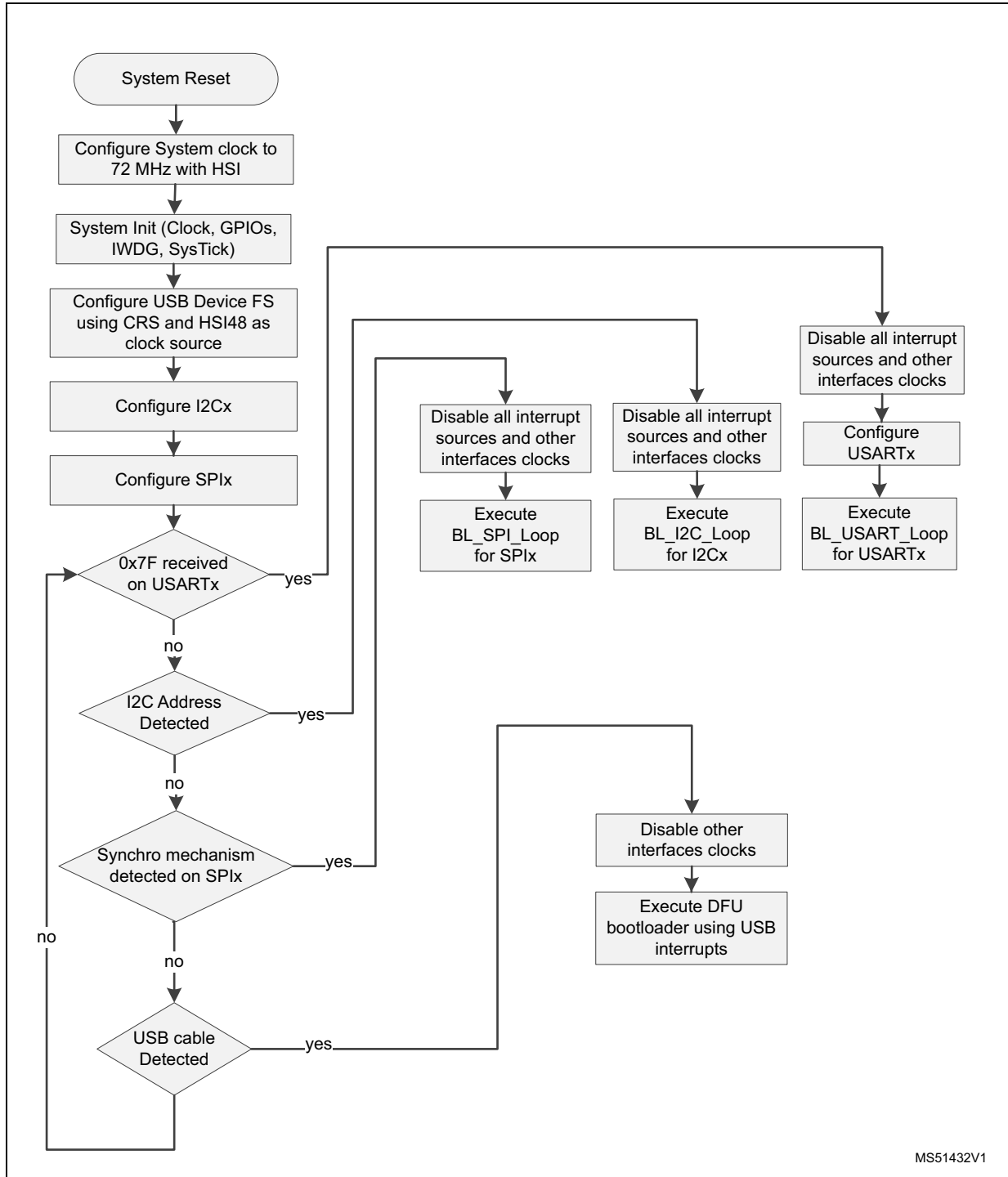
Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

46.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 57. Bootloader selection for STM32G431xx/441xx



46.3 Bootloader version

Table 100. STM32G431xx/441xx bootloader version

Version number	Description	Known limitations
V13.3 (0xD3)	Initial bootloader version	CCSRAM not supported
V13.4 (0xD4)	Fix V13.3 limitations	Add CCSRAM support

47 STM32G47xxx/48xxx devices bootloader

47.1 Bootloader configuration

The STM32G47xxx/48xxx bootloader is activated by applying Pattern 14 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 101. STM32G47xxx/48xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 72 MHz (using the PLL clocked by HSI)
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	-
-		-	
Securable memory area	-	-	The address to jump to the exit securable memory area @0x1FFF6800
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 101. STM32G47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010011x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PC4 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PA8 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010011x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain pull-up mode.
I2C4 bootloader	I2C4	Enabled	The I2C4 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010011x (where x = 0 for write and x = 1 for read)
	I2C4_SCL pin	Input/output	PC6 pin: clock line is used in open-drain pull-up mode.
	I2C4_SDA pin	Input/output	PC7 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull no pull-up, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

Table 101. STM32G47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, npull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, n pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

47.2 Bootloader selection

The figures below show the bootloader selection mechanism.

Figure 58. Bootloader selection for STM32G47xxx/48xxx

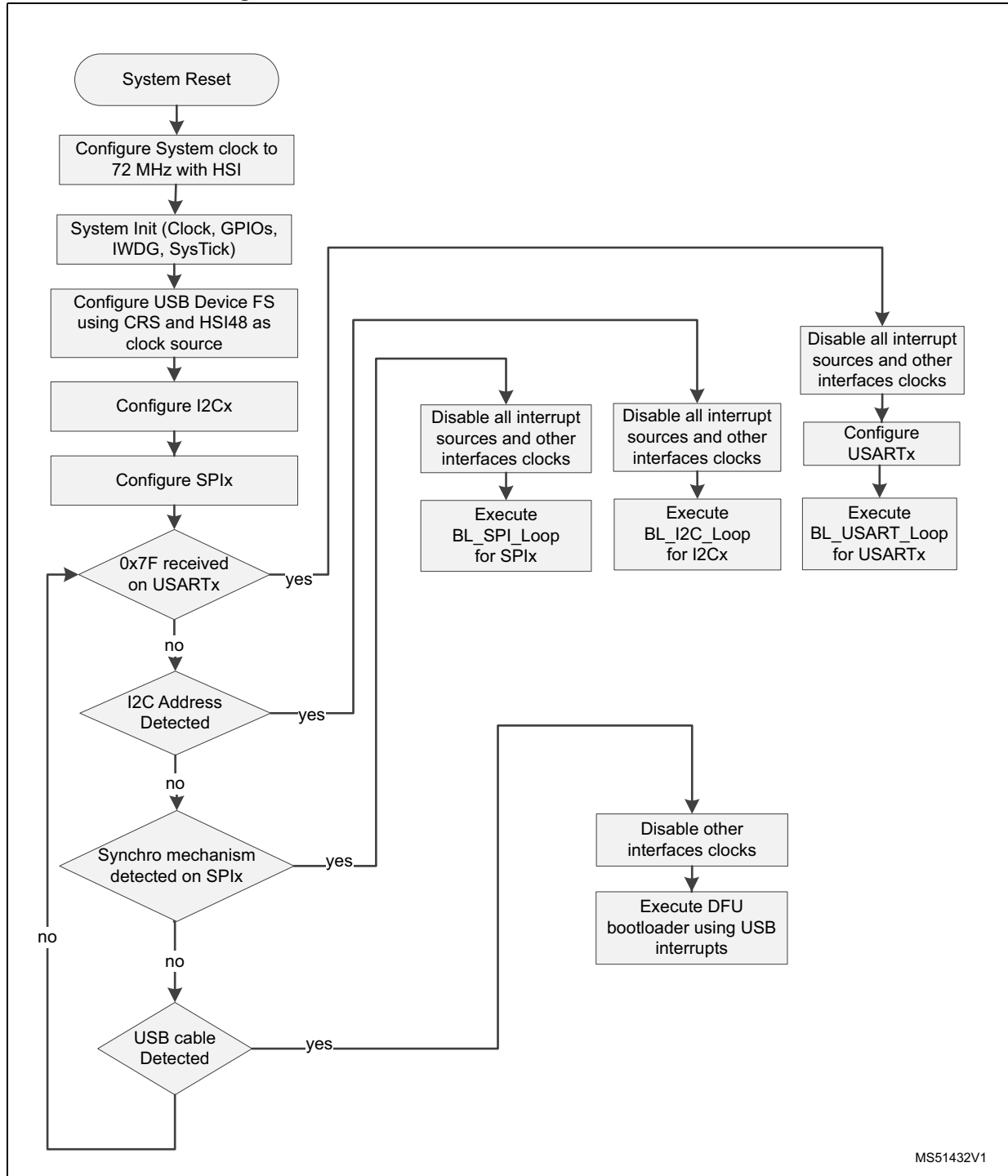
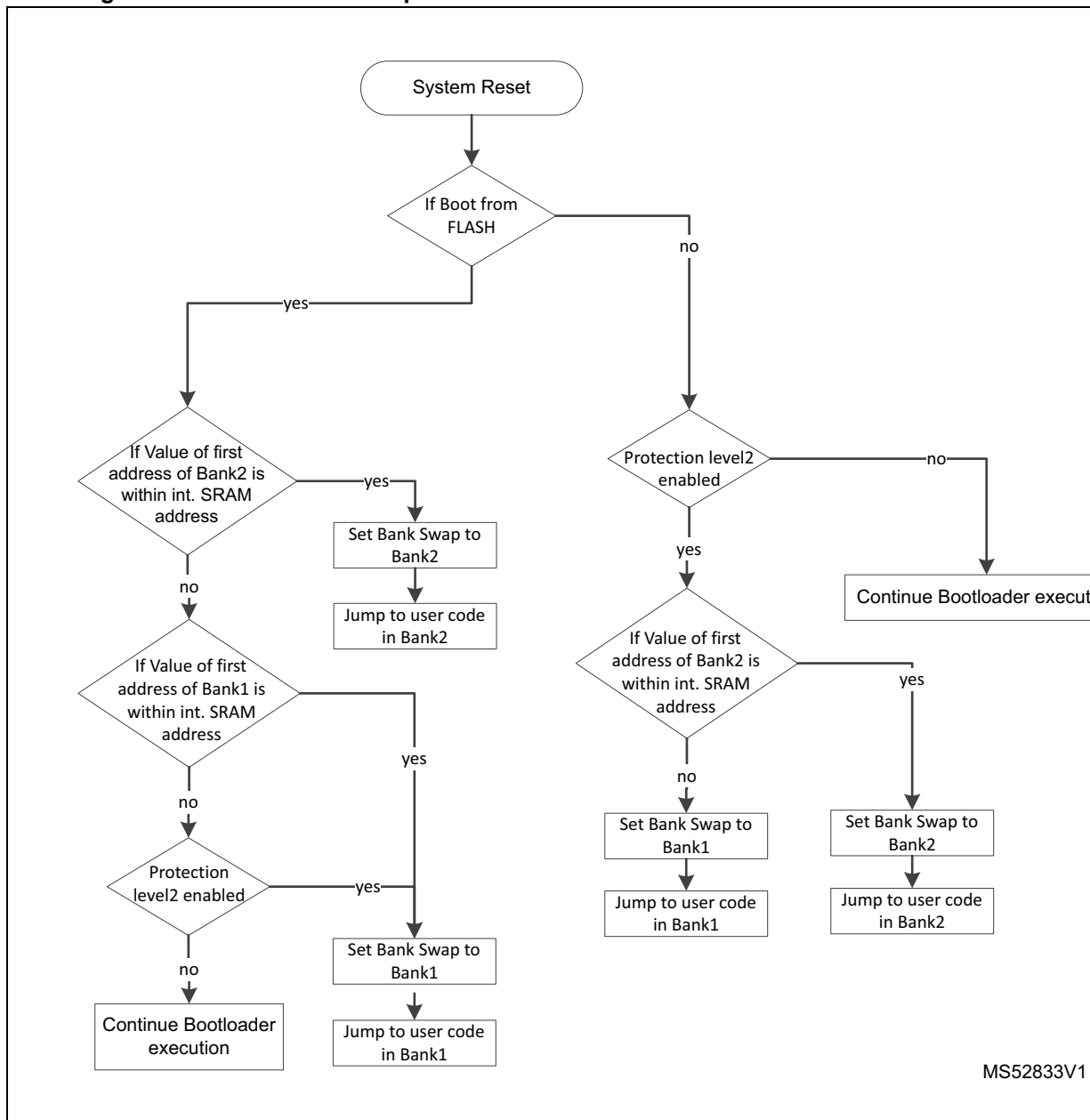


Figure 59. Dual bank boot implementation for STM32G47xxx/48xxx bootloader V13.x



MS52833V1

47.3 Bootloader version

Table 102. STM32G47xxx/48xxx bootloader version

Version number	Description	Known limitations
V13.3 (0xD3)	Initial bootloader version	Boot from bank2 is not working

Table 102. STM32G47xxx/48xxx bootloader version (continued)

Version number	Description	Known limitations
V13.4 (0xD4)	Fix V13.3 limitations	CCSRAM/ENGI not supported
V13.5 (0xD5)	– Fix V13.4 limitations – Add CCSRAM/ENGI support	None

48 STM32G491xx/4A1xx devices bootloader

48.1 Bootloader configuration

The STM32G491xx/4A1xx bootloader is activated by applying Pattern 15 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 103. STM32G491xx/4A1xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 72 MHz (using the PLL clocked by HSI)
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
	RAM	-	16 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Securable memory area	-	-	The address to jump to the exit securable memory area @0x1FFF6800
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 103. STM32G491xx/4A1xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011111x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PC4 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PA8 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011111x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC8 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull no pull-up, pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.

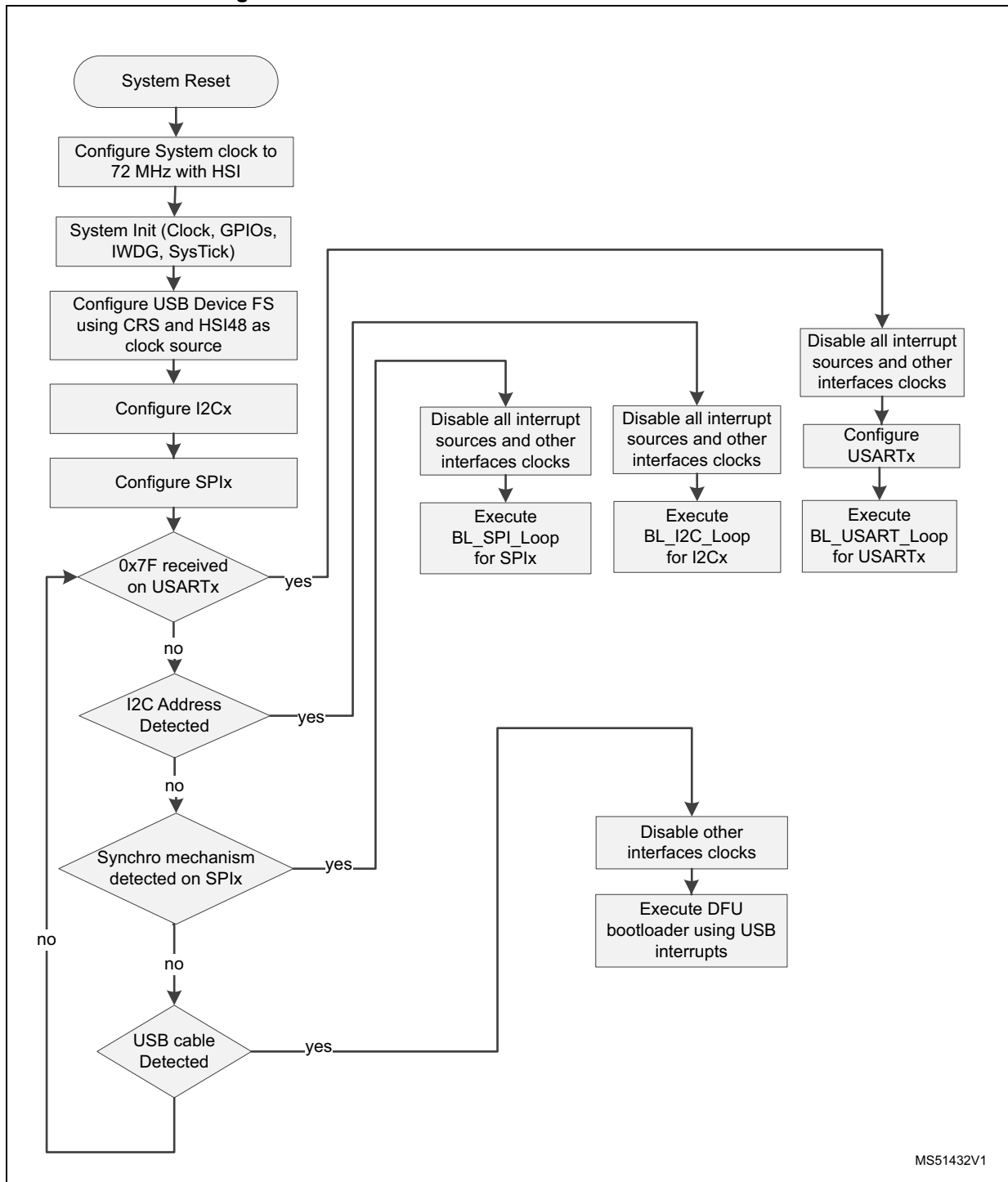
Table 103. STM32G491xx/4A1xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: <ul style="list-style-type: none"> – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, npull-down mode.
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, n pull-down mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader start-up after SPI initialization, as soon as bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line is set to 3.3 V.

48.2 Bootloader selection

Figure 60. Bootloader selection for STM32G491xx/4A1xx



MS51432V1

48.3 Bootloader version

Table 104. STM32G491xx/4A1xx bootloader version

Version number	Description	Known limitations
V13.2	Initial bootloader version	None

49 STM32H503xx devices bootloader

49.1 Bootloader configuration

The STM32H503xx bootloader is activated by applying Pattern 17 (described in [Table 2](#)). [Table 105](#) shows the hardware resources used by this bootloader.

Table 105. STM32H503xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 160 MHz (using PLL clocked by the HSI)
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes starting from address 0x24000000 are used by the bootloader firmware
	System memory	-	35 Kbytes starting from address 0x0BF87000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as Input until USART1 is detected.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA15 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA5 pin: USART2 in transmission mode. Set as Input until USART2 is detected.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PA3 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PA4 pin: USART3 in transmission mode. Set as Input until USART3 is detected.

Table 105. STM32H503xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1100111x, where x = 0 for write and x = 1 for read
	I2C2_SCL pin	Input/output	PB3 pin: clock line is used in open-drain. pull up mode.
	I2C2_SDA pin	Input/output	PB4 pin: data line is used in open-drain, pull up mode.
SPI1 bootloader	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA0 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA8 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PB8 pin: slave chip select pin used in push-pull, no pull mode.
SPI2 bootloader	SPI2_MOSI pin	Input	PB1 pin: slave data input line, used in push-pull no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PB10 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3 bootloader	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PD2 pin: slave chip select pin used in push-pull, no pull mode.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Table 105. STM32H503xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required
FDCAN bootloader	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PB5 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB15 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.
I3C bootloader	I3C	Enabled	– mode: target mode – Aval timing:0x4E – DMA Reg RX: disabled – DMA Req TX: Disabled – Status FIFO: Disabled – DMA Req status: Disabled – DMA Req control: Disabled – IBI: Enabled – Additional data after IBI Acked: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt) o The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PB6 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 106. STM32H503xx special commands

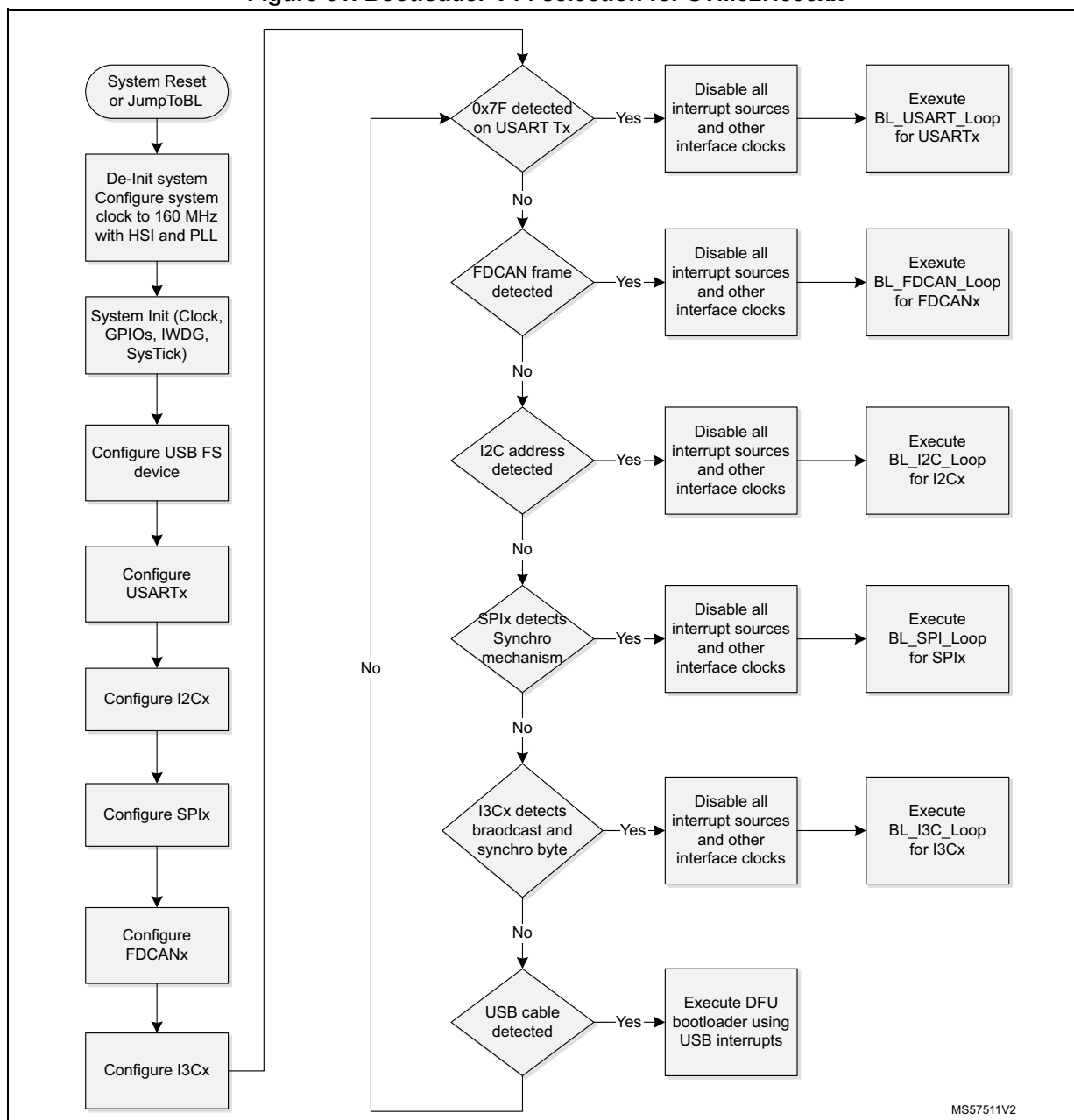
Special commands supported (USART/I2C/SPI/FDCAN/I3C) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent (MSB first)	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
Change Product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0

Note: *USB special commands are slightly different from the other protocols as per the USB protocol specificities:*

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data is sent on USB frame byte per byte (LSB first). No need to add number of data to be transmitted*
- *Returned data and status is formatted on the USB native protocol*

49.2 Bootloader selection

Figure 61. Bootloader V14 selection for STM32H503xx



MS57511V2

49.3 Bootloader version

Table 107. STM32H503xx bootloader version

Version number	Description	Known limitations
V14.1	Initial bootloader version	Bootloader crash when jumping to it with (HiDe Protection Level = 3 + product state ≥ Provisioned)

50 STM32H563xx/573xx devices bootloader

50.1 Bootloader configuration

The STM32H563xx/573xx bootloader is activated by applying Pattern 17 (described in [Table 2](#)). [Table 108](#) shows the hardware resources used by this bootloader.

Table 108. STM32H563xx/573xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 160 MHz (using PLL clocked by the HSI)
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	35 Kbytes starting from address 0x0BF97000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as Input until USART1 is detected.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as Input until USART2 is detected.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Set as Input until USART3 is detected.

Table 108. STM32H563xx/573xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1100101x, where x = 0 for write and x = 1 for read
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain. pull up mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain, pull up mode.
I2C4 bootloader	I2C4	Enabled	The I2C4 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1100101x, where x = 0 for write and x = 1 for read
	I2C4_SCL pin	Input/output	PD12 pin: clock line is used in open-drain. pull up mode.
	I2C4_SDA pin	Input/output	PD13 pin: data line is used in open-drain, pull up mode.
SPI1 bootloader	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2 bootloader	SPI2_MOSI pin	Input	PC1 pin: slave data input line, used in push, pull no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PB10 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3 bootloader	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.

Table 108. STM32H563xx/573xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required
FDCAN bootloader	FDCAN2	Enabled	Once initialized the FDCAN2 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN2_Rx pin	Input	PB5 pin: FDCAN2 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN2_Tx pin	Output	PB13 pin: FDCAN2 in transmission mode. Used in alternate push-pull, no pull mode.

Table 108. STM32H563xx/573xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I3C bootloader	I3C	Enabled	– mode: target mode – Aval timing:0x4E – DMA Reg RX: disabled – DMA Req TX: Disabled – Status FIFO: Disabled – DMA Req status: Disabled – DMA Req control: Disabled – IBI: Enabled – Additional data after IBI Acked: 1 byte – IBI configuration: Mandatory Data Byte (MDB) – All IT disabled except RXFNE (Receive FIFO Interrupt) o The RXFNE interruption is disabled after SYNC byte detection by the bootloader.
	I3C1_SCL pin	Input/output	PB6 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.
	I3C1_SDA pin		PB7 pin: I3C1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 109. STM32H563xx/573xx special commands

Special commands supported (USART/I2C/SPI/FDCAN/I3C) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent (MSB first)	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
Change Product state	0x01	0x4	Product state targeted Ex: 0x00000017	0x0	NA	0x1	0x0
Reset	0x02	0x4	0x0	0x0	NA	0x1	0x0
Data Provisioning Only when BL is on HDPL = 1	0x83	0x4	RAM address where Data to provision is written	0x0 - if success 0x1 - if fail	NA - if success Error code - if fail	0x1	0x0

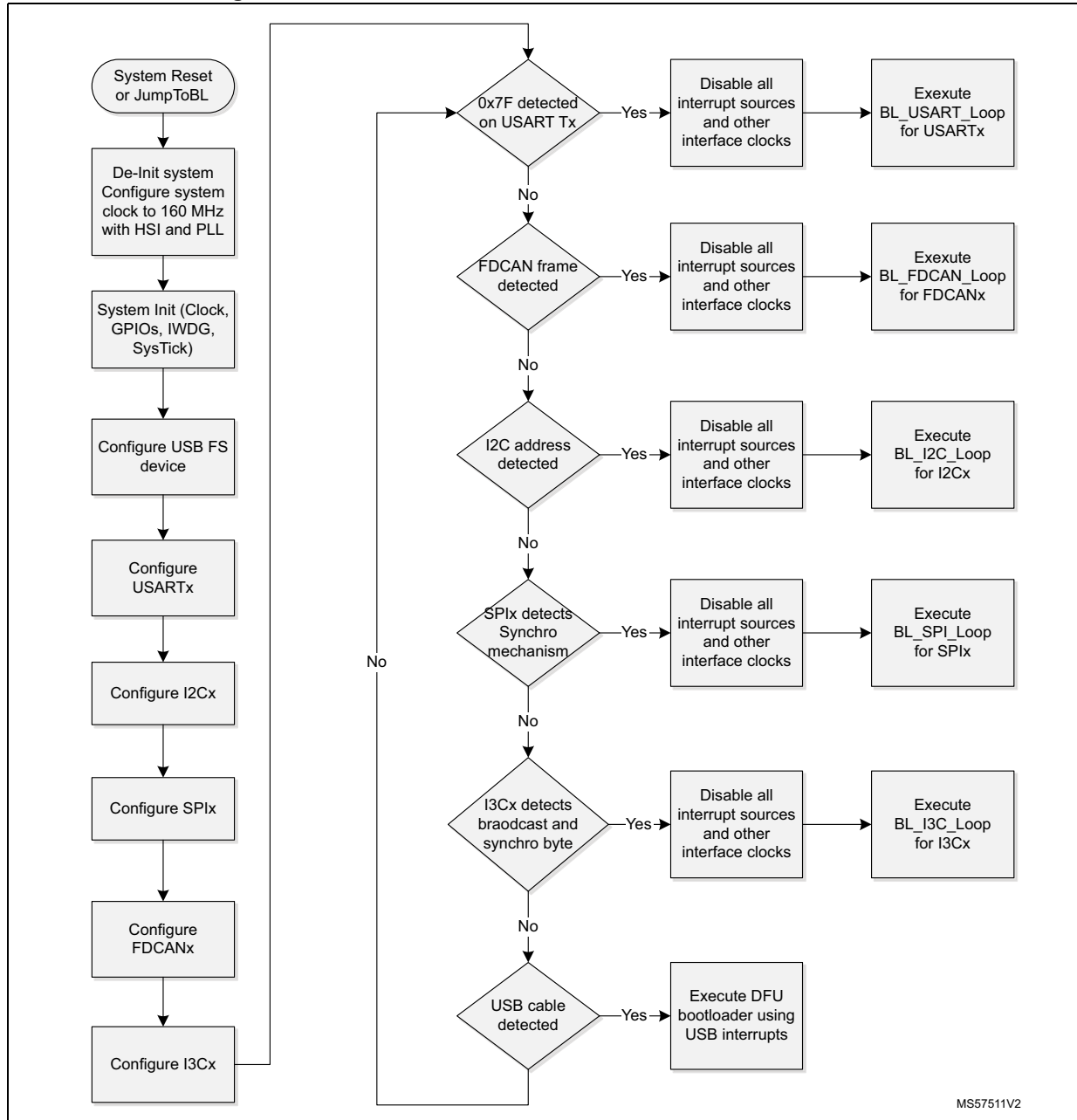
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- No Opcode is used, Sub-Opcode is used directly
- Sub-Opcode is treated in a single byte and not two bytes
- Data is sent on USB frame byte per byte (LSB first). No need to add number of data to be transmitted
- Returned data and status is formatted on the USB native protocol

50.2 Bootloader selection

Figure 62 shows the bootloader selection mechanism.

Figure 62. Bootloader V14 selection for STM32H563xx/573xx



50.3 Bootloader version

Table 110. STM32H563xx/573xx bootloader version

Version number	Description	Known limitations
V14.5	Fix known limitations ⁽¹⁾	None
V14.4	<ul style="list-style-type: none"> – Fix known limitations – Change BL system clock from 160 to 200 MHz 	EEPROM sector erase not working on 1 Mbyte devices.
V14.3	Initial bootloader version	Bootloader crash when jumping to it with the following condition (TrustZone [®] enabled + HiDe Protection = 3 + Product state ≥ Provisioned)

1. Only on 1 Mbytes devices.

A standalone EraseEEPROM function is added on the system memory at address 0x0BF9 F500. When an erase sector is needed:

1. Write at RAM address 0x2000 4000 (LSB to MSB)
 - a) Byte0: number of sectors to erase (N)
 - b) Byte1 to N (every byte contains the sector number, that is, 0 to 7 for Bank1, 8 to 15 for Bank2)
 - c) Example: to erase sector 3, 4, and 13, write 0x0303 040D at address 0x20004000.
2. After the erase, go back to the bootloader.
3. To continue using the bootloader, a reconnect is needed.

51 STM32H72xxx/73xxx devices bootloader

51.1 Bootloader configuration

The STM32H72xxx/73xxx bootloader is activated by applying Pattern 10 (described in [Table 2](#)). [Table 111](#) shows the hardware resources used by this bootloader.

Table 111. STM32H72xxx/73xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 66 MHz (using PLL clocked by the HSI)
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes, starting from address 0x24000000 are used by the bootloader firmware
	System memory	-	128 Kbytes starting from address 0x1FFF0000, contain the bootloader firmware. The bootloader start address is 0x1FF09800
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to Voltage Range 3. Bootloader SW is writing to the PWR_CR3 register using 4 bytes, which is locking this register. Only Power off/on will unlock it. This is fixed on the BL with 0x93 version.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. Set as Input until USART1 is detected on the BL version 0x93.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode. Set as Input until USART2 is detected on the BL version 0x93.

Table 111. STM32H72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader (on PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as Input until USART3 is detected on the BL version 0x93.
USART3 bootloader (on PD8/PD9)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as Input until USART3 is detected on the BL version 0x93.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010111x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010111x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010111x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.

Table 111. STM32H72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data input line, used in push-pull no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.

Table 111. STM32H72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data input line, used in push-pull, pull-down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, pull-down mode.
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, pull-down mode.
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, pull-up mode. Note: This IO can be tied to GND if the SPI master does not use it
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
FDCAN bootloader (on PH13/PH14)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PH14 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PH13 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.

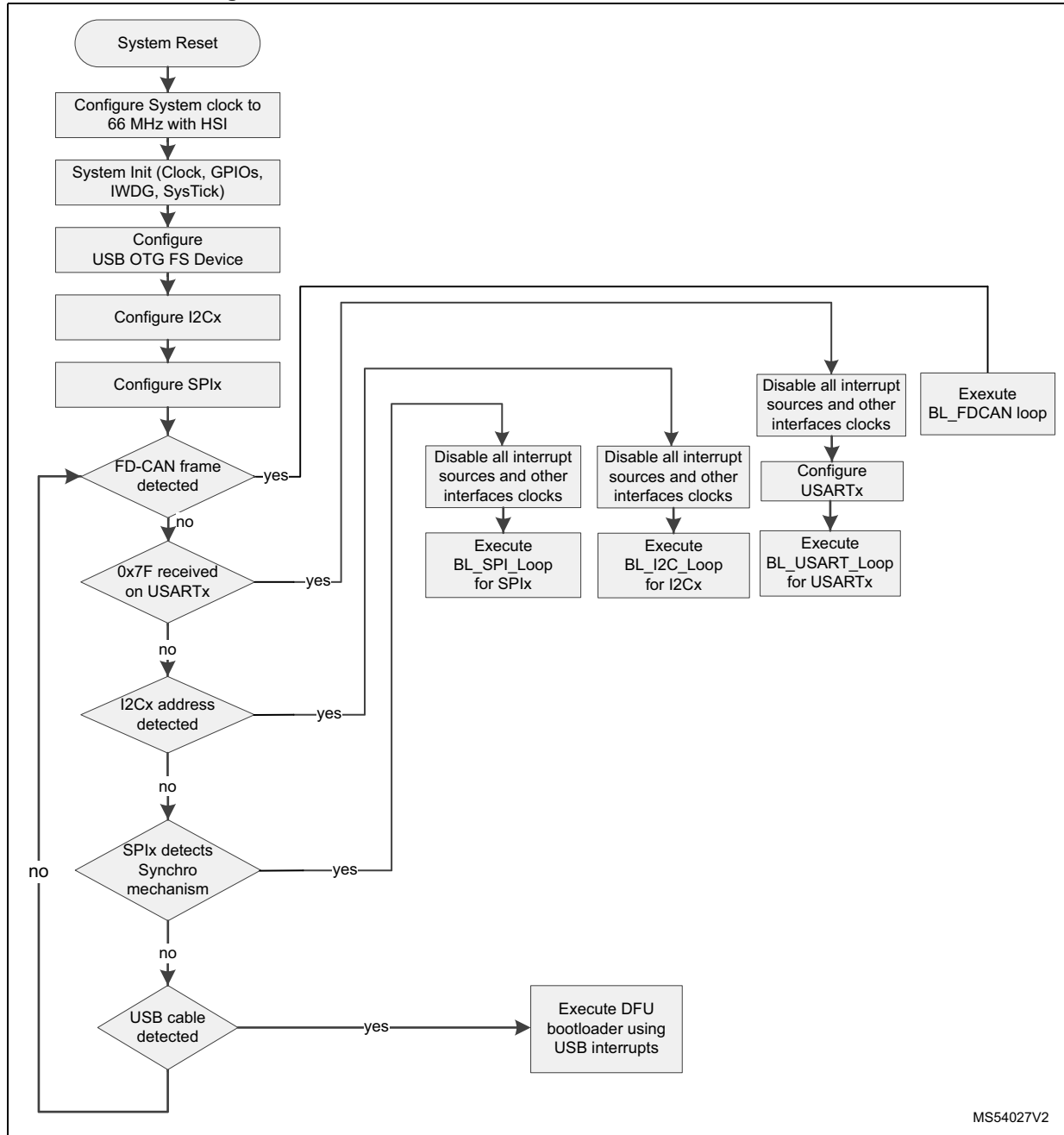
Table 111. STM32H72xxx/73xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN bootloader (on PD1/PD0)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PD0 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PD1 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.

51.2 Bootloader selection

Figure 63 shows the bootloader selection mechanism.

Figure 63. Bootloader V9.0 selection for STM32H72xxx/73xxx



51.3 Bootloader version

Table 114 lists the STM32H72xxx/73xxx devices bootloader versions.

Table 112. STM32H72xxx/73xxx bootloader version

Version number	Description	Known limitations
V9.1	Initial bootloader version	<ul style="list-style-type: none"> – TCM_AXI OB cannot be modified using all BL interfaces – String returned describing the memory size when using USB is wrong
V9.2	Fix all issues of previous release	<ul style="list-style-type: none"> – Crash loop when booting on the BL, setting RDP to Level1, doing a reset or power on/off and the USB cable is plugged. – BL is not working in RDP Level1 when TCM_AXI_SHARED option byte is not “0”. Value of this OB must be set to “0” before going to RDP L1. – Bootloader SW is writing to the PWR_CR3 register using 4 bytes, which is locking this register. Only Power off/on will unlock it.
V9.3	<ul style="list-style-type: none"> – Fix all issues of previous release. – Modify USART TX from push pull mode in the previous versions to input. 	None

52 STM32H74xxx/75xxx devices bootloader

52.1 Bootloader configuration

The STM32H74xxx/75xxx bootloader is activated by applying Pattern 10 (described in [Table 2](#)). [Table 113](#) shows the hardware resources used by this bootloader.

Table 113. STM32H74xxx/75xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 64 MHz using the HSI. The HSI clock source is used at startup (interface detection phase) and when USART or SPI or I2C interface is selected.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
		-	Clock used for the FDCAN is fixed to 20 MHz and is derived from PLLQ
	RAM	-	16 Kbytes, starting from address 0x20000000, and 208 Kbytes (reduced to 20 Kbytes in V9.1 version) starting from address 0x24000000 are used by the bootloader firmware
	System memory	-	122 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware. The bootloader start address is 0x1FF09800
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage is set to Range 3. Bootloader software writes to the PWR_CR3 register using 4 bytes, which locks this register. Only Power off/on unlocks it. This is fixed on the bootloader with 0x91 version.
USART1 bootloader (on PA9/PA10)	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. Set as input until USART1 is detected on the bootloader version 0x91.

Table 113. STM32H74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader (on PB14/PB15)	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PB15 pin: USART1 in reception mode. Used in input pull-up mode.
	USART1_TX pin	Output	PB14 pin: USART1 in transmission mode. Used in input pull-up mode. Set as input until USART2 is detected on the bootloader version 0x91.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, no pull mode. Used in alternate push-pull, no pull mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, no pull mode. Set as input until USART3 is detected on the bootloader version 0x91.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in alternate push-pull, no pull mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in alternate push-pull, no pull mode. Set as input until USART3 is detected on the bootloader version 0x91.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001110x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001110x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.

Table 113. STM32H74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001110x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, no pull mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data input line, used in push-pull, no pull mode.
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, no pull mode.

Table 113. STM32H74xxx/75xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data Input line, used in push-pull, no pull mode.
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, no pull mode.
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, no pull mode.
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, no pull mode.
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, no pull mode.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Table 113. STM32H74xxx/75xxx configuration in system memory boot mode (continued)

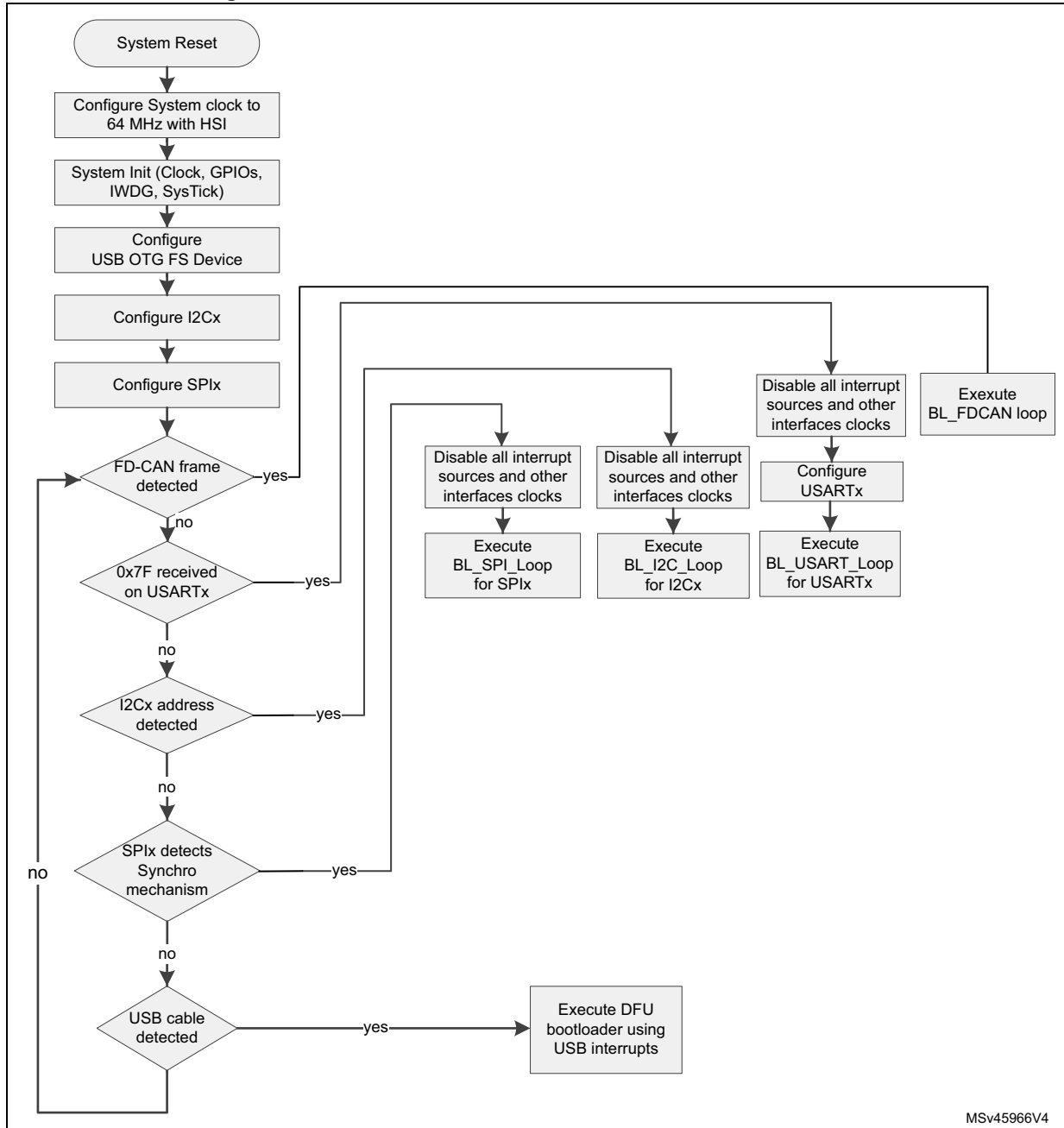
Bootloader	Feature/Peripheral	State	Comment
FDCAN bootloader	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PH14 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PH13 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

Note: To connect to the bootloader USART1 using PB14/PB15 pins, user must send two synchronization bytes. Baudrate is limited to 115200.
 DFU mode does not support USBREGEN mode. If STM32 is powered by 1.8 V source, it is not possible to use the BL DFU unless 3.3 V is provided

52.2 Bootloader selection

Figure 64 shows the bootloader selection mechanism.

Figure 64. Bootloader V9.x selection for STM32H74xxx/75xxx



52.3 Bootloader version

Table 114 lists the STM32H74xxx/75xxx devices bootloader versions.

Table 114. STM32H74xxx/75xxx bootloader version

Version number	Description	Known limitations
V13.2 (0xD2)	Initial bootloader version	<ul style="list-style-type: none"> – “Go” Command is not working – USART2 connection is not working – SPI1 connection is not working – Mass erase is not working well on I2C (only Bank2 is erased in this command)
V13.3 (0xD3)	<ul style="list-style-type: none"> – Switch USB clock input from HSE to HSI48 with CRS – Fix known limitations on the V13.2 	<ul style="list-style-type: none"> – Bank erase is not working on USART/SPI and I2C – DFU bootloader mass-erase not working
V9.0 (0x90)	<ul style="list-style-type: none"> – Add support of FDCAN interface – Fix V13.3 limitations – V9.0 is the latest version in production and replaces V13.2 and V13.3 	<ul style="list-style-type: none"> – First ACK not received on “Go” Command when using USART or SPI – On the FDCAN write memory, write of data with length > 63 bytes fails – If PB15 is set to GND, user cannot connect to BL interfaces. Only the USB is able to connect as it uses interrupt for detection. PB15 must not be pulled down if USART1 on PB14/PB15 is not used – Jump issue on some application. Application stack pointer must be lower than (RAM end @ - 16 bytes) to guarantee it is working – Additional reset needed after power off/on to enable connection to the BL interfaces. As a workaround user can add a pull up on PA11 pin.’ – Cannot program the "CM4_BOOT_ADDx" option byte using BL in dual core case – FDCAN Get version command is giving a bad FDCAN protocol version (0x11). It must be 0 x10 (V1.0) – SRAM1/SRAM2/SRAM3 (0x30000000-0x30047FFF) and ITCM memories not accessible by the BL – Number of supported commands is wrong (13 instead of 11)
V9.1 (0x91)	<ul style="list-style-type: none"> – Fix V9.0 limitations – Fix the configuration of PWR control register CR3. Bootloader is no more blocking the change of PWR source – Adjust USB, I²C erase and program timings and fix them – Fix FDCAN version from V1.0 to V1.1 – Fix write issue when using FDCAN – Fix missing PCROP disable in RDP level1 regression – Update option byte support to handle all possible use cases 	<ul style="list-style-type: none"> – If PB15 is set to GND, user will not be able to connect to BL interfaces – SRAM1/SRAM2/SRAM3 (0x30000000-0x30047FFF) and ITCM memories not accessible by the BL

53 STM32H7A3xx/B3xx devices bootloader

53.1 Bootloader configuration

The STM32H7A3xx/7B3xx bootloader is activated by applying Pattern 10 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 115. STM32H7A3xx/7B3xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 64 MHz using the HSI.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz
		-	Clock used for the FDCAN is fixed to 20 MHz and is derived from PLLQ
	RAM	-	16 Kbytes, starting from address 0x24000000 are used by the bootloader firmware
	System memory	-	128 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware. The bootloader start address is 0x1FF0A000
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Bootloader software is writing to the PWR_CR3 register using four bytes, which is locking this register. Only Power off/on unlocks it. This is fixed on the bootloader with 0x92 versions.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode. Set as Input until USART1 is detected on the bootloader version 0x92.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode. Set as Input until USART2 is detected on the bootloader version 0x92.

Table 115. STM32H7A3xx/7B3xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader on (PB10/PB11)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PB11 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PB10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as Input until USART3 is detected on the bootloader version 0x92.
USART3 bootloader on (PD8/PD9)	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PD9 pin: USART3 in reception mode. Used in alternate push-pull, pull-down mode.
	USART3_TX pin	Output	PD8 pin: USART3 in transmission mode. Used in alternate push-pull, pull-down mode. Set as Input until USART3 is detected on the bootloader version 0x92.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b10101111x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB9 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b10101111x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PF1 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PF0 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b10101111x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA8 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC9 pin: data line is used in open-drain no pull mode.

Table 115. STM32H7A3xx/7B3xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, no pull-up no pull-down mode.
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull-up no pull-down mode.
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull no pull-up, no pull-up no pull-down mode.
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PI3 pin: slave data Input line, used in push-pull, no pull mode.
	SPI2_MISO pin	Output	PI2 pin: slave data output line, used in push-pull, no pull mode.
	SPI2_SCK pin	Input	PI1 pin: slave clock line, used in push-pull, no pull mode.
	SPI2_NSS pin	Input	PI0 pin: slave chip select pin used in push-pull, no pull mode.
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PC12 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PC11 pin: slave data output line, used in push-pull, no pull mode.
	SPI3_SCK pin	Input	PC10 pin: slave clock line, used in push-pull, no pull mode.
	SPI3_NSS pin	Input	PA15 pin: slave chip select pin used in push-pull, no pull mode.

Table 115. STM32H7A3xx/7B3xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI4 bootloader	SPI4	Enabled	The SPI4 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI4_MOSI pin	Input	PE14 pin: slave data Input line, used in push-pull, no pull up, no pull down mode
	SPI4_MISO pin	Output	PE13 pin: slave data output line, used in push-pull, no pull up, no pull down mode.
	SPI4_SCK pin	Input	PE12 pin: slave clock line, used in push-pull, no pull up, no pull down mode.
	SPI4_NSS pin	Input	PE11 pin: slave chip select pin used in push-pull, no pull up, no pull down mode.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
FDCAN bootloader on (PH13/PH14)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PH14 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PH13 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.

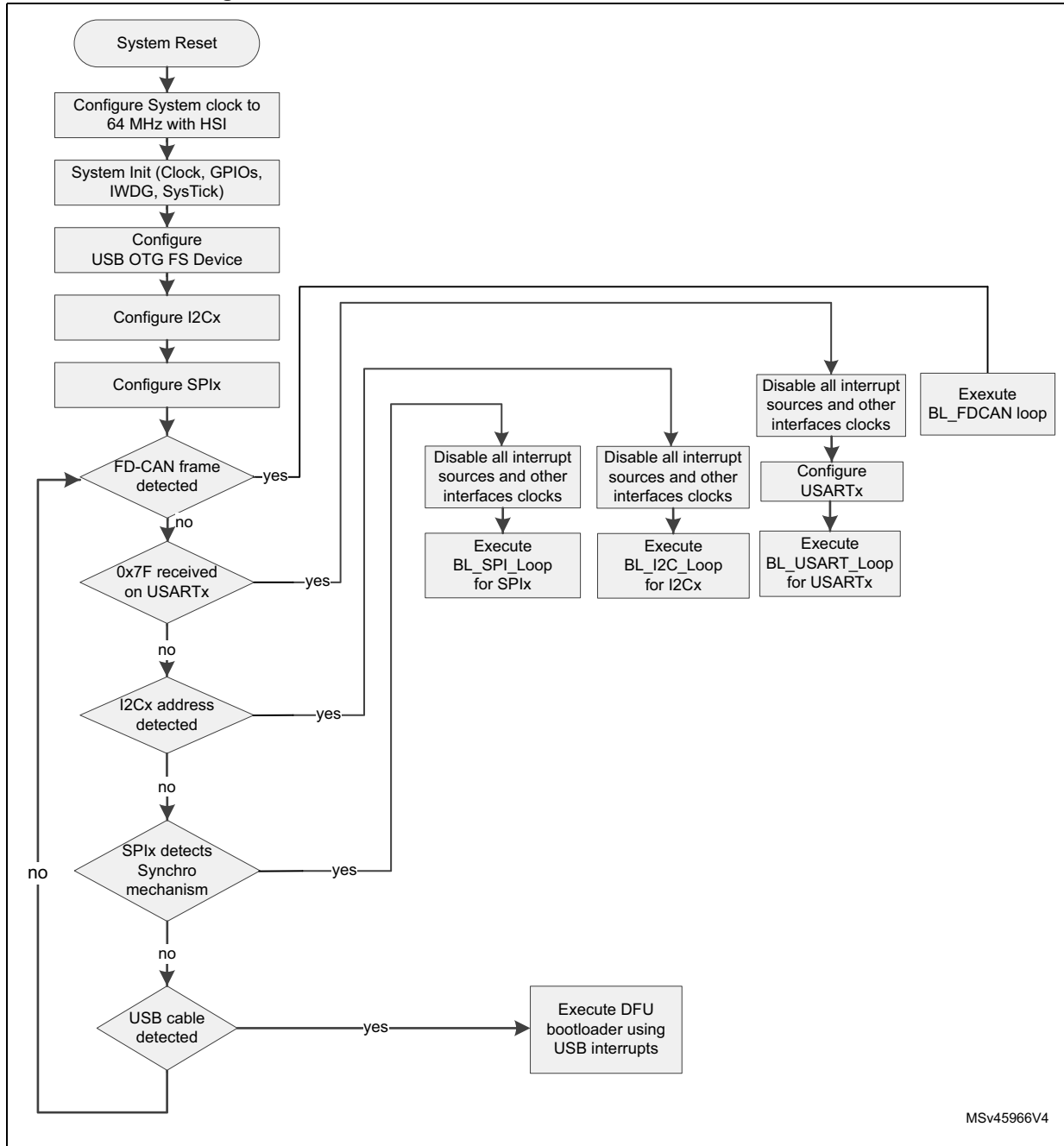
Table 115. STM32H7A3xx/7B3xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN bootloader on (PD1/PD0)	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input	PD0 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-down mode.
	FDCAN1_Tx pin	Output	PD1 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-down mode.

53.2 Bootloader selection

Figure 64 shows the bootloader selection mechanism.

Figure 65. Bootloader V9.x selection for STM32H7A3xx/7B3xx



53.3 Bootloader version

[Table 114](#) lists the STM32H7A3xx/7B3xx devices bootloader versions.

Table 116. STM32H7A3xx/7B3xx bootloader version

Version number	Description	Known limitations
V9.0	Initial bootloader version	<ul style="list-style-type: none"> – String returned describing the flash memory size when using USB is wrong (expected value 256 x 8 KB, but returns 256 x 2 KB) – OTP memory is not supported by the bootloader
V9.1	Fixes all issues of previous release.	<ul style="list-style-type: none"> – Crash loop when booting on the bootloader, setting RDP to Level1, doing a reset or power on/off and the USB cable is plugged. – Bootloader software is writing to the PWR_CR3 register using four bytes, which is locking this register. Only Power off/on unlocks it
V9.2	<ul style="list-style-type: none"> – Fix all issues of previous release – Modify USART TX from push pull mode in the previous versions to input. 	None

54 STM32L01xxx/02xxx devices bootloader

54.1 Bootloader configuration

The STM32L01xxx/02xxx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 117](#) shows the hardware resources used by this bootloader.

Table 117. STM32L01xxx/02xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	2 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	4 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART2 bootloader (on PA9/PA10)	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA10 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in input pull-up
USART2 bootloader (on PA2/PA3)	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode.Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART2 bootloader	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 117. STM32L01xxx/02xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader (for all device packages except TSSOP14)	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI1 bootloader (only for devices on TSSOP14 package)	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA14 pin: slave data output line, used in push-pull, pull-down mode. Note: This IO is also used as SWCLK for debug interface, as a consequence debugger cannot connect to the device in "on-the-fly" mode when the bootloader is running.
	SPI1_SCK pin	Input	PA13 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: NSS pin synchronization is required on bootloader with SPI1 interface for devices on TSSOP14 package.

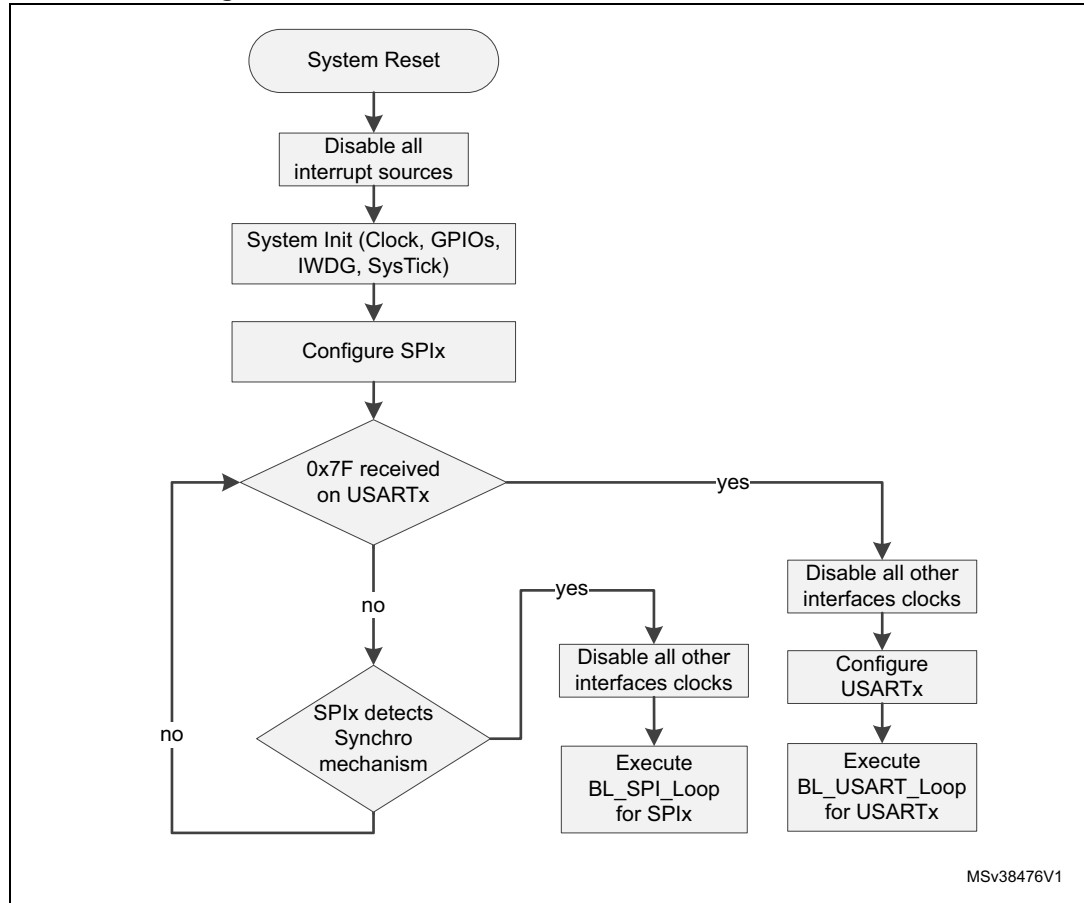
The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

Note: *Due to empty check mechanism present on this product, it is not possible to jump from user code to system bootloader. Such jump results in a jump back to user flash memory space. But if the first 4 bytes of user flash memory (at 0x0800 0000) are empty at the moment of the jump (i.e. erase first sector before jump or execute code from SRAM while flash is empty), then system bootloader is executed when jumped to.*

54.2 Bootloader selection

The [Table 66](#) shows the bootloader selection mechanism.

Figure 66. Bootloader selection for STM32L01xxx/02xxx



54.3 Bootloader version

The following table lists the STM32L01xxx/02xxx devices bootloader versions.

Table 118. STM32L01xxx/02xxx bootloader versions

Version number	Description	Known limitations
V12.2	Initial bootloader version	Bootloader not functional with SPI1 interface for devices on TSSOP14 package.
V12.3	Adds support of SPI interface for devices in TSSOP14 package.	For the SPI1 interface for devices in TSSOP14, a falling edge on NSS pin is required before starting communication, to properly synchronize the SPI interface. If the NSS pin is grounded (all time from device reset) the SPI communication is not synchronized and bootloader does not work properly with the SPI interface.

55 STM32L031xx/041xx devices bootloader

55.1 Bootloader configuration

The STM32L031xx/041xx bootloader is activated by applying Pattern 2 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 119. STM32L031xx/041xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	4 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART2 bootloader (on PA9/PA10)	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA10 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in input pull-up mode.
USART2 bootloader (on PA2/PA3)	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART2 bootloader	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 119. STM32L031xx/041xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

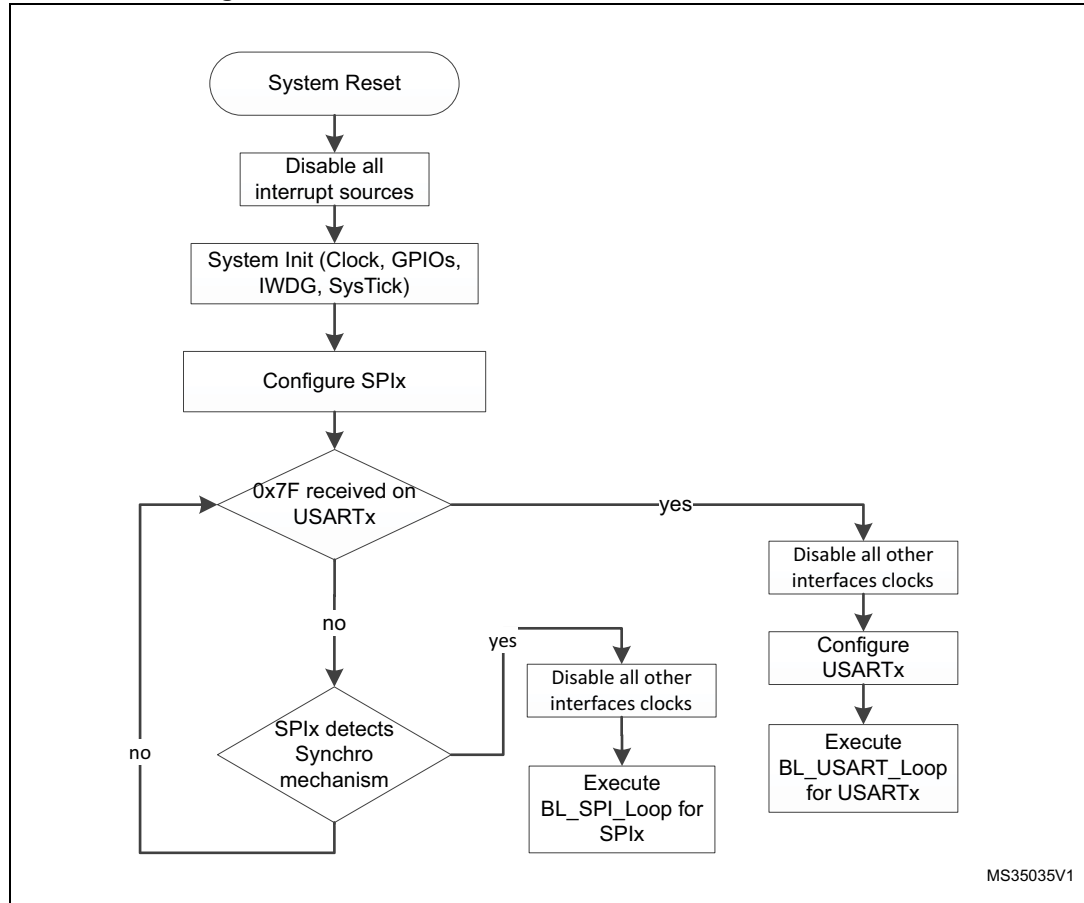
The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

The bootloader Read/Write commands do not support SRAM space for this product.

55.2 Bootloader selection

Figure 67 shows the bootloader selection mechanism.

Figure 67. Bootloader selection for STM32L031xx/041xx



55.3 Bootloader version

Table 120 lists the STM32L031xx/041xx devices bootloader versions.

Table 120. STM32L031xx/041xx bootloader versions

Version number	Description	Known limitations
V12.0	Initial bootloader version	None

56 STM32L05xxx/06xxx devices bootloader

56.1 Bootloader configuration

The STM32L05xxx/06xxx bootloader is activated by applying Pattern 1 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 121. STM32L05xxx/06xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	Power	-	Voltage range is set to Voltage Range 1.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	4 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 121. STM32L05xxx/06xxx configuration in system memory boot mode (continued)

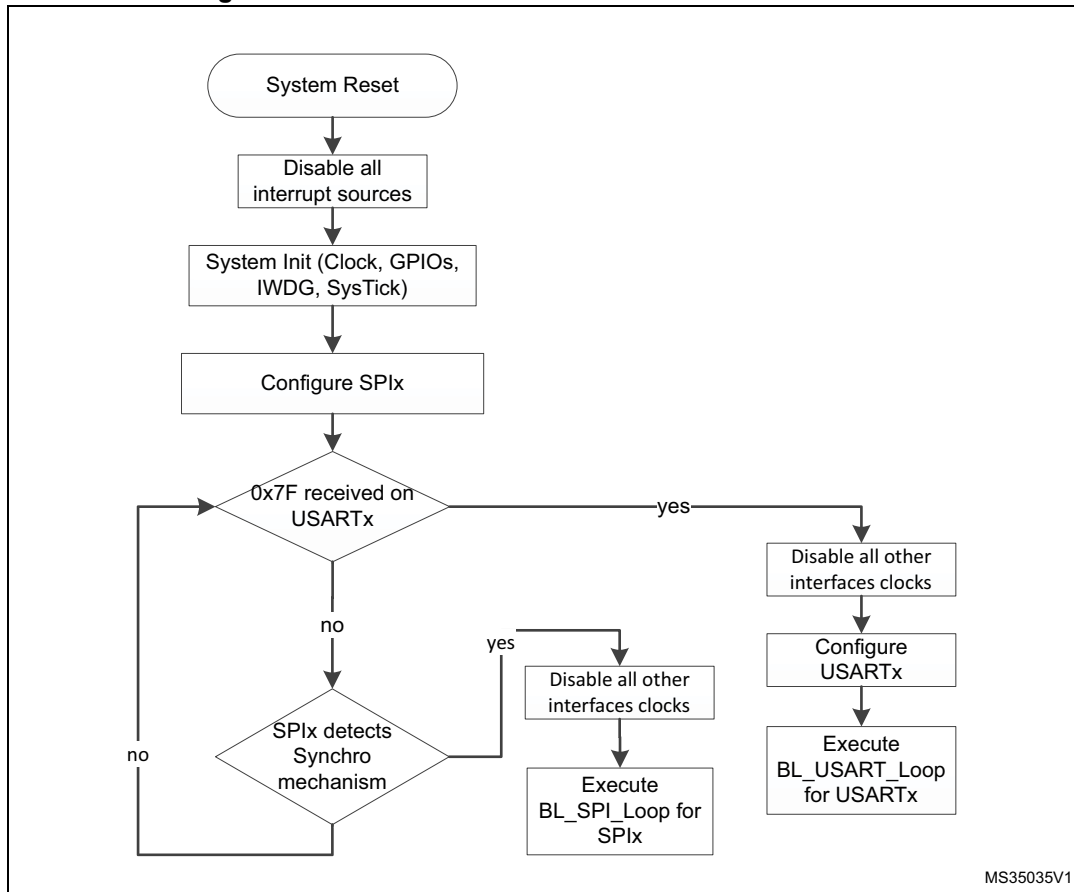
Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

56.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 68. Bootloader selection for STM32L05xxx/06xxx



56.3 Bootloader version

The following table lists the STM32L05xxx/06xxx devices bootloader versions:

Table 122. STM32L05xxx/06xxx bootloader versions

Version number	Description	Known limitations
V12.0	Initial bootloader version	PA13 set in alternate push-pull, pull-up mode and PA14 set in alternate pull-up pull-down mode even if not used

57 STM32L07xxx/08xxx devices bootloader

Two bootloader versions are available on STM32L07xxx/08xxx devices:

- V4.x supporting USART1, USART2, and DFU (USB FS device).
This version is embedded in STM32L072xx/73xx and STM32L082xx/83xx devices.
- V11.x supporting USART1, USART2, I2C1, I2C2, SPI1 and SPI2.
This version is embedded in other STM32L071xx/081xx devices.

57.1 Bootloader V4.x

57.1.1 Bootloader configuration

The STM32L07xxx/08xxx bootloader is activated by applying Pattern 2 or Pattern 7 when dual bank boot feature is available (described in [Table 2](#)). [Table 123](#) shows the hardware resources used by this bootloader.

Table 123. STM32L07xxx/08xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.

Table 123. STM32L07xxx/08xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

57.1.2 Bootloader selection

Figure 69 and Figure 70 show the bootloader selection mechanism.

Figure 69. Dual bank boot implementation for STM32L07xxx/08xxx bootloader V4.x

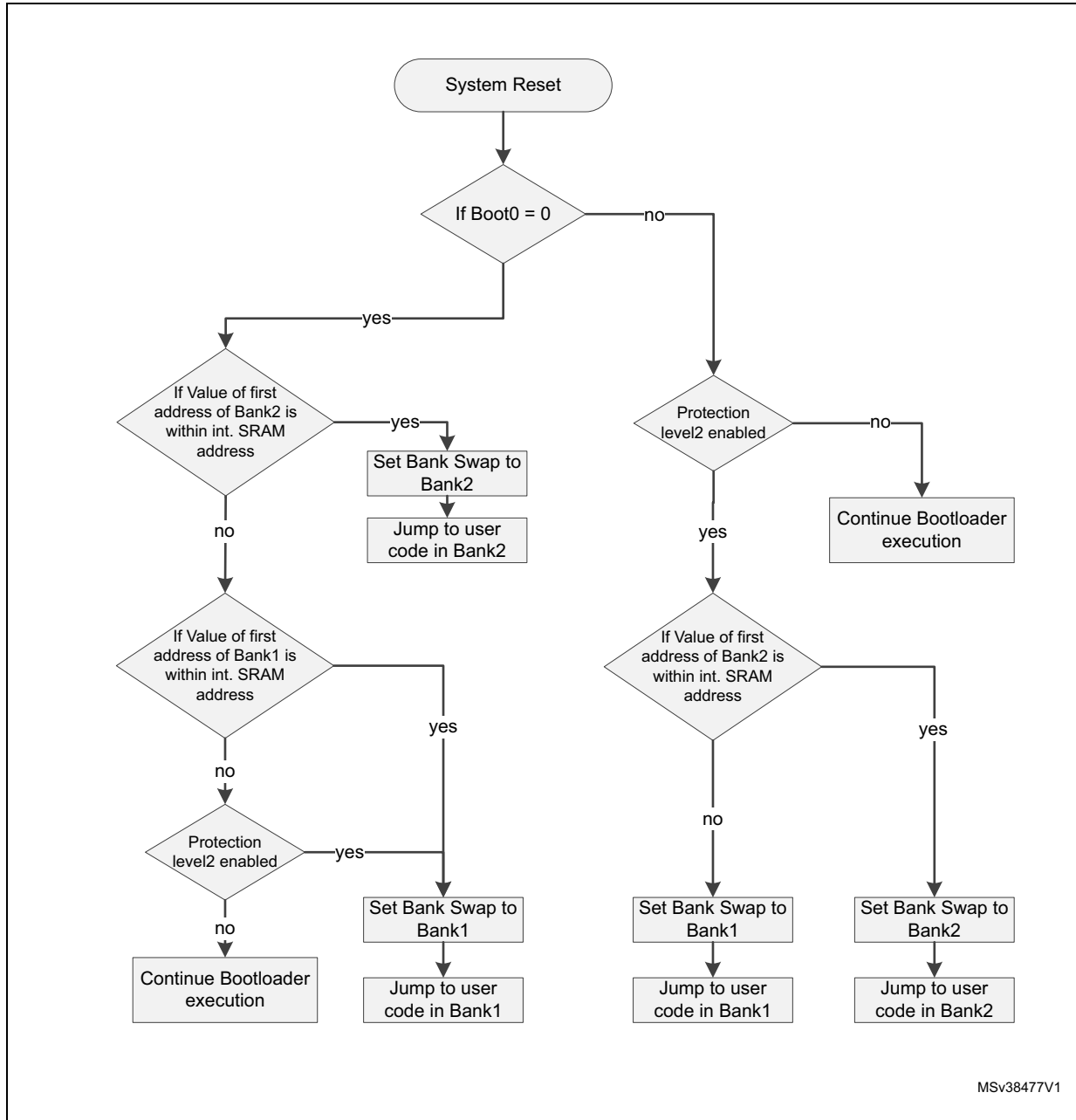
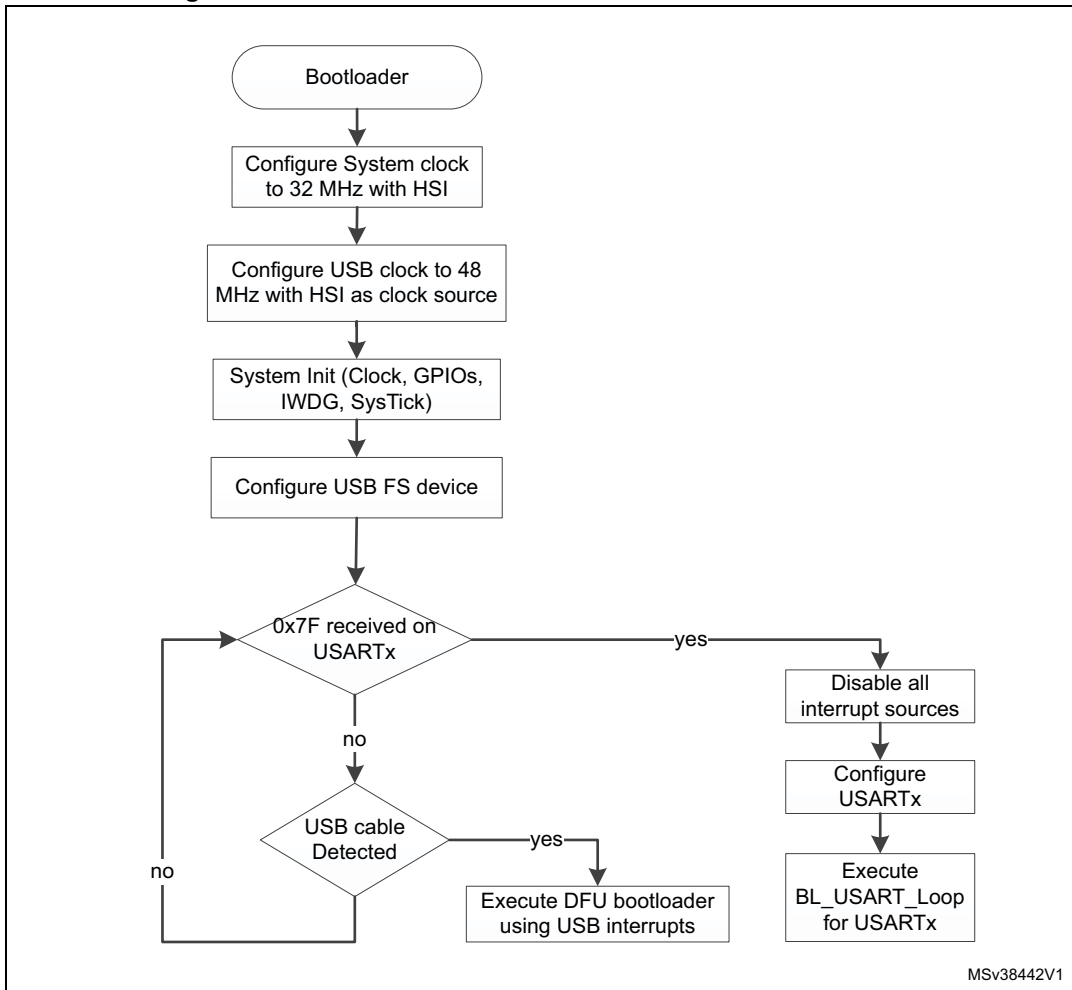


Figure 70. Bootloader V4.x selection for STM32L07xxx/08xxx



57.1.3 Bootloader version

Table 124 lists the STM32L07xxx/08xxx devices bootloader versions.

Table 124. STM32L07xxx/08xxx bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	PA4, PA5, PA6 and PA7 IOs are configured in pull-down mode despite not used by bootloader
V4.1	This new version implements the Dual Bank Boot feature.	PA4, PA5, PA6 and PA7 IOs are configured in pull-down mode despite not used by bootloader

57.2 Bootloader V11.x

57.2.1 Bootloader configuration

The STM32L07xxx/08xxx bootloader is activated by applying Pattern 2 or Pattern 7 when dual bank boot feature is available (see in [Table 2](#)). [Table 125](#) shows the hardware resources used by this bootloader.

Table 125. STM32L07xxx/08xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 32 MHz with HSI 16 MHz as clock source.
	RAM	-	5 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	8 Kbytes, starting from address 0x1FF00000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1000010x – (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: I2C1 clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: I2C1 data line is used in open-drain no pull mode.

Table 125. STM32L07xxx/08xxx configuration in system memory boot mode (continued)

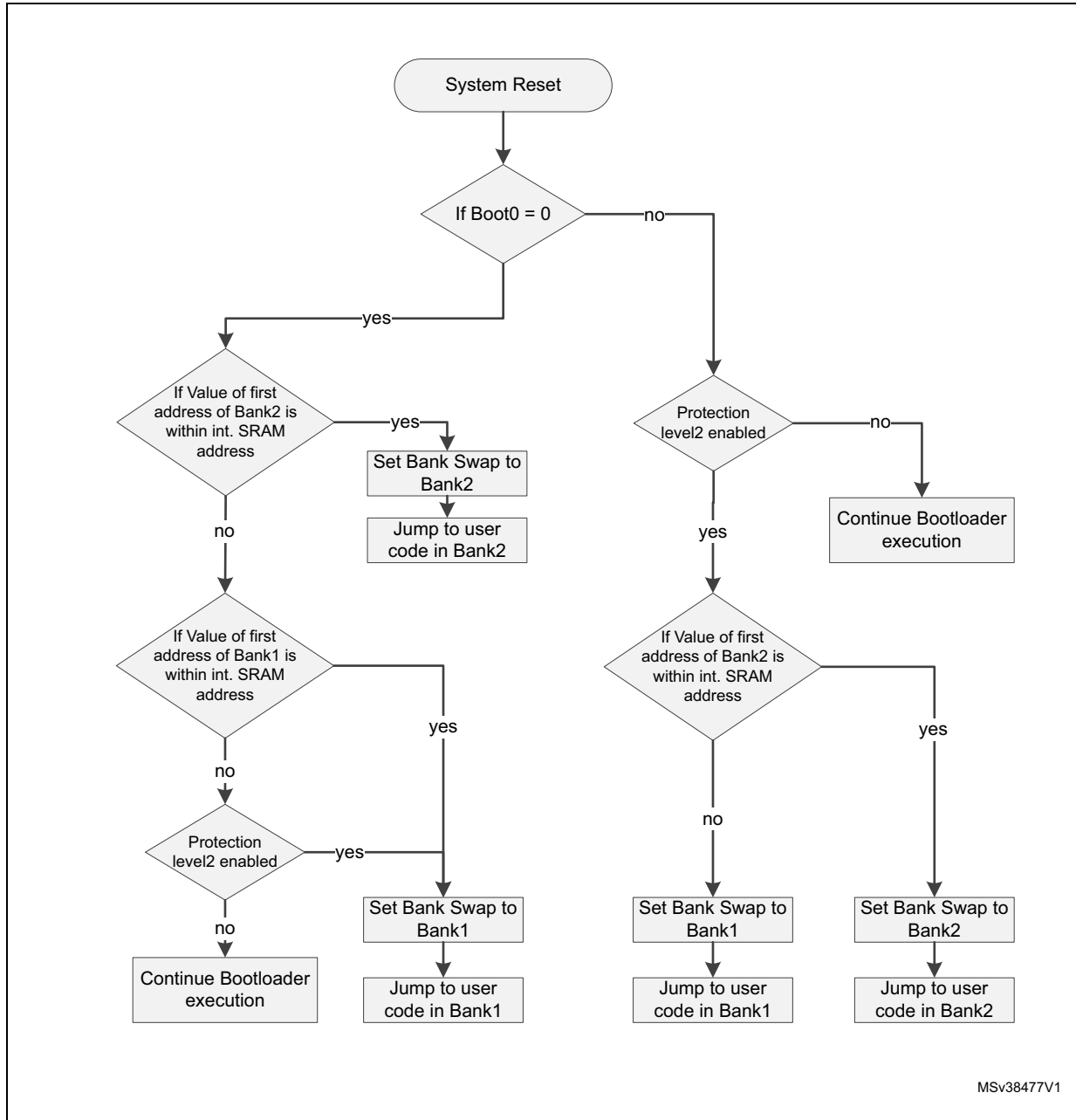
Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1000010x – (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: I2C2 clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: I2C2 data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

The system clock is derived from the embedded internal high-speed RC for all bootloader interfaces. No external quartz is required for bootloader operations.

57.2.2 Bootloader selection

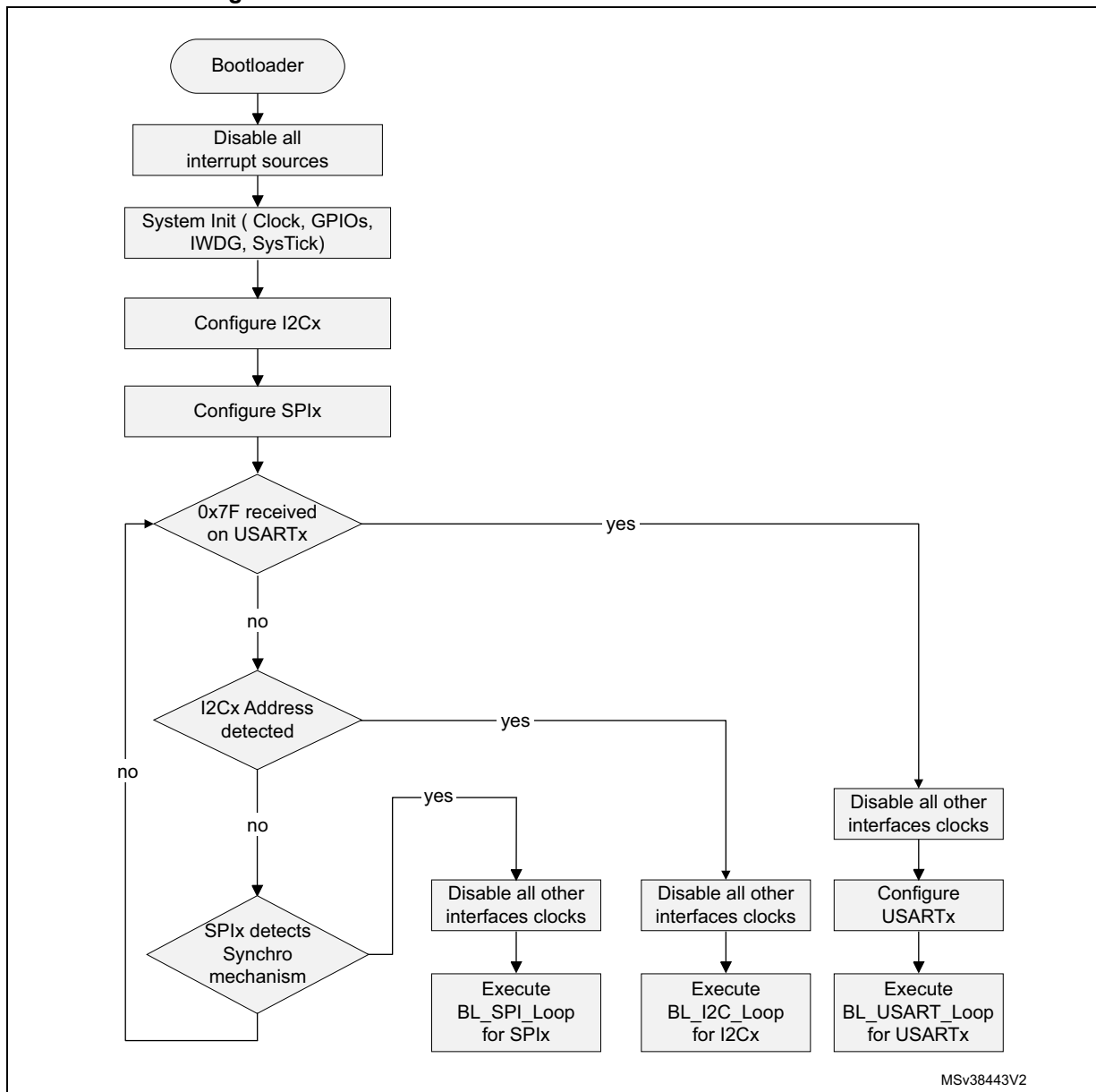
Figure 71 and Figure 72 show the bootloader selection mechanism.

Figure 71. Dual bank boot implementation for STM32L07xxx/08xxx bootloader V11.x



MSv38477V1

Figure 72. Bootloader V11.x selection for STM32L07xxx/08xxx



57.2.3 Bootloader version

The following table lists the STM32L07xxx/08xxx devices bootloader versions:

Table 126. STM32L07xxx/08xxx bootloader V11.x versions

Version number	Description	Known limitations
V11.1	Initial bootloader version	None
V11.2	This new version implements the Dual Bank Boot feature.	None



58 STM32L1xxx6(8/B)A devices bootloader

58.1 Bootloader configuration

The STM32L1xxx6(8/B)A bootloader is activated by applying Pattern 1 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 127. STM32L1xxx6(8/B)A configuration in system memory boot mode

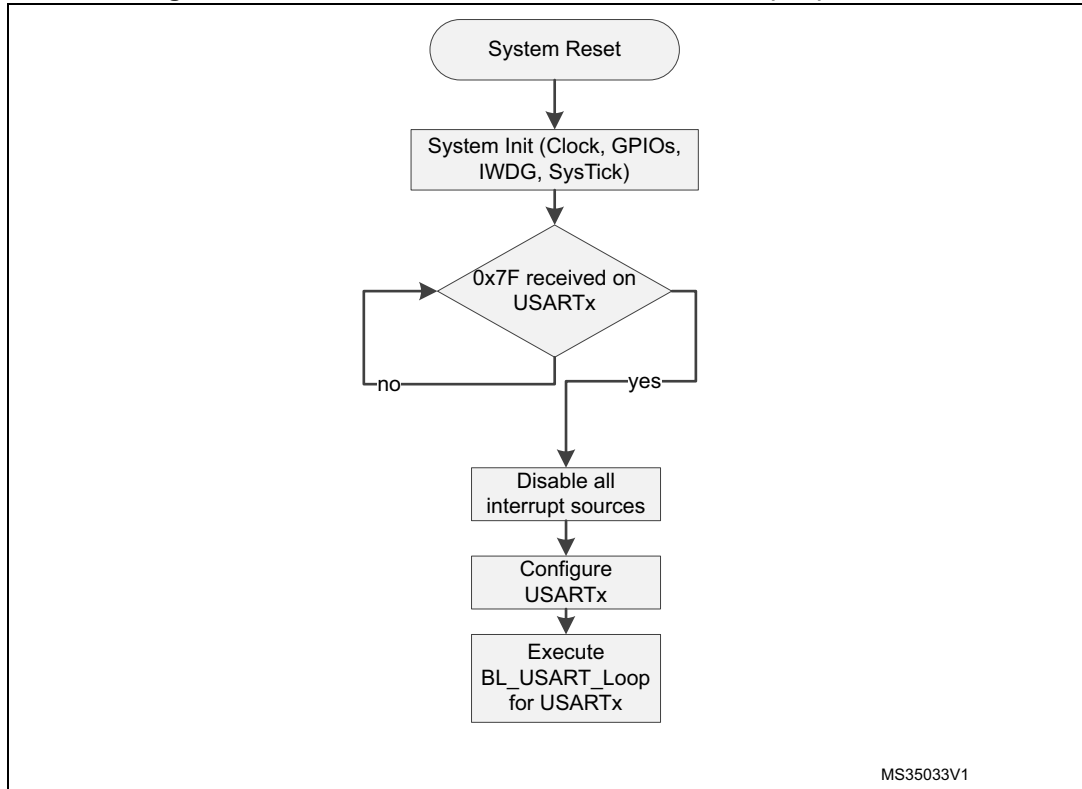
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 16 MHz.
	RAM	-	2 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	4 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to Voltage Range 1.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC, no external . No external quartz is required for the bootloader execution.

58.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 73. Bootloader selection for STM32L1xxx6(8/B)A devices



58.3 Bootloader version

The following table lists the STM32L1xxx6(8/B)A devices bootloader versions:

Table 128. STM32L1xxx6(8/B)A bootloader versions

Version number	Description	Known limitations
V2.0	Initial bootloader version	When a Read Memory or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (the number of bytes to be read/written and its checksum) are considered as a new command and its checksum. ⁽¹⁾

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code, the limitation is not perceived from the host, as the command is NACKed anyway (as an unsupported new command).

59 STM32L1xxx6(8/B) devices bootloader

59.1 Bootloader configuration

The STM32L1xxx6(8/B) bootloader is activated by applying Pattern 1 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 129. STM32L1xxx6(8/B) configuration in system memory boot mode

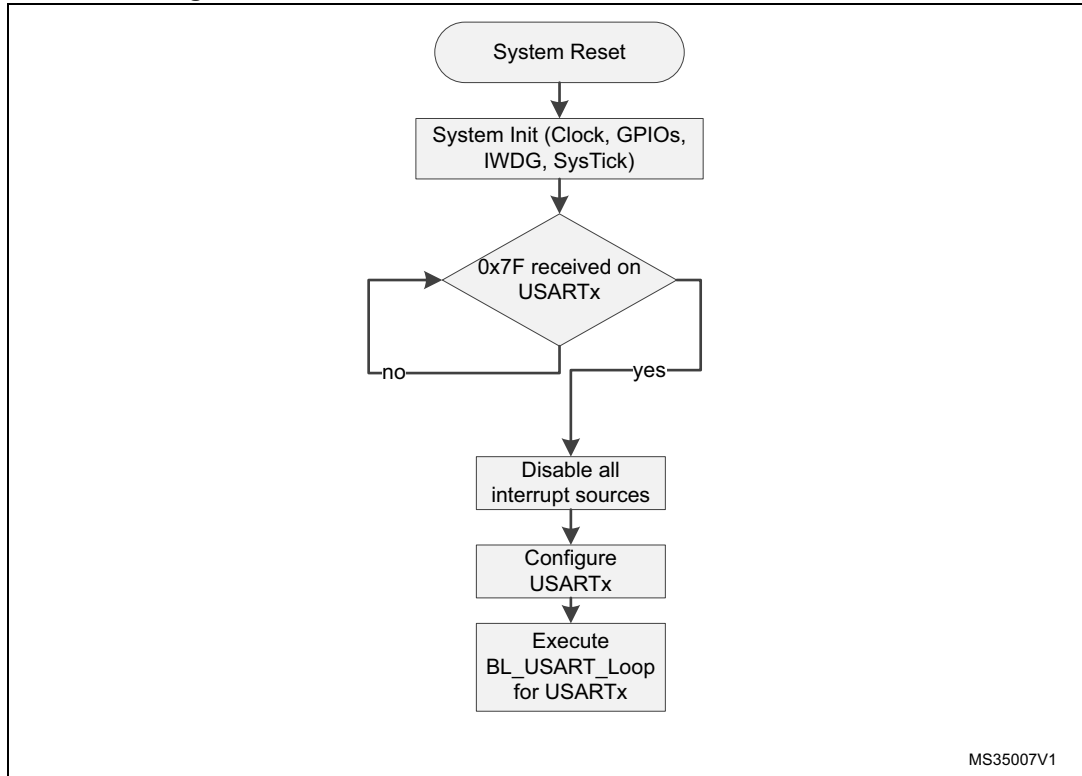
Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 16 MHz.
	RAM	-	2 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	4 Kbytes, starting from address 0x1FF00000 contain the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to Voltage Range 1.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host.

The system clock is derived from the embedded internal high-speed RC, no external . No external quartz is required for the bootloader execution.

59.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 74. Bootloader selection for STM32L1xxx6(8/B) devices



59.3 Bootloader version

The following table lists the STM32L1xxx6(8/B) devices bootloader versions:

Table 130. STM32L1xxx6(8/B) bootloader versions

Version number	Description	Known limitations
V2.0	Initial bootloader version	<ul style="list-style-type: none"> – When a Read Memory or Write Memory command is issued with an unsupported memory address and a correct address checksum (i.e. address 0x6000 0000), the command is aborted by the bootloader device, but the NACK (0x1F) is not sent to the host. As a result, the next 2 bytes (the number of bytes to be read/written and its checksum) are considered as a new command and its checksum.⁽¹⁾ – PA13/14/15 is configured in alternate push-pull (PA14 in pull-down) even if not used.

1. If the “number of data - 1” (N-1) to be read/written is not equal to a valid command code, the limitation is not perceived from the host, as the command is NACKed anyway (as an unsupported new command).

60 STM32L1xxxC devices bootloader

60.1 Bootloader configuration

The STM32L1xxxC bootloader is activated by applying Pattern 1 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 131. STM32L1xxxC configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 16 MHz using the HSI. This is used only for USARTx bootloaders and during USB detection for DFU bootloader (once the DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for the DFU bootloader and must be in the following range: [24, 16, 12, 8, 6, 4, 3, 2] MHz. The PLL is used to generate the USB 48 MHz clock and the 32 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates a system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000 contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog resets (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to Voltage Range 1.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity and 1 stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 131. STM32L1xxxC configuration in system memory boot mode (continued)

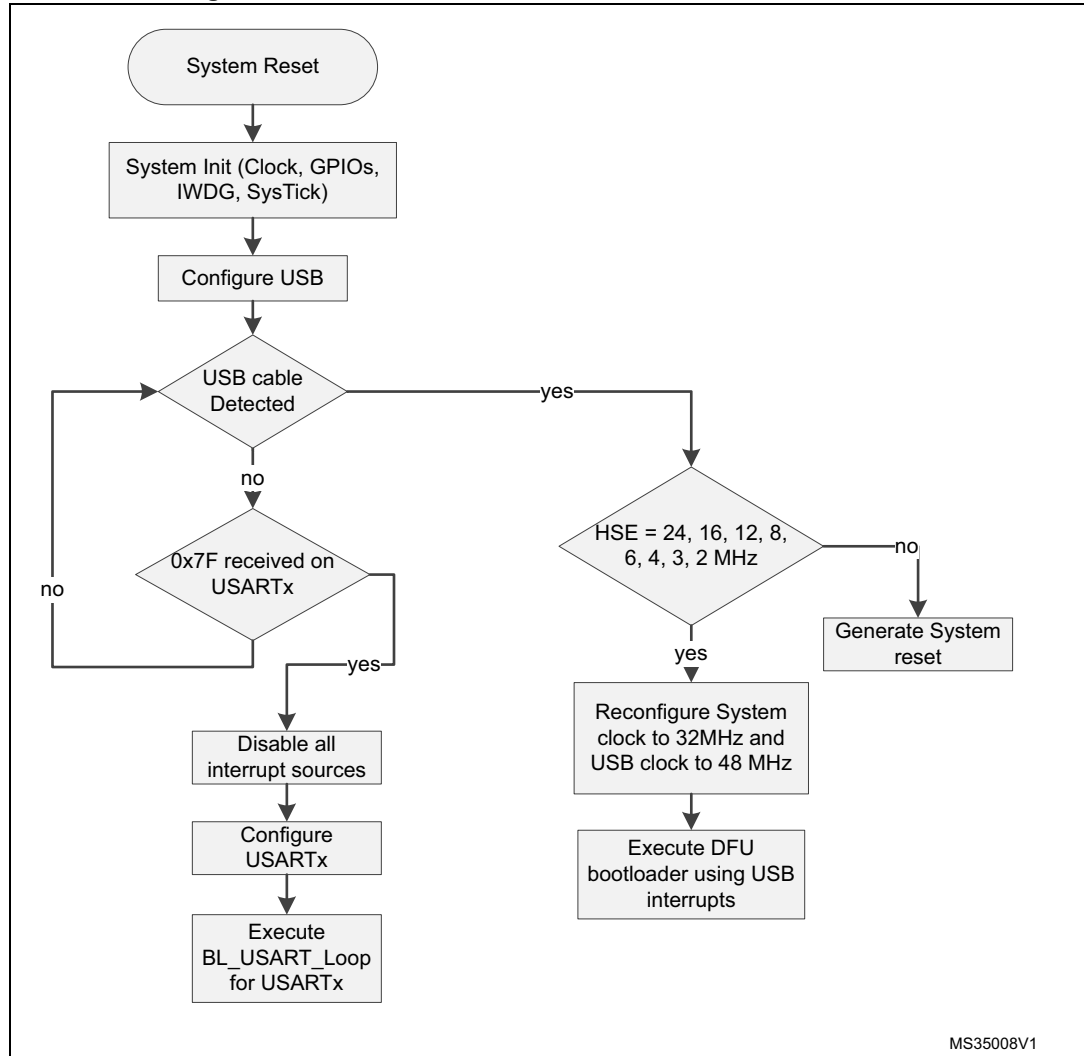
Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity and 1 stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for the USARTx bootloader.
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode.

The system clock is derived from the embedded internal high-speed RC for the USARTx bootloader. This internal clock is also used for the DFU bootloader, but only for the selection phase. An external clock in the range of [24, 16, 12, 8, 6, 4, 3, 2] MHz is required for the execution of the DFU bootloader after the selection phase.

60.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 75. Bootloader selection for STM32L1xxxC devices



60.3 Bootloader version

The following table lists the STM32L1xxxC devices bootloader versions.

Table 132. STM32L1xxxC bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	For the USART interface, two consecutive NACKs instead of 1 NACK are sent when a Read Memory or Write Memory command is sent and the RDP level is active. PA13/14/15 configured in alternate push-pull, pull (PA14 in pull-down) even if not used

61 STM32L1xxxD devices bootloader

61.1 Bootloader configuration

The STM32L1xxxD bootloader is activated by applying Pattern 4 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 133. STM32L1xxxD configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 16 MHz using the HSI. This is used only for USARTx bootloaders and during USB detection for DFU bootloader (once the DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for DFU bootloader and it must be in the following range: [24, 16, 12, 8, 6, 4, 3, 2] MHz. The PLL is used to generate the USB 48 MHz clock and the 32 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000 contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to Voltage Range 1.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 133. STM32L1xxxD configuration in system memory boot mode (continued)

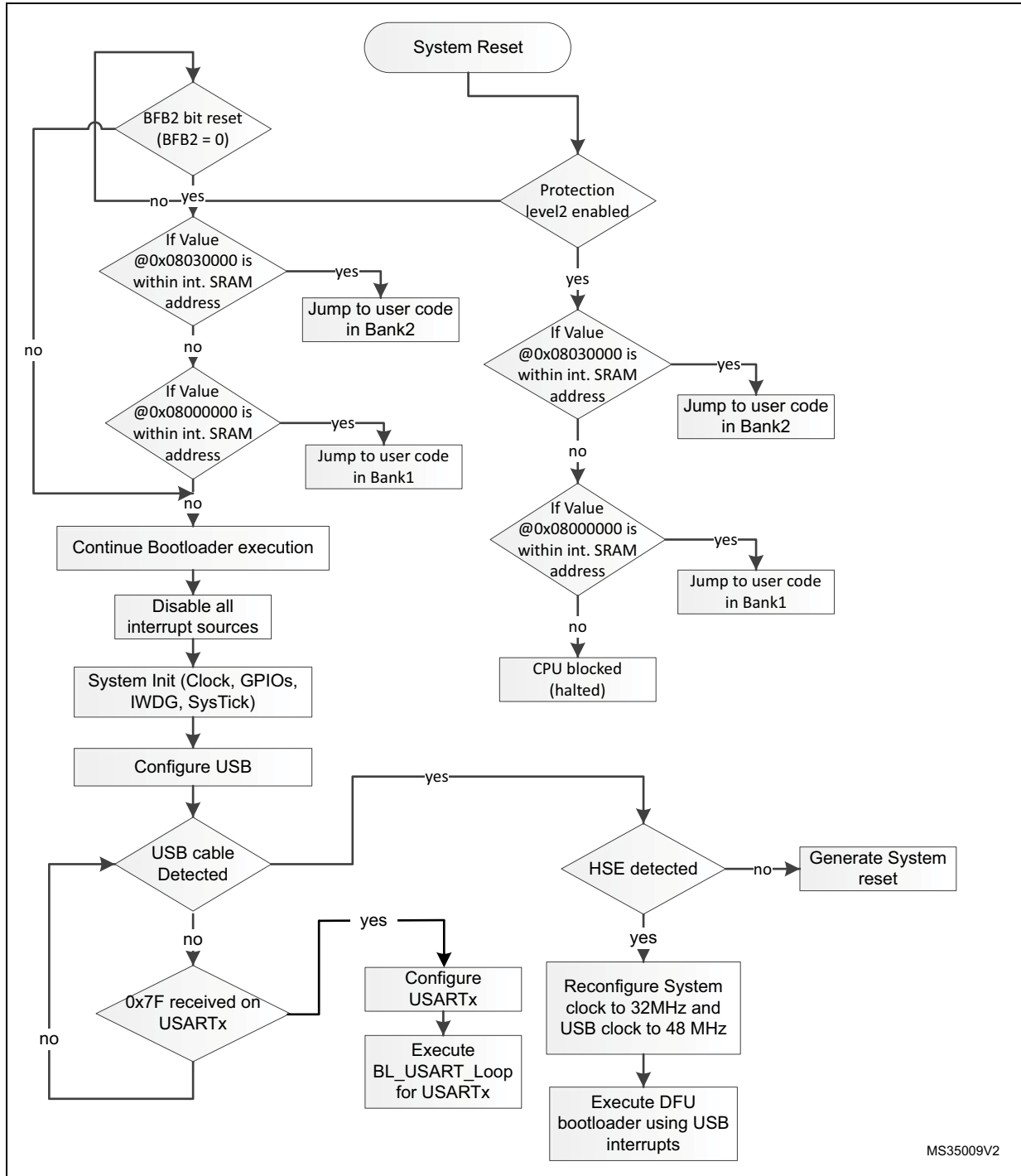
Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode.

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU bootloader, but only for the selection phase. An external clock in the range of [24, 16, 12, 8, 6, 4, 3, 2] MHz is required for DFU bootloader execution after the selection phase.

61.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 76. Bootloader selection for STM32L1xxxD devices



MS35009V2

61.3 Bootloader version

The following table lists the STM32L1xxxD devices bootloader versions:

Table 134. STM32L1xxxD bootloader versions

Version number	Description	Known limitations
V4.1	Initial bootloader version	<ul style="list-style-type: none"> – In the bootloader code the PA13 (JTMS/SWDIO) I/O output speed is configured to 400 kHz, as a consequence some debugger cannot connect to the device in Serial Wire mode when the bootloader is running. – When the DFU bootloader is selected, the RTC is reset and thus all RTC information (such as calendar, alarm) are lost including backup registers. Note: When the USART bootloader is selected there is no change on the RTC configuration (including backup registers).
V4.2	Fix V4.1 limitations (available on Rev.Z devices only)	<ul style="list-style-type: none"> – Stack overflow by 8 bytes when jumping to Bank1/Bank2 if BFB2=0 or when Read Protection level is set to 2. Workaround: the user code must force in the startup file the top of stack address before to jump to the main program. This can be done in the “Reset_Handler” routine. – When the Stack of the user code is placed outside the SRAM (i.e. @ 0x2000C000) the bootloader cannot jump to that user code which is considered invalid. This might happen when using compilers which place the stack at a non-physical address at the top of the SRAM (i.e. @ 0x2000C000). Workaround: place manually the stack at a physical address.
V4.5	Fix V4.2 limitations. DFU interface robustness enhancements (available on Rev.Y devices only).	<ul style="list-style-type: none"> – For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active.

62 STM32L1xxxE devices bootloader

62.1 Bootloader configuration

The STM32L1xxxE bootloader is activated by applying Pattern 4 (described in [Table 2](#)). The following table shows the hardware resources used by this bootloader.

Table 135. STM32L1xxxE configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 16 MHz using the HSI. This is used only for USARTx bootloaders and during USB detection for DFU bootloader (once the DFU bootloader is selected, the clock source is derived from the external crystal).
		HSE enabled	The external clock is mandatory only for DFU bootloader and it must be in the following range: [24, 16, 12, 8, 6, 4, 3, 2] MHz. The PLL is used to generate the USB 48 MHz clock and the 32 MHz clock for the system clock.
		-	The CSS interrupt is enabled for the DFU bootloader. Any failure (or removal) of the external clock generates system reset.
	RAM	-	4 Kbytes, starting from address 0x20000000 are used by the bootloader firmware.
	System memory	-	8 Kbytes, starting from address 0x1FF00000 contains the bootloader firmware.
	IWDG	-	The IWDG prescaler is configured to its maximum value and is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	Voltage range is set to Voltage Range 1.
USART1 bootloader	USART1	Enabled	Once initialized, the USART1 configuration is 8 bits, even parity, and one stop bit.
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 135. STM32L1xxxE configuration in system memory boot mode (continued)

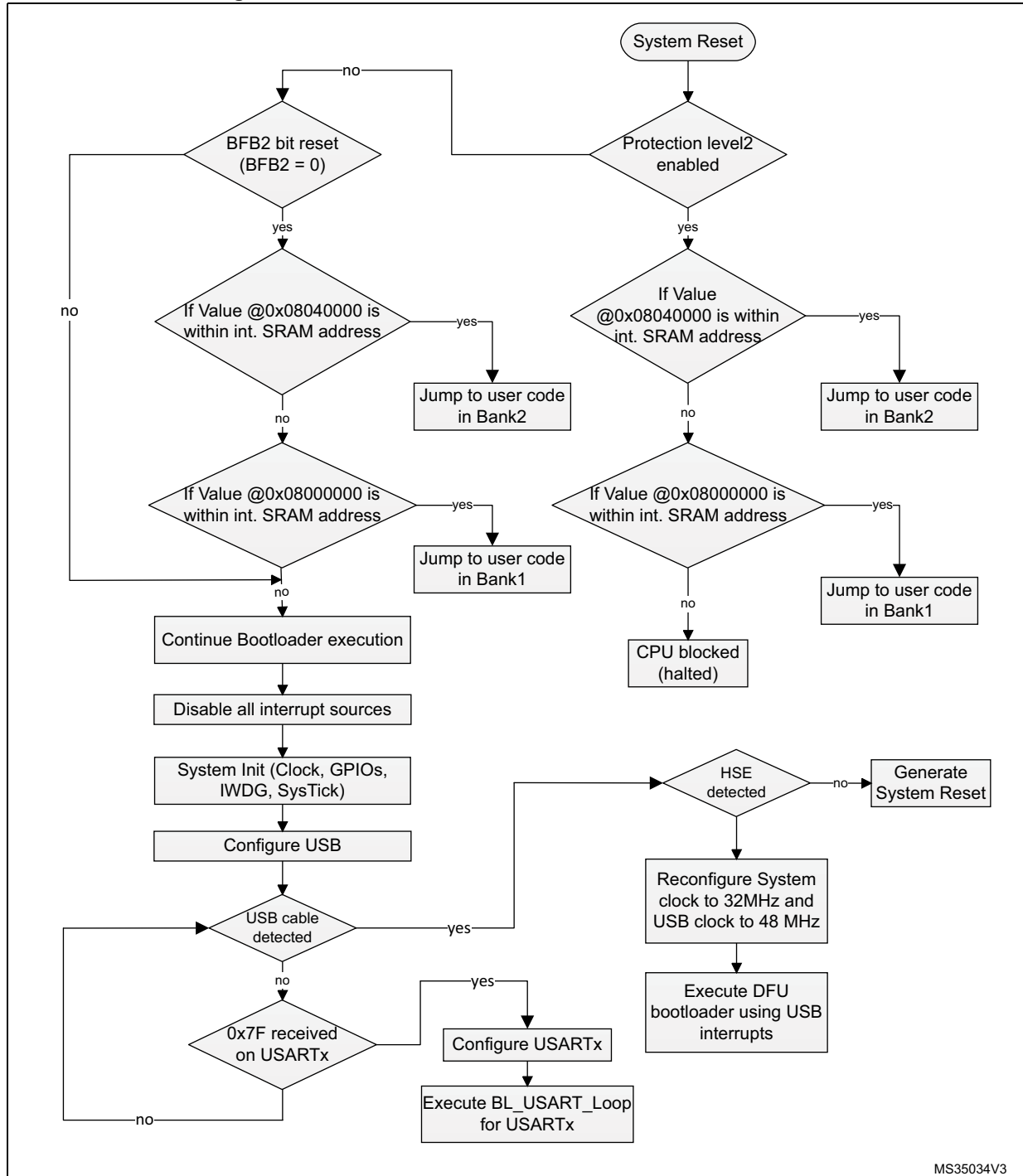
Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized, the USART2 configuration is 8 bits, even parity, and one stop bit. The USART2 uses its remapped pins.
	USART2_RX pin	Input	PD6 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PD5 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloader.
DFU bootloader	USB	Enabled	USB used in FS mode
	USB_DM pin	Input/output	PA11: USB DM line.
	USB_DP pin		PA12: USB DP line.

The system clock is derived from the embedded internal high-speed RC for USARTx bootloader. This internal clock is used also for DFU bootloader, but only for the selection phase. An external clock in the range of [24, 16, 12, 8, 6, 4, 3, 2] MHz is required for DFU bootloader execution after the selection phase.

62.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 77. Bootloader selection for STM32L1xxxE devices



MS35034V3

62.3 Bootloader version

[Table 136](#) lists the STM32L1xxxE devices bootloader versions:

Table 136. STM32L1xxxE bootloader versions

Version number	Description	Known limitations
V4.0	Initial bootloader version	For the USART interface, two consecutive NACKs (instead of 1 NACK) are sent when a Read Memory or Write Memory command is sent and the RDP level is active. PA13/14/15 configured in alternate push-pull, pull (PA14 in pull-down) even if not used.

63 STM32L412xx/422xx devices bootloader

63.1 Bootloader configuration

The STM32L412xx/422xx bootloader is activated by applying Pattern 16 (described in [Table 2](#)). [Table 137](#) shows the hardware resources used by this bootloader.

Table 137. STM32L412xx/422xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.

Table 137. STM32L412xx/422xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010010x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010010x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010010x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

Table 137. STM32L412xx/422xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode. ⁽¹⁾
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

1. SPI Tx (MISO) is handled by DMA. On the bootloader startup after SPI initialisation as soon as the bit DMATx enable on SPI CR2 register is set to 0x1, the MISO line will be set to 3.3 V.

Note: *If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product’s datasheet and errata sheet.*

63.2 Bootloader selection

The figures below show the bootloader selection mechanism.

Figure 78. Dual bank boot Implementation for STM32L412xx/422xx bootloader V9.x

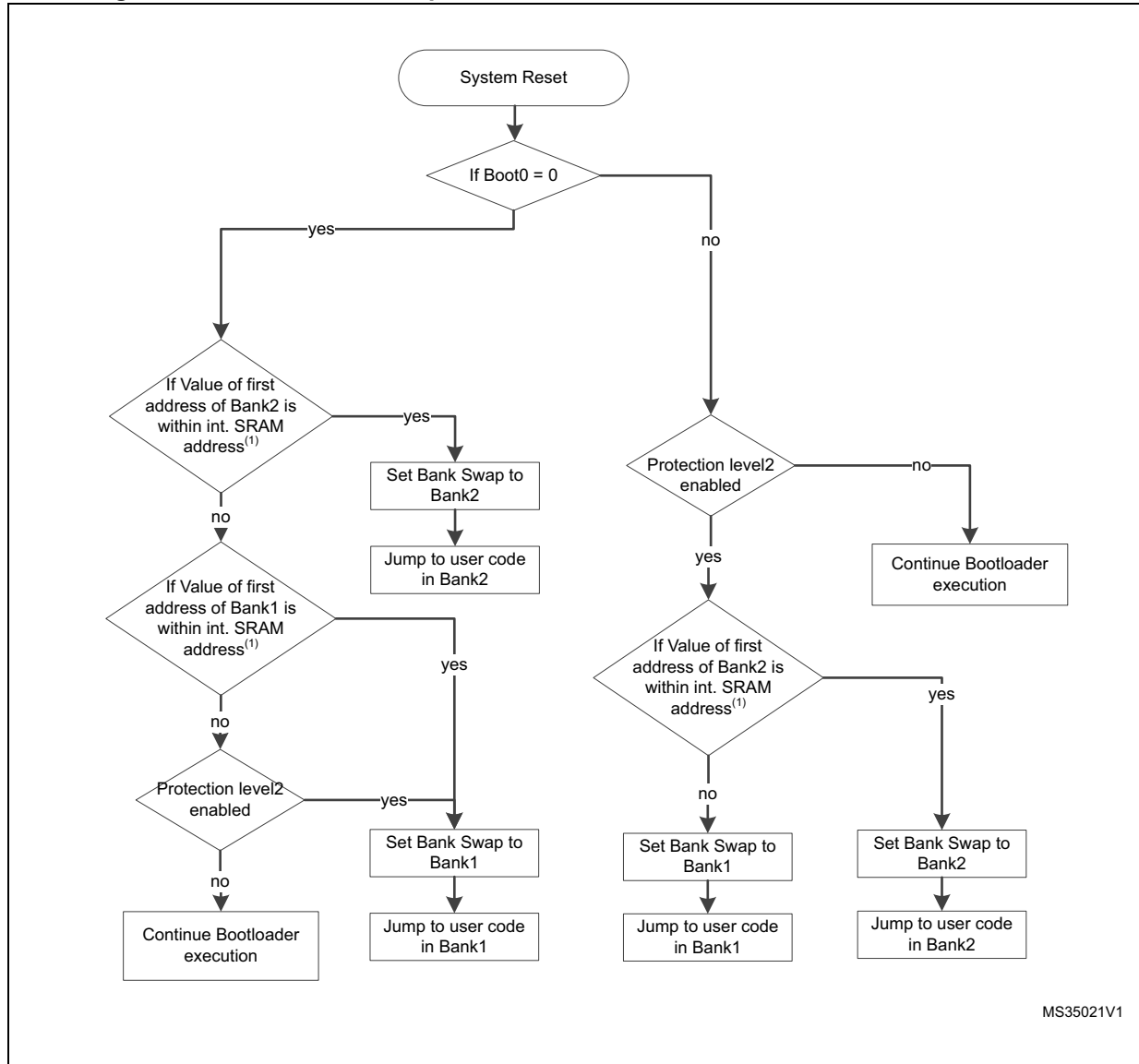
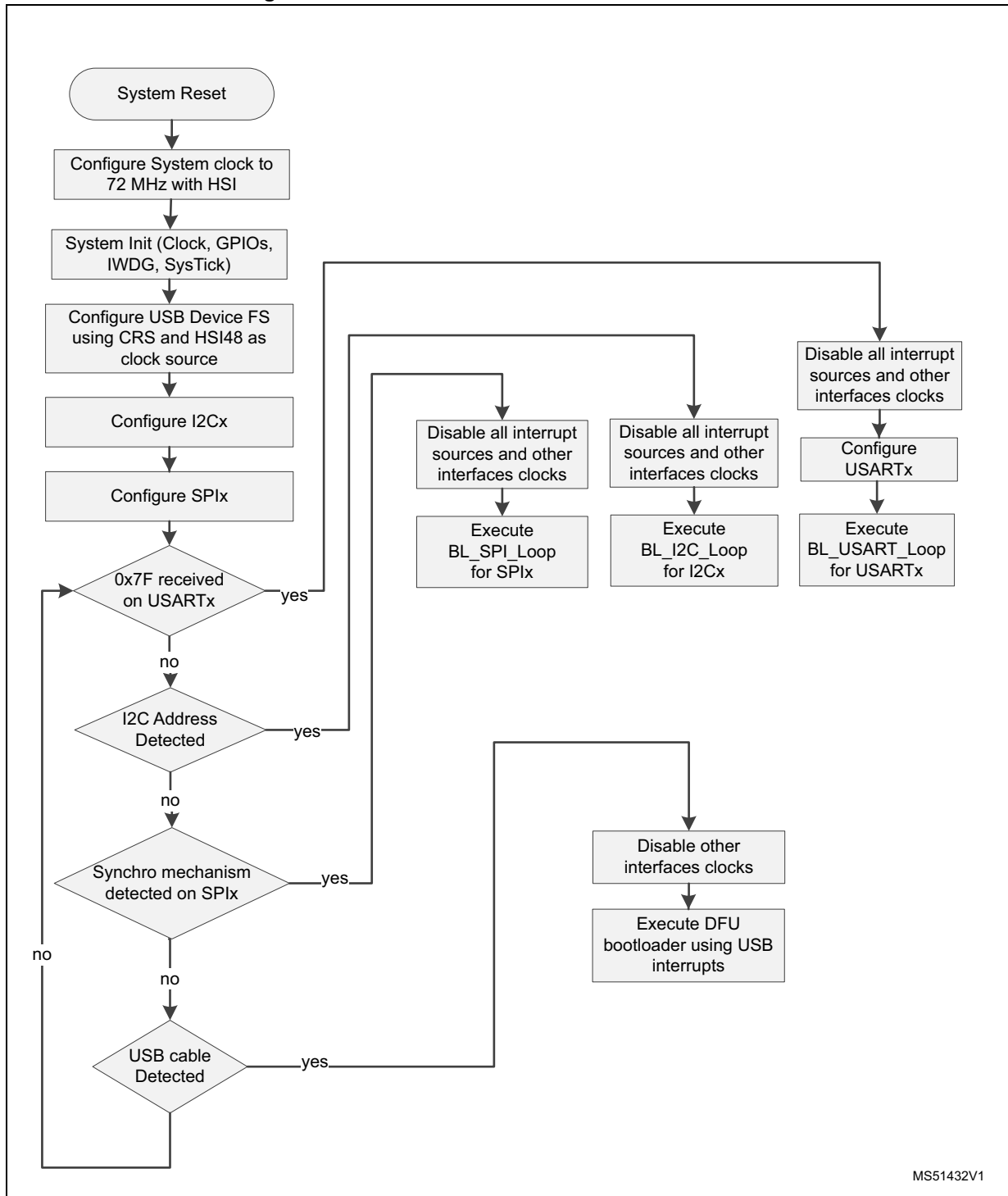


Figure 79.Bootloader V13.x selection for STM32L412xx/422xx



63.3 Bootloader version

[Table 138](#) lists the STM32L412xx/422xx devices bootloader version.

Table 138. STM32L412xx/422xx bootloader versions

Version number	Description	Known limitations
V13.1	Initial bootloader version	<ul style="list-style-type: none">– On connection phase, USART responds with two ACK bytes (0x79) instead of one.– PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using Half-Word access. Workaround: load a code snippet in SRAM using Bootloader interface, then jump to it, and that code writes PcROP value.

64 STM32L43xxx/44xxx devices bootloader

64.1 Bootloader configuration

The bootloader V9.1 version is updated to fix known limitations relative to USB-DFU interface, and is implemented on devices with version information ID equal to 0x10 (refer to [Table 140](#) for more details).

The STM32L43xxx/44xxx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 139](#) shows the hardware resources used by this bootloader.

Table 139. STM32L43xxx/44xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values [24,20,18,16,12,9,8,6,4] MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.	
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 139. STM32L43xxx/44xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001000x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001000x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001000x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 139. STM32L43xxx/44xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
CAN1 bootloader	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 139. STM32L43xxx/44xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Note: If VDDUSB pin is not connected to V_{DD} , SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.

64.2 Bootloader selection

The following figures show the bootloader selection mechanism.

Figure 80. Dual bank boot Implementation for STM32L3x2xx/44xxx bootloader V9.x

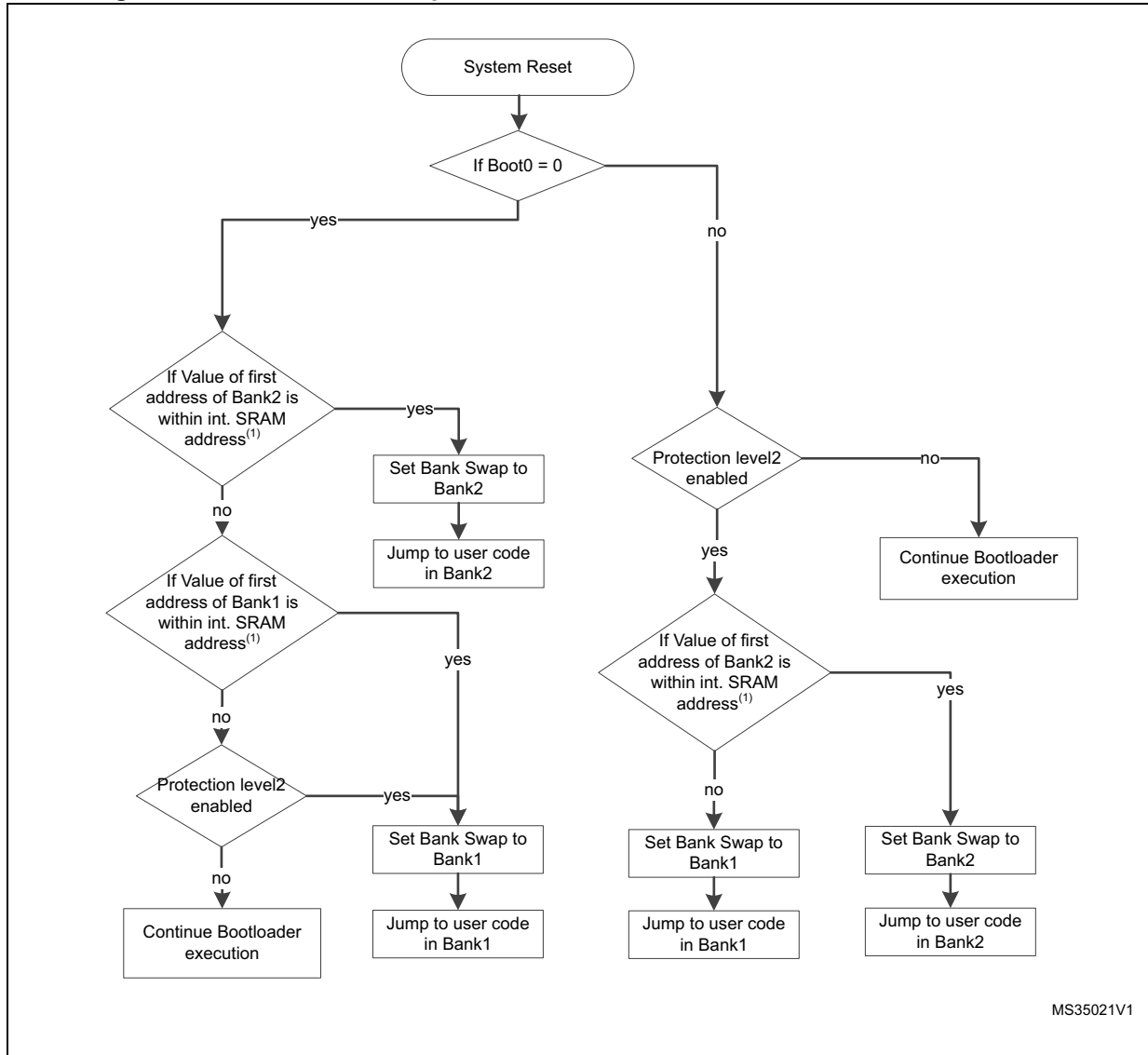
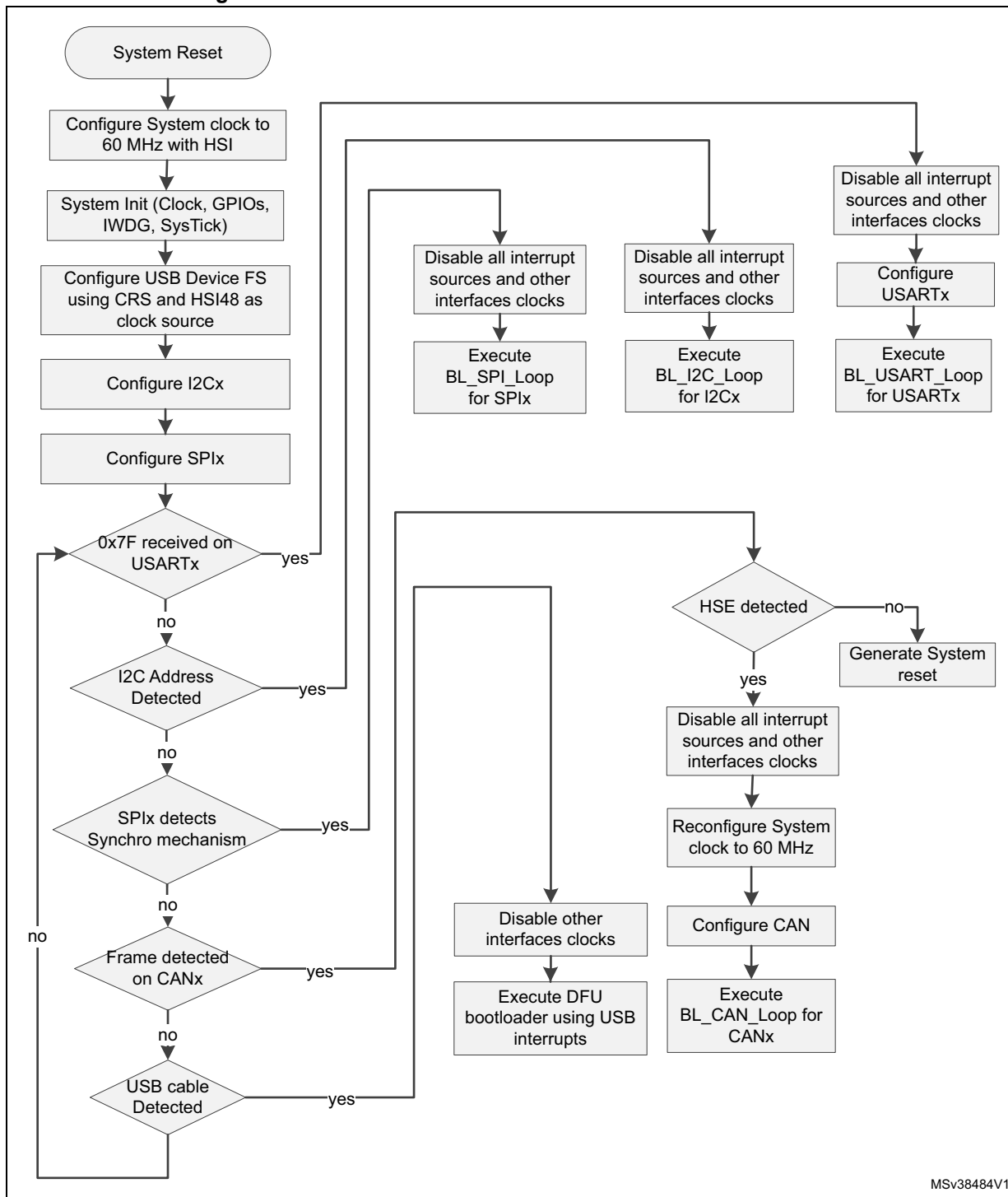


Figure 81. Bootloader V9.x selection for STM32L43xxx/44xxx



MSv38484V1

64.3 Bootloader version

Table 140 lists the STM32L43xxx/44xxx devices bootloader versions.

Table 140. STM32L43xxx/44xxx bootloader versions

Version number	Description	Known limitations
V9.1	Initial bootloader version	<p>Check the Version Information ID of your STM32L43xxx/44xxx device, which can be read at 0x1FFF6FF2 address.</p> <p>Version Information ID equal to 0xFF:</p> <ul style="list-style-type: none"> – For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. – For the USB-DFU interface, the CRS (clock recovery system) is not correctly configured and this may lead to random USB communication errors (depending on temperature and voltage). In most case communication error will manifest by a "Stall" response to setup packets. – On the "Go" command, system bootloader de-init clears the RTCAPBEN bit in the RCC_APB1ENR register Workaround: manually call <code>__HAL_RCC_RTC_CLK_ENABLE()</code> in the software which sets the RTCAPBEN bit. <p>Version Information ID equal to 0x10: None</p> <ul style="list-style-type: none"> – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using Half-Word access. Workaround: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value.

Table 140. STM32L43xxx/44xxx bootloader versions (continued)

Version number	Description	Known limitations
V9.1 (continued)	Initial bootloader version (continued)	<ul style="list-style-type: none"> - SPI write operation fail Limitation: <ul style="list-style-type: none"> a. During bootloader SPI write flash memory operation, some random 64-bits (2 double-words) may be left blank at 0xFF. <p>Root cause:</p> <ul style="list-style-type: none"> a. Bootloader uses 64-bits cast write operation which is interrupted by SPI DMA and it leads to double access on same flash memory address and the 64-bits are not written. <p>Workarounds:</p> <ul style="list-style-type: none"> a. WA1: add a delay between sending write command and its ACK request. Its duration must be the duration of the 256-Bytes flash memory write time. b. WA2: read back after write and in case of error start write again. c. WA3: Patch in RAM to write in flash memory that implements write memory without 64-bits cast. WA1 and WA3 are more efficient than WA2 in terms of total programming time. <p>How critical is the limitation:</p> <ul style="list-style-type: none"> a. The limitation leads to a modification in customer SPI host software by adding 3-4 ms delay to each write operation. b. The delay is not waste because it is anyway the flash memory write period of time that host has to wait anyway (so instead of waiting by sending ACK requests, host will wait by delay). c. Limitation has been seen only on SPI and cannot impact USART/I2C/CAN - If the RTC is used by application prior to booting (through a system reset) on system bootloader, it is possible that CAN interface does not work correctly (cannot establish connection) unless a power cycle is performed or RTC is reset by application before booting on System Bootloader

65 STM32L45xxx/46xxx devices bootloader

65.1 Bootloader configuration

The STM32L45xxx/46xxx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 141](#) shows the hardware resources used by this bootloader.

Table 141. STM32L45xxx/46xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI48 48 MHz.
		HSE enabled	The system clock frequency is 60 MHz. The HSE is used only when the CAN interface is selected. The HSE must have one of the following values [24,20,18,16,12,9,8,6,4] MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.	
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 141. STM32L45xxx/46xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001010x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001010x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001010x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 141. STM32L45xxx/46xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
CAN1 bootloader	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 141. STM32L45xxx/46xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Note: If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.

65.2 Bootloader selection

The following figures show the bootloader selection mechanism.

Figure 82. Dual bank boot implementation for STM32L45xxx/46xxx bootloader V9.x

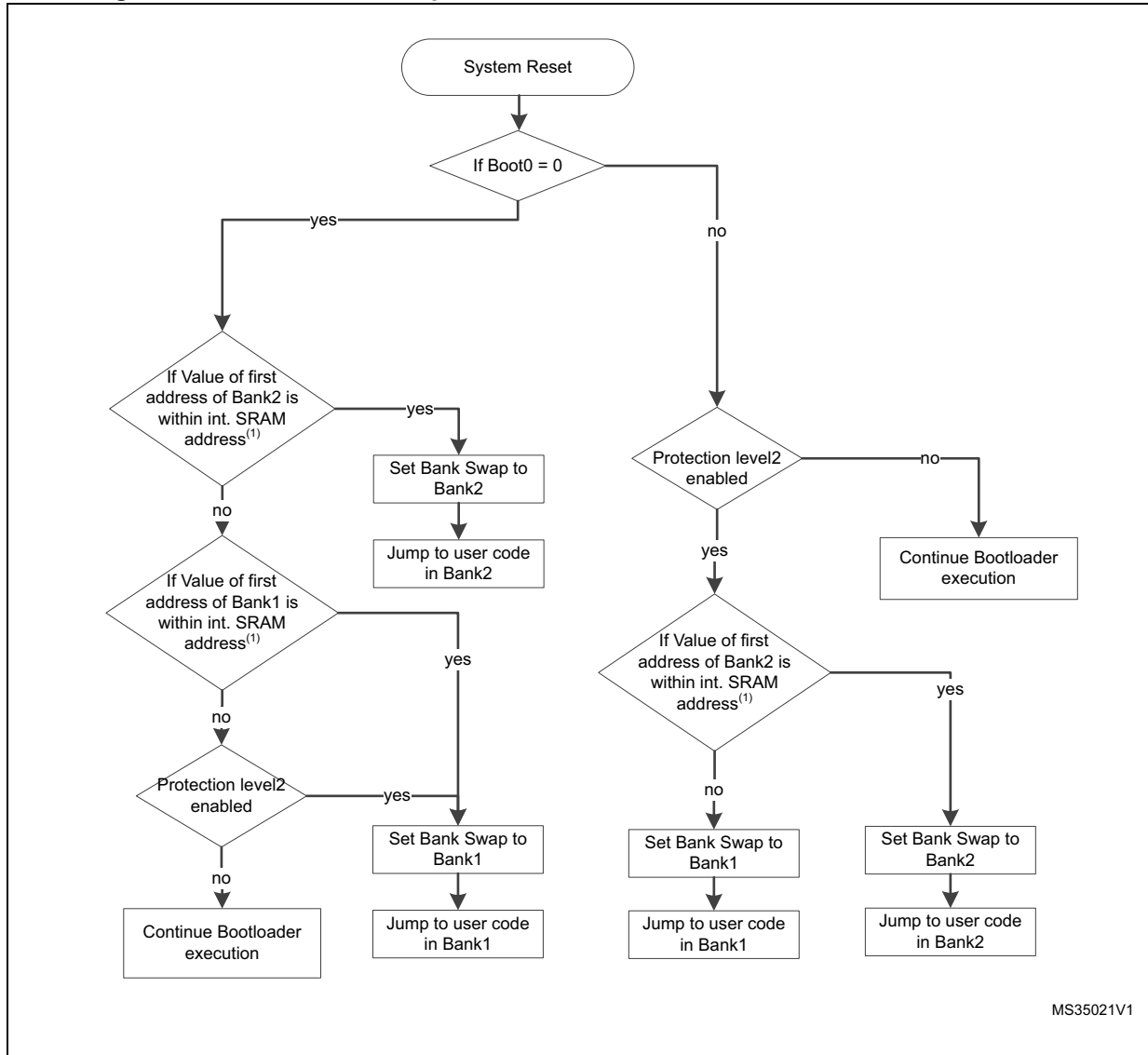
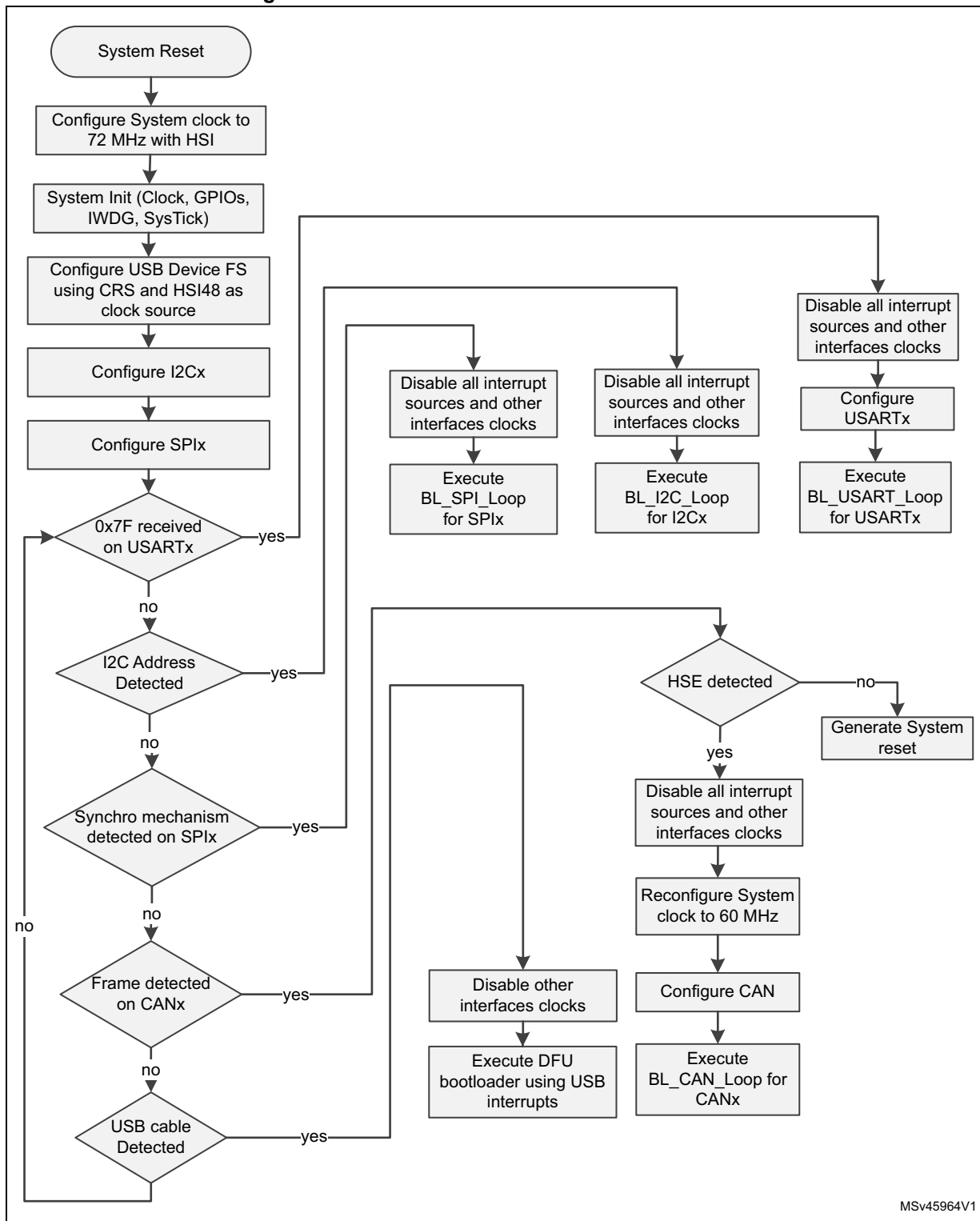


Figure 83.Bootloader V9.x selection for STM32L45xxx/46xxx



MSv45964V1

65.3 Bootloader version

Table 142 lists the STM32L45xxx/46xxx devices bootloader versions.

Table 142. STM32L45xxx/46xxx bootloader versions

Version number	Description	Known limitations
V9.2	Initial bootloader version	<ul style="list-style-type: none"> - PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using Half-Word access. Workaround: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value. - SPI write operation fail limitation: <ul style="list-style-type: none"> a. During Bootloader SPI write flash memory operation, some random 64-bits (2 double-words) may be left blank at 0xFF. Root cause: <ul style="list-style-type: none"> a. Bootloader uses 64-bits cast write operation which is interrupted by SPI DMA and it leads to double access on same flash memory address and the 64-bits are not written Workarounds: <ul style="list-style-type: none"> a. WA1: add a delay between sending write command and its ACK request. Its duration must be the duration of the 256-Bytes flash memory write time. b. WA2: read back after write and in case of error start write again. c. WA3: Patch in RAM to write in flash memory that implements write memory without 64-bits cast. WA1 and WA3 are more efficient than WA2 in terms of total programming time How critical is the limitation: <ul style="list-style-type: none"> a. The limitation leads to a modification in customer SPI host software by adding 3-4 ms delay to each write operation. b. The delay is not waste because it is anyway the flash memory write period of time that host has to wait anyway (so instead of waiting by sending ACK requests, host will wait by delay). c. Limitation has been seen only on SPI and cannot impact USART/I2C/CAN.

66 STM32L47xxx/48xxx devices bootloader

Two bootloader versions are available on STM32L47xxx/48xxx:

- V10.x supporting USART, I2C and DFU (USB FS device).
This version is embedded in STM32L47xxx/48xxx rev. 2 and rev. 3 devices.
- V9.x supporting USART, I2C, SPI, CAN and DFU (USB FS device).
This version is embedded in STM32L47xxx/48xxx rev. 4 devices.

66.1 Bootloader V10.x

66.1.1 Bootloader configuration

The STM32L47xxx/48xxx bootloader is activated by applying Pattern 7 (described in [Table 2](#)). [Table 143](#) shows the hardware resources used by this bootloader.

Table 143. STM32L47xxx/48xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 24 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the USB interface is selected and the LSE is not present. The HSE must have one of the following values: 24,20,18,16,12,9,8,6,4 MHz.
		LSE enabled	The LSE is used to trim the MSI which is configured to 48 MHz as USB clock source. The LSE must be equal to 32,768 kHz. If the LSE is not detected, the HSE is used instead if USB is connected.
		MSI enabled	The MSI is configured to 48 MHz and is used as USB clock source. The MSI is used only if LSE is detected, otherwise, HSE is used if USB is connected.
		-	The CSS interrupt is enabled when LSE or HSE is enabled. Any failure (or removal) of the external clock generates system reset.
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.

Table 143. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000011x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000011x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address is 0b1000011x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 143. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required
	TIM17	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 24 MHz using PLL and HSE.

For USARTx and I2Cx bootloaders no external clock is required.

USB bootloader (DFU) requires either an LSE (low-speed external clock) or a HSE (high-speed external clock):

- In case, the LSE is present regardless the HSE presence, the MSI is configured and trimmed by the LSE to provide an accurate clock equal to 48 MHz, which is the clock source of the USB. The system clock is kept clocked to 24 MHz by the HSI.
- In case, the HSE is present, the system clock and USB clock is configured respectively to 24 MHz and 48 MHz with HSE as clock source.

66.1.2 Bootloader selection

Figure 84 and Figure 85 show the bootloader selection mechanism.

Figure 84. Dual bank boot implementation for STM32L47xxx/48xxx bootloader V10.x

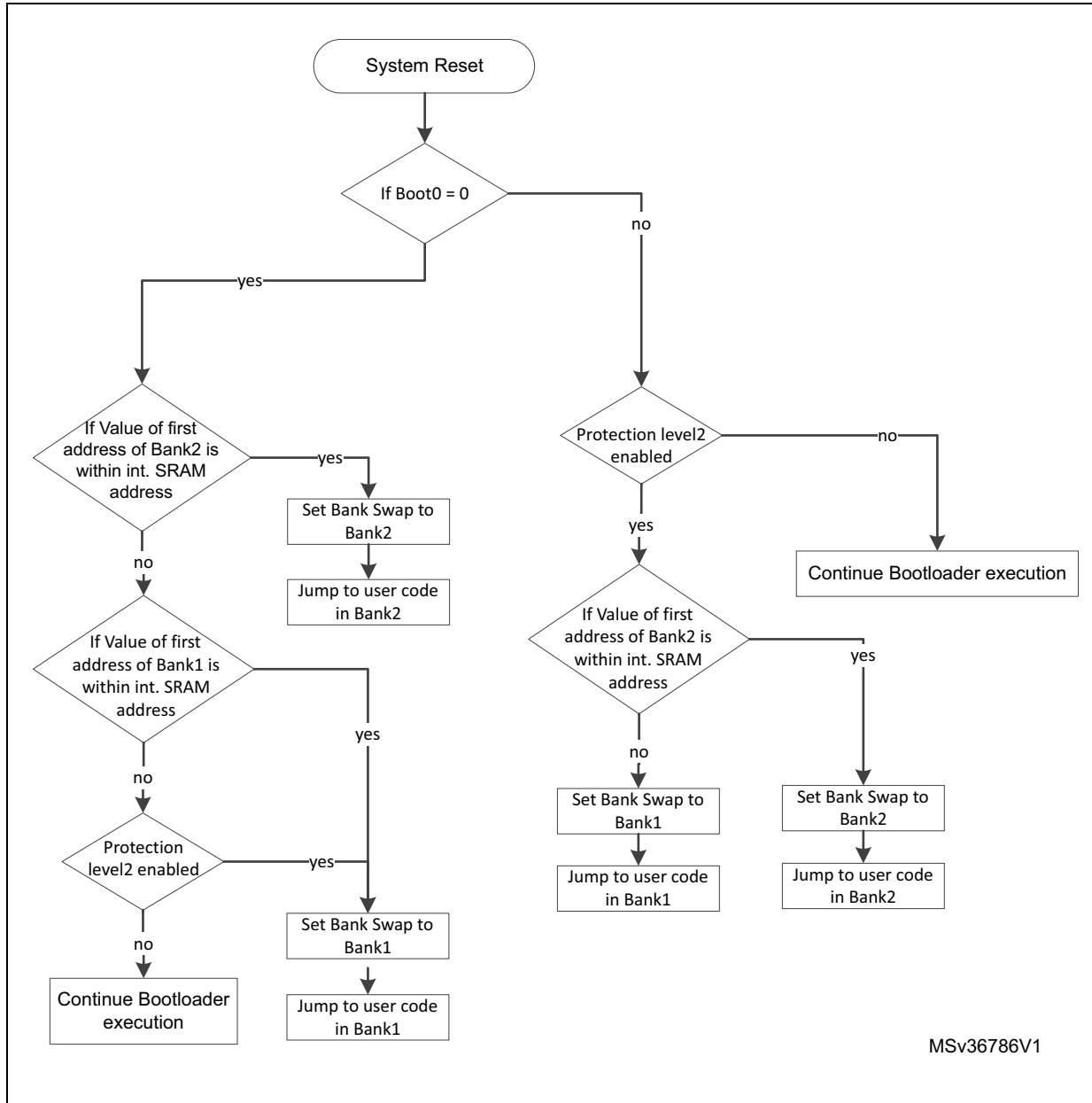
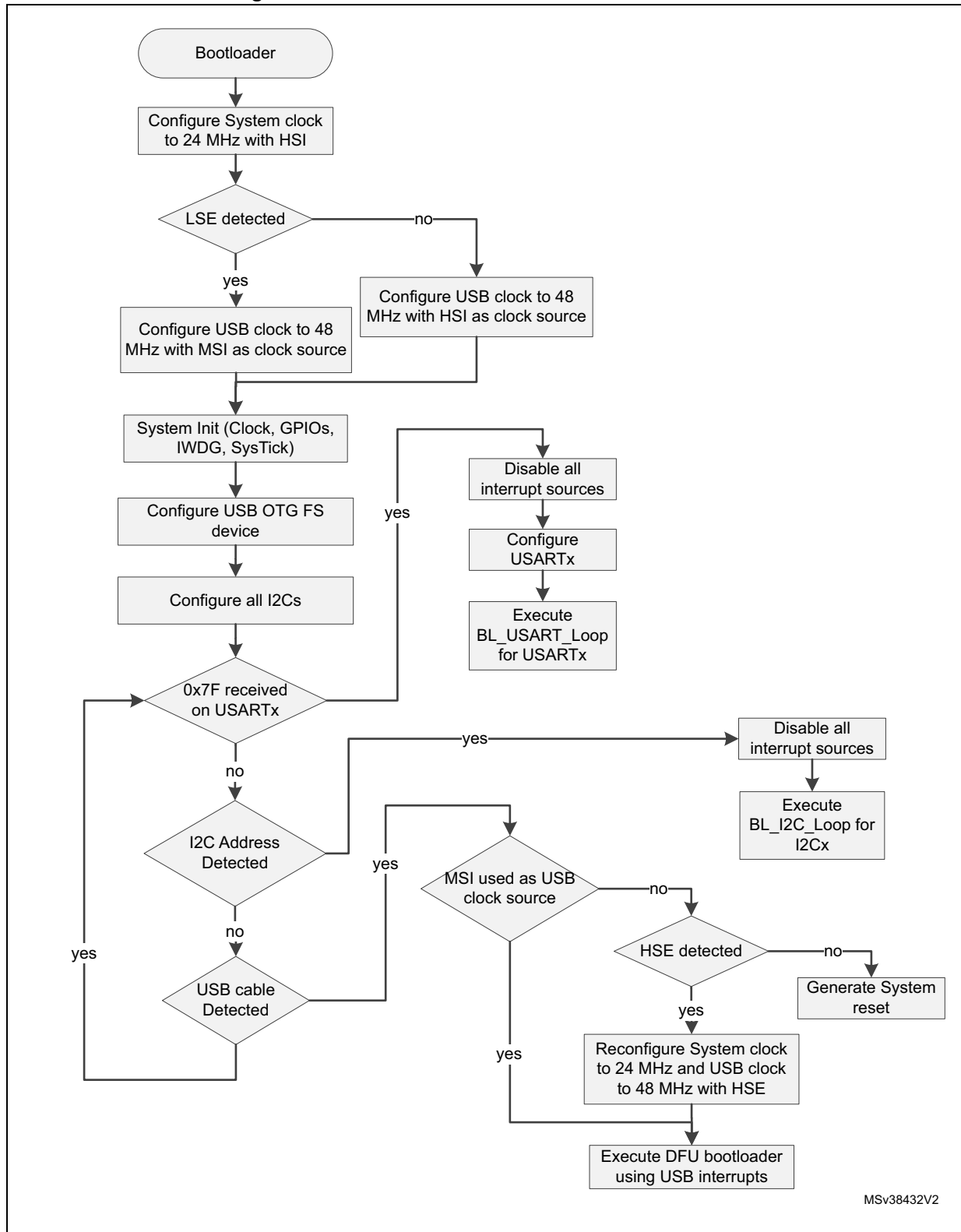


Figure 85.Bootloader V10.x selection for STM32L47xxx/48xxx



MSv38432V2

66.1.3 Bootloader version

Table 144 lists the STM32L47xxx/48xxx devices bootloader V10.x versions:

Table 144. STM32L47xxx/48xxx bootloader V10.x versions

Version number	Description	Known limitations
V10.1	Initial bootloader version	For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. Write in SRAM is corrupted.
V10.2	Fix write in SRAM issue	For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size.
V10.3	Add support of MSI as USB clock source (MSI is trimmed by LSE). Update dual bank boot feature to support the case when user stack is mapped in SRAM2.	<ul style="list-style-type: none"> – For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using Half-Word access. Workaround: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value.

66.2 Bootloader V9.x

66.2.1 Bootloader configuration

The STM32L47xxx/48xxx bootloader is activated by applying Pattern 7 (described in [Table 2](#)). [Table 145](#) shows the hardware resources used by this bootloader.

Table 145. STM32L47xxx/48xxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART and I2C bootloader operation.
		HSE enabled	The HSE is used only when the USB interface is selected and the LSE is not present. The HSE must have one of the following values: 24,20,18,16,12,8,6,4 MHz. System is clocked at 72 MHz if USB is used or 60 MHz if CAN is used.
		LSE enabled	The LSE is used to trim the MSI which is configured to 48 MHz as USB clock source. The LSE must be equal to 32,768 kHz. If the LSE is not detected, the HSE is used instead if USB is connected.
		MSI enabled	The MSI is configured to 48 MHz and is used as USB clock source. The MSI is used only if LSE is detected, otherwise, HSE is used if USB is connected.
		CSS	The CSS interrupt is enabled when LSE or HSE is enabled. Any failure (or removal) of the external clock generates system reset.
	RAM	-	13 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
	Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART2 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART2 in transmission mode. Used in input no pull mode.

Table 145. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000011x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000011x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 400 kHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1000011x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 145. STM32L47xxx/48xxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: Slave mode, Full Duplex, 8-bit MSB, Speed up to 8 MHz, Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.
CAN1 bootloader	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11-bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11 pin: USB FS DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12 pin: USB FS DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required.

In case, the HSE is present, the system clock and USB clock is configured respectively to 72 MHz and 48 MHz with PLL (clocked by HSE) as a clock source.

Note: *If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product's datasheet and errata sheet.*

66.2.2 Bootloader selection

Figure 86 and Figure 87 show the bootloader selection mechanism.

Figure 86. Dual bank boot implementation for STM32L47xxx/48xxx bootloader V9.x

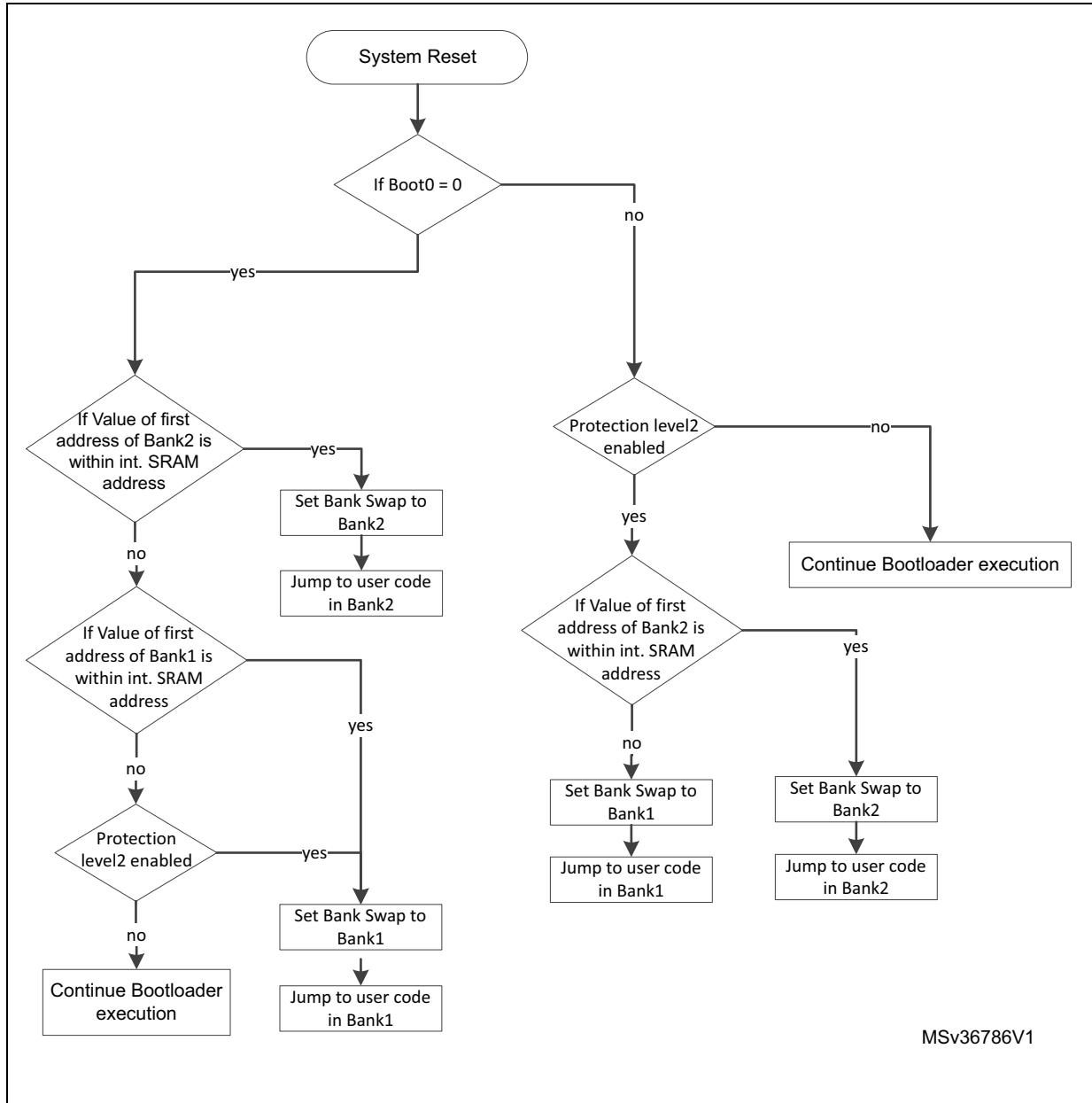
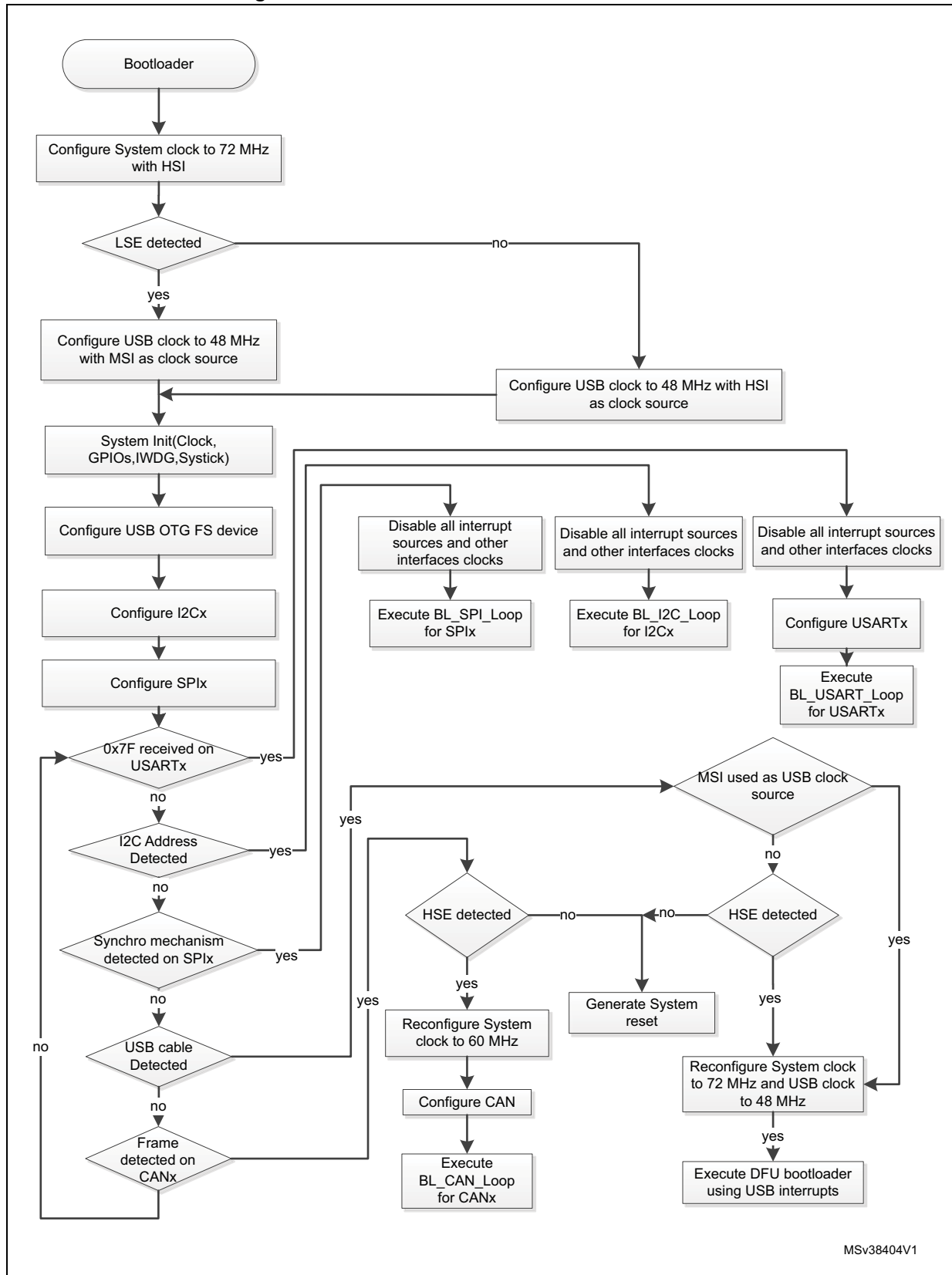


Figure 87.Bootloader V9.x selection for STM32L47xxx/48xxx



MSv38404V1

66.2.3 Bootloader version

Table 146 lists the STM32L47xxx/48xxx devices bootloader V9.x versions:

Table 146. STM32L47xxx/48xxx bootloader V9.x versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. Write in SRAM is corrupted
V9.1	Deprecated version (not used)	None
V9.2	Fix write in SRAM issue	<ul style="list-style-type: none"> – For memory write operations using DFU interface: If the buffer size is larger than 256 bytes and not multiple of 8 bytes, the write memory operation result is corrupted. Workaround: if the file size is larger than 256 bytes, add byte padding to align it on 8-bytes multiple size. – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using Half-Word access. Workaround: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value.

67 STM32L496xx/4A6xx devices bootloader

67.1 Bootloader configuration

The STM32L496xx/4A6xx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 147](#) shows the hardware resources used by this bootloader.

Table 147. STM32L496xx/4A6xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 72 MHz and for USART, I2C and SPI bootloader operation.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values: 24,20,18,16,12,9,8,6,4 MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	12 Kbytes, starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes, starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	The DFU cannot be used to communicate with bootloader if voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.	
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input no pull mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input no pull mode.

Table 147. STM32L496xx/4A6xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input no pull mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input no pull mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1001100x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1001100x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1001100x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 147. STM32L496xx/4A6xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
CAN1 bootloader	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11-bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 147. STM32L496xx/4A6xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB OTG FS configured in forced device mode. USB OTG FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

Note: If VDDUSB pin is not connected to V_{DD}, SPI flash memory write operations may be corrupted due to voltage issue. For more details, refer to product’s datasheet and errata sheet.

67.2 Bootloader selection

The figures below show the bootloader selection mechanism.

Figure 88. Dual bank boot Implementation for STM32L496xx/4A6xx bootloader V9.x

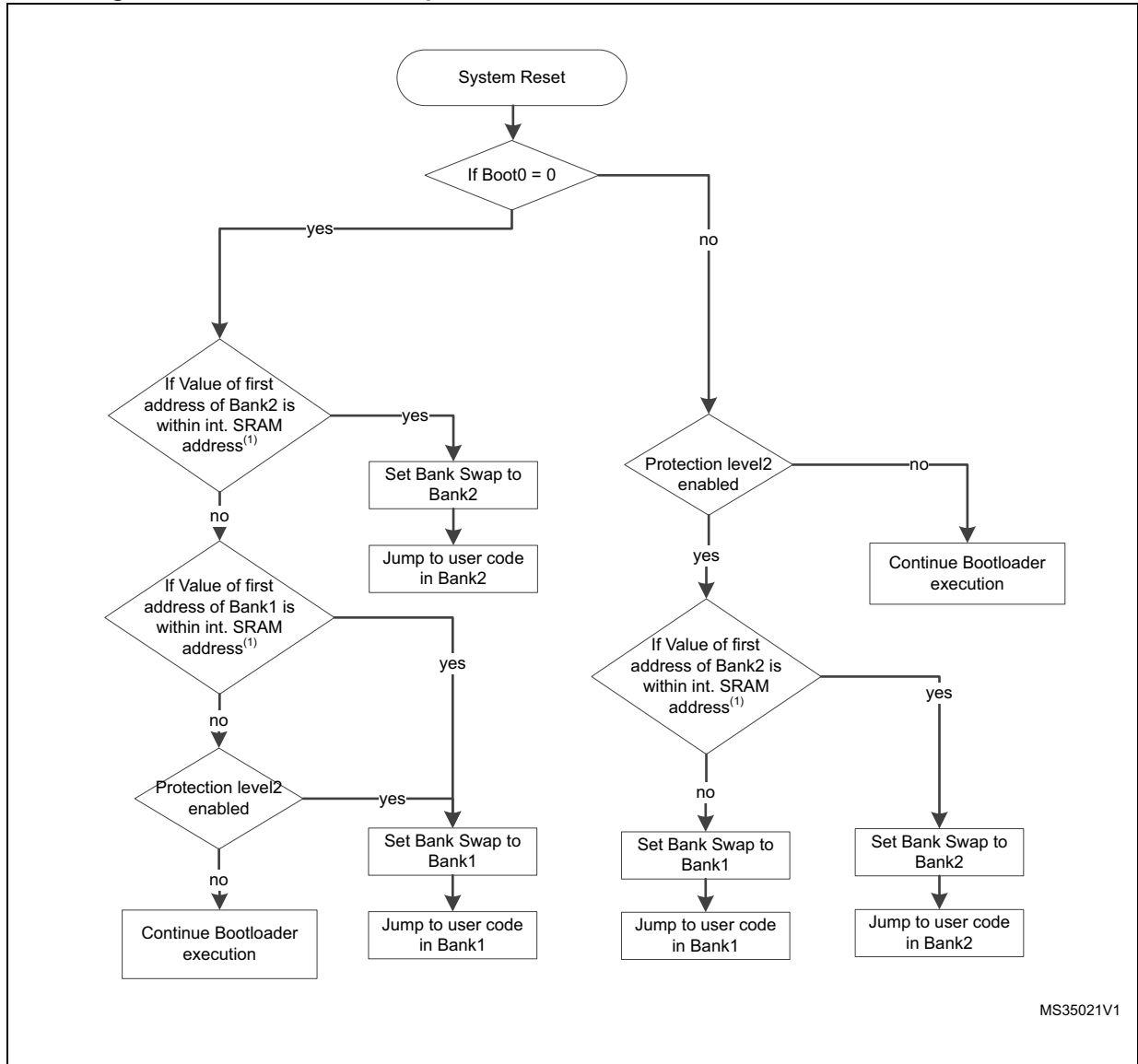
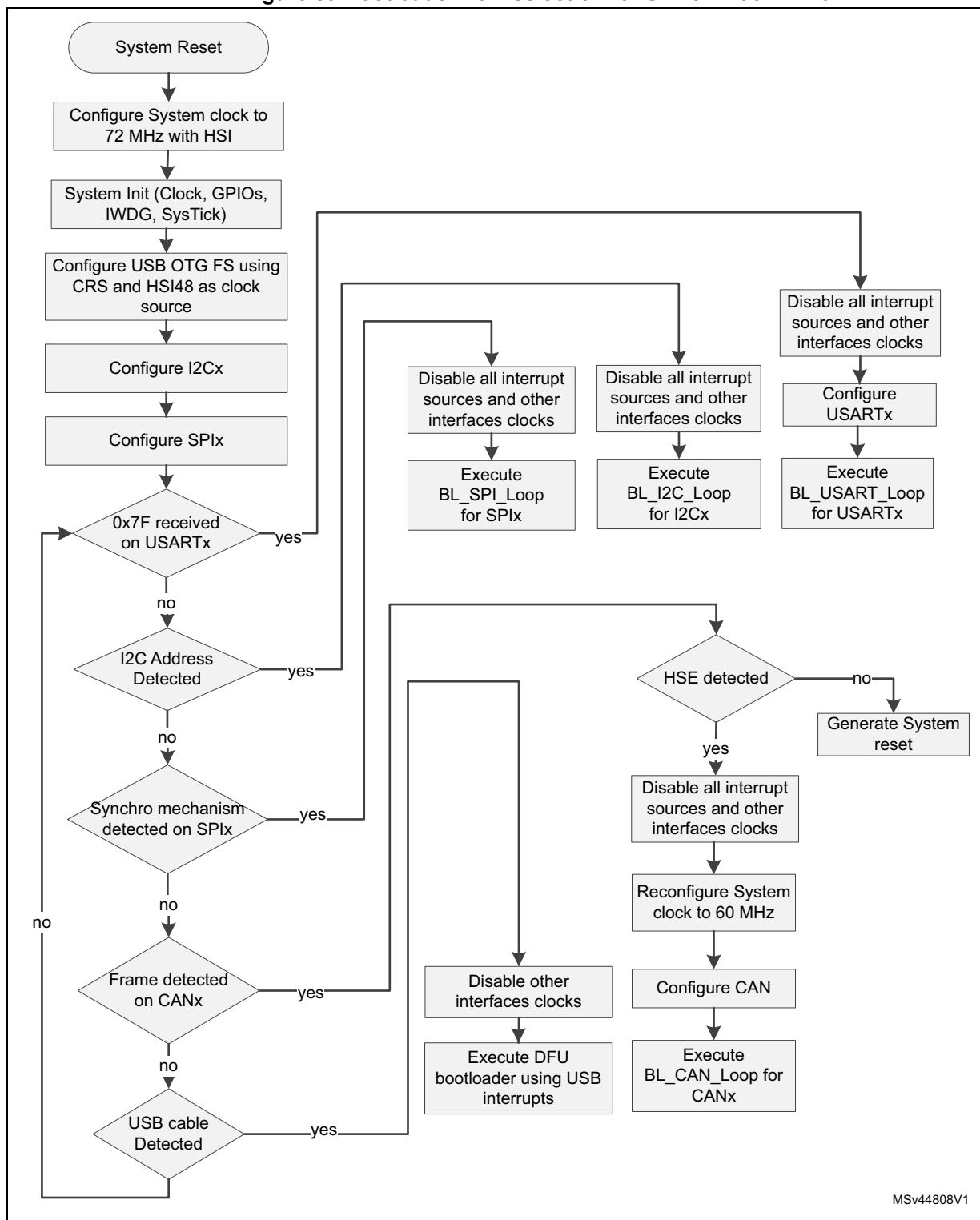


Figure 89.Bootloader V9.x selection for STM32L496xx/4A6xx



67.3 Bootloader version

Table 148 lists the STM32L496xx/4A6xx devices bootloader versions.

Table 148. STM32L496xx/4A6xx bootloader version

Version number	Description	Known limitations
V9.3	Initial bootloader version	<ul style="list-style-type: none"> – The Bank Erase command is aborted by the bootloader device, and the NACK (0x1F) is sent to the host. Workaround: Perform Bank erase operation through page erase using the Erase command (0x44). – SPI write operation fail <p>Limitation:</p> <ul style="list-style-type: none"> a. During Bootloader SPI write flash memory operation, some random 64-bits (2 double-words) may be left blank at 0xFF. <p>Root cause:</p> <ul style="list-style-type: none"> a. Bootloader uses 64-bits cast write operation which is interrupted by SPI DMA and it leads to double access on same flash memory address and the 64-bits are not written <p>Workarounds:</p> <ul style="list-style-type: none"> a. WA1: add a delay between sending write command and its ACK request. Its duration must be the duration of the 256-Bytes flash memory write time. b. WA2: read back after write and in case of error start write again. c. WA3: Patch in RAM to write in flash memory that implements write memory without 64-bits cast. <p>WA1 and WA3 are more efficient than WA2 in terms of total programming time</p> <p>How critical is the limitation:</p> <ul style="list-style-type: none"> a. The limitation leads to a modification in customer SPI host software by adding 3-4 ms delay to each write operation. b. The delay is not waste because it is anyway the flash memory write period of time that host has to wait anyway (so instead of waiting by sending ACK requests, host will wait by delay). c. Limitation has been seen only on SPI and cannot impact USART/I2C/CAN. <ul style="list-style-type: none"> – PcROP option bytes cannot be written as Bootloader uses Byte access while PcROP must be accessed using Half-Word access. <p>Workaround: load a code snippet in SRAM using Bootloader interface then jump to it, and that code writes the PcROP value.</p>

68 STM32L4P5xx/4Q5xx devices bootloader

68.1 Bootloader configuration

The STM32L4P5xx/4Q5xx bootloader is activated by applying Pattern 7 (described in [Table 2](#)). [Table 151](#) shows the hardware resources used by this bootloader.

Table 149. STM32L4P5xx/4Q5xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values 24,20,18,16,12,9,8,6,4 MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.	
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.

Table 149. STM32L4P5xx/4Q5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011011x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011011x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1011011x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 149. STM32L4P5xx/4Q5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
CAN1 bootloader	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 149. STM32L4P5xx/4Q5xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in alternate push-pull, no pull mode.
	USB_DP pin		PA12: USB DP line. Used in alternate push-pull, no pull mode. No external pull-up resistor is required

68.2 Bootloader selection

Figure 92 and Figure 93 show the bootloader selection mechanisms.

Figure 90. Dual bank boot implementation for STM32L4P5xx/4Q5xx bootloader V9.x

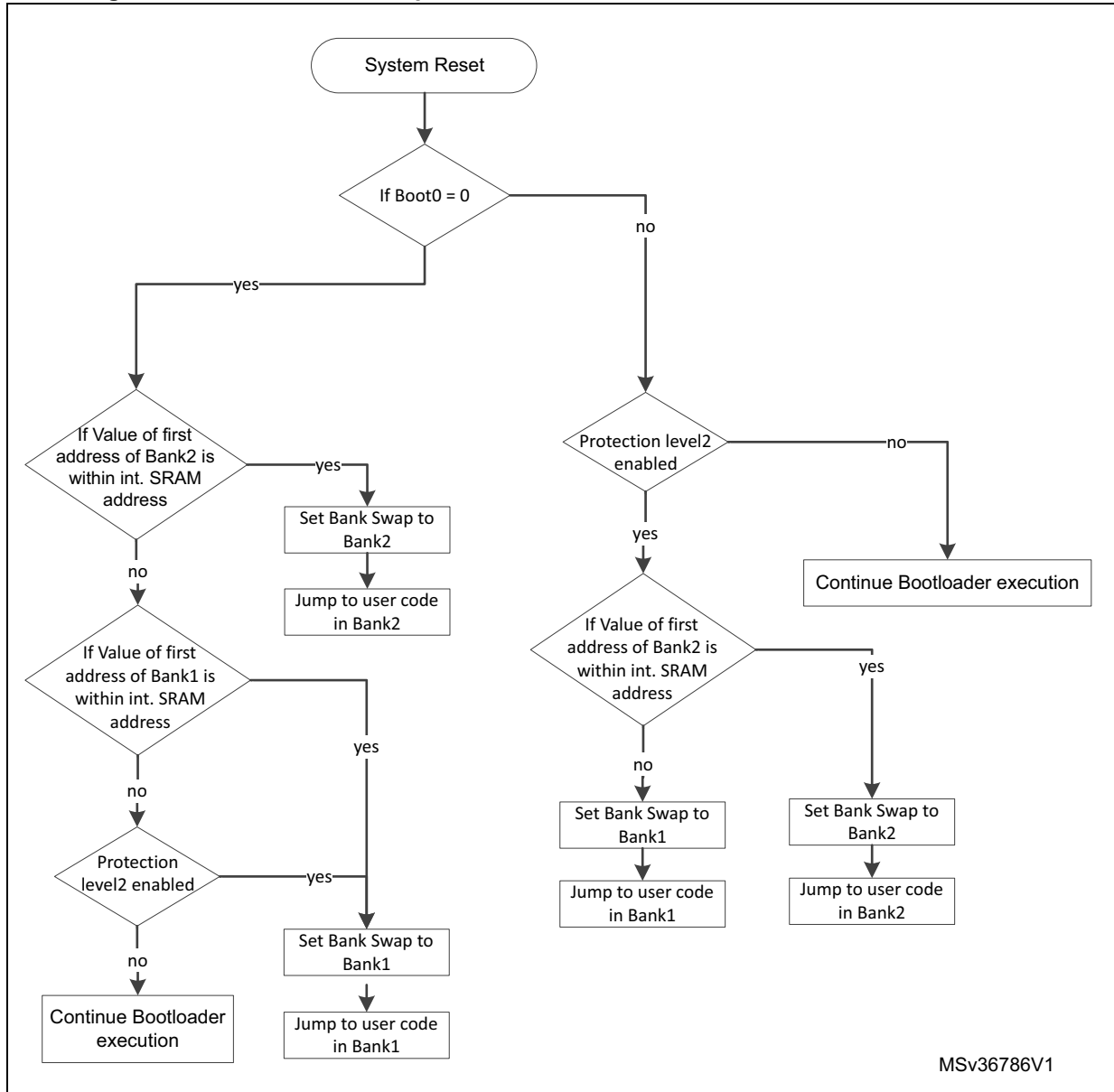
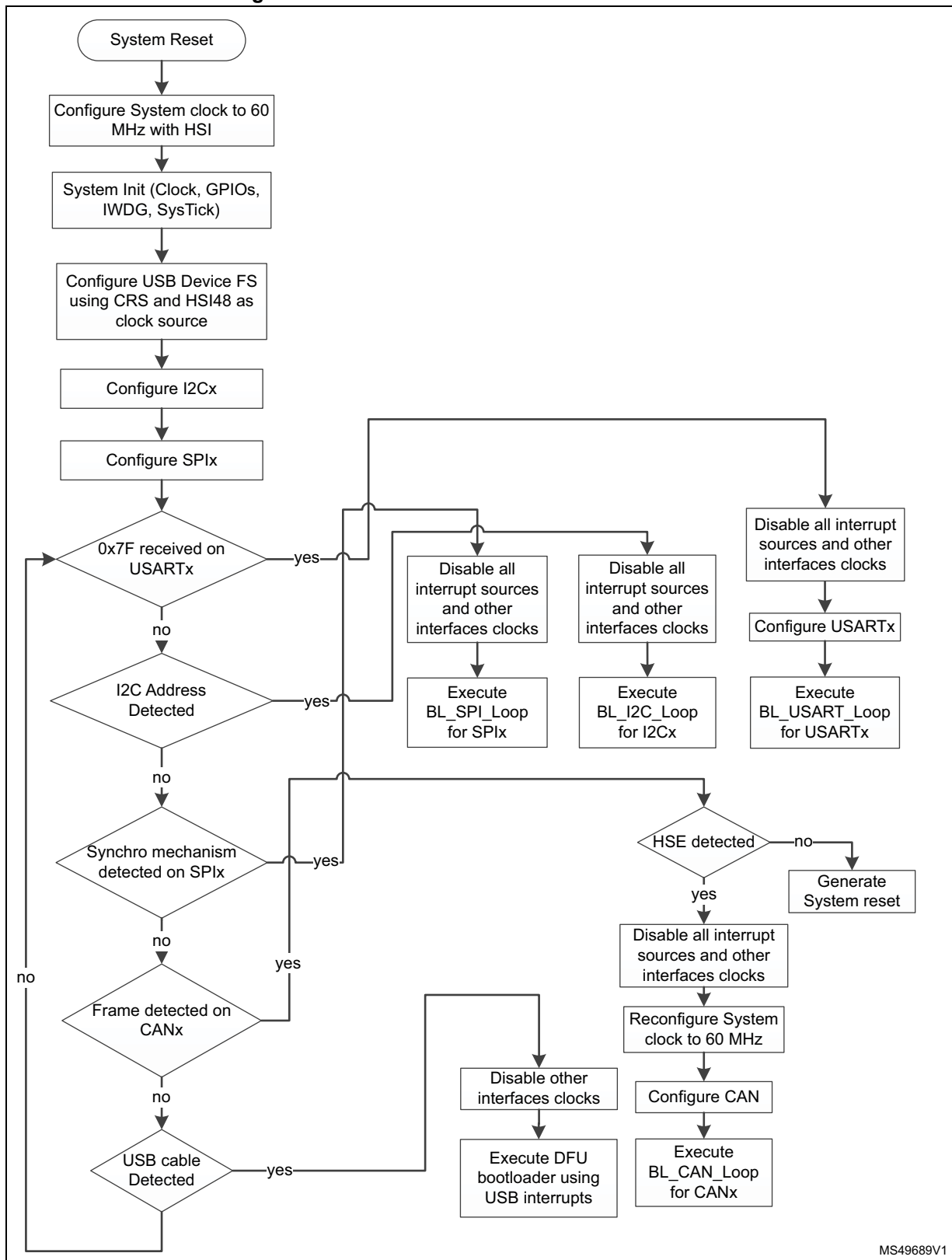


Figure 91.Bootloader V9.x selection for STM32L4P5xx/4Q5xx



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68.3 Bootloader version

[Table 150](#) lists the STM32L4P5xx/4Q5xx devices bootloader versions.

Table 150. STM32L4P5xx/4Q5xx bootloader versions

Version number	Description	Known limitations
V9.0	Initial bootloader version on cut 1.0 samples	<ul style="list-style-type: none">– PcROP option bytes cannot be written as bootloader uses byte access while PcROP must be accessed using half-word access. Workaround: load a code snippet in SRAM using bootloader interface then jump to it, and that code writes PcROP value.

69 STM32L4Rxxx/4Sxxx devices bootloader

69.1 Bootloader configuration

The STM32L4Rxx/4Sxx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 151](#) shows the hardware resources used by this bootloader.

Table 151. STM32L4Rxxx/4Sxxx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The HSI is used at startup as clock source for system clock configured to 60 MHz and for USART, I2C, SPI and USB bootloader operation.
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI 48 MHz.
		HSE enabled	The HSE is used only when the CAN interface is selected. The HSE must have one of the following values: 24,20,18,16,12,9,8,6,4 MHz.
		-	The CSS interrupt is enabled when HSE is enabled. Any failure (or removal) of the external clock generates system reset
	RAM	-	12 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28672 bytes starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
Power	-	The DFU cannot be used to communicate with bootloader if the voltage scaling range 2 is selected. Bootloader firmware does not configure voltage scaling range value in PWR_CR1 register.	
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in input no pull mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in input no pull mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in input pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in input pull-up mode.

Table 151. STM32L4Rxxx/4Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in input pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in input pull-up mode.
USARTx bootloaders	SysTick timer	Enabled	Used to automatically detect the serial baud rate from the host for USARTx bootloaders.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010000x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010000x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain no pull mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain no pull mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1010000x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.

Table 151. STM32L4Rxxx/4Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
CAN1 bootloader	CAN1	Enabled	Once initialized the CAN1 configuration is: Baudrate 125 kbps, 11 -bit identifier.
	CAN1_RX pin	Input	PB8 pin: CAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	CAN1_TX pin	Output	PB9 pin: CAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
	TIM16	Enabled	This timer is used to determine the value of the HSE. Once the HSE frequency is determined, the system clock is configured to 60 MHz using PLL and HSE.

Table 151. STM32L4Rxxx/4Sxxx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line.
	USB_DP pin		PA12: USB DP line No external pull-up resistor is required

69.2 Bootloader selection

Figure 92 and Figure 93 show the bootloader selection mechanisms.

Figure 92. Dual bank boot implementation for STM32L4Rxxx/STM32L4Sxxx bootloader V9.x

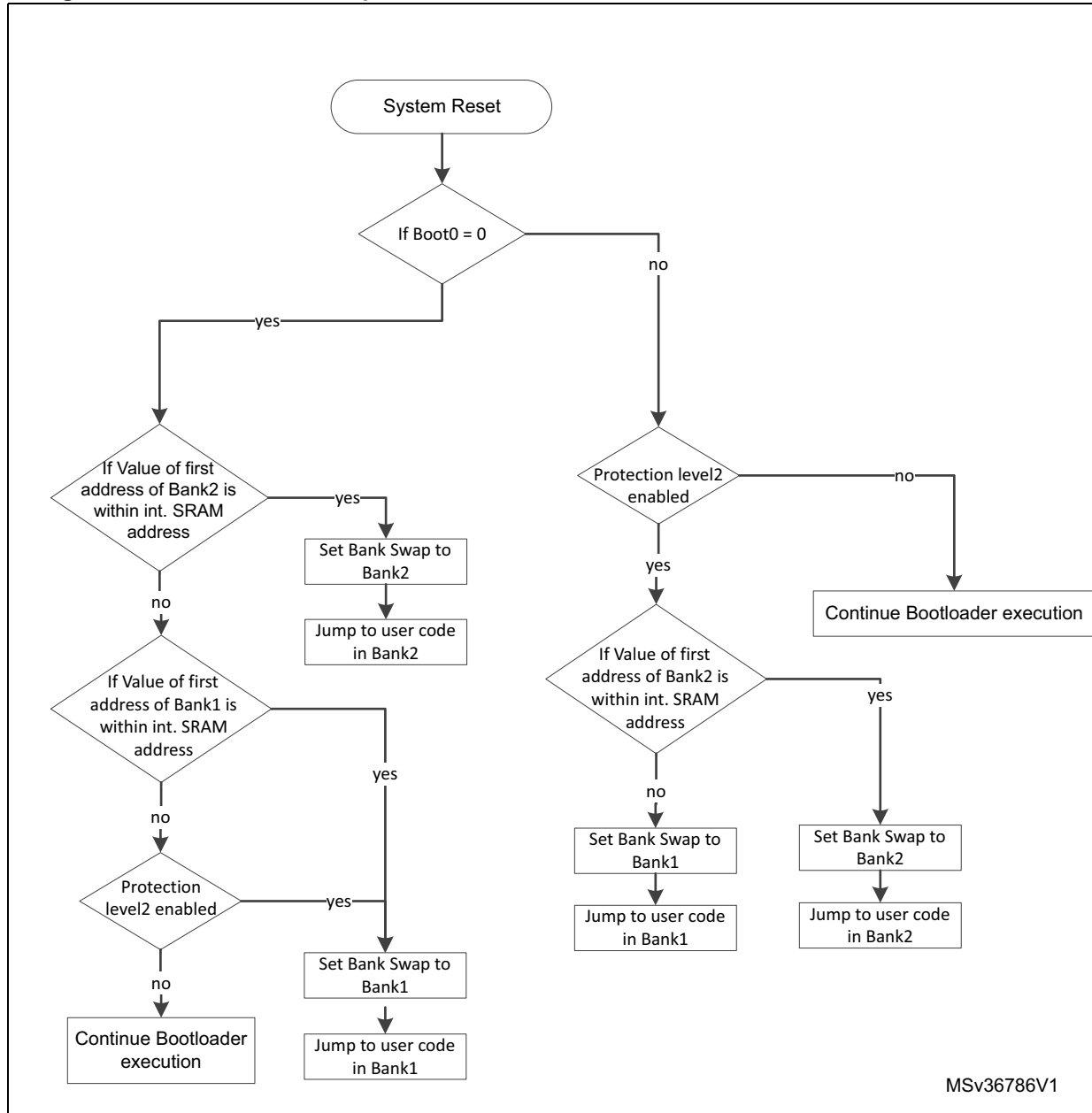
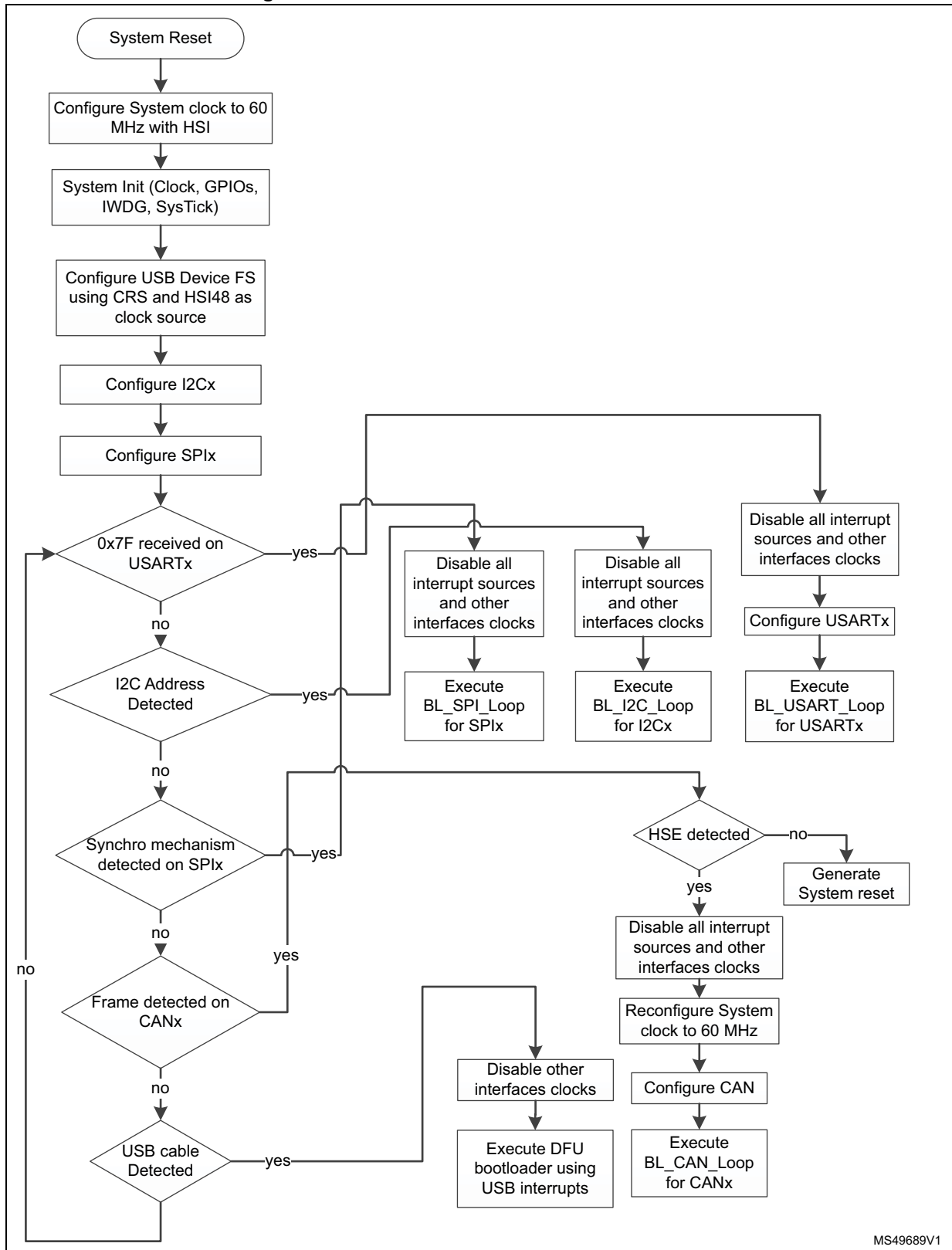


Figure 93.Bootloader V9.x selection for STM32L4Rxx/4Sxx



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69.3 Bootloader version

[Table 152](#) lists the STM32L4Rxx/4Sxx devices bootloader versions.

Table 152. STM32L4Rxx/4Sxx bootloader versions

Version number	Description	Known limitations
V9.0	Initial bootloader version on cut 1.0 samples	– None

70 STM32L552xx/STM32L562xx devices bootloader

70.1 Bootloader configuration

The STM32L552xx/562xx bootloader is activated by applying Pattern 12 (described in [Table 2](#)). [Table 153](#) shows the hardware resources used by this bootloader.

Table 153. STM32L552xx/562xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI 48 MHz.
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	32 Kbytes starting from address 0x0BF90000.
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.

Table 153. STM32L552xx/562xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0101100x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0101100x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b0101100x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

Table 153. STM32L552xx/562xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI3 bootloader	SPI3	Enabled	The SPI configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PG10 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PG9 pin: slave clock line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

Table 153. STM32L552xx/562xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
FDCAN bootloader	FDCAN1	Enabled	Once initialized the FDCAN1 configuration is: Connection bit rate 250 kbit/s Data bit rate 1000 kbit/s FrameFormat = FDCAN_FRAME_FD_BRS Mode = FDCAN_MODE_NORMAL AutoRetransmission = ENABLE TransmitPause = DISABLE ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB9 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PB8 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 154. STM32L552cc/562xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0

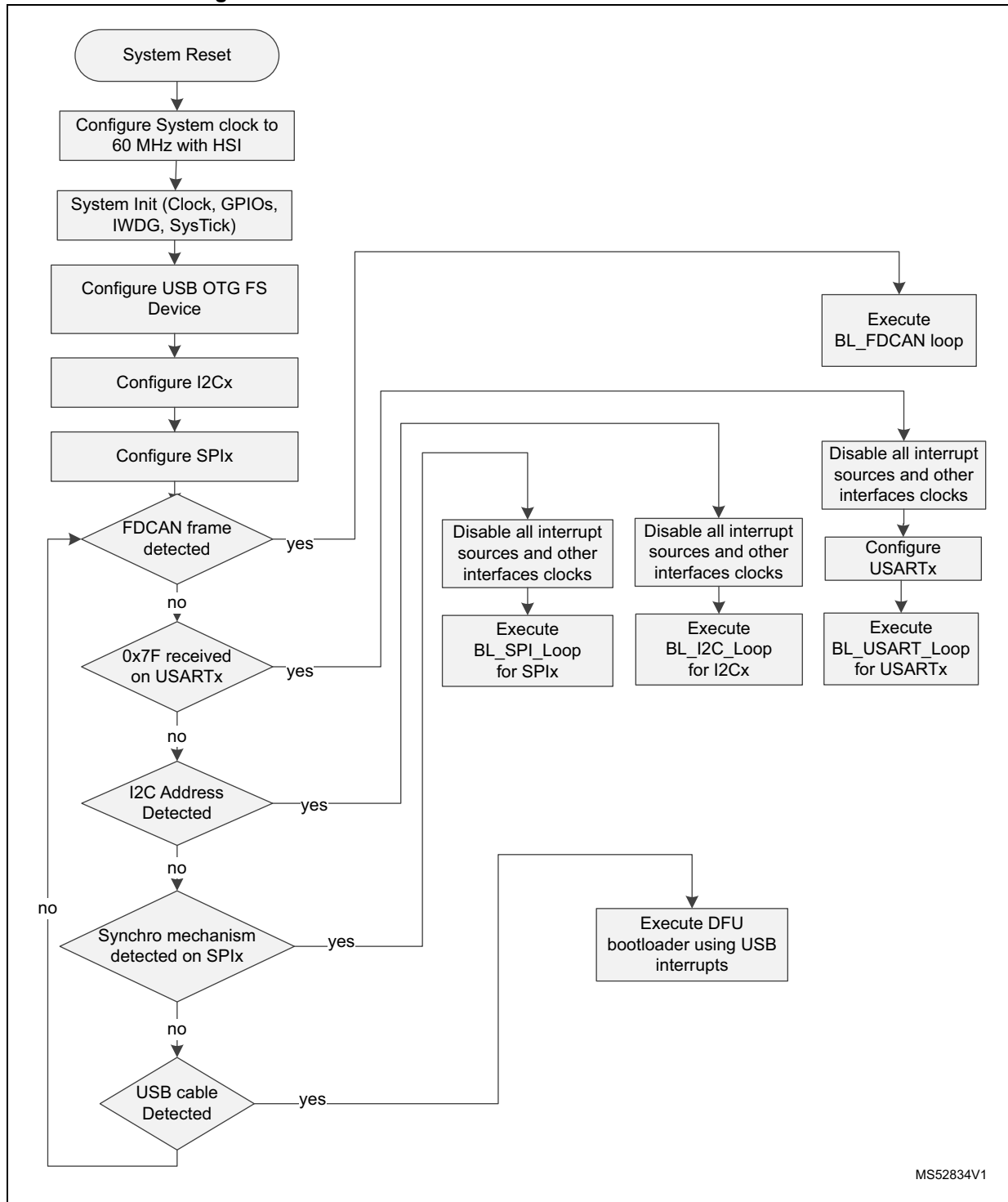
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- No Opcode is used, Sub-Opcode is used directly
- Sub-Opcode is treated in a single byte and not two bytes
- Data is sent on USB frame byte per byte. No need to add number of data to be transmitted
- Returned data and status is formatted on the USB native protocol

70.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 94. Bootloader V9.x selection for STM32L552xx/562xx



70.3 Bootloader version

Table 155 lists the STM32L552xx/562xx devices bootloader versions.

Table 155. STM32L552xx/562xx bootloader versions

Version number	Description	Known limitations
V13.0	Initial bootloader version on cut1.0 samples	<ul style="list-style-type: none"> – USART3 not working – SPI3 not working – OB launch not working on USB-DFU – No read/write SRAM2 in all protocols – Read Secure Option bytes only implemented on USART/I2C – Regression from TZen = 1 to TZen = 0 is done automatically on RDP regression
V9.0	Release supported only in cut2.0 – Fix all issues on previous release – Add FDCAN support – New command added for TZen disable – Support of sales type 256KB	<ul style="list-style-type: none"> – Not able to set TZen to 1 option byte using all interfaces of the BL No WA available – Cannot set RDP level 0.5 nor option bytes in RDP level 0.5 using BL interfaces No WA available – Multiple reset seen when enabling HW IWDG option byte in TZen = 1 No WA available – Not able to set secure option bytes setting when TZen = 1 and RDP level is 0 No WA available – “Go” Command on USB is not working – FDCAN erase not working as page number endianness is not aligned with the protocol (device waits for LSB first but host sends MSB first) – WA - Send data MSB first to the BL
V9.1	<ul style="list-style-type: none"> – Fix all known limitations of previous release – Add enable BOOT_LOCK BL command – Add support of RDP L1 to 0.5 regression 	<ul style="list-style-type: none"> – Option byte programming is not working properly when using FDCAN interface. This makes the change of the Option byte not effective until a power off/power on. – FDCAN erase not working as page number endianness is not aligned with the protocol (device waits for LSB first but host sends MSB first) – WA - Send data MSB first to the BL
V9.2	<ul style="list-style-type: none"> – Fix all known limitations of previous release – Version for silicon revision Z 	FDCAN Readout unprotect command does not send the command ID to the host

Note: When jumping to the BL the cache must be disabled.



71 STM32WBA52xx devices bootloader

71.1 Bootloader Configuration

The STM32WBA52xx bootloader is activated by applying Pattern12 (described in [Table 2](#)). [Table 156](#) shows the hardware resources used by this bootloader.

Table 156. STM32WBA52xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	32 Kbytes starting from address 0x0BF88000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA8 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PB12 pin: USART1 in transmission mode. Not set until USART1 is detected.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA11 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA12 pin: USART2 in transmission mode. Not set until USART2 is detected.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1100110x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB2 pin: clock line is used in open-drain pull up mode.
	I2C1_SDA pin	Input/output	PB1 pin: data line is used in open-drain pull up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1100110x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PA6 pin: clock line is used in open-drain pull up mode.
	I2C3_SDA pin	Input/output	PA7 pin: data line is used in open-drain pull up mode.

Table 156. STM32WBA52xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3 bootloader	SPI3	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB8 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PB9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PA0 pin: slave clock line, used in push-pull, no pull mode
	SPI3_NSS pin	Input	PA5 pin: slave chip select pin used in push-pull, no pull mode.

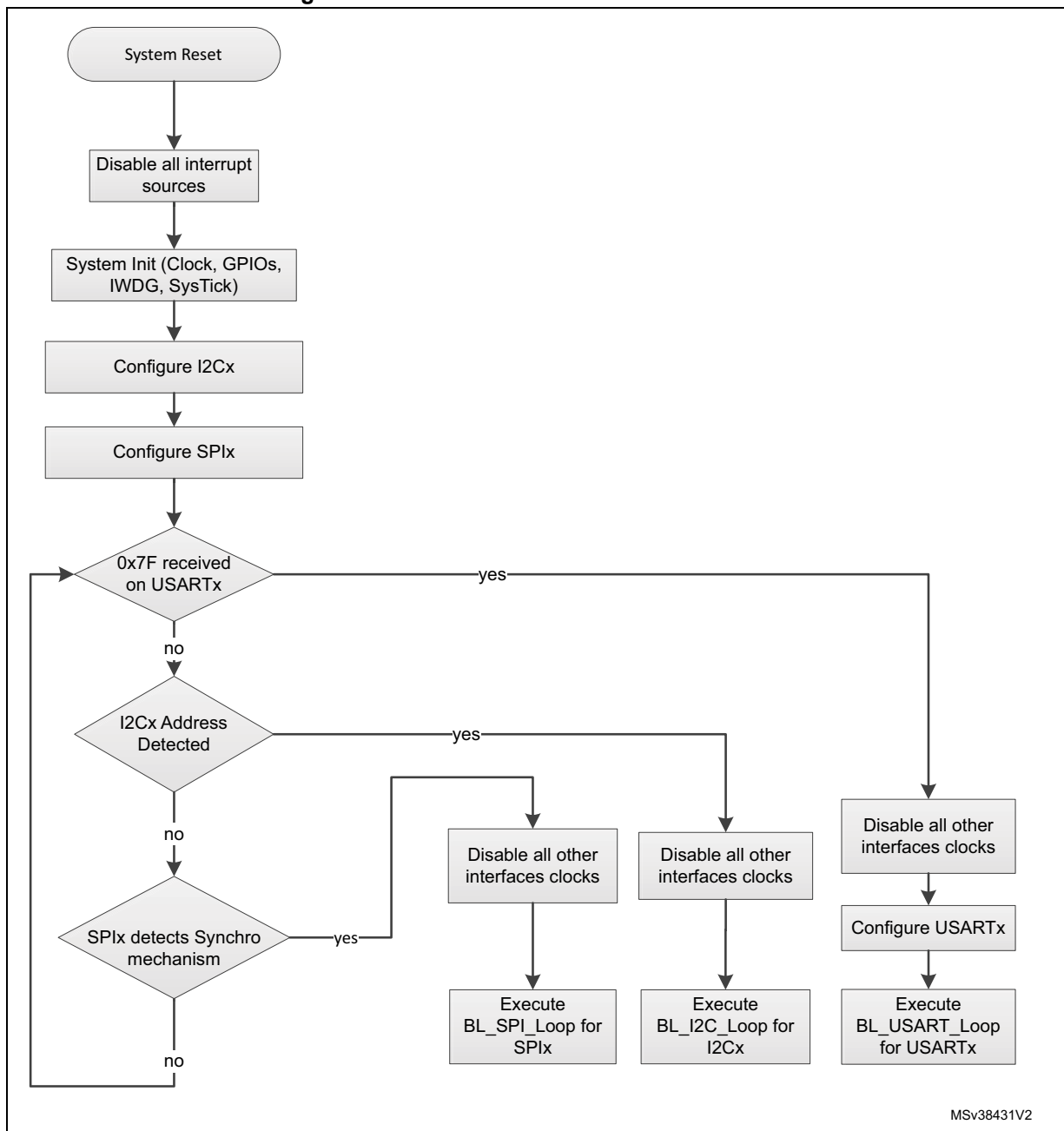
Table 157. STM32WBA52xx special commands

Special commands supported (USART/I2C/SPI) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02 ⁽¹⁾	0x0	NA	0x1	0x0

1. 0xYY can have 3 values (0: WRP area, 1: WRP1A, 2: WRP2A)

71.2 Bootloader selection

Figure 95.Bootloader V11.x selection for STM32WBA52xx



71.3 Bootloader version

Table 158. STM32WBA52xx bootloader versions

Version number	Description	Known limitations
V11.0	Initial bootloader version	None

72 STM32WB10xx/15xx devices bootloader

72.1 Bootloader configuration

The STM32WB10xx/15xx bootloader is activated by applying Pattern 6 (described in [Table 2](#)). [Table 161](#) shows the hardware resources used by this bootloader.

Table 159. STM32WB10xx/15xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	MSI enabled	The system clock frequency is 64 MHz (using PLL clocked by MSI).
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001111x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

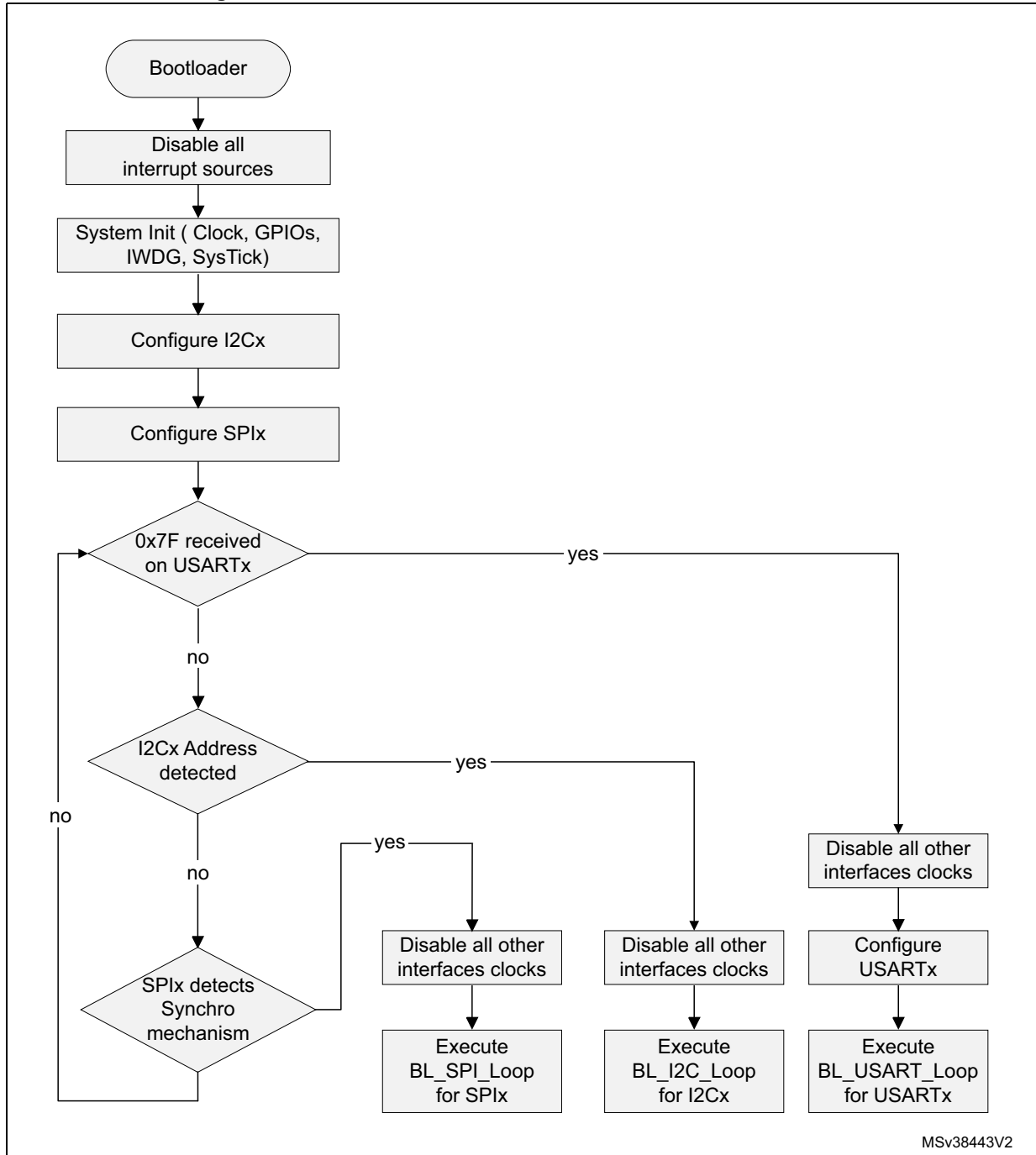
Table 159. STM32WB10xx/15xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: <ul style="list-style-type: none"> – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

72.2 Bootloader selection

The figure below shows the bootloader selection mechanism.

Figure 96. Bootloader V11.x selection for STM32WB10xx/15xx



72.3 Bootloader version

Table 160. STM32WB10xx/15xx bootloader versions

Version number	Description	Known limitations
V11.1	Initial bootloader version	<ul style="list-style-type: none">– I2C Write Protect command (0x73) performs a Read Unprotect instead of disabling write protection.– Workaround: Use No-Stretch Write Unprotect command (0x74) that is performing correctly the write unprotect operation

73 STM32WB30xx/35xx/50xx/55xx devices bootloader

73.1 Bootloader configuration

The STM32WBxxx bootloader is activated by applying Pattern 16 (described in [Table 2](#)). [Table 161](#) shows the hardware resources used by this bootloader.

Table 161. STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	MSI enabled	The system clock frequency is 64 MHz (using PLL clocked by MSI).
		-	The clock recovery system (CRS) is enabled for the DFU bootloader to allow USB to be clocked by HSI 48 MHz.
	RAM	-	20 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	28 Kbytes starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001111x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain no pull mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain no pull mode.

Table 161. STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. Slave 7-bit address: 0b1001111x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain no pull mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain no pull mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

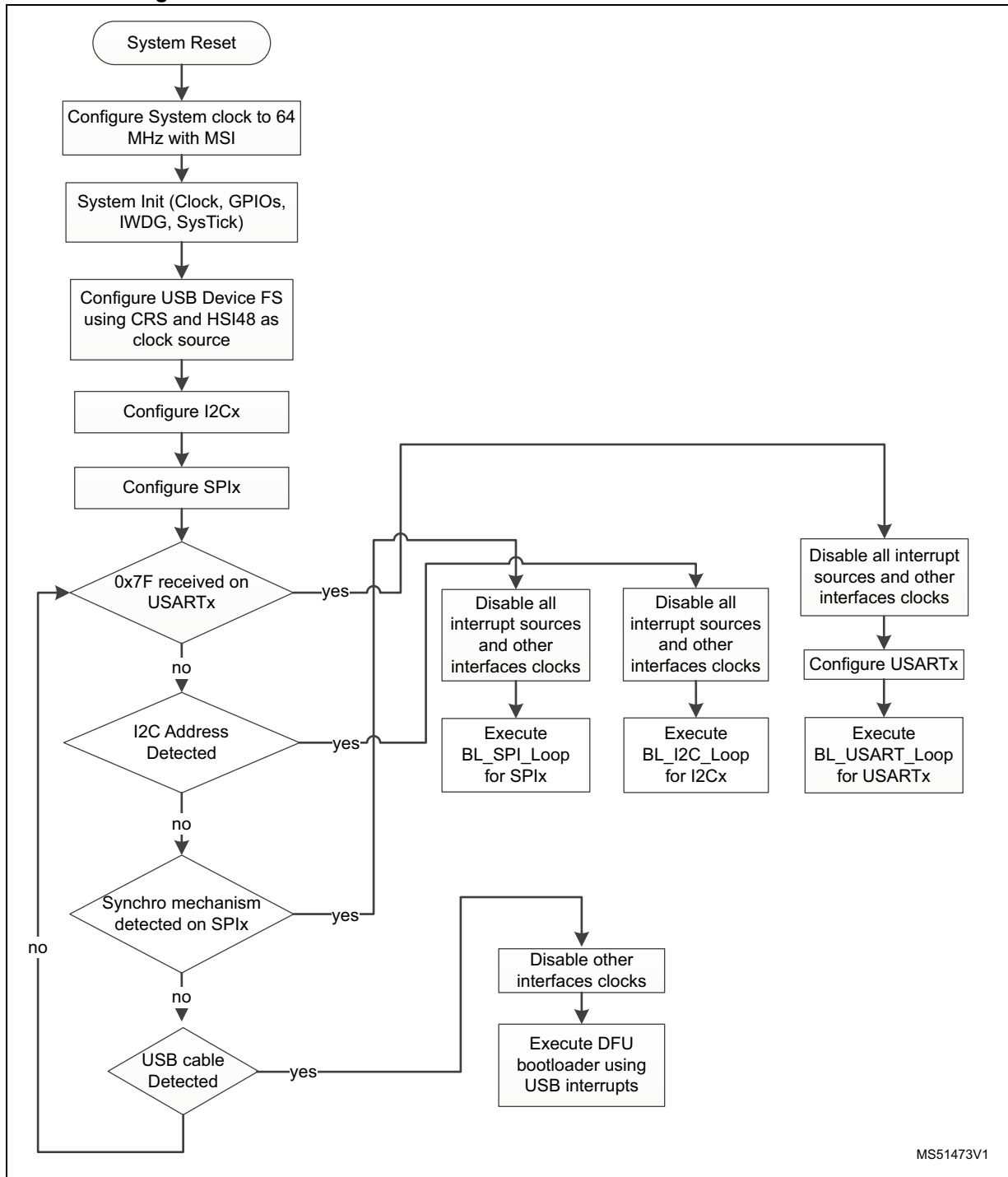
Table 161. STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

73.2 Bootloader selection

Figure 97 shows the bootloader selection mechanism.

Figure 97. Bootloader V13.0 selection for STM32WB30xx/35xx/50xx/55xx



73.3 Bootloader version

Table 162. STM32WB30xx/35xx/50xx/55xx bootloader versions

Version number	Description	Known limitations
V13.5	Initial bootloader version	<ul style="list-style-type: none"> – Readout Unprotect Command is not working properly as at the end of the command an NVIC_SystemReset is done instead of a flash option bytes reload. This makes the change of the RDP level not effective until a power off power on. – I2C Write Protect command (0x73) performs a Read Unprotect instead of disabling write protection. Workaround: Uses No-Stretch Write Unprotect command (0x74) that is performing correctly the write unprotect operation

Note: Instability when performing multiple resets during operations ongoing causing Overrun or FrameError errors on USART Bootloader and not recoverable unless Hardware Reset is performed. Fixed by workaround in FUS V1.0.1 and V1.0.2.

74 STM32WLE5xx/55xx devices bootloader

74.1 Bootloader configuration

The STM32WLE5xx/55xx bootloader is activated by applying Pattern 13 (described in [Table 2](#)). [Table 163](#) shows the hardware resources used by this bootloader.

Table 163. STM32WLE5xx/55xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 48 MHz (using PLL clocked by HSI).
	RAM	-	8 Kbytes, starting from address 0x20000000, are used by the bootloader firmware
	System memory	-	16 Kbytes starting from address 0x1FFF0000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.

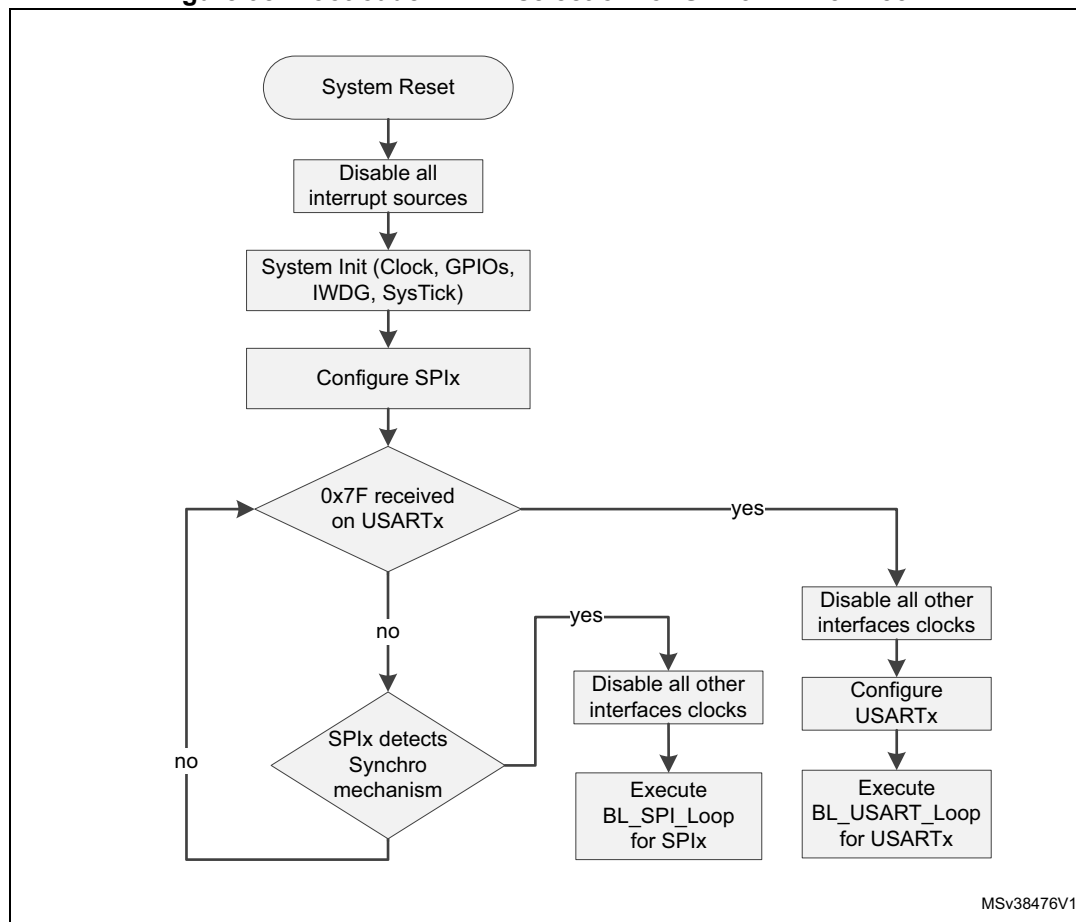
Table 163. STM32WLE5xx/55xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode. Note: This IO can be tied to GND if the SPI master does not use it.

74.2 Bootloader selection

Figure 98 shows the bootloader selection mechanism.

Figure 98. Bootloader V12.x selection for STM32WLE5xx/55xx



74.3 Bootloader version

Table 164. STM32WLE5xx/55xx bootloader versions

Version number	Description	Known limitations
V12.2	Initial bootloader version on rev. Z samples	BL cannot write/read the following option bytes: – FLASH_SFR (Offset - 0x80) – FLASH_SRRVR (Offset - 0x84)
V12.3	Final bootloader version on rev Z samples	BL cannot write/read the following option bytes: – FLASH_SFR (Offset - 0x80) – FLASH_SRRVR (Offset - 0x84)
V12.4	Final bootloader version on rev Y samples	BL cannot write/read the following option bytes: – FLASH_SFR (Offset - 0x80) – FLASH_SRRVR (Offset - 0x84)

75 STM32U535xx/545xx devices bootloader

75.1 Bootloader configuration

The STM32U535xx/545xx bootloader is activated by applying Pattern 12 (described in [Table 2](#)). [Table 165](#) shows the hardware resources used by this bootloader.

Table 165. STM32U535xx/545xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	20 MHz derived from the PLLQ is used for FDCAN
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	64 Kbytes starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Set as input until USART1 is detected.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1101000x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.

Table 165. STM32U535xx/545xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1101000x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1101000x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.

Table 165. STM32U535xx/545xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PG10 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, no pull mode.
FDCAN bootloader	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 166. STM32U535xx/545xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02 ⁽¹⁾	0x0	NA	0x1	0x0

1. 0xYY can have four values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

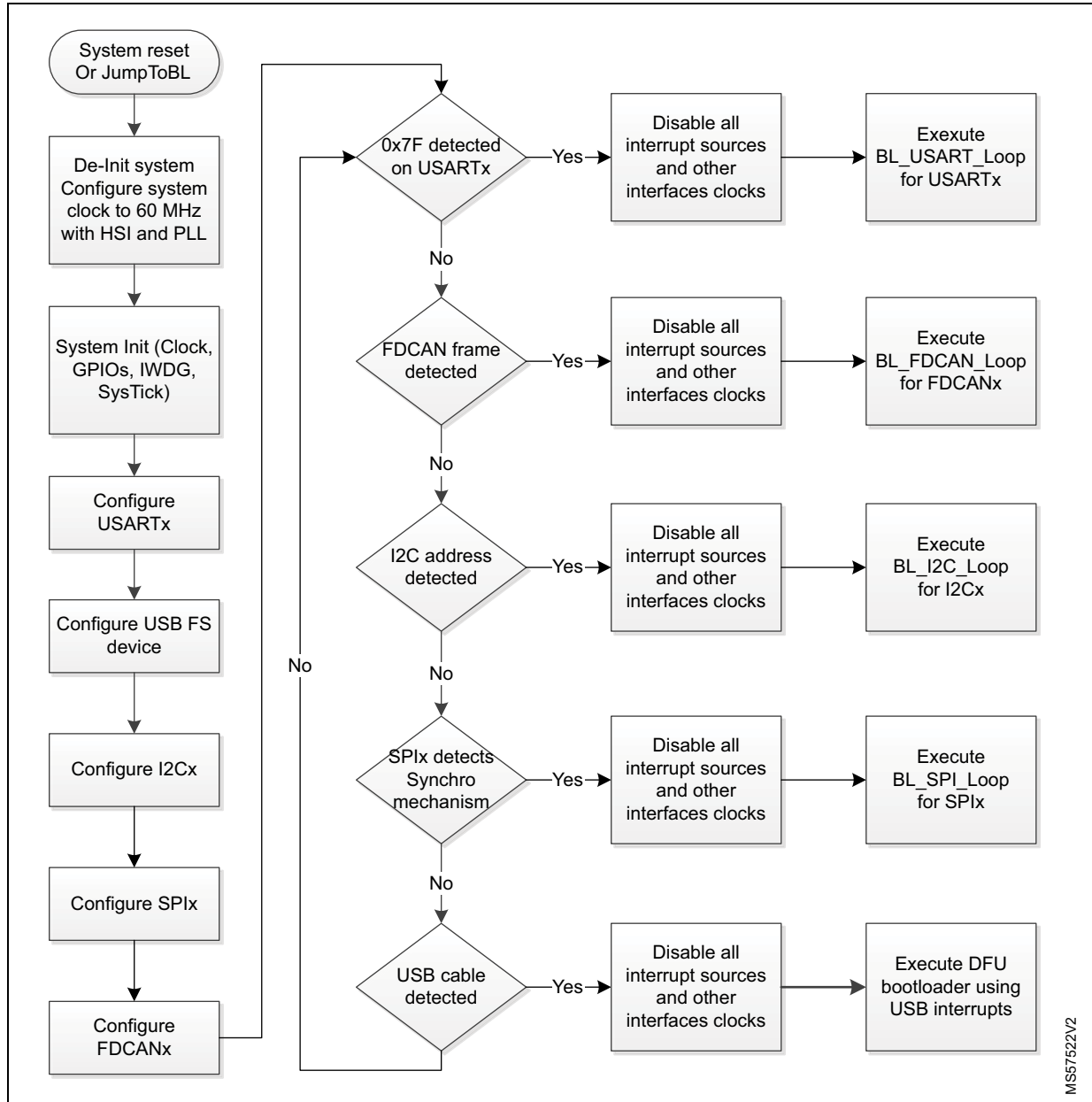
Note: *USB special commands are slightly different from the other protocols as per the USB protocol specificities:*

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data is sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status is formatted on the USB native protocol*

75.2 Bootloader selection

Figure 99 shows the bootloader selection mechanism.

Figure 99. Bootloader V9.x selection for STM32U535xx/545xx



75.3 Bootloader version

Table 167. STM32U535xx/545xx bootloader versions

Version number	Description	Known limitations
V9.1	Initial bootloader version	FDCAN Readout unprotect command does not send the command ID to the host

76 STM32U575xx/85xx devices bootloader

76.1 Bootloader configuration

The STM32U575xx/85xx bootloader is activated by applying Pattern 12 (described in [Table 2](#)). [Table 168](#) shows the hardware resources used by this bootloader.

Table 168. STM32U575xx/85xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	64 Kbytes starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Used in alternate push-pull, pull-up mode.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Used in alternate push-pull, pull-up mode.
USART3 bootloader	USART3	Enabled	Once initialized the USART3 configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Used in alternate push-pull, pull-up mode.
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1011010x (where x = 0 for write and x = 1 for read)
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.

Table 168. STM32U575xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1011010x (where x = 0 for write and x = 1 for read)
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1011010x (where x = 0 for write and x = 1 for read)
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1	Enabled	The SPI1 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, pull-down mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, pull-down mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, pull-down mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, pull-down mode.
SPI2 bootloader	SPI2	Enabled	The SPI2 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, pull-down mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, pull-down mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, pull-down mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, pull-down mode.

Table 168. STM32U575xx/85xx configuration in system memory boot mode (continued)

Bootloader	Feature/Peripheral	State	Comment
SPI3 bootloader	SPI3	Enabled	The SPI3 configuration is: – Slave mode – Full Duplex – 8-bit MSB – Speed up to 8 MHz – Polarity: CPOL low, CPHA low, NSS hardware.
	SPI3_MOSI pin	Input	PB5 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_MISO pin	Output	PG10 pin: slave data Input line, used in push-pull, pull-down mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, pull-down mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, pull-down mode.
FDCAN bootloader	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, pull-up mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, pull-up mode.
DFU bootloader	USB	Enabled	USB FS configured in forced device mode. USB FS interrupt vector is enabled and used for USB DFU communications. Note: VDDUSB IO must be connected to 3.3 V as USB peripheral is used by the bootloader.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required

Table 169. STM32U575xx/585xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02 ⁽¹⁾	0x0	NA	0x1	0x0

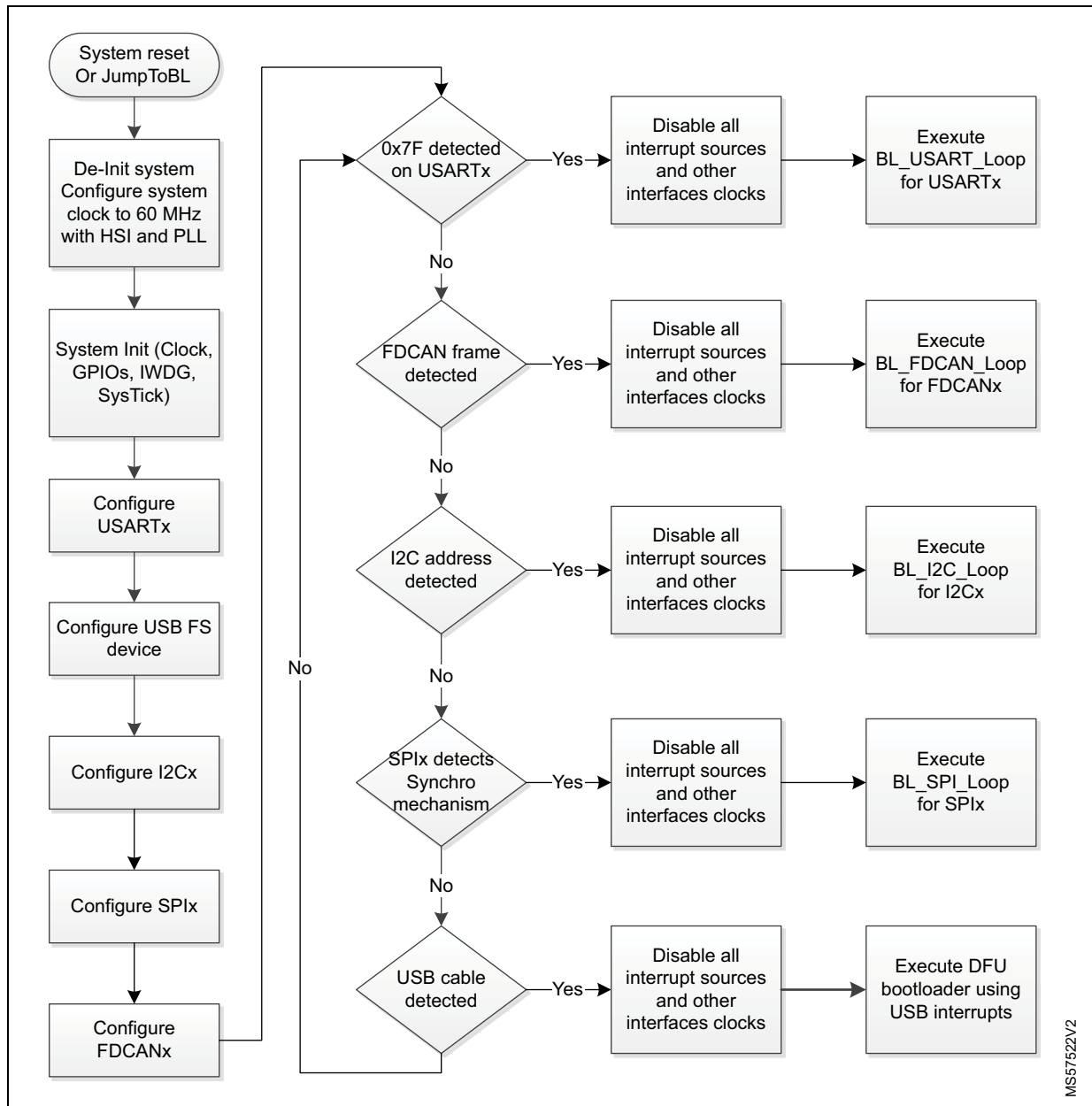
1. 0xYY can have four values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

Note: *USB special commands are slightly different from the other protocols as per the USB protocol specificities:*

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data is sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status is formatted on the USB native protocol*

76.2 Bootloader selection

Figure 100. Bootloader V9.x selection for STM32U575xx/85xx



MS57522V2

76.3 Bootloader version

Table 170. STM32U575xx/85xx bootloader versions

Version number	Description	Known limitations
V9.2	Initial bootloader version	FDCAN Readout unprotect command does not send the command ID to the host

77 STM32U595xx/599xx/5A5xx/5A9xx devices bootloader

77.1 Bootloader configuration

The STM32U595xx/599xx/5A5xx/5A9xx bootloader is activated by applying Pattern 12 (described in [Table 2](#)). [Table 171](#) shows the hardware resources used by this bootloader.

Table 171. STM32U595xx/599xx/5A5xx/5A9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	20 MHz derived from the PLLQ is used for FDCAN
		HSE enabled	When USB cable is detected, SW tries to detect if a quartz is plugged in the board to configure the USBPHY clock. Supported quartz: 8, 12, 16, 20, 24, 26, and 32 MHz. If no quartz is detected a system reset is triggered.
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	64 Kbytes starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as input until USART1 is detected.
USART3 bootloader	USART3	Enabled	Once initialized the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Set as input until USART1 is detected.

Table 171. STM32U595xx/599xx/5A5xx/5A9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1100000x, where x = 0 for write and x = 1 for read.
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1100000x, where x = 0 for write and x = 1 for read.
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1100000x, where x = 0 for write and x = 1 for read.
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, no pull mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2 bootloader	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3 bootloader	SPI3_MOSI pin	Input	PB5 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PG10 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, no pull mode.

Table 171. STM32U595xx/599xx/5A5xx/5A9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB HS configured in forced device mode. USB HS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required
FDCAN bootloader	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 172. STM32U595xx/599xx/5A5xx/5A9xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02 ⁽¹⁾	0x0	NA	0x1	0x0

1. 0xYY can have four values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

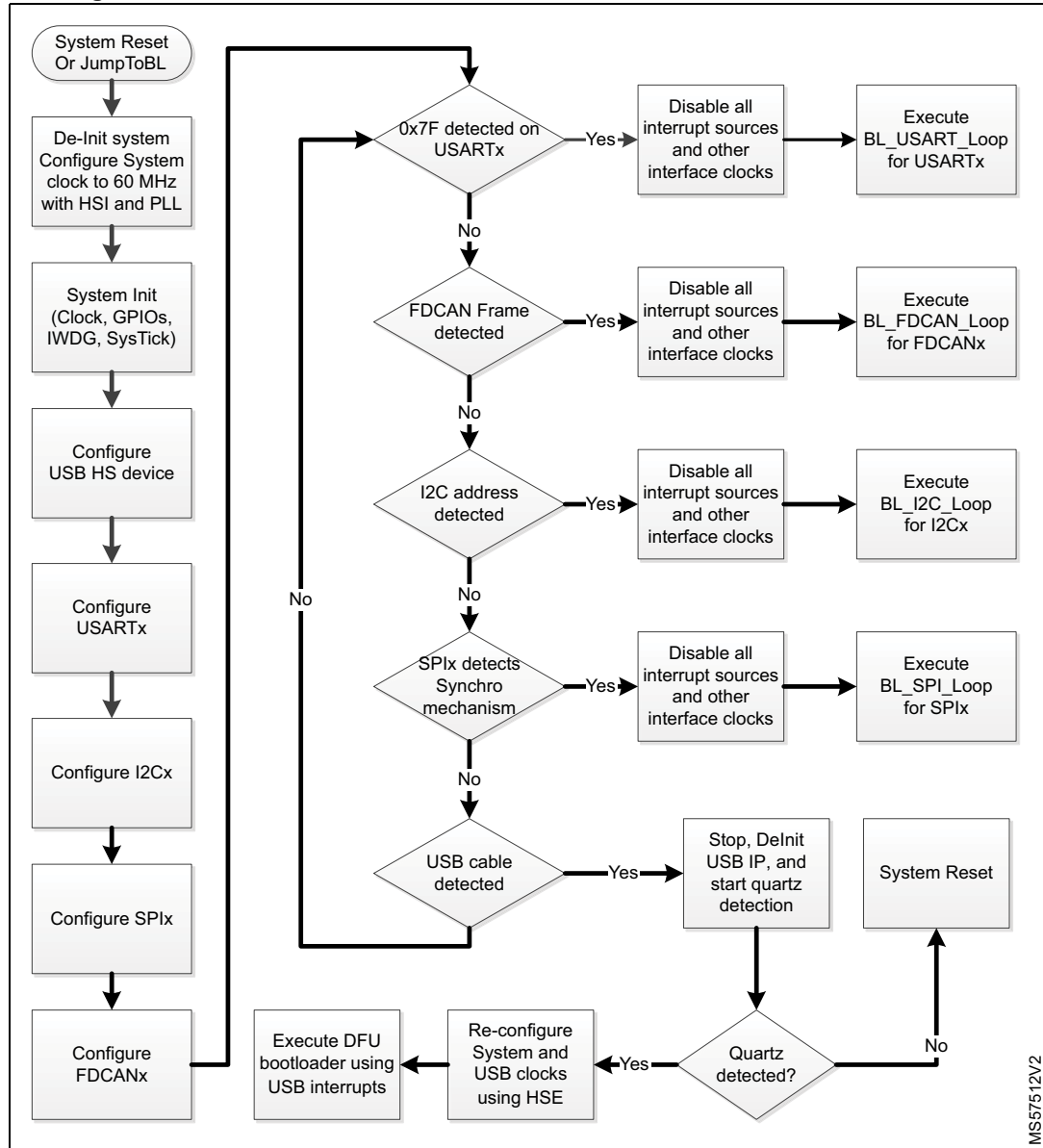
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data is sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status is formatted on the USB native protocol*

77.2 Bootloader selection

Figure 101 shows the bootloader selection mechanism.

Figure 101. Bootloader V9.x selection for STM32U595xx/599xx/5A5xx/5A9xx



77.3 Bootloader version

Table 173. STM32U595xx/599xx/5A5xx/5A9xx bootloader versions

Version number	Description	Known limitations
V9.2	Initial bootloader version	FDCAN Readout unprotect command does not send the command ID to the host

78 STM32U5F7xx/5F9xx/5G7xx/5G9xx devices bootloader

78.1 Bootloader configuration

The STM32U5F7xx/5F9xx/5G7xx/5G9xx bootloader is activated by applying Pattern 12 (described in [Table 2](#)). [Table 174](#) shows the hardware resources used by this bootloader.

Table 174. STM32U5F7xx/5F9xx/5G7xx/5G9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
Common to all bootloaders	RCC	HSI enabled	The system clock frequency is 60 MHz (using PLL clocked by HSI).
		-	20 MHz derived from the PLLQ is used for FDCAN
		HSE enabled	When USB cable is detected, SW tries to detect if a quartz is plugged in the board to configure the USBPHY clock. Supported quartz: 8, 12, 16, 20, 24, 26, and 32 MHz If no quartz detected a system reset is triggered.
	RAM	-	16 Kbytes starting from address 0x20000000 are used by the bootloader firmware
	System memory	-	64 Kbytes starting from address 0x0BF90000, contain the bootloader firmware
	IWDG	-	The IWDG prescaler is configured to its maximum value. It is periodically refreshed to prevent watchdog reset (if the hardware IWDG option was previously enabled by the user).
USART1 bootloader	USART1	Enabled	Once initialized the USART1 configuration is 8-bit, even parity, and one stop bit
	USART1_RX pin	Input	PA10 pin: USART1 in reception mode. Used in alternate push-pull, pull-up mode.
	USART1_TX pin	Output	PA9 pin: USART1 in transmission mode. Set as input until USART1 is detected.
USART2 bootloader	USART2	Enabled	Once initialized the USART2 configuration is 8-bit, even parity, and one stop bit
	USART2_RX pin	Input	PA3 pin: USART2 in reception mode. Used in alternate push-pull, pull-up mode.
	USART2_TX pin	Output	PA2 pin: USART2 in transmission mode. Set as input until USART1 is detected.
USART3 bootloader	USART3	Enabled	Once initialized the configuration is 8-bit, even parity, and one stop bit
	USART3_RX pin	Input	PC11 pin: USART3 in reception mode. Used in alternate push-pull, pull-up mode.
	USART3_TX pin	Output	PC10 pin: USART3 in transmission mode. Set as input until USART1 is detected.

Table 174. STM32U5F7xx/5F9xx/5G7xx/5G9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
I2C1 bootloader	I2C1	Enabled	The I2C1 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1101001x, where x = 0 for write and x = 1 for read.
	I2C1_SCL pin	Input/output	PB6 pin: clock line is used in open-drain pull-up mode.
	I2C1_SDA pin	Input/output	PB7 pin: data line is used in open-drain pull-up mode.
I2C2 bootloader	I2C2	Enabled	The I2C2 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1101001x, where x = 0 for write and x = 1 for read.
	I2C2_SCL pin	Input/output	PB10 pin: clock line is used in open-drain pull-up mode.
	I2C2_SDA pin	Input/output	PB11 pin: data line is used in open-drain pull-up mode.
I2C3 bootloader	I2C3	Enabled	The I2C3 configuration is: – I2C speed: up to 1 MHz, 7-bit address, slave mode, analog filter ON. – Slave 7-bit address: 0b1101001x, where x = 0 for write and x = 1 for read.
	I2C3_SCL pin	Input/output	PC0 pin: clock line is used in open-drain pull-up mode.
	I2C3_SDA pin	Input/output	PC1 pin: data line is used in open-drain pull-up mode.
SPI1 bootloader	SPI1_MOSI pin	Input	PA7 pin: slave data Input line, used in push-pull, no pull mode
	SPI1_MISO pin	Output	PA6 pin: slave data output line, used in push-pull, no pull mode
	SPI1_SCK pin	Input	PA5 pin: slave clock line, used in push-pull, no pull mode
	SPI1_NSS pin	Input	PA4 pin: slave chip select pin used in push-pull, no pull mode.
SPI2 bootloader	SPI2_MOSI pin	Input	PB15 pin: slave data Input line, used in push-pull, no pull mode
	SPI2_MISO pin	Output	PB14 pin: slave data output line, used in push-pull, no pull mode
	SPI2_SCK pin	Input	PB13 pin: slave clock line, used in push-pull, no pull mode
	SPI2_NSS pin	Input	PB12 pin: slave chip select pin used in push-pull, no pull mode.
SPI3 bootloader	SPI3_MOSI pin	Input	PB5 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_MISO pin	Output	PG10 pin: slave data Input line, used in push-pull, no pull mode
	SPI3_SCK pin	Input	PG9 pin: slave data output line, used in push-pull, no pull mode
	SPI3_NSS pin	Input	PG12 pin: slave chip select pin used in push-pull, no pull mode.

Table 174. STM32U5F7xx/5F9xx/5G7xx/5G9xx configuration in system memory boot mode

Bootloader	Feature/Peripheral	State	Comment
DFU bootloader	USB	Enabled	USB HS configured in forced device mode. USB HS interrupt vector is enabled and used for USB DFU communications.
	USB_DM pin	Input/output	PA11: USB DM line. Used in input no pull mode.
	USB_DP pin		PA12: USB DP line. Used in input no pull mode. No external pull-up resistor is required
FDCAN bootloader	FDCAN1	Enabled	Once initialized the configuration is: – Connection bit rate 250 kbit/s – Data bit rate 1000 kbit/s – FrameFormat = FDCAN_FRAME_FD_BRS – Mode = FDCAN_MODE_NORMAL – AutoRetransmission = ENABLE – TransmitPause = DISABLE – ProtocolException = ENABLE
	FDCAN1_Rx pin	Input/	PB8 pin: FDCAN1 in reception mode. Used in alternate push-pull, no pull mode.
	FDCAN1_Tx pin	Output	PB9 pin: FDCAN1 in transmission mode. Used in alternate push-pull, no pull mode.

Table 175. STM32U5F7xx/5F9xx/5G7xx/5G9xx special commands

Special commands supported (USART/I2C/SPI/FDCAN) Opcode - 0x50							
Function	Sub-Opcode (2 bytes)	Number of data sent (2 bytes)	Data sent	Number of data received	Data received	Number of status data received (2 bytes)	Status data received
TrustZone disable Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x0	0x0	NA	0x1	0x0
Regression from RDP L1 to RDP 0.5 Must be run when TZEN = 1 and RDP = 1	0x82	0x4	0x1	0x0	NA	0x1	0x0
Unlock write protection Must be run when RDP = 1	0x82	0x4	0xYY02 ⁽¹⁾	0x0	NA	0x1	0x0

1. 0xYY can have four values (0: WRP area, 1: WRP1A, 2: WRP2A, 3: WRP1B, 4: WRP2B)

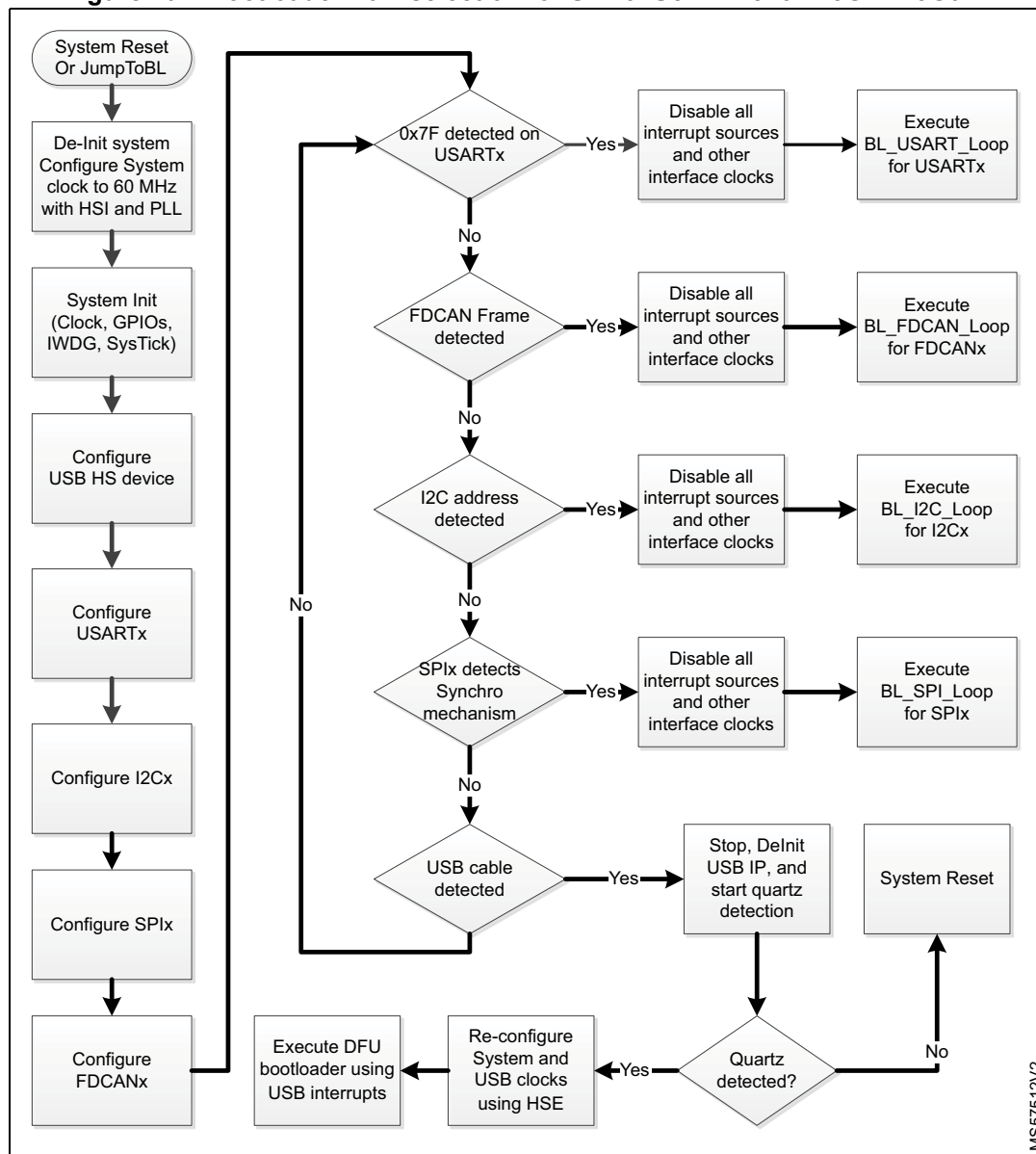
Note: USB special commands are slightly different from the other protocols as per the USB protocol specificities:

- *No Opcode is used, Sub-Opcode is used directly*
- *Sub-Opcode is treated in a single byte and not two bytes*
- *Data is sent on USB frame byte per byte. No need to add number of data to be transmitted*
- *Returned data and status is formatted on the USB native protocol*

78.2 Bootloader selection

Figure 101 shows the bootloader selection mechanism.

Figure 102. Bootloader V9.x selection for STM32U5F7xx/5F9xx/5G7xx/5G9xx



78.3 Bootloader version

Table 176. STM32U5F7xx/5F9xx/5G7xx/5G9xx bootloader versions

Version number	Description	Known limitations
V9.0	Initial bootloader version	FDCAN Readout unprotect command does not send the command ID to the host

79 Device-dependent bootloader parameters

The bootloader protocol command set and sequences for each serial peripheral are the same for all STM32 devices. However, some parameters depend on device and bootloader version:

- PID (Product ID)
- Valid RAM addresses (RAM area used during bootloader execution is not accessible) accepted by the bootloader when the Read Memory, Go and Write Memory commands are requested.
- System memory area.

[Table 177](#) shows the values of these parameters for each STM32 device.

Table 177. Bootloader device-dependent parameters

STM32 series	Device	PID	BL ID	RAM	System memory
C0	STM32C011xx	0x443	0x51	0x20000000 - 0x20002FFF	0x1FFF0000 - 0x1FFF17FF
	STM32C031xx	0x453	0x52	0x20002000 - 0x200017FF	
F0	STM32F05xxx and STM32F030x8	0x440	0x21	0x20000800 - 0x20001FFF	0x1FFFE000 - 0x1FFFF7FF
	STM32F03xx4/6	0x444	0x10	0x20000800 - 0x20000FFF	
	STM32F030xC	0x442	0x52	0x20001800 - 0x20007FFF	0x1FFFD800 - 0x1FFFF7FF
	STM32F04xxx	0x445	0xA1	NA	0x1FFFC400 - 0x1FFFF7FF
	STM32F070x6	0x445	0xA2	NA	0x1FFFC400 - 0x1FFFF7FF
	STM32F070xB	0x448	0xA2	NA	0x1FFFC800 - 0x1FFFF7FF
	STM32F071xx/072xx	0x448	0xA1	0x20001800 - 0x20003FFF	0x1FFFC800 - 0x1FFFF7FF
	STM32F09xxx	0x442	0x50	NA	0x1FFFD800 - 0x1FFFF7FF

Table 177. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory	
F1	STM32F10xxx	Low-density	0x412	NA	0x20000200 - 0x200027FF	0x1FFFF000 - 0x1FFFF7FF
		Medium-density	0x410	NA	0x20000200 - 0x20004FFF	
		High-density	0x414	NA	0x20000200 - 0x2000FFFF	
		Medium-density value line	0x420	0x10	0x20000200 - 0x20001FFF	
		High-density value line	0x428	0x10	0x20000200 - 0x20007FFF	
	STM32F105xx/107xx	0x418	NA	0x20001000 - 0x2000FFFF	0x1FFFB000 - 0x1FFFF7FF	
STM32F10xxx XL-density	0x430	0x21	0x20000800 - 0x20017FFF	0x1FFFE000 - 0x1FFFF7FF		
F2	STM32F2xxxx	0x411	0x20	0x20002000 - 0x2001FFFF	0x1FFF0000 - 0x1FFF77FF	
			0x33			
F3	STM32F373xx	0x432	0x41	0x20001400 - 0x20007FFF	0x1FFFD800 - 0x1FFFF7FF	
	STM32F378xx		0x50	0x20001000 - 0x20007FFF		
	STM32F302xB(C)/303xB(C)	0x422	0x41	0x20001400 - 0x20009FFF		
	STM32F358xx		0x50			
	STM32F301xx/302x4(6/8)	0x439	0x40	0x20001800 - 0x20003FFF		
	STM32F318xx		0x50			
	STM32F303x4(6/8)/334xx/328xx	0x438	0x50	0x20001800 - 0x20002FFF		
	STM32F302xD(E)/303xD(E)	0x446	0x40	0x20001800 - 0x2000FFFF		
STM32F398xx	0x446	0x50	0x20001800 - 0x2000FFFF			

Table 177. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
F4	STM32F40xxx/41xxx	0x413	0x31	0x20002000 - 0x2001FFFF	0x1FFF0000 - 0x1FFF77FF
			0x91	0x20003000 - 0x2001FFFF	
	STM32F42xxx/43xxx	0x419	0x70	0x20003000 - 0x2002FFFF	
			0x91	0x2002FFFF	
	STM32F401xB(C)	0x423	0xD1	0x20003000 - 0x2000FFFF	
	STM32F401xD(E)	0x433	0xD1	0x20003000 - 0x20017FFF	
	STM32F410xx	0x458	0xB1	0x20003000 - 0x20007FFF	
	STM32F411xx	0x431	0xD0	0x20003000 - 0x2001FFFF	
	STM32F412xx	0x441	0x90	0x20003000 - 0x2003FFFF	
	STM32F446xx	0x421	0x90	0x20003000 - 0x2001FFFF	
STM32F469xx/479xx	0x434	0x90	0x20003000 - 0x2005FFFF		
STM32F413xx/423xx	0x463	0x90	0x20003000 - 0x2004FFFF		
F7	STM32F72xxx/73xxx	0x452	0x90	0x20004000 - 0x2003FFFF	0x1FF00000 - 0x1FF0EDBF
	STM32F74xxx/75xxx	0x449	0x70	0x20004000 - 0x2004FFFF	0x1FF00000 - 0x1FF0EDBF
			0x90	0x20004000 - 0x2004FFFF	0x1FF00000 - 0x1FF0EDBF
STM32F76xxx/77xxx	0x451	0x93	0x20004000 - 0x2007FFFF	0x1FF00000 - 0x1FF0EDBF	

Table 177. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
G0	STM32G03xxx/04xxx	0x466	0x52	0x20001000 - 0x20001FFF	0x1FFF0000 - 0x1FFF1FFF
	STM32G07xxx/08xxx	0x460	0xB3	0x20002700 - 0x20009000	0x1FFF0000 - 0x1FFF6FFF
	STM32G0B0xx	0x467	0xD0	0x20004000 - 0x20020000	0x1FFF0000 - 0x1FFF6FFF 0x1FFF8000 - 0x1FFFEFFF
	STM32G0B1xx/0C1xx	0x467	0x92	0x20004000 - 0x20020000	0x1FFF0000 - 0x1FFF6FFF 0x1FFF8000 - 0x1FFFEFFF
	STM32G05xxx/061xx	0x456	0x51	0x20001000 - 0x20002000	0x1FFF0000 - 0x1FFF1FFF
G4	STM32G431xx/441xx	0x468	0xD4	0x20004000 - 0x20005800	0x1FFF0000 - 0x1FFF7000
	STM32G47xxx/48xxx	0x469	0xD5	0x20004000 - 0x20018000	0x1FFF0000 - 0x1FFF7000
	STM32G491xx/A1xx	0x479	0xD2	0x20004000 - 0x2001C000	0x1FFF0000 - 0x1FFF7000
H5	STM32H503xx	0x474	0xE1	0x20004000 - 0x20007FFF	0x0BF87000 - 0x0BF8FFFF
	STM32H563xx/573xx	0x484	0xE3	0x20000000 - 0x2009FFFF	0x0BF97000 - 0x0BF9FFFF
H7	STM32H72xxx/73xxx	0x483	0x93	0x20004100 - 0x2001FFFF 0x24004000 - 0x2404FFFF	0x1FF00000 - 0x1FF1E7FF
	STM32H74xxx/75xxx	0x450	0x91	0x20004100 - 0x2001FFFF 0x24005000 - 0x2407FFFF	0x1FF00000 - 0x1FF1E7FF
	STM32H7A3xx/B3xx	0x480	0x92	0x20004100 - 0x2001FFFF 0x24034000 - 0x2407FFFF	0x1FF00000 - 0x1FF13FFF

Table 177. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
L0	STM32L01xxx/02xxx	0x457	0xC3	NA	0x1FF00000 - 0x1FF00FFF
	STM32L031xx/041xx	0x425	0xC0	0x20001000 - 0x20001FFF	0x1FF00000 - 0x1FF00FFF
	STM32L05xxx/06xxx	0x417	0xC0	0x20001000 - 0x20001FFF	0x1FF00000 - 0x1FF00FFF
	STM32L07xxx/08xxx	0x447	0x41	0x20001000 - 0x20004FFF	0x1FF00000 - 0x1FF01FFF
	0xB2		0x20001400 - 0x20004FFF		
L1	STM32L1xxx6(8/B)	0x416	0x20	0x20000800 - 0x20003FFF	0x1FF00000 - 0x1FF01FFF
	STM32L1xxx6(8/B)A	0x429	0x20	0x20001000 - 0x20007FFF	
	STM32L1xxxC	0x427	0x40		
	STM32L1xxxD	0x436	0x45	0x20001000 - 0x2000BFFF	
	STM32L1xxxE	0x437	0x40	0x20001000 - 0x20013FFF	
L4	STM32L412xx/422xx	0x464	0xD1	0x20002100 - 0x20008000	0x1FFF0000 - 0x1FFF6FFF
	STM32L43xxx/44xxx	0x435	0x91	0x20003100 - 0x2000BFFF	0x1FFF0000 - 0x1FFF6FFF
	STM32L45xxx/46xxx	0x462	0x92	0x20003100 - 0x2001FFFF	0x1FFF0000 - 0x1FFF6FFF
	STM32L47xxx/48xxx	0x415	0xA3	0x20003000 - 0x20017FFF	0x1FFF0000 - 0x1FFF6FFF
			0x92	0x20003100 - 0x20017FFF	
	STM32L496xx/4A6xx	0x461	0x93	0x20003100 - 0x2003FFFF	0x1FFF0000 - 0x1FFF6FFF
	STM32L4Rxx/4Sxx	0x470	0x95	0x20003200 - 0x2009FFFF	0x1FFF0000 - 0x1FFF6FFF
	STM32L4P5xx/Q5xx	0x471	0x90	0x20004000 - 0x2004FFFF	0x1FFF0000 - 0x1FFF6FFF
L5	STM32L552xx/562xx	0x472	0x92	0x20004000 - 0x2003FFFF	0x0BF90000 - 0x0BF97FFF
WBA	STM32WBA52xx	0x492	0XB0	0x20000000 - 0x20001FFF	0x0BF88000 - 0x0BF8FFFF

Table 177. Bootloader device-dependent parameters (continued)

STM32 series	Device	PID	BL ID	RAM	System memory
WB	STM32WB10xx/15xx	0x494	0xB1	0x20005000 - 0x20040000	0x1FFF0000 - 0x1FFF7000
	STM32WB30xx/35xx/50xx/WB55xx	0x495	0xD5	0x20004000 - 0x2000BFFF	0x1FFF0000 - 0x1FFF7000
WL	STM32WLE5xx/WL55xx	0x497	0xC4	0x20002000 - 0x2000FFFF	0x1FFF0000 - 0x1FFF3FFF
U5	STM32U535xx/545xx	0x455	0x91	0x20004000 - 0x2023FFFF	0x0BF90000 - 0x0BF9FFFF
	STM32U575xx/ STM32U585xx	0x482	0x92	0x20004000 - 0x200BFFFF	0x0BF90000 - 0x0BF9FFFF
	STM32U595xx/599xx/5A9xx	0x481	0x92	0x20004000 - 0x2026FFFF	0x0BF90000 - 0x0BF9FFFF
	STM32U5F7xx/5F9xx/5G7xx/5G9xx	0x476	0x90	0x20004000 - 0x202EFFFF	0x0BF90000 - 0x0BF9FFFF

80 Bootloader timings

This section presents the timings of the bootloader firmware to use for correct synchronization between host and the STM32 device.

Two types of timings are described, namely STM32 device bootloader resources initialization duration, and communication interface selection duration.

After these timings the bootloader is ready to receive and execute host commands.

80.1 Bootloader startup timing

After bootloader reset, the host must wait until the STM32 bootloader is ready to start detection phase with a specific interface communication. This time corresponds to bootloader startup timing, during which resources used by bootloader are initialized.

Figure 103. Bootloader startup timing description

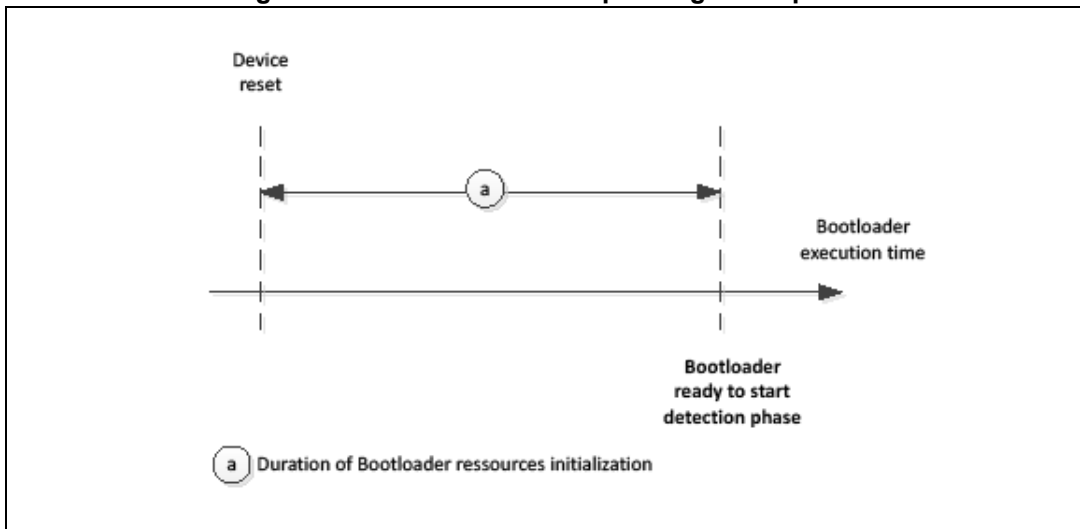


Table 178. Bootloader startup timings (ms) for STM32 devices

Device	Minimum bootloader startup	HSE timeout
STM32F03xx4/6	1.612	NA
STM32F05xxx and STM32F030x8 devices	1.612	NA
STM32F04xxx	0.058	NA
STM32F071xx/072xx	0.058	NA
STM32F070x6	HSE connected	200
	HSE not connected	
STM32F070xB	HSE connected	200
	HSE not connected	
STM32F09xxx	2	NA

Table 178. Bootloader startup timings (ms) for STM32 devices (continued)

Device		Minimum bootloader startup	HSE timeout
STM32F030xC		2	NA
STM32F10xxx		1.227	NA
STM32F105xx/107xx	PA9 pin low	1.396	NA
	PA9 pin high	524.376	
STM32F10xxx XL-density		1.227	NA
STM32F2xxxx	V2.x	134	NA
	V3.x	84.59	0.790
STM32F301xx/302x4(6/8)	HSE connected	45	560.5
	HSE not connected	560.8	
STM32F302xB(C)/303xB(C)	HSE connected	43.4	2.236
	HSE not connected	2.36	
STM32F302xD(E)/303xD	HSE connected	7.53	NA
	HSE not connected	146.71	NA
STM32F303x4(6/8)/334xx/328xx		0.155	NA
STM32F318xx		0.182	NA
STM32F358xx		1.542	NA
STM32F373xx	HSE connected	43.4	2.236
	HSE not connected	2.36	
STM32F378xx		1.542	NA
STM32F398xx		1.72	NA
STM32F40xxx/41xxx	V3.x	84.59	0.790
	V9.x	74	96
STM32F401xB(C)		74.5	85
STM32F401xD(E)		74.5	85
STM32F410xx		0.614	NA
STM32F411xx		74.5	85
STM32F412xx		0.614	180
STM32F413xx/423xx		0.642	165
STM32F429xx/439xx	V7.x	82	97
	V9.x	74	97
STM32F446xx		73.61	96
STM32F469xx/479xx		73.68	230
STM32F72xxx/73xxx		17.93	50
STM32F74xxx/75xxx		16.63	50

Table 178. Bootloader startup timings (ms) for STM32 devices (continued)

Device		Minimum bootloader startup	HSE timeout
STM32G03xxx/04xxx		0.390	NA
STM32G07xxx/08xxx		0.390	NA
STM32G0Bxxx/Cxxx		0.390	NA
STM32G05xxx/061xx		0.390	NA
STM32G4xxxx		0.390	NA
STM32H503xx		0,238	NA
STM32H563xx/73xx		0.292	NA
STM32H72xxx/73xxx		53.975	NA
STM32H74xxx/75xxx		53.975	2
STM32H7A3xx/B3xx		545	NA
STM32L01xxx/02xxx		0.63	NA
STM32L031xx/041xx		0.62	NA
STM32L05xxx/06xxx		0.22	NA
STM32L07xxx/08xxx	V4.x	0.61	NA
	V11.x	0.71	NA
STM32L1xxx6(8/B)A		0.542	NA
STM32L1xxx6(8/B)		0.542	NA
STM32L1xxxC		0.708	80
STM32L1xxxD		0.708	80
STM32L1xxxE		0.708	200
STM32L43xxx/44xxx		0.86	100
STM32L45xxx/46xxx		0.86	NA
STM32L47xxx/48xxx	V10.x	LSE connected	55
		LSE not connected	2560
	V9.x	LSE connected	55.40
		LSE not connected	2560.51
STM32L412xx/422xx		0.86	NA
STM32L496xx/4A6xx		76.93	100
STM32L4P5xx /Q5xx		NA	NA
STM32L4Rxx/4Sxx		NA	NA
STM32L552xx/562xx		0.390	NA
STM32BA52xx		0.390	NA
STM32WB10xx/15xx/30xx/35xx/50xx/55xx		0.390	NA
STM32WLE5xx/WL55xx		0.390	NA

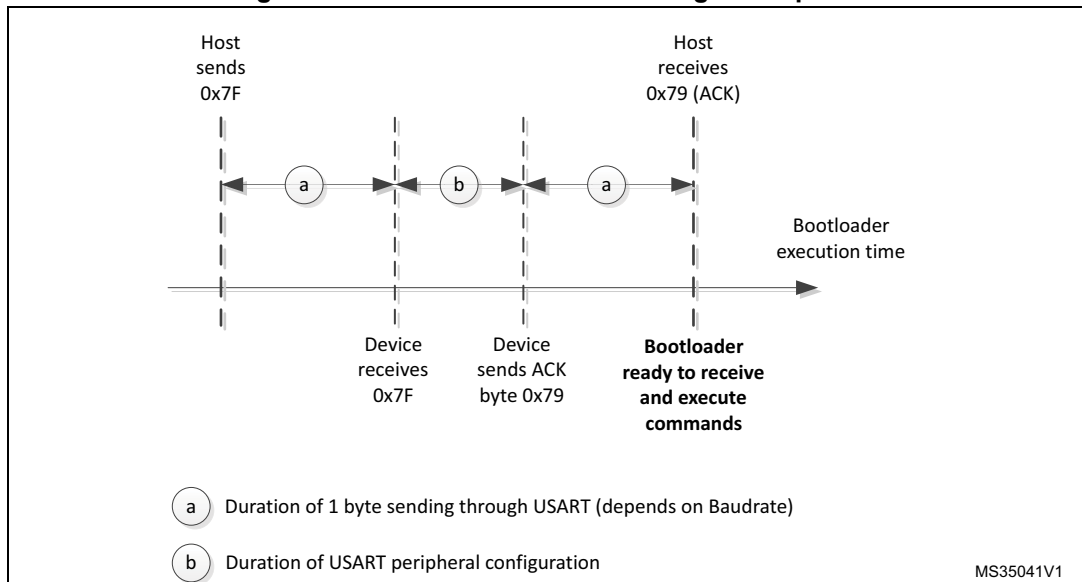
Table 178. Bootloader startup timings (ms) for STM32 devices (continued)

Device	Minimum bootloader startup	HSE timeout
STM32U535xx/545xx	0.390	NA
STM32U575xx/85xx	0.390	NA
STM32U595xx/599xx/5A5xx/5A9xx	0.390	NA
STM32U5F7xx/5F9xx/5G7xx/5G9xx	0.390	NA

80.2 USART connection timing

USART connection timing is the time that the host must wait for between sending the synchronization data (0x7F) and receiving the first acknowledge response (0x79).

Figure 104. USART connection timing description



1. Receiving characters different from 0x7F (or line glitches) causes bootloader to start communication using a wrong baudrate. Bootloader measures the signal length between rising edge of the first bit to the falling edge of the last bit to deduce the baudrate value
2. Bootloader does not realign the calculated baudrate to standard baudrate values (i.e. 1200, 9600, 115200).

Note: PA9 pin (USB_VBUS) on STM32F105xx/107xx devices is used to detect the USB host connection. The initialization of USB peripheral is performed only if PA9 is high at detection phase, which means that a host is connected to the port and delivering 5 V on the USB bus. When PA9 level is high at detection phase, more time is required to initialize and shutdown the USB peripheral. To minimize bootloader detection time when PA9 pin is not used, keep PA9 low during USART detection phase, from the moment the device is reset, until a device ACK is sent.

Table 179. USART bootloader minimum timings (ms) for STM32 devices

Device	One USART byte sending	USART configuration	USART connection
STM32F03xx4/6	0.078125	0.0064	0.16265
STM32F05xxx and STM32F030x8 devices	0.078125	0.0095	0.16575
STM32F04xxx	0.078125	0.007	0.16325
STM32F071xx/072xx	0.078125	0.007	0.16325
STM32F070x6	0.078125	0.014	0.17
STM32F070xB	0.078125	0.08	0.23
STM32F09xxx	0.078125	0.07	0.22
STM32F030xC	0.078125	0.07	0.22
STM32F10xxx	0.078125	0.002	0.15825
STM32F105xx/107xx	PA9 pin low	0.078125	0.007
		PA9 pin High	105
STM32F10xxx XL-density	0.078125	0.006	0.16225
STM32F2xxxx	V2.x	0.078125	0.009
	V3.x		
STM32F301xx/302x4(6/8)	HSE connected	0.078125	0.002
	HSE not connected		
STM32F302xB(C)/303xB(C)	HSE connected	0.078125	0.002
	HSE not connected		
STM32F302xD(E)/303xD	0.078125	0.002	0.15885
STM32F303x4(6/8)/334xx/328xx	0.078125	0.002	0.15825
STM32F318xx	0.078125	0.002	0.15825
STM32F358xx	0.15625	0.001	0.3135
STM32F373xx	HSE connected	0.078125	0.002
	HSE not connected		
STM32F378xx	0.15625	0.001	0.3135
STM32F398xx	0.078125	0.002	0.15885
STM32F40xxx/41xxx	V3.x	0.078125	0.009
	V9.x		0.0035
STM32F401xB(C)	0.078125	0.00326	0.15951
STM32F401xD(E)	0.078125	0.00326	0.15951
STM32F410xx	0.078125	0.002	0.158
STM32F411xx	0.078125	0.00326	0.15951
STM32F412xx	0.078125	0.002	0.158
STM32F413xx/423xx	0.078125	0.002	0.158

Table 179. USART bootloader minimum timings (ms) for STM32 devices (continued)

Device		One USART byte sending	USART configuration	USART connection
STM32F429xx/439xx	V7.x	0.078125	0.007	0.16325
	V9.x		0.00326	0.15951
STM32F446xx		0.078125	0.004	0.16
STM32F469xx/479xx		0.078125	0.003	0.159
STM32F72xxx/73xxx		0.078125	0.070	0.22
STM32F74xxx/75xxx		0.078125	0.065	0.22
STM32G03xxx/04xxx		0.078125	0.01	0.11
STM32G07xxx/08xxx		0.078125	0.01	0.11
STM32G0Bxxx/Cxxx		0.078125	0.01	0.11
STM32G05xxx/061xx		0.078125	0.01	0.11
STM32G4xxxx		0.078125	0.003	0.159
STM32H503xx		0.048	0.05	0.101
STM32H563xx/73xx		0.047	0.06	0.100
STM32H72xxx/73xxx		0.078125	0.072	0.22825
STM32H74xxx/75xxx		0.078125	0.072	0.22825
STM32H7A3xx/B3xx		0.078125	0.072	0.22825
STM32L01xxx/02xxx		0.078125	0.016	0.17
STM32L031xx/041xx		0.078125	0.018	0.174
STM32L05xxx/06xxx		0.078125	0.018	0.17425
STM32L07xxx/08xxx	V4.x	0.078125	0.017	0.173
	V11.x	0.078125	0.017	0.158
STM32L1xxx6(8/B)A		0.078125	0.008	0.16425
STM32L1xxx6(8/B)		0.078125	0.008	0.16425
STM32L1xxxC		0.078125	0.008	0.16425
STM32L1xxxD		0.078125	0.008	0.16425
STM32L1xxxE		0.078125	0.008	0.16425
STM32L412xx/422xx		0.078125	0.005	0.2
STM32L43xxx/44xxx		0.078125	0.003	0.159
STM32L45xxx/46xxx		0.078125	0.07	0.22
STM32L47xxx/48xxx	V10.x	0.078125	0.003	0.159
	V9.x	0.078125	0.003	0.159
STM32L496xx/4A6xx		0.078125	0.003	0.159
STM32L4Rxx/4Sxx		NA	NA	NA
STM32L4P5xx/4Q5xx		NA	NA	NA

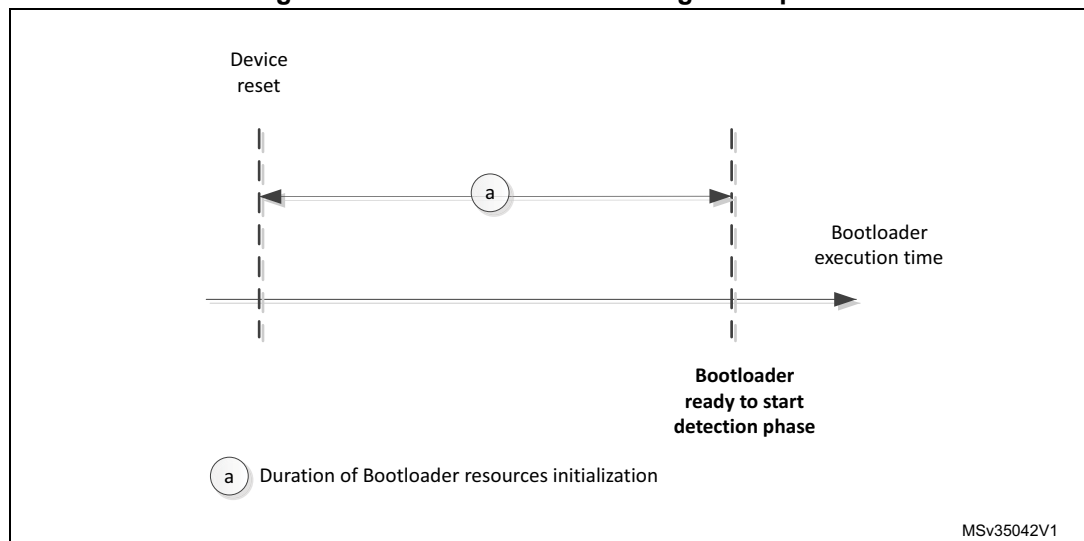
Table 179. USART bootloader minimum timings (ms) for STM32 devices (continued)

Device	One USART byte sending	USART configuration	USART connection
STM32L552xx/562xx	0.078125	0.01	0.11
STM32WBA52xx	0.078125	0.001	NA
STM32WB10xx/15xx/30xx/35xx/50xx/55xx	0.078125	0.003	0.159
STM32WLE5xx/WL55xx	0.078125	0.001	0.110
STM32U535xx/545xx	0.078125	0.001	NA
STM32U575xx/85xx	0.078125	0.001	NA
STM32U595xx/599xx/5A5xx/5A9xx	0.078125	0.001	NA
STM32U5F7xx/5F9xx/5G7xx/5G9xx	0.078125	0.001	NA

80.3 USB connection timing

USB connection timing is the time that the host must wait for between plugging the USB cable and establishing a correct connection with the device. This timing includes enumeration and DFU components configuration. USB connection depends on the host.

Figure 105. USB connection timing description



Note: For STM32F105xx/107xx devices, if the external HSE crystal frequency is different from 25 MHz (14.7456 MHz or 8 MHz), the device performs several unsuccessful enumerations (with connect/disconnect sequences) before establishing a correct connection with the host. This is due to the HSE automatic detection mechanism based on Start Of Frame (SOF) detection.

Table 180. USB bootloader minimum timings (ms) for STM32 devices

Device		USB connection
STM32F04xxx		350
STM32F070x6		TBD
STM32F070xB		320
STM32F105xx/107xx	HSE = 25 MHz	460
	HSE = 14.7465 MHz	4500
	HSE = 8 MHz	13700
STM32F2xxxx		270
STM32F301xx/302x4(6/8)		300
STM32F302xB(C)/303xB(C)		300
STM32F302xD(E)/303xD		100
STM32F373xx		300
STM32F40xxx/41xxx	V3.x	270
	V9.x	250
STM32F401xB(C)		250
STM32F401xD(E)		250
STM32F411xx		250
STM32F412xx		380
STM32F413xx/423xx		350
STM32F429xx/439xx	V7.x	250
	V9.x	
STM32F446xx		200
STM32F469xx/479xx		270
STM32F72xxx/73xxx		320
STM32F74xxx/75xxx		230
STM32G0B1xx/C1xx		300
STM32G4xxxx		300
STM32H503xx		251
STM32H563xx/73xx		245
STM32H72xxx/73xxx		53.9764
STM32H74xxx/75xxx		53.9764
STM32H7A3xx/B3xx		53.9764
STM32L07xxx/08xxx		140
STM32L1xxxC		849
STM32L1xxxD		849
STM32L412xx/422xx		820

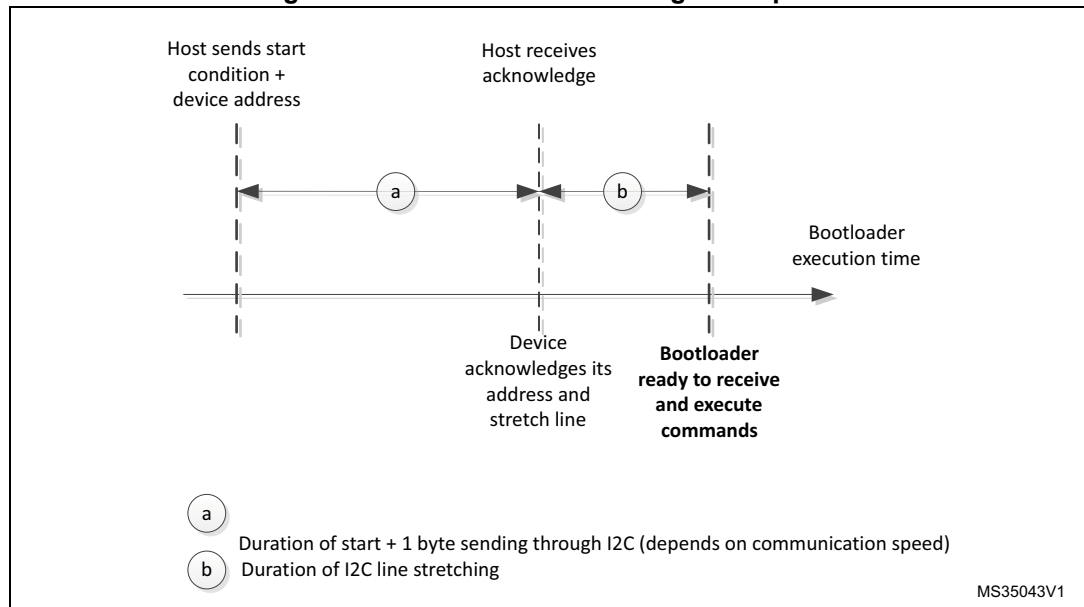
Table 180. USB bootloader minimum timings (ms) for STM32 devices (continued)

Device		USB connection
STM32L43xxx/44xxx		820
STM32L45xxx/46xxx		330
STM32L47xxx/48xxx	V10.x	300
	V9.x	
STM32L496xx/4A6xx		430
STM32L4P5xx/4Q5xx		NA
STM32L4Rxx/4Sxx		NA
STM32L552xx/L562xx		300
STM32WB30xx/35xx/50xx/55xx		300
STM32U535xx/545xx		300
STM32U575xx/85xx		300
STM32U595xx/599xx/5A5xx/5A9xx		300
STM32U5F7xx/5F9xx/5G7xx/5G9xx		300

80.4 I2C connection timing

I2C connection timing is the time that the host must wait for between sending I2C device address and sending command code. This timing includes I2C line stretching duration.

Figure 106. I2C connection timing description



Note: For I2C communication, a timeout mechanism is implemented and must be respected to execute bootloader commands correctly. This timeout is implemented between two I2C frames in the same command (example: for Write memory command, a timeout is inserted between command sending frame and address memory sending frame). The same timeout period is inserted between two successive data receptions or transmissions in the same I2C frame. If the timeout period elapses, a system reset is generated to avoid bootloader crash.

In Erase memory and Read-out unprotect commands, consider the duration of the operation when implementing the host side. After sending the code of pages to erase, the host must wait until the bootloader device performs page erasing to complete the remaining steps of erase command.

Table 181. I2C bootloader minimum timings (ms) for STM32 devices

Device	Start condition + one I2C byte sending	I2C line stretching	I2C connection	I2C timeout
STM32F04xxx	0.0225	0.0025	0.0250	1000
STM32F070x6	0.0225	0.0025	0.0245	1000
STM32F070xB	0.0225	0.0025	0.0245	1000
STM32F071xx/072xx	0.0225	0.0025	0.0250	1000
STM32F09xxx	0.0225	0.0025	0.0245	1000
STM32F030xC	0.0225	0.0025	0.0250	1000
STM32F303x4(6/8)/334xx/328xx	0.0225	0.0027	0.0252	1000

Table 181. I2C bootloader minimum timings (ms) for STM32 devices (continued)

Device	Start condition + one I2C byte sending	I2C line stretching	I2C connection	I2C timeout	
STM32F318xx	0.0225	0.0027	0.0252	1000	
STM32F358xx	0.0225	0.0055	0.0280	10	
STM32F378xx	0.0225	0.0055	0.0280	10	
STM32F398xx	0.0225	0.0020	0.0245	1500	
STM32F40xxx/41xxx	0.0225	0.0022	0.0247	1000	
STM32F401xB(C)	0.0225	0.0022	0.0247	1000	
STM32F401xD(E)	0.0225	0.0022	0.0247	1000	
STM32F410xx	0.0225	0.0020	0.0245	1000	
STM32F411xx	0.0225	0.0022	0.0247	1000	
STM32F412xx	0.0225	0.0020	0.0245	1000	
STM32F413xx/423xx	0.0225	0.0020	0.0245	1000	
STM32F42xxx/43xxx	V7.x	0.0225	0.0033	0.0258	1000
	V9.x	0.0225	0.0022	0.0247	1000
STM32F446xx	0.0225	0.0020	0.0245	1000	
STM32F469xx/479xx	0.0225	0.0020	0.0245	1000	
STM32F72xxx/73xxx	0.0225	0.0020	0.0245	1000	
STM32F74xxx/75xxx	0.0225	0.0020	0.0245	500	
STM32G03xxx/04xxx	0.0225	0.0020	0.0245	1000	
STM32G07xxx/08xxx	0.0225	0.0020	0.0245	1000	
STM32G0Bxx/Cxx	0.0225	0.0020	0.0245	1000	
STM32G05xxx/061xx	0.0225	0.0020	0.0245	1000	
STM32G4xxxx	0.0225	0.0020	0.0245	1000	
STM32H503xx	0.038	0.03	0.041	1000	
STM32H563xx/73xx	0.039	0.02	0.041	1000	
STM32H72xxx/73xxx	0.0225	0.05	0.0745	1000	
STM32H74xxx/75xxx	0.0225	0.05	0.0725	1000	
STM32H7A3xx/7B3xx	0.0225	0.05	0.0745	1000	
STM32L07xxx/08xxx	0.0225	0.0020	0.0245	1000	
STM32L412xx/422xx	0.0225	0.0020	0.0245	1000	
STM32L43xxx/44xxx	0.0225	0.0020	0.0245	1000	
STM32L45xxx/46xxx	0.0225	0.0020	0.0245	1000	
STM32L47xxx/48xxx	V10.x	0.0225	0.0020	0.0245	1000
	V9.x	0.0225	0.0020	0.0245	1000

Table 181. I2C bootloader minimum timings (ms) for STM32 devices (continued)

Device	Start condition + one I2C byte sending	I2C line stretching	I2C connection	I2C timeout
STM32L496xx/4A6xx	0.0225	0.0020	0.0245	1000
STM32L4P5xx/4Q5xx	NA	NA	NA	NA
STM32L4Rxx/4Sxx	NA	NA	NA	NA
STM32L552xx/L562xx	0.0225	0.0020	0.0245	1000
STM32WBA52xx	0.0225	0.0020	0.0245	1000
STM32WB10xx/15xx/30xx/35xx/50xx/55xx	0.0225	0.0020	0.0245	1000
STM32U535xx/545xx	0.0225	0.0020	0.0245	1000
STM32U575xx/85xx	0.0225	0.0020	0.0245	1000
STM32U595xx/599xx/5A5xx/5A9xx	0.0225	0.0020	0.0245	1000
STM32U5F7xx/5F9xx/5G7xx/5G9xx	0.0225	0.0020	0.0245	1000

80.5 SPI connection timing

SPI connection timing is the time that the host must wait for between sending the synchronization data (0xA5) and receiving the first acknowledge response (0x79).

Figure 107. SPI connection timing description

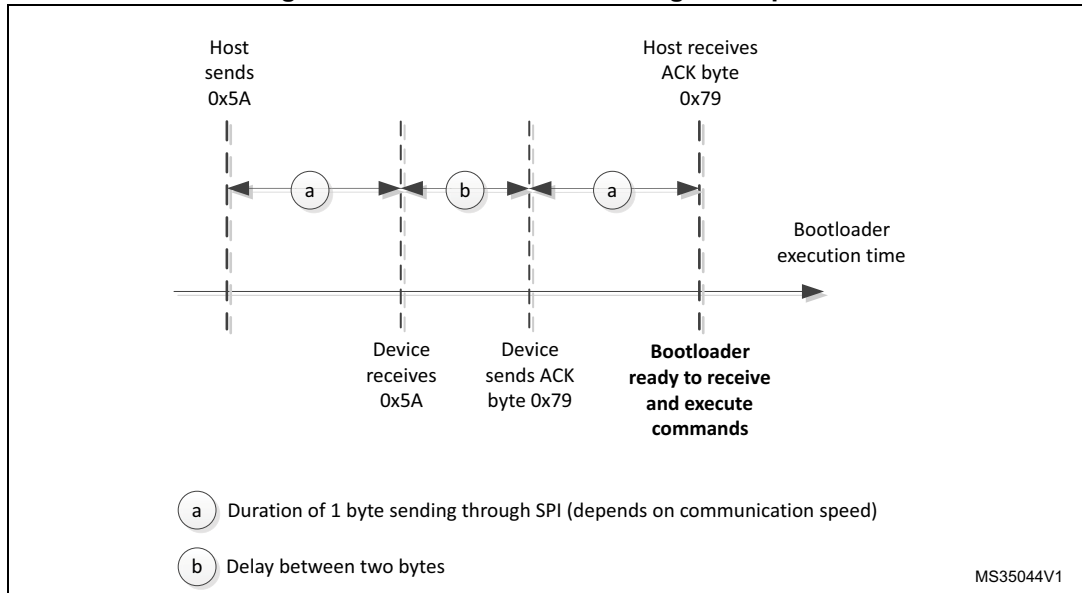


Table 182. SPI bootloader minimum timings (ms) for STM32 devices

Device	One SPI byte sending	Delay between two bytes	SPI connection
All products	0.001	0.008	0.01

Appendix A Example of function to use the “ExitSecureMemory” function

```

/**
*****
****
* @file    main.c
*****
****
*/

/* Includes -----
---*/
#include "main.h"

/* Private function prototypes -----
---*/
static void ConfigClock(void);

void JUMP_WITHOUT_PARAM(uint32_t jump_address);
void JUMP_WITH_PARAM(uint32_t jump_address, uint32_t magic, uint32_t
applicationVectorAddress);

/* Private functions -----
---*/

/**
* @brief  Main program
* @param  None
* @retval None
*/
int main(void)
{
    ConfigClock();

    uint32_t application_address           = 0x08000800;
    uint32_t exit_secure_memory_address   = 0x1FFF1E00;
    uint32_t magic_number                 = 0x08192A3C;
    uint32_t exit_with_magic_number       = 0x0;

    if (exit_with_magic_number)
    {
        JUMP_WITH_PARAM(exit_secure_memory_address, magic_number,
application_address);
    }
}

```

```
else
{
    JUMP_WITHOUT_PARAM(exit_secure_memory_address);
}
}

/**
 * @brief ConfigClock
 * @param None
 * @retval None
 */
static void ConfigClock(void)
{
    /* Will be developed as per the template of the needed project */
}

/**
 * @brief JUMP_WITHOUT_PARAM
 * @param jump_address
 * @retval None
 */
void JUMP_WITHOUT_PARAM(uint32_t jump_address)
{
    asm ("LDR R1, [R0]");    // jump_address
    asm ("LDR R2, [R0,#4]");
    asm ("MOV SP, R1");
    asm ("BX R2");
}

/**
 * @brief JUMP_WITH_PARAM
 * @param jump_address, magic, applicationVectorAddress
 * @retval None
 */
void JUMP_WITH_PARAM(uint32_t jump_address, uint32_t magic, uint32_t
applicationVectorAddress)
{
    asm ("MOV R3, R0");    // jump_address
    asm ("LDR R0, [R3]");
    asm ("MOV SP, R0");
    asm ("LDR R0, [R3,#4]");
    asm ("BX R0");
}
```

```
/****** (C) COPYRIGHT STMicroelectronics *****END OF  
FILE*****/
```

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Table 183. Document revision history

Date	Revision	Changes
21-Feb-2019	36	<p>Updated Table 1: Applicable products, Section 3: Glossary, Table 3: Embedded bootloaders, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 180: USB bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices.</p> <p>Added Section 73: STM32WB30xx/35xx/50xx/55xx devices bootloader</p>
06-May-2019	37	<p>Updated Table 1: Applicable products, Section 3: Glossary, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 180: USB bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices.</p> <p>Added Section 46: STM32G431xx/441xx devices bootloader, Section 47: STM32G47xxx/48xxx devices bootloader</p>
08-Jul-2019	38	<p>Updated:</p> <ul style="list-style-type: none"> – Table 1: Applicable products, Table 2: Bootloader activation patterns, Table 3: Embedded bootloaders, Table 71: STM32F413xx/423xx configuration in system memory boot mode, Table 113: STM32H74xxx/75xxx configuration in system memory boot mode, Table 114: STM32H74xxx/75xxx bootloader version, Table 119: STM32L031xx/041xx configuration in system memory boot mode, Table 140: STM32L43xxx/44xxx bootloader versions, Table 141: STM32L45xxx/46xxx configuration in system memory boot mode, Table 148: STM32L496xx/4A6xx bootloader version, Table 162: STM32WB30xx/35xx/50xx/55xx bootloader versions, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 180: USB bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices – Section 3: Glossary, Section 4.1: Bootloader activation, Section 41.1: Bootloader configuration, Section 46.1: Bootloader configuration – Figure 64: Bootloader V9.x selection for STM32H74xxx/75xxx, Figure 92: Dual bank boot implementation for STM32L4Rxxx/STM32L4Sxxx bootloader V9.x <p>Added Note: in Section 4.2, Note: in Section 15.3, Note: in Section 52.1, Note: in Section 54.1, Section 41: STM32G03xxx/STM32G04xxx devices bootloader</p>

Table 183. Document revision history (continued)

Date	Revision	Changes
16-Sep-2019	39	<p>Updated:</p> <ul style="list-style-type: none"> – Table 1: Applicable products, Table 2: Bootloader activation patterns, Table 3: Embedded bootloaders, Table 90: STM32G03xx/04xxx bootloader versions, Table 138: STM32L412xx/422xx bootloader versions, Table 140: STM32L43xxx/44xxx bootloader versions, Table 142: STM32L45xxx/46xxx bootloader versions, Table 144: STM32L47xxx/48xxx bootloader V10.x versions, Table 146: STM32L47xxx/48xxx bootloader V9.x versions, Table 148: STM32L496xx/4A6xx bootloader version, Table 150: STM32L4P5xx/4Q5xx bootloader versions, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 180: USB bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices – Section 3: Glossary, Section 4.2: Bootloader identification <p>Added Figure 59: Dual bank boot implementation for STM32G47xxx/48xxx bootloader V13.x, Section 70: STM32L552xx/STM32L562xx devices bootloader, note in Section 73.3: Bootloader version</p>
03-Oct-2019	40	<p>Updated Table 3: Embedded bootloaders, Table 155: STM32L552xx/562xx bootloader versions, Table 162: STM32WB30xx/35xx/50xx/55xx bootloader versions</p>
25-Oct-2019	41	<p>Updated:</p> <ul style="list-style-type: none"> – Table 82: STM32F72xxx/73xxx bootloader V9.x versions, Table 84: STM32F74xxx/75xxx bootloader V7.x versions, Table 86: STM32F74xxx/75xxx bootloader V9.x versions, Table 88: STM32F76xxx/77xxx bootloader V9.x versions, Table 89: STM32G03xxx/G04xxx configuration in system memory boot mode, Table 114: STM32H74xxx/75xxx bootloader version, Table 150: STM32L4P5xx/4Q5xx bootloader versions, Table 153: STM32L552xx/562xx configuration in system memory boot mode, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices – Section 18: STM32F2xxxx devices bootloader
05-Dec-2019	42	<p>Updated:</p> <ul style="list-style-type: none"> – Table 1: Applicable products, Table 2: Bootloader activation patterns, Table 3: Embedded bootloaders, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 180: USB bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices – Section 3: Glossary <p>Added: Section 53: STM32H7A3xx/B3xx devices bootloader, Section 68: STM32L4P5xx/4Q5xx devices bootloader, Section 74: STM32WLE5xx/55xx devices bootloader</p>

Table 183. Document revision history (continued)

Date	Revision	Changes
04-Jun-2020	43	<p>Updated:</p> <ul style="list-style-type: none"> – Table 1: Applicable products, Table 2: Bootloader activation patterns, Table 3: Embedded bootloaders, Table 99: STM32G431xx/441xx configuration in system memory boot mode, Table 101: STM32G47xxx/48xxx configuration in system memory boot mode, Table 102: STM32G47xxx/48xxx bootloader version, Table 114: STM32H74xxx/75xxx bootloader version, Table 116: STM32H7A3xx/7B3xx bootloader version, Table 150: STM32L4P5xx/4Q5xx bootloader versions, Table 153: STM32L552xx/562xx configuration in system memory boot mode, Table 155: STM32L552xx/562xx bootloader versions, Table 161: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode, Table 177: Bootloader device-dependent parameters – Section 3: Glossary, Section 39: STM32F74xxx/75xxx devices bootloader, Section 41.1: Bootloader configuration, Section 42.1: Bootloader configuration, Section 46.1: Bootloader configuration, Section 47.1: Bootloader configuration, Section 52.1: Bootloader configuration <p>Added:</p> <ul style="list-style-type: none"> – Section 4.5: Bootloader UART baudrate detection, Section 4.6: Programming constraints, Section 4.7: ExitSecureMemory feature – Note in: Section 28.1.1: Bootloader configuration, Section 28.2.1: Bootloader configuration, Section 29.1: Bootloader configuration, Section 30.1: Bootloader configuration, Section 32.1: Bootloader configuration, Section 33.1: Bootloader configuration, Section 34.1: Bootloader configuration, Section 35.1.1: Bootloader configuration, Section 35.2.1: Bootloader configuration, Section 36.1: Bootloader configuration, Section 37.1: Bootloader configuration, Section 38.1: Bootloader configuration, Section 39.1.1: Bootloader configuration, Section 39.2.1: Bootloader configuration, Section 40.1: Bootloader configuration – Figure 80: Dual bank boot Implementation for STM32L3x2xx/44xxx bootloader V9.x, Figure 82: Dual bank boot implementation for STM32L45xxx/46xxx bootloader V9.x, Figure 88: Dual bank boot Implementation for STM32L496xx/4A6xx bootloader V9.x – Appendix A: Example of function to use the “ExitSecureMemory” function <p>Deleted Figure 48. Access to securable memory area from the bootloader for STM32G03xxx/G04xxx, Figure 50. Access to securable memory area from the bootloader for STM32G07xxx/G08xxx, Figure 52. Access to securable memory area, Figure 54. Access to securable memory area</p>
29-Jul-2020	44	<p>Introduced STM32H72xxx/73xxx devices, hence added Section 51: STM32H72xxx/73xxx devices bootloader and its subsections.</p> <p>Updated Section 3: Glossary, note in Section 41.1: Bootloader configuration and Section 73.1: Bootloader configuration.</p> <p>Updated Table 1: Applicable products, Table 2: Bootloader activation patterns, Table 3: Embedded bootloaders, Table 8: ExitSecureMemory entry address, Table 101: STM32G47xxx/48xxx configuration in system memory boot mode, Table 116: STM32H7A3xx/7B3xx bootloader version, Table 131: STM32L1xxxC configuration in system memory boot mode, Table 133: STM32L1xxxD configuration in system memory boot mode, Table 135: STM32L1xxxE configuration in system memory boot mode, Table 153: STM32L552xx/562xx configuration in system memory boot mode, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 180: USB bootloader minimum timings (ms) for STM32 devices and Table 181: I2C bootloader minimum timings (ms) for STM32 devices.</p> <p>Updated Figure 64: Bootloader V9.x selection for STM32H74xxx/75xxx.</p> <p>Minor text edits across the whole document.</p>

Table 183. Document revision history (continued)

Date	Revision	Changes
06-Nov-2020	45	<p>Introduced STM32WB30xx, STM32WB35xx, STM32WI55xx in Table 1: Applicable products, Table 3: Embedded bootloaders and in Section 3: Glossary</p> <p>Updated:</p> <ul style="list-style-type: none"> – Table 65: STM32F410xx configuration in system memory boot mode, Table 71: STM32F413xx/423xx configuration in system memory boot mode, Table 77: STM32F446xx configuration in system memory boot mode, Table 79: STM32F469xx/479xx configuration in system memory boot mode, Table 81: STM32F72xxx/73xxx configuration in system memory boot mode, Table 85: STM32F74xxx/75xxx configuration in system memory boot mode, Table 87: STM32F76xxx/77xxx configuration in system memory boot mode, Table 91: STM32G07xxx/8xxx configuration in system memory boot mode, Table 99: STM32G431xx/441xx configuration in system memory boot mode, Table 100: STM32G431xx/441xx bootloader version, Table 101: STM32G47xxx/48xxx configuration in system memory boot mode, Table 113: STM32H74xxx/75xxx configuration in system memory boot mode, Table 114: STM32H74xxx/75xxx bootloader version, Table 115: STM32H7A3xx/7B3xx configuration in system memory boot mode, Table 116: STM32H7A3xx/7B3xx bootloader version, Table 117: STM32L01xxx/02xxx configuration in system memory boot mode, Table 119: STM32L031xx/041xx configuration in system memory boot mode, Table 124: STM32L07xxx/08xxx bootloader versions, Table 125: STM32L07xxx/08xxx configuration in system memory boot mode, Table 137: STM32L412xx/422xx configuration in system memory boot mode, Table 149: STM32L4P5xx/4Q5xx configuration in system memory boot mode, Table 151: STM32L4Rxxx/4Sxxx configuration in system memory boot mode, Table 153: STM32L552xx/562xx configuration in system memory boot mode, Table 161: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode, Table 163: STM32WLE5xx/55xx configuration in system memory boot mode, Table 164: STM32WLE5xx/55xx bootloader versions, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices – title of Table 73: STM32WB30xx/35xx/50xx/55xx devices bootloader, Table 161: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode, Table 74: STM32WLE5xx/55xx devices bootloader, Table 163: STM32WLE5xx/55xx configuration in system memory boot mode, Table 98: Bootloader V12.x selection for STM32WLE5xx/55xx, Table 164: STM32WLE5xx/55xx bootloader versions
02-Dec-2020	46	<p>Updated:</p> <ul style="list-style-type: none"> – Table 3: Embedded bootloaders, Table 89: STM32G03xxx/G04xxx configuration in system memory boot mode, Table 101: STM32G47xxx/48xxx configuration in system memory boot mode, Table 140: STM32L43xxx/44xxx bootloader versions, Table 142: STM32L45xxx/46xxx bootloader versions <p>Added following notes:</p> <ul style="list-style-type: none"> – Note: on page 312, Note: on page 319, Note: on page 327, Note: on page 339, Note: on page 346

Table 183. Document revision history (continued)

Date	Revision	Changes
16-Feb-2021	47	<p>Updated:</p> <ul style="list-style-type: none"> – Table 1: Applicable products, Table 3: Embedded bootloaders, Table 8: ExitSecureMemory entry address, Table 88: STM32F76xxx/77xxx bootloader V9.x versions, Table 101: STM32G47xxx/48xxx configuration in system memory boot mode, Table 137: STM32L412xx/422xx configuration in system memory boot mode, Table 139: STM32L43xxx/44xxx configuration in system memory boot mode, Table 141: STM32L45xxx/46xxx configuration in system memory boot mode, Table 145: STM32L47xxx/48xxx configuration in system memory boot mode, Table 147: STM32L496xx/4A6xx configuration in system memory boot mode, Table 149: STM32L4P5xx/4Q5xx configuration in system memory boot mode, Table 151: STM32L4Rxxx/4Sxxx configuration in system memory boot mode, Table 153: STM32L552xx/562xx configuration in system memory boot mode, Table 161: STM32WB30xx/35xx/50xx/55xx configuration in system memory boot mode, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 180: USB bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices – Section 3: Glossary <p>Added Section 43: STM32G0B0xx device bootloader and Section 44: STM32G0B1xx/0C1xx device bootloader</p>
01-Apr-2021	48	<p>Updated:</p> <ul style="list-style-type: none"> – Table 1: Applicable products, Table 3: Embedded bootloaders, Table 8: ExitSecureMemory entry address, Table 177: Bootloader device-dependent parameters, Table 178: Bootloader startup timings (ms) for STM32 devices, Table 179: USART bootloader minimum timings (ms) for STM32 devices, Table 181: I2C bootloader minimum timings (ms) for STM32 devices <p>Added Section 45: STM32G05xxx/061xx devices bootloader and Section 48: STM32G491xx/4A1xx devices bootloader</p>
06-Jul-2021	49	<p>Updated:</p> <ul style="list-style-type: none"> – Section 3: Glossary, Section 28.2.1: Bootloader configuration – Table 3, Table 13, from Table 15 to Table 20, from Table 23 to Table 28, Table 29, Table 31, Table 33, Table 37, Table 39, Table 41, Table 43, Table 45, Table 47, Table 49, Table 51, Table 53, Table 55, Table 57, Table 59, Table 60, Table 61, Table 63, Table 65, Table 67, Table 69, Table 71, Table 73, Table 75, Table 77, Table 79, Table 81, Table 83, Table 85, Table 87, Table 89, Table 91, Table 93, Table 95, Table 97, Table 99, Table 101, Table 102, Table 103, Table 111, Table 113, Table 115, Table 115, Table 117, Table 119, Table 121, Table 122, Table 123, Table 125, Table 127, Table 129, Table 130, Table 131, Table 132, Table 133, Table 135, Table 136, Table 137, Table 139, Table 141, Table 143, Table 145, Table 147, Table 149, Table 151, Table 153, Table 161, Table 163, Table 177 <p>Added Table 154: STM32L552cc/562xx special commands and Section 72: STM32WB10xx/15xx devices bootloader</p>
23-Sep-2021	50	<p>Updated:</p> <ul style="list-style-type: none"> – Section 3: Glossary, Section 43.1: Bootloader configuration, Section 44.1: Bootloader configuration, – Table 1, Table 2, Table 3, Table 92, Table 112, Table 114, Table 116, Table 140, Table 160, Table 162, Table 177, Table 178, Table 179, Table 180, Table 181 <p>Added Section 76: STM32U575xx/85xx devices bootloader</p>

Table 183. Document revision history (continued)

Date	Revision	Changes
20-Oct-2021	51	Updated: – Table 3 , Table 60 , Table 92 , Table 112 , Table 177 – Section 28.2.1: Bootloader configuration
04-Feb-2022	52	Updated: – Section 3: Glossary , Section 4.1: Bootloader activation , – Table 1 , Table 2 , Table 3 , Table 7 , Table 92 , Table 114 , Table 177 – Figure 54 Added Section 5: STM32C011xx devices bootloader and Section 6: STM32C031xx devices bootloader
01-Mar-2022	53	Updated: – Table 3 , Table 111 , Table 112 , Table 177 . – Section 4.1: Bootloader activation , Section 41.1: Bootloader configuration , Section 42.1: Bootloader configuration , Section 43.1: Bootloader configuration , Section 45.1: Bootloader configuration
20-Apr-2022	54	Updated: – Table 3 , Table 111 , Table 115 , Table 116 , Table 177
22-Jun-2022	55	Updated: – Table 3 , Table 113 , Table 112 , Table 177
14-Dec-2022	56	Added Section 4.8: IWDG usage in Bootloader , Section 71: STM32WBA52xx devices bootloader Updated: – Table 1 , Table 2 , Table 3 , Table 7 , Table 114 , Table 115 , Table 164 , Table 177 , Table 178 , Table 179 , Table 181 – Section 3: Glossary , Section 4.1: Bootloader activation – added note 1 in Table 91 , Table 93 , Table 95 , Table 99 , Table 101 , Table 103 , Table 137
21-Feb-2023	57	Updated: – Table 1: Applicable products , Table 2: Bootloader activation patterns , Table 3: Embedded bootloaders , Table 7: Flash memory alignment constraints on STM32 products , Table 177: Bootloader device-dependent parameters , Table 178: Bootloader startup timings (ms) for STM32 devices , Table 179: USART bootloader minimum timings (ms) for STM32 devices , Table 180: USB bootloader minimum timings (ms) for STM32 devices , Table 181: I2C bootloader minimum timings (ms) for STM32 devices – Section 3: Glossary , Section 4.2: Bootloader identification Added Section 49: STM32H503xx devices bootloader , Section 50: STM32H563xx/573xx devices bootloader , Section 77: STM32U595xx/599xx/5A5xx/5A9xx devices bootloader
04-Apr-2023	58	Updated: – Table 1: Applicable products , Table 3: Embedded bootloaders , Table 177: Bootloader device-dependent parameters , Table 178: Bootloader startup timings (ms) for STM32 devices , Table 179: USART bootloader minimum timings (ms) for STM32 devices , Table 180: USB bootloader minimum timings (ms) for STM32 devices , Table 181: I2C bootloader minimum timings (ms) for STM32 devices – Section 3: Glossary Added Section 75: STM32U535xx/545xx devices bootloader

Table 183. Document revision history (continued)

Date	Revision	Changes
21-Jun-2023	59	Updated Table 3: Embedded bootloaders , Table 92: STM32G07xx/08xxx bootloader versions , and Table 177: Bootloader device-dependent parameters . Minor text edits across the whole document.
25-Oct-2023	60	Updated Section 2: Related documents , note in Section 4.1: Bootloader activation , Section 50.3: Bootloader version , and Section 63.1: Bootloader configuration . Updated Table 2: Bootloader activation patterns , Table 3: Embedded bootloaders , Table 62: STM32F401xB(C) bootloader versions , Table 95: STM32G0B1xx/OC1xx configuration in system memory boot mode , Table 105: STM32H503xx configuration in system memory boot mode , Table 108: STM32H563xx/573xx configuration in system memory boot mode , Table 110: STM32H563xx/573xx bootloader version , Table 111: STM32H72xxx/73xxx configuration in system memory boot mode , Table 113: STM32H74xxx/75xxx configuration in system memory boot mode , Table 115: STM32H7A3xx/7B3xx configuration in system memory boot mode , Table 153: STM32L552xx/562xx configuration in system memory boot mode , Table 155: STM32L552xx/562xx bootloader versions , Table 165: STM32U535xx/545xx configuration in system memory boot mode , Table 165: STM32U535xx/545xx configuration in system memory boot mode , Table 167: STM32U535xx/545xx bootloader versions , Table 170: STM32U575xx/85xx bootloader versions , Table 171: STM32U595xx/599xx/5A5xx/5A9xx configuration in system memory boot mode , Table 173: STM32U595xx/599xx/5A5xx/5A9xx bootloader versions , and Table 178: Bootloader startup timings (ms) for STM32 devices . Updated Figure 61: Bootloader V14 selection for STM32H503xx , Figure 62: Bootloader V14 selection for STM32H563xx/573xx , Figure 99: Bootloader V9.x selection for STM32U535xx/545xx , Figure 100: Bootloader V9.x selection for STM32U575xx/85xx , and Figure 101: Bootloader V9.x selection for STM32U595xx/599xx/5A5xx/5A9xx . Minor text edits across the whole document.
11-Jan-2024	61	Added STM32U5F7xx, STM32U5F9xx, STM32U5G7xx, and STM32U5G9xx devices. Updated Table 1: Applicable products , Table 3: Embedded bootloaders , and tables 177 to 181 . Updated Section 3: Glossary . Added Section 78: STM32U5F7xx/5F9xx/5G7xx/5G9xx devices bootloader and its subsections. Minor text edits across the whole document.

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